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# **NextGEng Project**

## **WP3**

### **International team-teaching pilot program**

#### **Deliverable 3.5c**

#### **Developed laboratory work, tailored seminars for course C5 and C6**

September 2024



<b>WP3</b>	<b>R3.5c - Developed laboratory work, tailored seminars for course C5 and C6</b>
<b>Authors</b>	Ciprian Rad
<b>Short Description</b>	This report presents the results of the laboratory worked, tailored seminars developed for courses C5 and C6 within second round of course and laboratory upgrading process in WP3.
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<b>Contributions by:</b>	Ciprian Lapusan
<b>Project web site</b>	<a href="http://www.nextgeng.eu">www.nextgeng.eu</a>

#### Document History

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Final	29.09.2024	Ciprian Rad	Final Version

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## 1. Introduction

This report presents the outcomes of the course upgrading and team-teaching development carried out within WP3 of the NextGEng project. The implementation process led to the creation of **5 new laboratory activities and tailored seminars** were created in cooperation with industry partners, including ISR (3 labs), Valmet (4 labs), and Bosch (4 labs). These activities strengthen the applied dimension of the curriculum and enhance the connection between academic learning and industrial practice.

The development process was highly collaborative, involving **16 coordination meetings** across the co-teaching teams of courses C5 and C6, with the participation of **12 higher-education teachers** and **5 industry experts**. This joint effort ensured alignment of content, consistent implementation across institutions, and the integration of industry-relevant competencies.

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In the next Chapters the produced laboratories modules are presented.



## 2. Laboratories topics

### C5 - Computer Aided Design

Laboratory 1 – Design of a Specular Vision System (in collaboration with ISR)

Laboratory 2 – Fit-for-purpose 3D modelling (in collaboration with VALMET)

Laboratory 3 - Design of parametrized parts with applications in logistics (in collaboration with BOSCH)

### C6 - Manufacturing Technology

Laboratory 1 - Additive manufacturing at Valmet (in collaboration with VALMET)

Laboratory 2 - Solder Paste Printing Process (in collaboration with BOSCH)



# C5 – Computer Aided Design

## L1 – Design of a Specular Vision System

P3-ISR

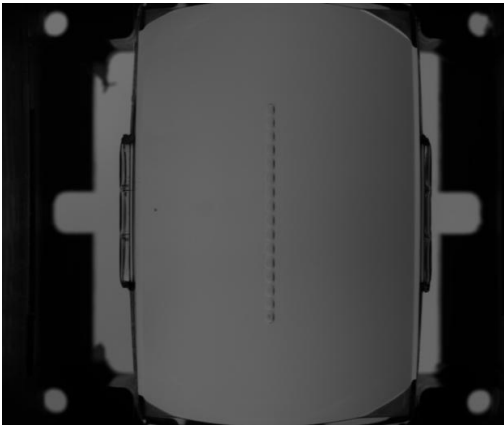
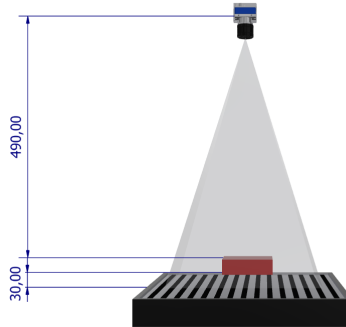
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# Computer Aided Design

## Project work - Design of a Specular Vision System



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# Design of a Specular Vision System demonstrative stand

## Project overview:

### Objectives

- Design a demonstrative stand for a specular vision system, aiming to illustrate the principles of light reflection and image formation on reflective surfaces
- The stand should integrate optical components, mechanical supports, and measurement/observation tools for vision-related applications

### Pre-requisite

- Basic skills and knowledge of SolidWorks and of technical drawings
- Mechanical Design Fundamentals - machine elements and supports
- Basic knowledge of measurement techniques and optics

### Equipment used for laboratory

- PCs with SolidWorks



# Design of a Specular Vision System demonstrative stand

**Upon completion of this activity, the student will be able to:**

- 1) Explain the principles of light reflection and image formation on specular surfaces
- 2) Design and assemble a demonstrative stand integrating optical components, mechanical supports, and measurement/observation tools, considering technical specifications, alignment, functionality, and cost-effectiveness
- 3) Document, present, and justify design choices; evaluate system performance;

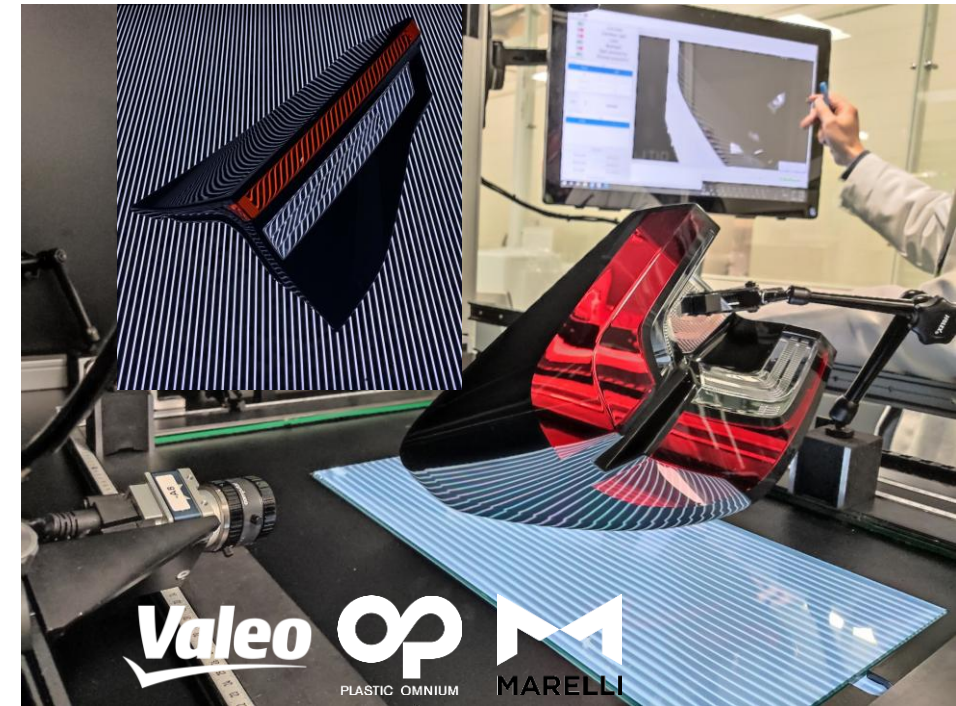


# Content

- Introduction
  - Motivation and relevance of specular vision in engineering and applied sciences.
  - Theoretical concepts related to Specular Vision
  - Industrial applications that use Specular Vision
- Project task description
  - Design requirements and constraints
  - Technical specifications
  - Aesthetic and Promotional Aspects
- Summary, Discussions & Feedback



# What is Specular Vision



Automatic inspection of aesthetic quality of parts and components with specular surfaces (transparent and reflective), using artificial vision equipment and patented lighting systems in:

✓ Optical Inspection Technology [OIT®]

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# How is the process

The eyes of the industry

I need to inspect  
**automatically** this part.



In less than 20 s!



Free-of-charge feasibility study based on  
Artificial Vision Techniques



**ISR Team**  
(Innovation and  
Engineering)

**Industry Professional**  
(our customer)

## Industrial Inspection System OIT ®

- ✓ Flexible solutions
- ✓ 4.0. Ecosystem
- ✓ Customer driven quotations
- ✓ Adapted to surface



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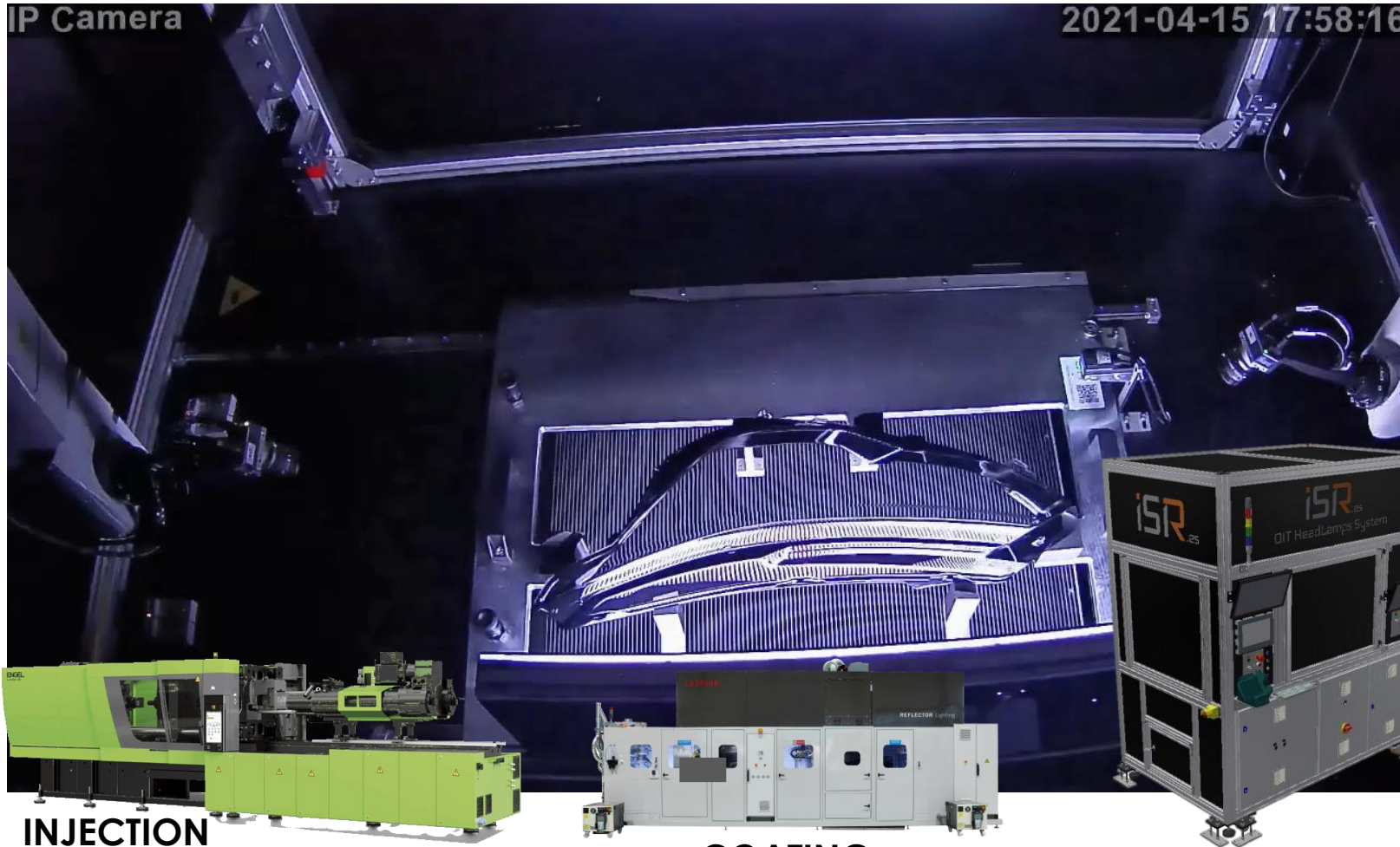
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# Our OIT solutions in industry

The eyes of the industry

Success Case: OIT HeadLamps (HL) / RearLamps (RL) System



INJECTION

COATING

- **Specular Vision® technology adaptation** considering productive process requirements.
- New **HL / RL models** integration through Vision Jig development.

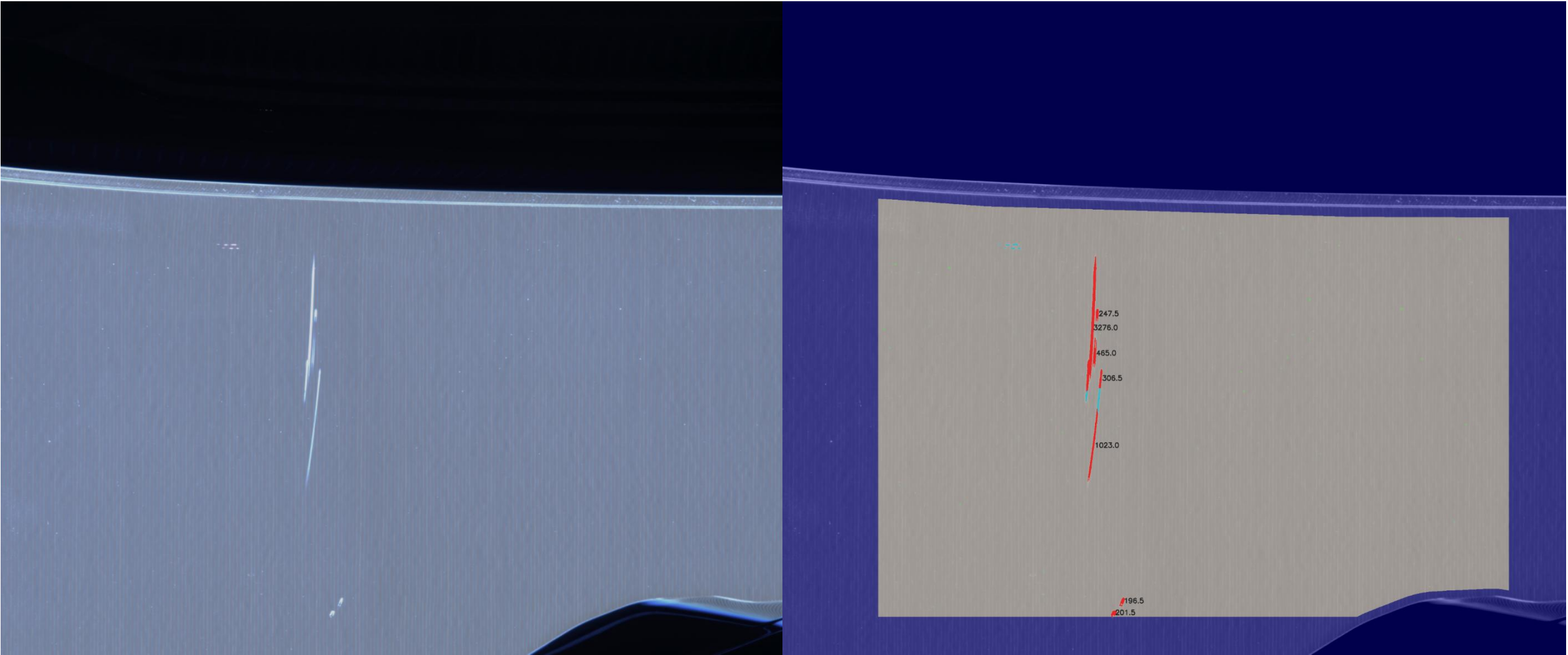


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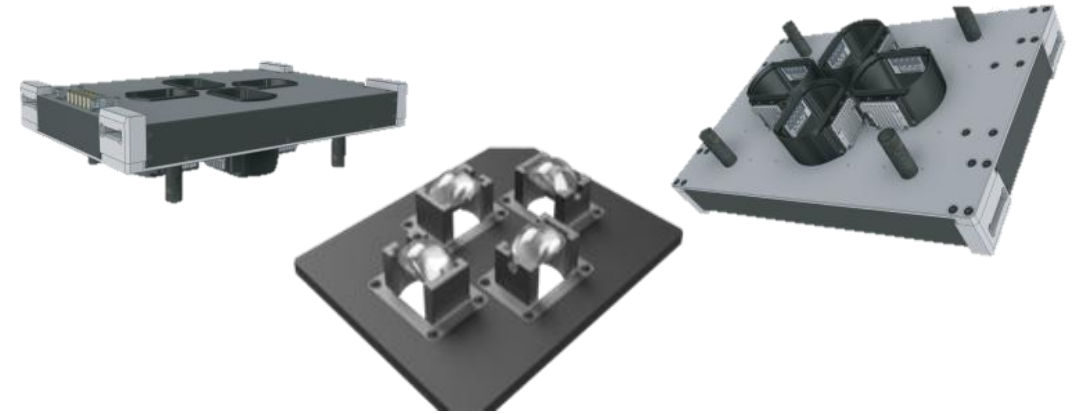
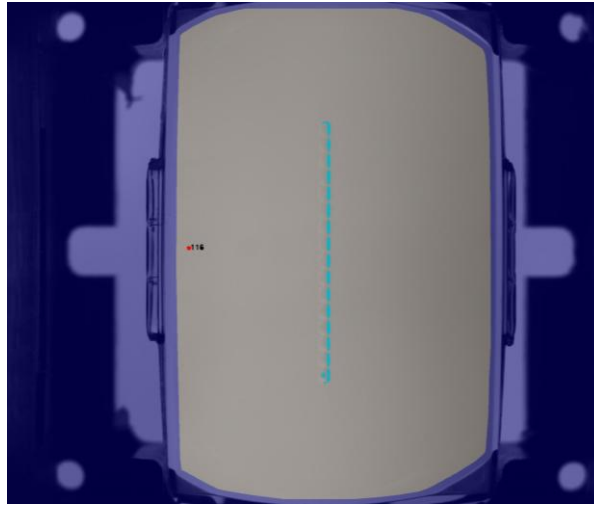
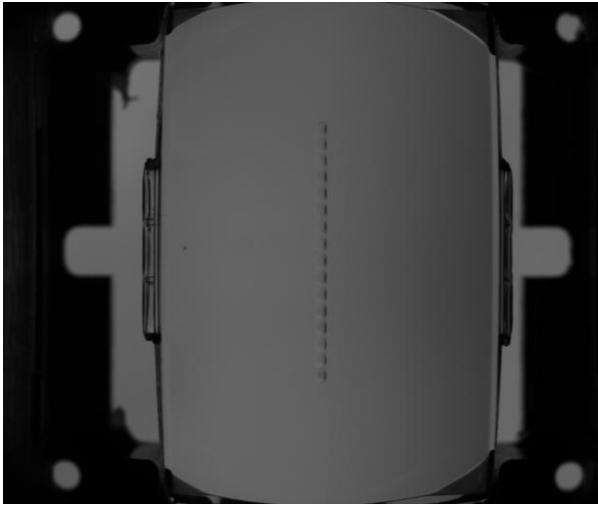


Success Case: OIT HeadLamps (HL) / RearLamps (RL) System



# Our OIT solutions in industry

Success Case: OIT Thick Lenses Inspection System

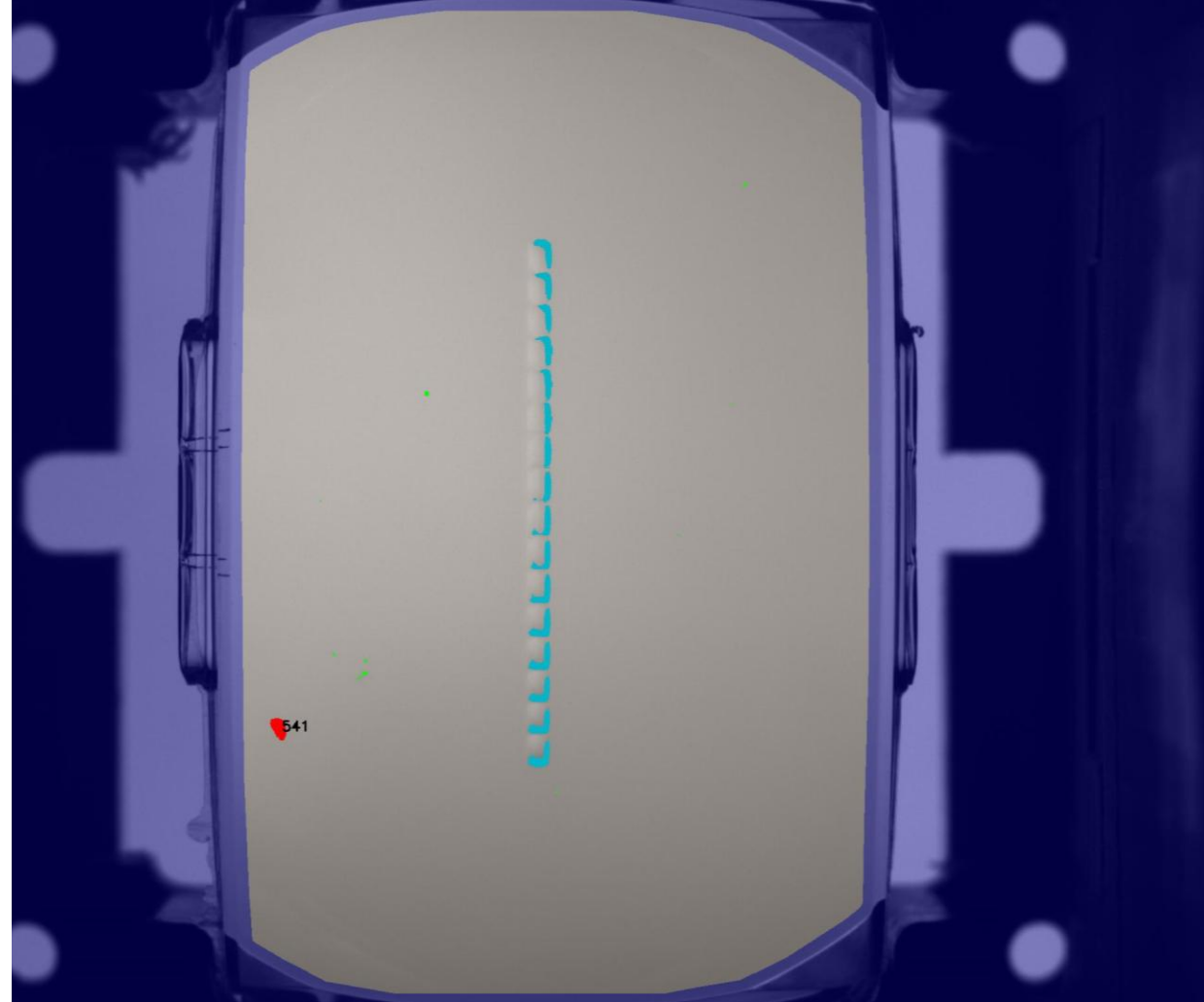


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# Our OIT solutions in industry

Success Case: OIT Thick Lenses Inspection System



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# Design challenge: Demonstration System for ISR Inspection Technology

## Context and Objective

- Given the need to demonstrate to the public the capabilities of the inspection technology developed by ISR, the design of a compact, functional, and visually attractive demonstration system is proposed. This system will be transferred to Stemmer Imaging, camera supplier and technology partner, for use at trade shows and events such as the upcoming edition in Barcelona. The objective is to increase the visibility of the inspection technology developed by ISR, through a demonstrator that allows its use in exhibition environments without compromising technical quality or incurring unnecessary costs

### Restrictions and economic considerations

This system will not generate direct revenue, so the design must prioritize low-cost solutions, using readily available or inexpensive materials without compromising functionality or display aesthetics.



# Design challenge: Demonstration System for ISR Inspection Technology

## Functional concept of the system

- The system is based on the inspection of transparent parts using image composition generated between an illumination panel (LCD) and a camera placed in front of it, pointing towards the screen. The part to be inspected is positioned between these two elements, allowing the evaluation of defects or properties using artificial vision techniques adapted to transparent surfaces.



# Demonstration System for ISR Inspection Technology

## Technical specifications and requirements

- **Maximum system dimensions:** 800 x 800 x 1600 mm. A reduction in these dimensions is prioritized to facilitate installation on a table. If these dimensions are exceeded, the system must be equipped with wheels to allow for transport.
- **Weight:** It should be limited if used on a tabletop. In freestanding installations, weight is not a limiting factor, provided the solution is stable and easily movable.
- **Part to be inspected:** Maximum size of 200x200mm. The system must integrate centering devices or fixings for:
  - Inspection BILED lens

# Demonstration System for ISR Inspection Technology

## Components to be integrated:

- Industrial inspection camera
- 19-inch LCD panel
- Industrial PC and switch
- Additional screen for displaying results and system configuration (visible at 2-3 m distance)

## Physical and ergonomic design:

- Closed structure with side access (removable door or panel with magnetic fixings)
- Height adjustment of the chamber to adjust the distance to the panel according to the test configuration.
- Possibility of table mounting or in a free-standing configuration with casters






# Demonstration System for ISR Inspection Technology

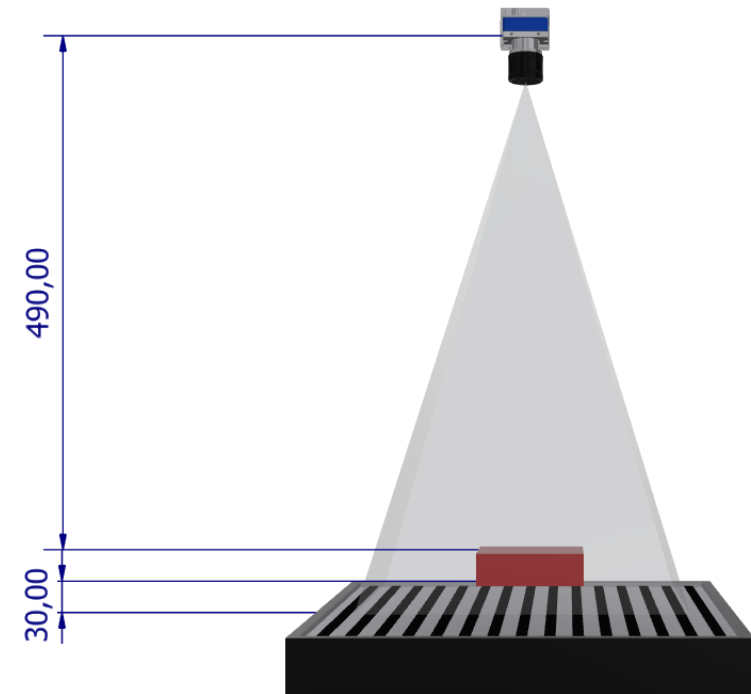
## Visual and promotional aspects:

- Striking and professional design, aimed at capturing the attention of visitors at trade shows
- Incorporation of graphic elements or screen printing that reinforce the visual identity of ISR
- Adequate arrangement of the system to facilitate interaction and observation of the process from various angles

# Demonstration System for ISR Inspection Technology

Upon completion of this project, the student will be able to:

- 1) Analyze and interpret technical requirements.
- 2) Apply optical and vision-based inspection principles. 
- 3) Design a compact and functional demonstrator system.
- 4) Evaluate cost-effectiveness and technical feasibility.





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# C5 – Computer Aided Design

L2 - Fit-for-purpose 3D modelling

P5 - Valmet

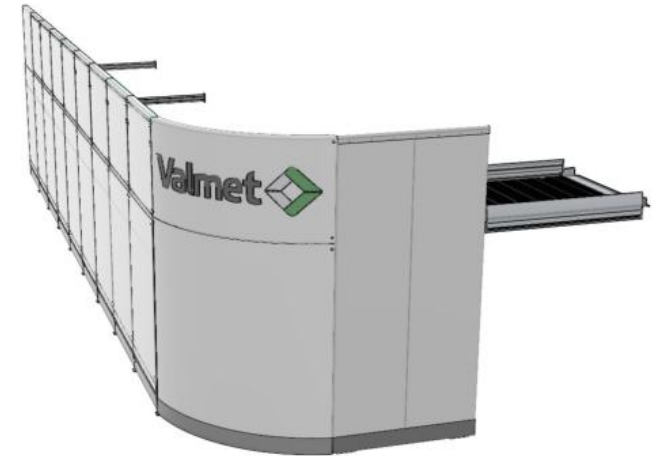
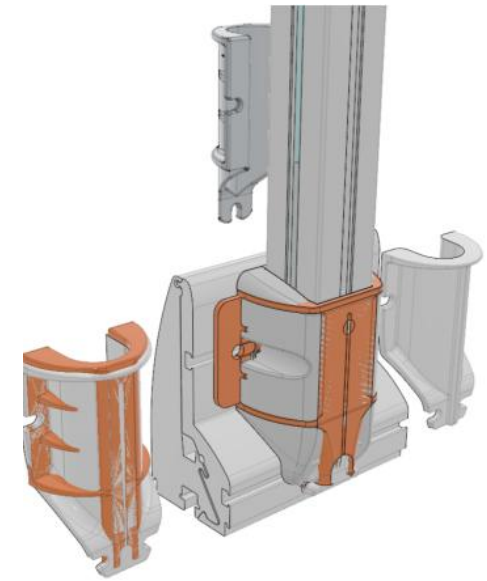
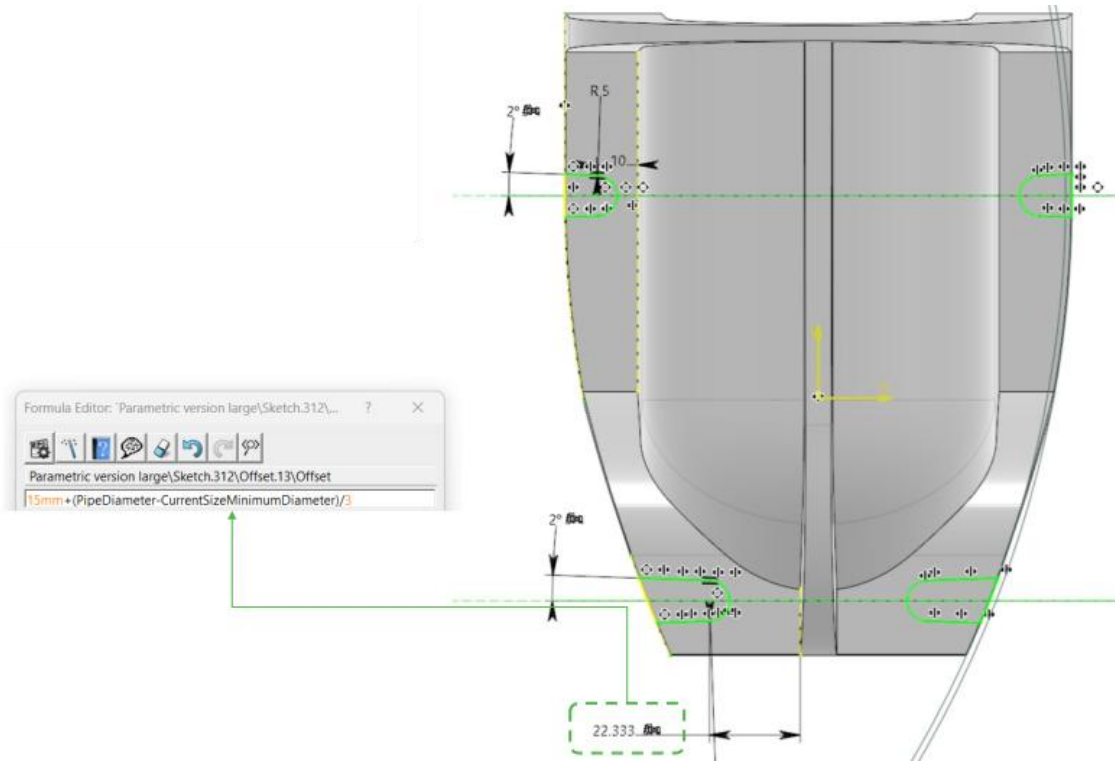
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# Computer Aided Design

## Laboratory work - Fit-for-purpose 3D modelling



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# Fit-for-purpose 3D modelling

## Laboratory overview:

### Objectives

- acquire the ability to apply different levels of modelling—ranging from PowerPoint CAD and concept models to engineering/development and parametric models—in a resource-efficient manner.
- The activity integrates lean and agile principles, and fosters critical decision-making skills in selecting a “fit-for-purpose” level of detail, thereby avoiding unnecessary complexity and optimizing the modelling process

### Pre-requisite

- Basic skills of CAD/3D modelling software
- Fundamentals of manufacturing/product engineering
- Awareness of LEAN and agile principles (avoiding over-processing, maximizing value)

### Equipment used for laboratory

- PCs with Katia



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# Fit-for-purpose 3D modelling

**Upon completion of this activity, the student will be able to:**

- 1) Select and justify the appropriate modelling approach for a given design task based on its purpose and available resources;
- 2) Create 3D models at different levels of resolution (from quick sketches to parameterized models) while avoiding unnecessary features and complexity;
- 3) Assess when (and when not) parametric modelling or high-detail modelling is worth the additional effort;



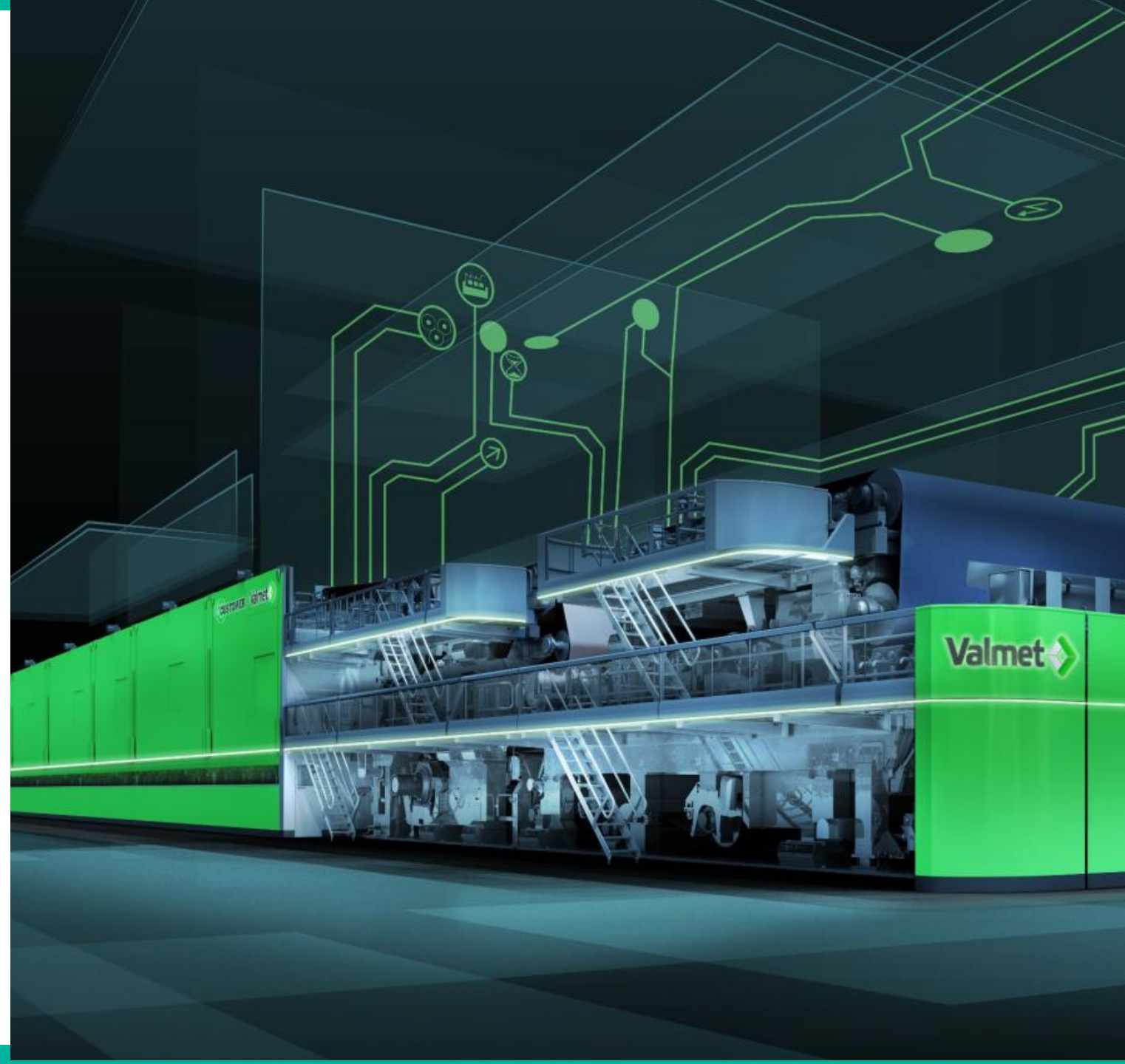


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# Content

- Introduction
- Valmet company introduction
- Modeling 4 different type cases
  - Power point -CAD
  - Concept models
  - Development/engineering models
  - Parametric models
- Summary, Discussions & Feedback





# 1 | Introduction

## 2 | Valmet company introduction

# This is Valmet

We aim to become the global champion in serving our customers. Our 14,000 professionals around the world work close to our customers and are committed to moving our customers' performance forward – every day.



- Market's widest offering combining process technologies, services and automation
- Research and development spend EUR 71 million in 2019



## Market leadership

- Leading market position in all markets
- Pulp #1–2
- Energy #1–3
- Board #1
- Tissue #1
- Paper #1
- Services #1–2
- Automation #1–3



## Strong global presence

- Approx. 100 service centers
  - 96 sales offices
  - 39 production units
  - 16 R&D centers
  - 14,000 professionals
- |               |       |
|---------------|-------|
| EMEA          | 8,700 |
| China         | 1,800 |
| North America | 1,700 |
| Asia-Pacific  | 900   |
| South America | 500   |



## Leader in sustainability

- Eight consecutive years in Dow Jones Sustainability Index
- Four consecutive years in Ethibel Sustainability Index Europe
- A- rating in CDP climate program 2020

# A strong financial profile and balanced business portfolio

## 2022 key figures of Valmet

**Orders received**  
EUR 5,194 million

**Net sales**  
EUR 5,074 million

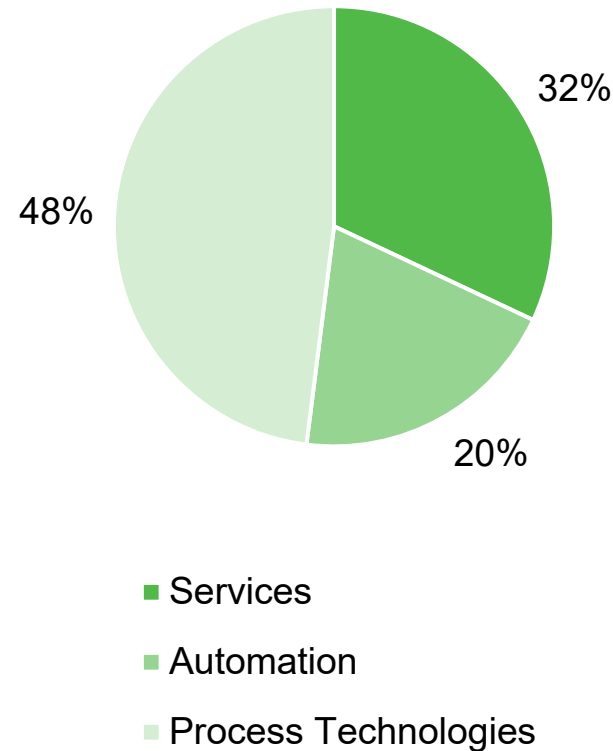
**Comparable EBITA**  
EUR 533 million

**Comparable EBITA margin**  
10.5%

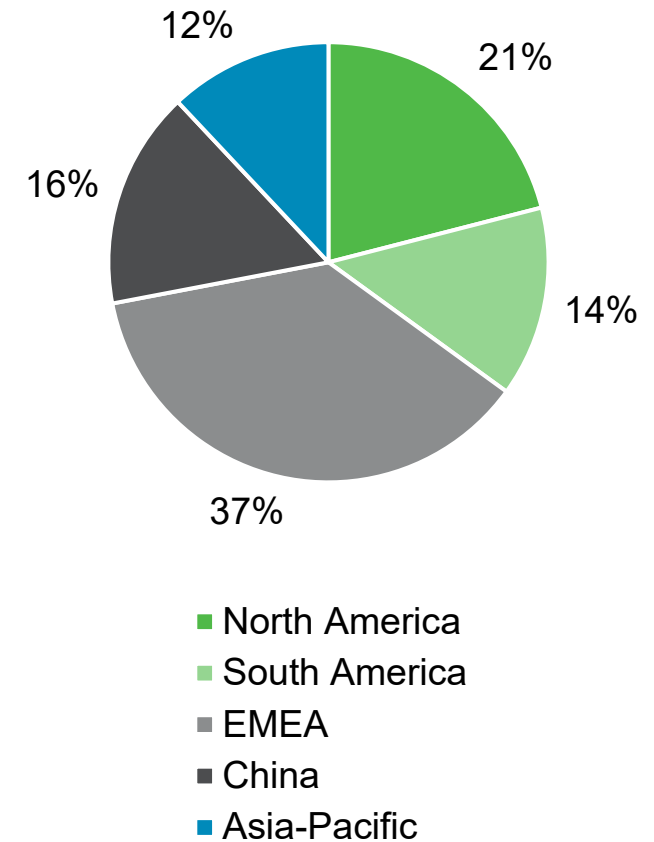
**Order backlog**  
EUR 4,403 million

**Employees**  
19 000+

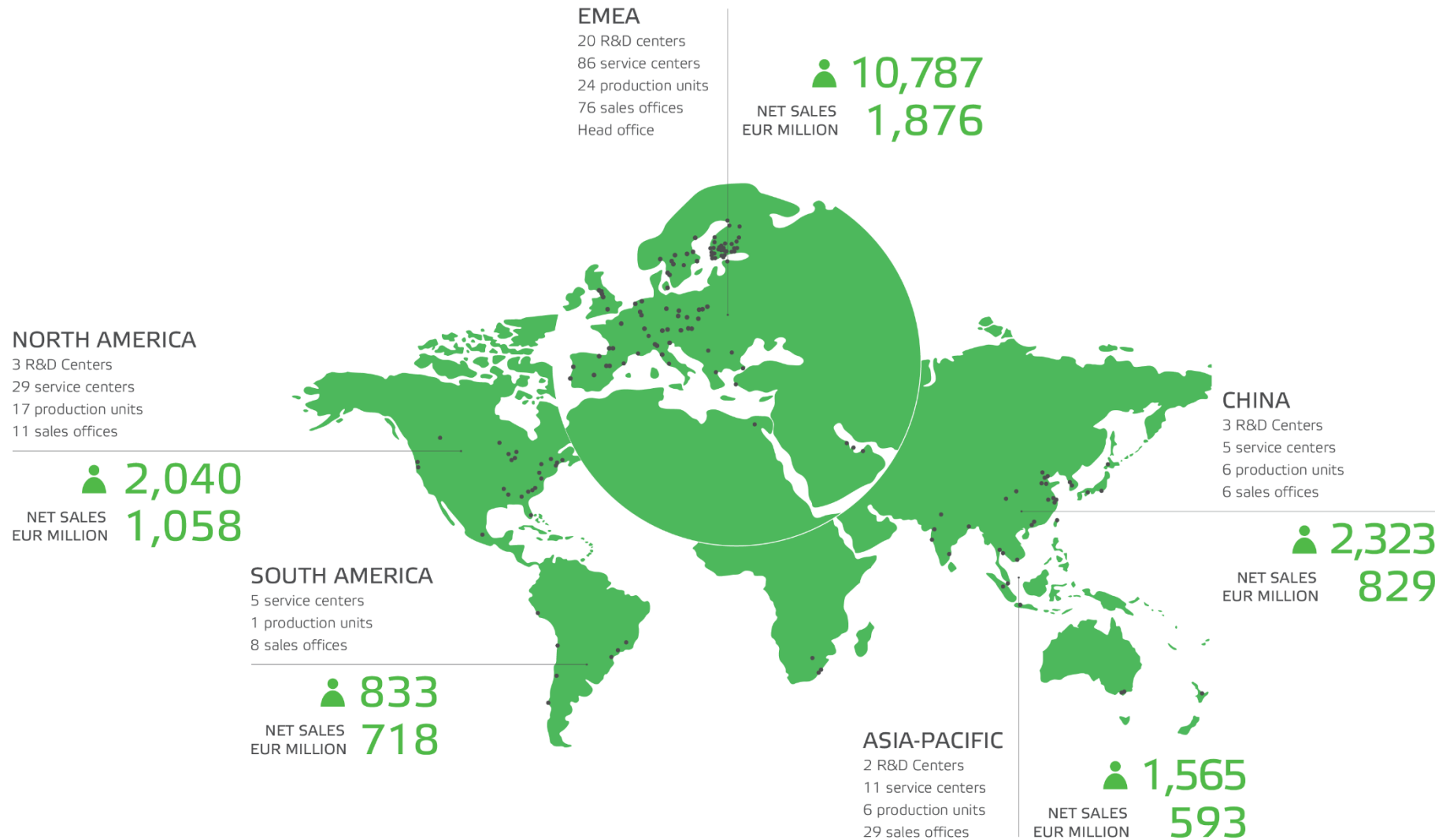
Net sales by segment



Net sales by area



# Global presence creating a good platform for growth




# Global presence creating a good platform for growth

## Spain | 6 Valmet locations

**Barcelona** | Valmet Flow Control Services, valves & spare parts  
**Bilbao** | Pulp and Paper Sales & Service  
**Madrid** | Automation Sales & Service  
**Zaragoza** | Services  
**Zaragoza** | Maintenance center  
**Zaragoza** | Roll Service Center

### EMEA

20 R&D centers  
86 service centers  
24 production units  
76 sales offices  
Head office

 **10,787**  
NET SALES  
EUR MILLION **1,876**

### NORTH AMERICA

3 R&D Centers  
29 service centers  
17 production units  
11 sales offices

 **2,040**  
NET SALES  
EUR MILLION **1,058**

### SOUTH AMERICA

5 service centers  
1 production units  
8 sales offices

 **833**  
NET SALES  
EUR MILLION **718**

### CHINA

3 R&D Centers  
5 service centers  
6 production units  
6 sales offices

 **2,323**  
NET SALES  
EUR MILLION **829**

### ASIA-PACIFIC

2 R&D Centers  
11 service centers  
6 production units  
29 sales offices

 **1,565**  
NET SALES  
EUR MILLION **593**



**>130**  
service centers



**>50**  
Production  
units



**28**  
R&D centers

# General overview of a paper/board machine | Tending side view

## Headbox

- Hundreds of side-by-side nozzles sprays the pulp – a mixture of water and natural fibers – on top of a fabric.

## Former (forming section)

- The web is formed and moved between the fabrics, because the material is still too wet to hold its own weight.
- The speed of which the web is moving is typically ~1200-1600 m/min (~60-100 km/h).
- Water is removed mainly gravitationally, with some help of vacuums.

## Press

- Water is removed mechanically by pressing the web between "nips" that are created by two rolls.
- When the web enters the press section, it is already strong enough to support itself and so dry that the drying principle need to be changed (= forming is not viable anymore).

## (Pre-)Dryer

- The web is dried to its final dryness with multiple groups of steam-heated cylinders.
- Drying section is covered with a hood, keeping the ambient temperature stable and ensuring good energy-efficiency.
- Temperature inside the hood is very high, up to 100-120°C. People are generally not allowed inside it when the machine is running.



# General overview of a paper/board machine | Tending side view

## Sizer

- Gluing and coatings are applied to the surface of the web to obtain the desired paper/board properties.
- Mainly the tensile strength and surface quality are being improved.

## After-Dryer

- Coatings applied on the sizer section are dried.
- Functionalities and environment are identical to the pre-dryer.

## Calender

- Surface quality of the web is being improved in nips. The amount of nips may vary.
- This process step produces the desired thickness and a smooth and glossy finish.

## Reel

- The finished product is rolled to large parent rolls.
- A temporary store of the parent rolls is located next to the reel section
- Weight of the rolls can be up to 100 tons.

## Winder

- Large rolls are "winded": They are cut in the machine direction to smaller customer rolls that are better sized for further processing.
- Speeds are considerably higher than with the production process, of up to 3000 m/min (180 km/h).







Traditional paper machine  
Valmet | Around 1970-1980s



The Valmet logo is displayed on the side of a large, white, curved industrial machine. It consists of the word "Valmet" in a bold, black, sans-serif font, followed by a green graphic element that resembles a stylized arrow or a folded piece of paper pointing to the right.

## 3 | Modelling

### 4 different types of cases

**Disclaimer:** The times stated in the modelling example are times it took to reverse engineer / 3D-model the features. Development times are an order of magnitude longer than what it takes just to model the geometries.



# practical resolution

= aiming for the smallest possible effort  
that achieves the set targets

See also:

- *"The art of maximizing the amount of work not done"* as a foundational principle in agile software development or
- *"Extra processing"* as one of the eight wastes of LEAN

10 Minutes

= a proper amount of time used  
if the target is to draw...

***“a nicely shaded  
representation of a  
Spiderman”***

Comparable to a “product model”  
in 3D-modelling

1 minute

= a proper amount of time used  
if the target is to draw...

***“a clean representation  
of a Spiderman”***

Comparable to an “engineering /  
development model”  
in 3D-modelling

10 seconds

= a proper amount of time used  
if the target is to draw...

***“a recognizable  
Spiderman”***

Comparable to a napkin sketch,  
“PowerPoint CAD” or a “3D sketch”



# Bonus question

When the equivalent “*a photorealistic representation of a Spiderman*” would be justified in 3D modelling in engineering context?

(almost)

## Never

In a world of finite resources, perfect is the opposite of good.

(Comparable to a parametric model with an excessive range of adjustability in 3D-modelling)

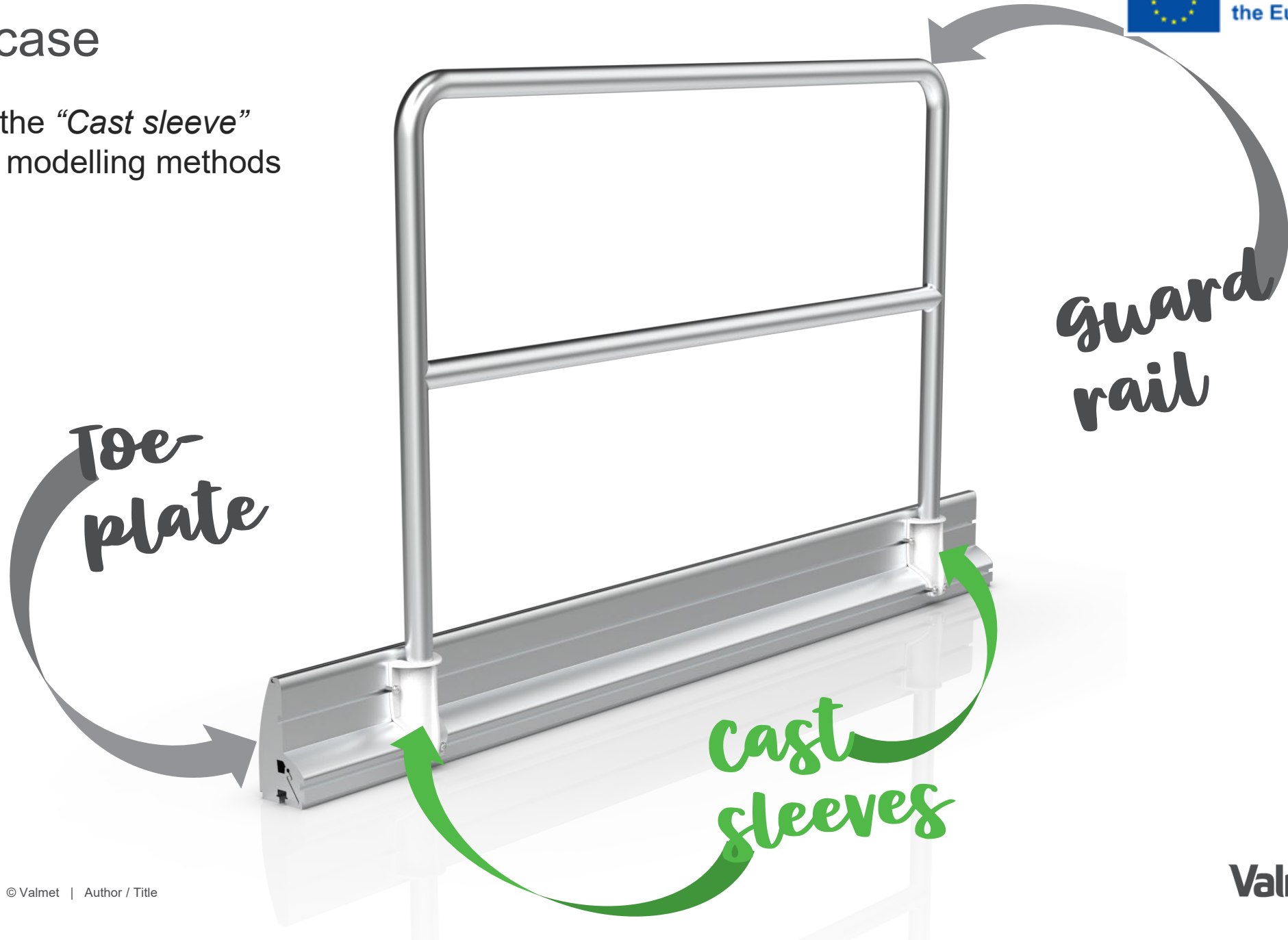


Screenshot: neilyong05 (TikTok)



# Example case

Today we'll do the "*Cast sleeve*"  
with 4 different modelling methods



## 3A. PowerPoint CAD

Essentially first visualizations of an idea to get everyone understand the idea the same way

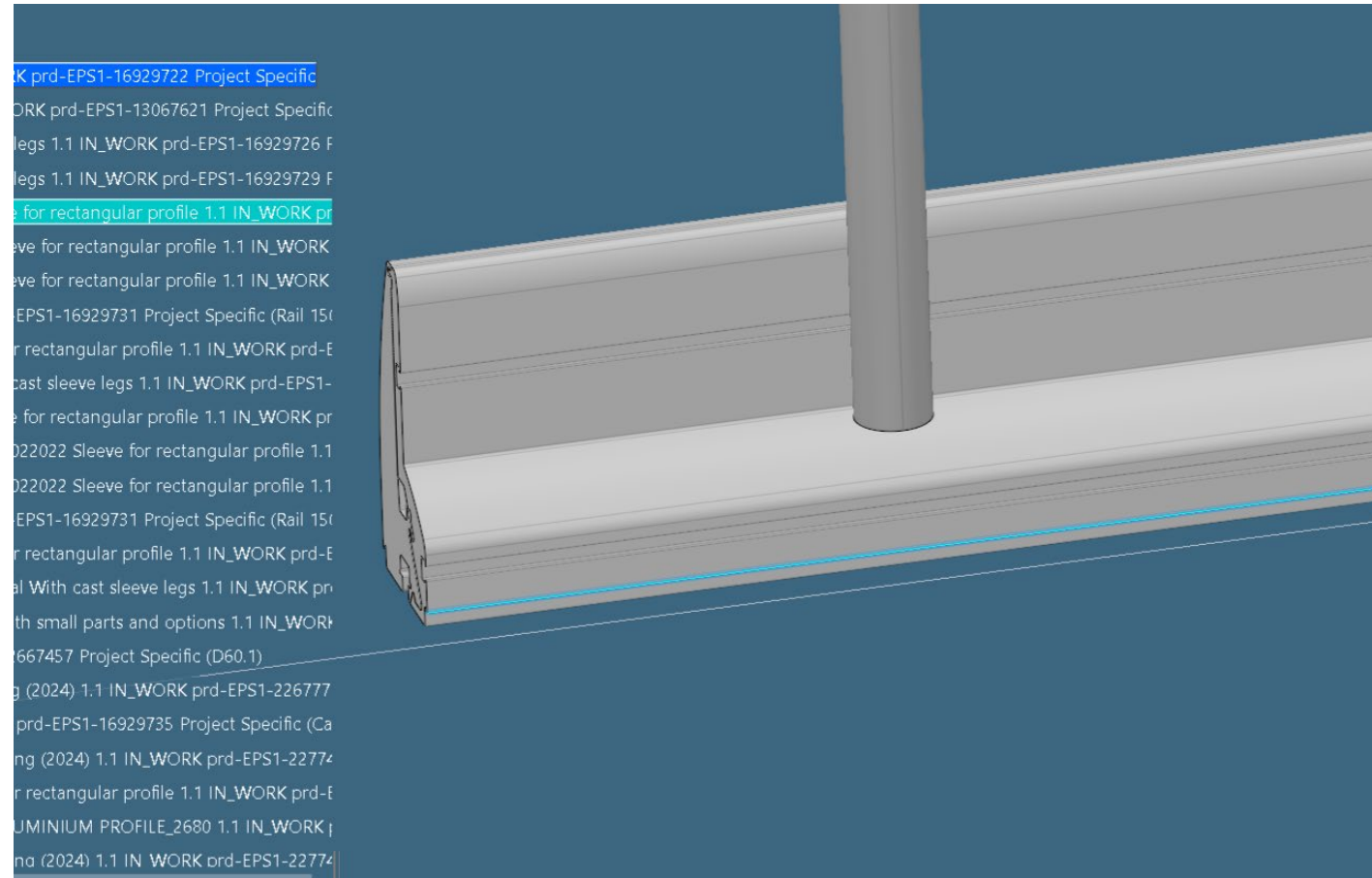
Examples:

10 seconds for the first example

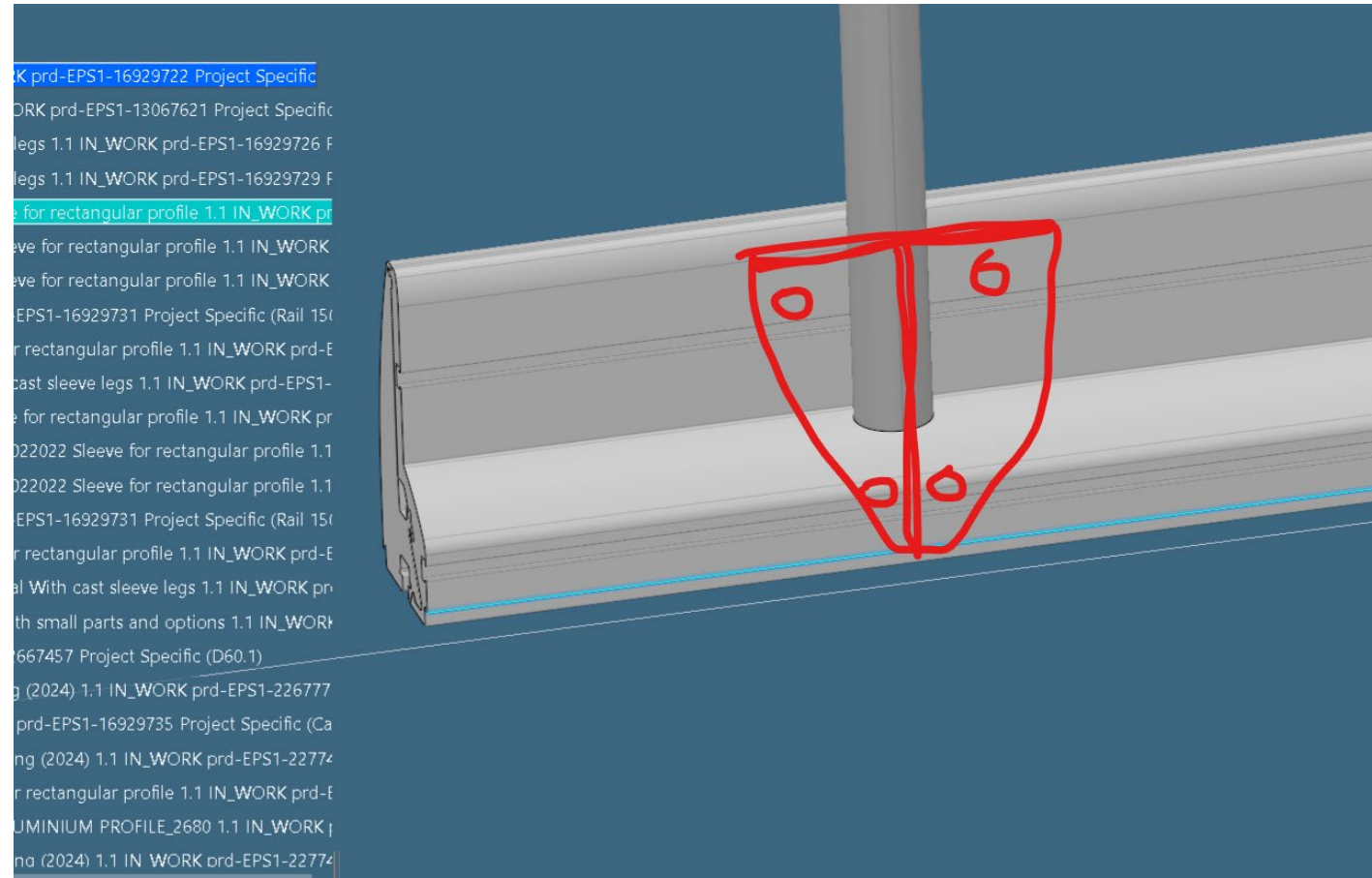
1 minute for the second example

10 minutes for the third example

# 10 seconds



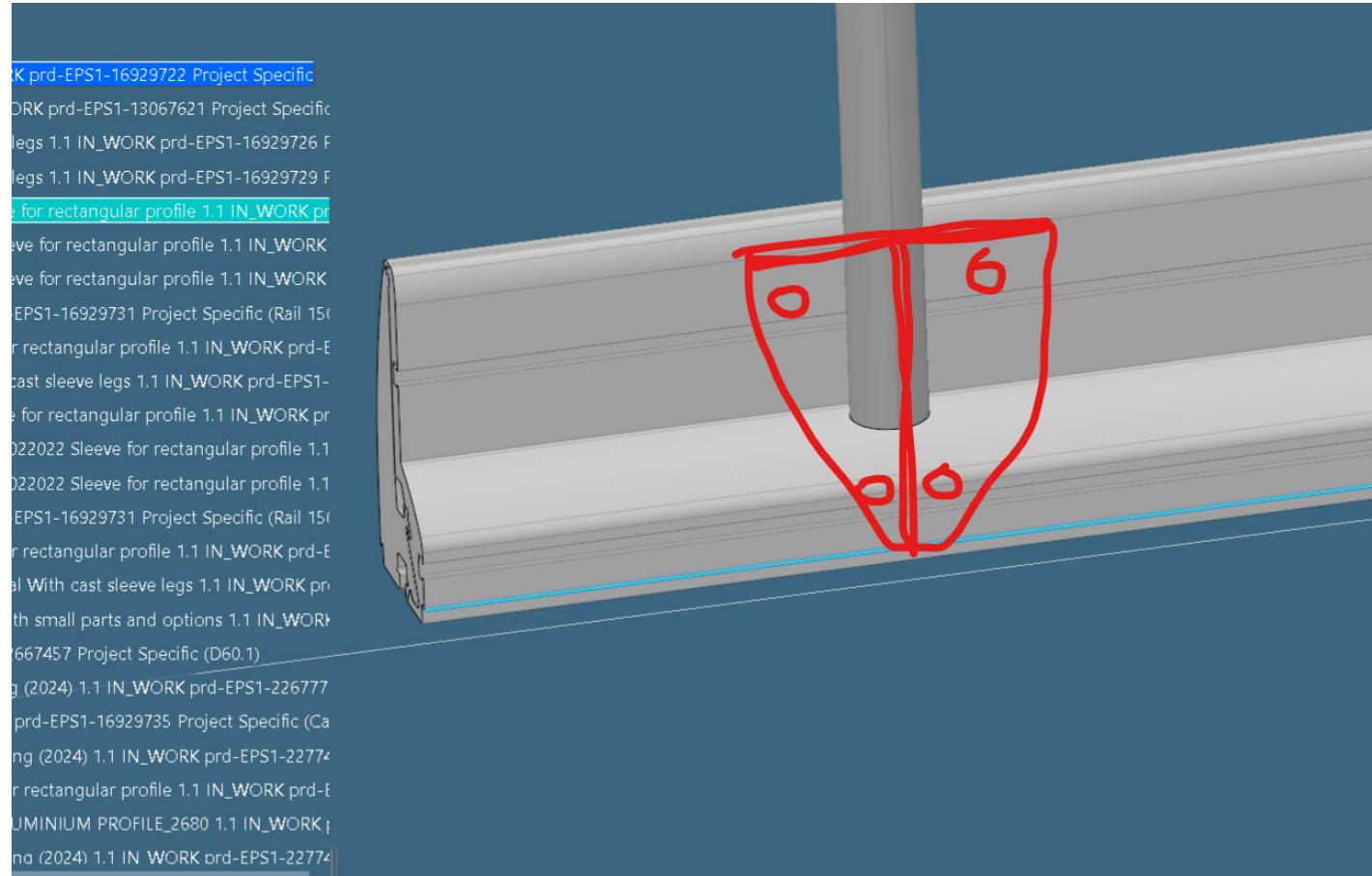
# 10 seconds



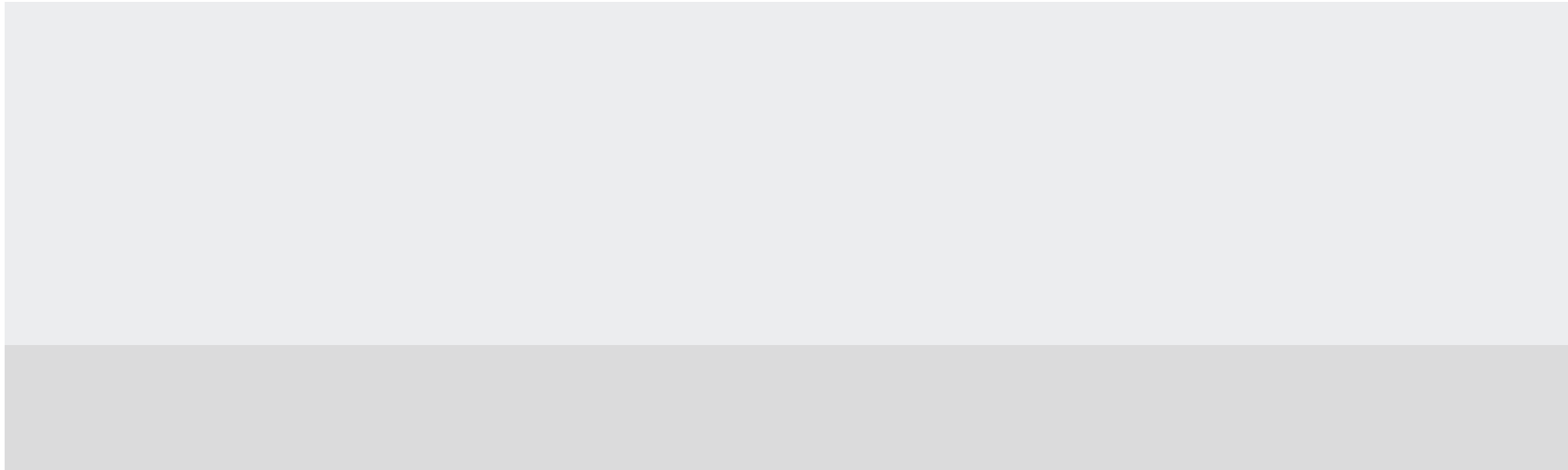
# 10 seconds

Uusi valuholkki

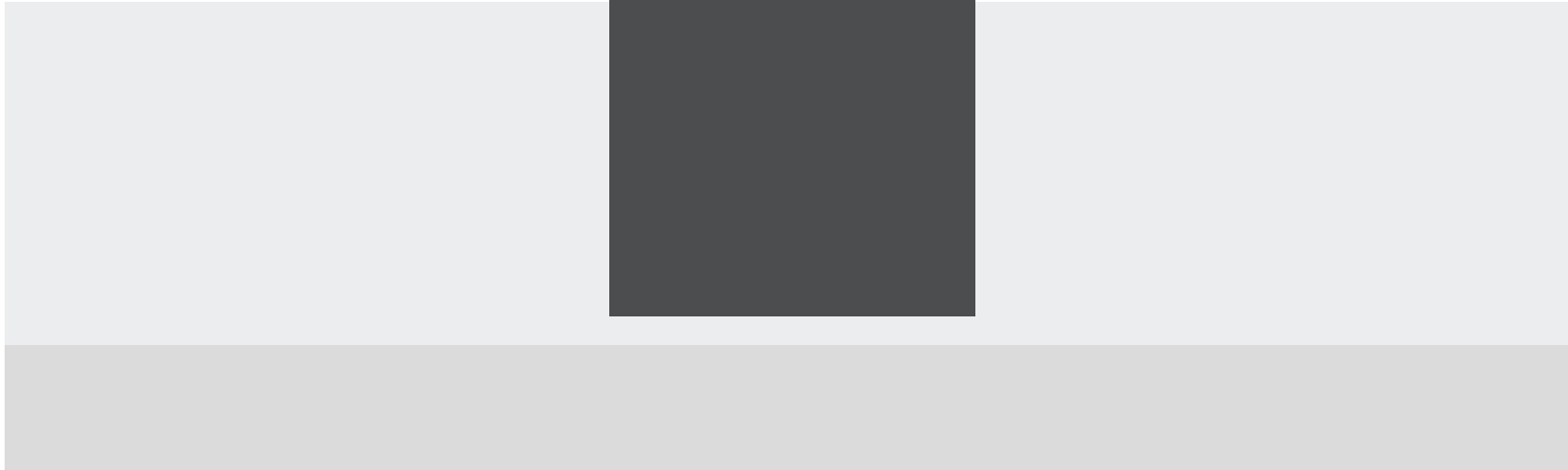
Vesa mallintaa  
ensi palaveriin



# 1 minute

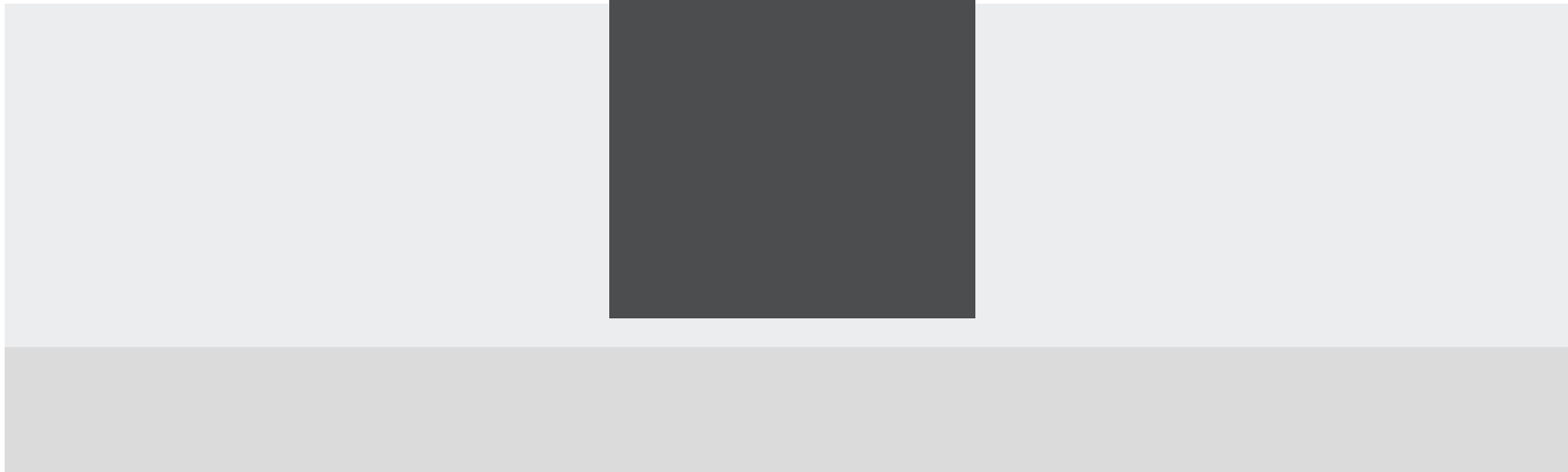


# 1 minute





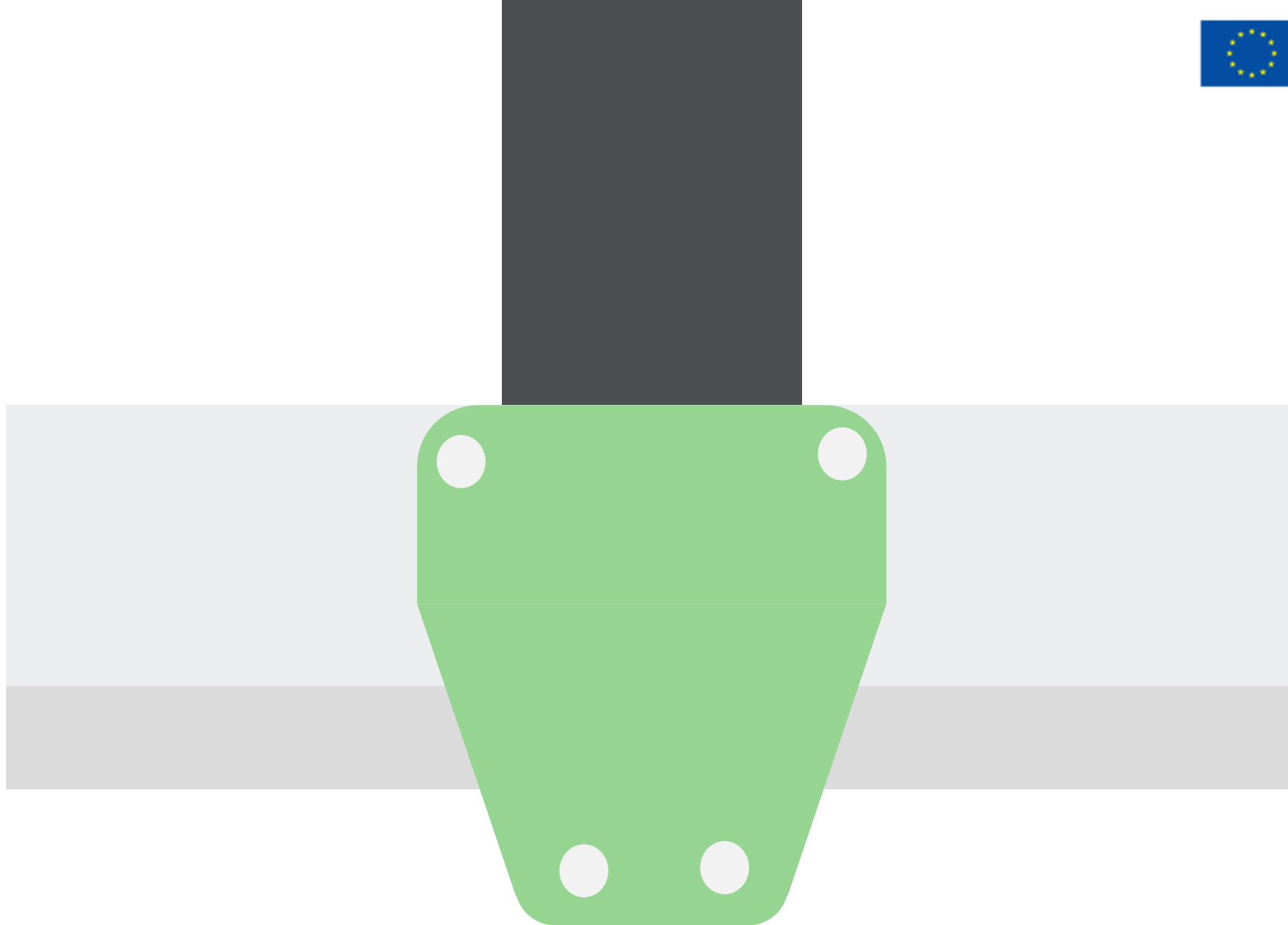
# 1 minute



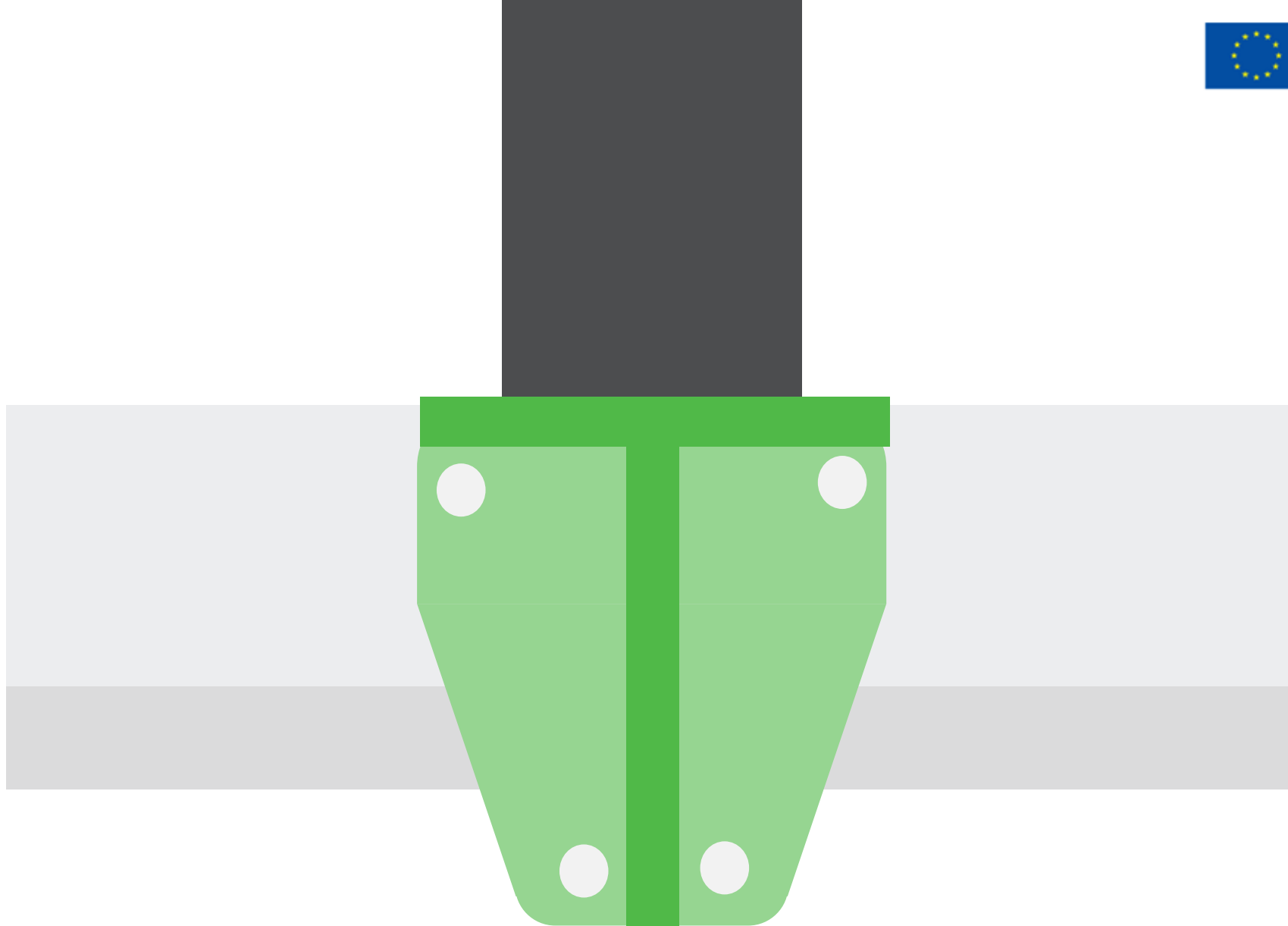
# 1 minute



# 1 minute



# 1 minute



10 minutes

Toe-plate

10 minutes

Toe-plate

Floor

10 minutes



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Guard  
rail leg

Toe-plate

Floor



10 minutes



10 minutes



Toe-plate

Floor

10 minutes



Toe-plate

Floor

10 minutes



Floor

10 minutes



10 minutes



Floor

10 minutes





10 minutes



## 3B. Concept models

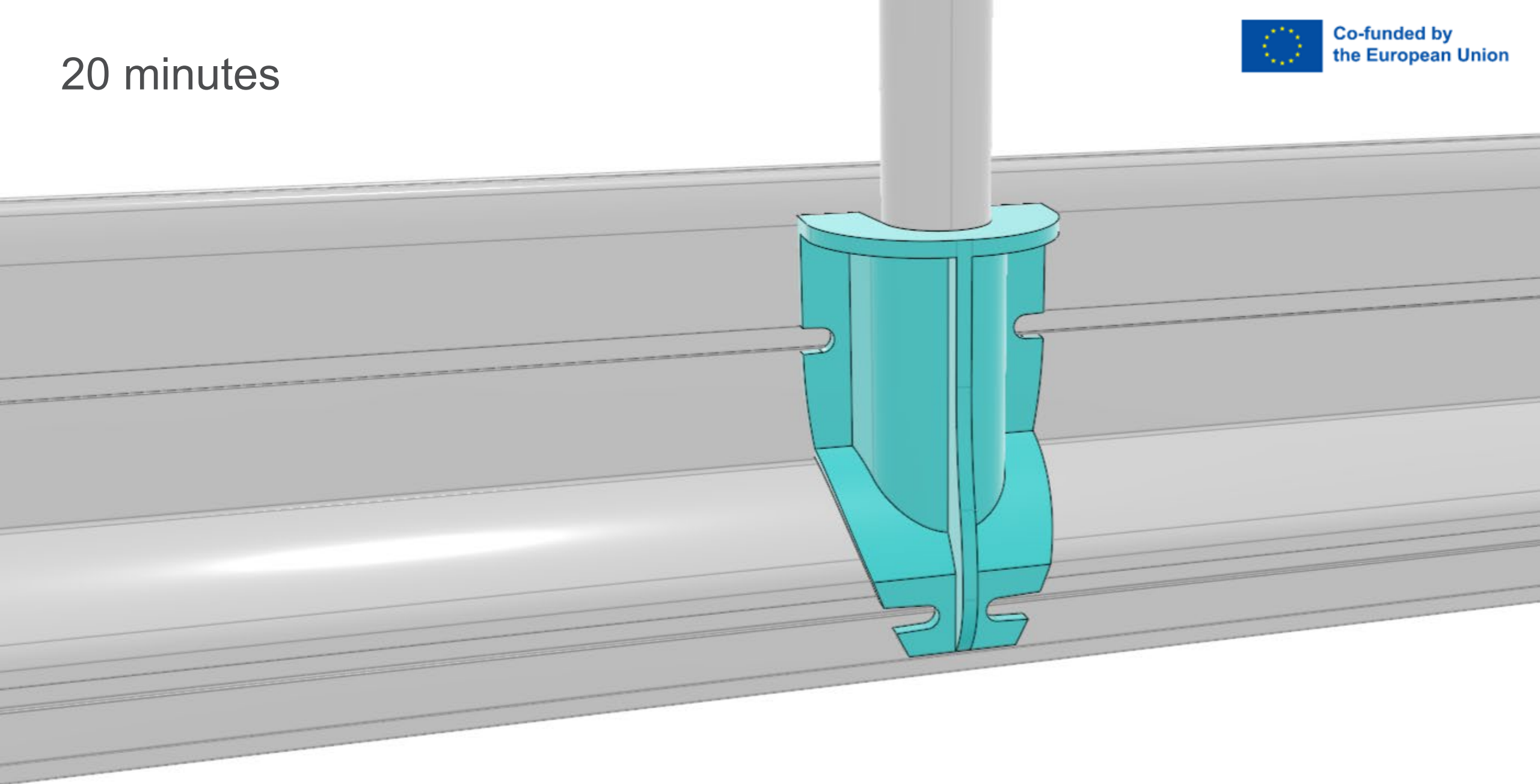
Essentially a “3D-sketch” or an “idea feasibility study in 3D”

Example:

20 minutes to 3D model the plain version

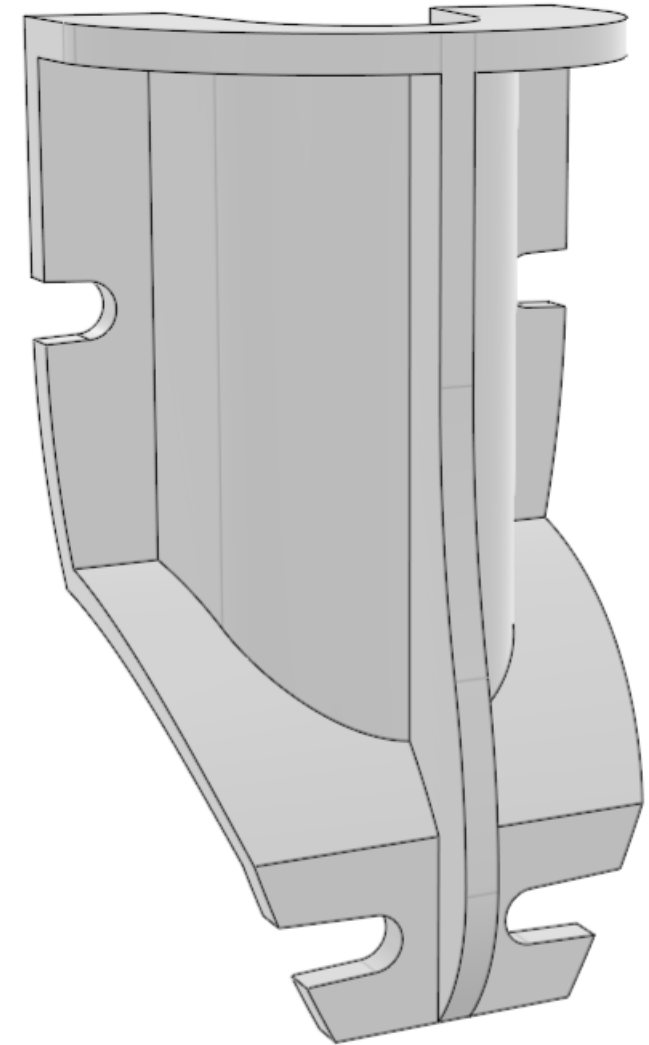
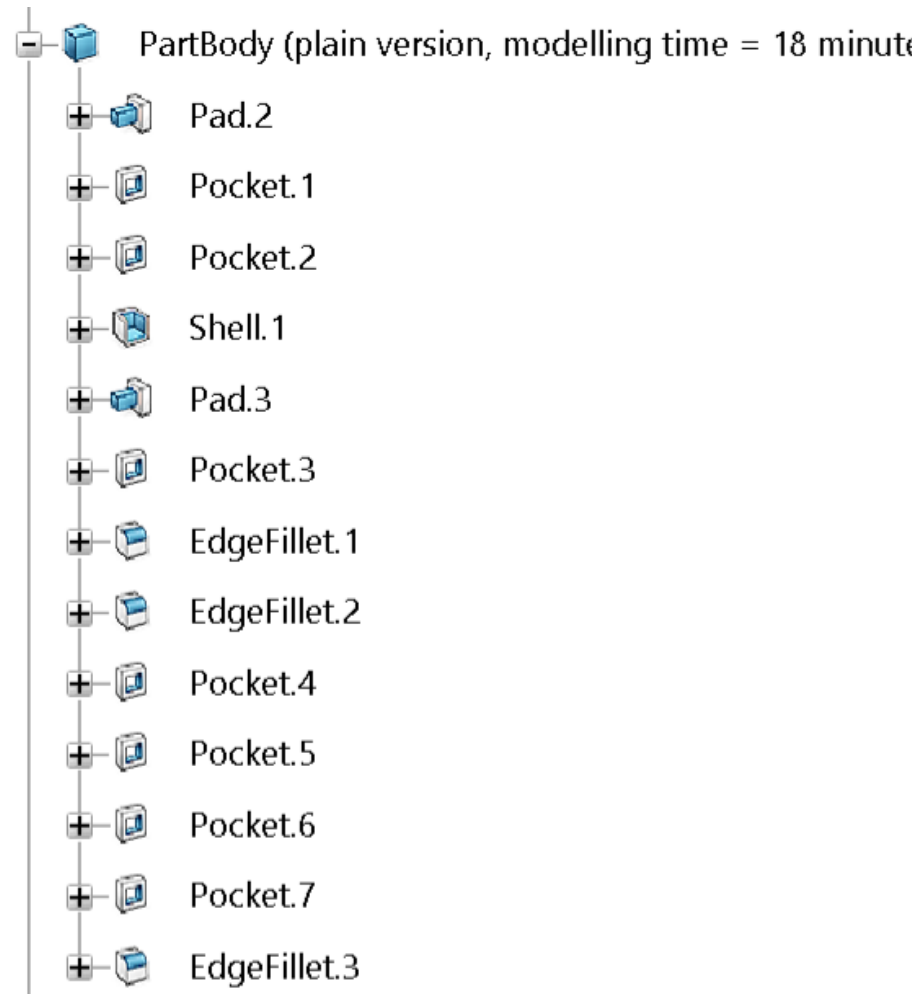
25 minutes to 3D model the filleted version

20 minutes



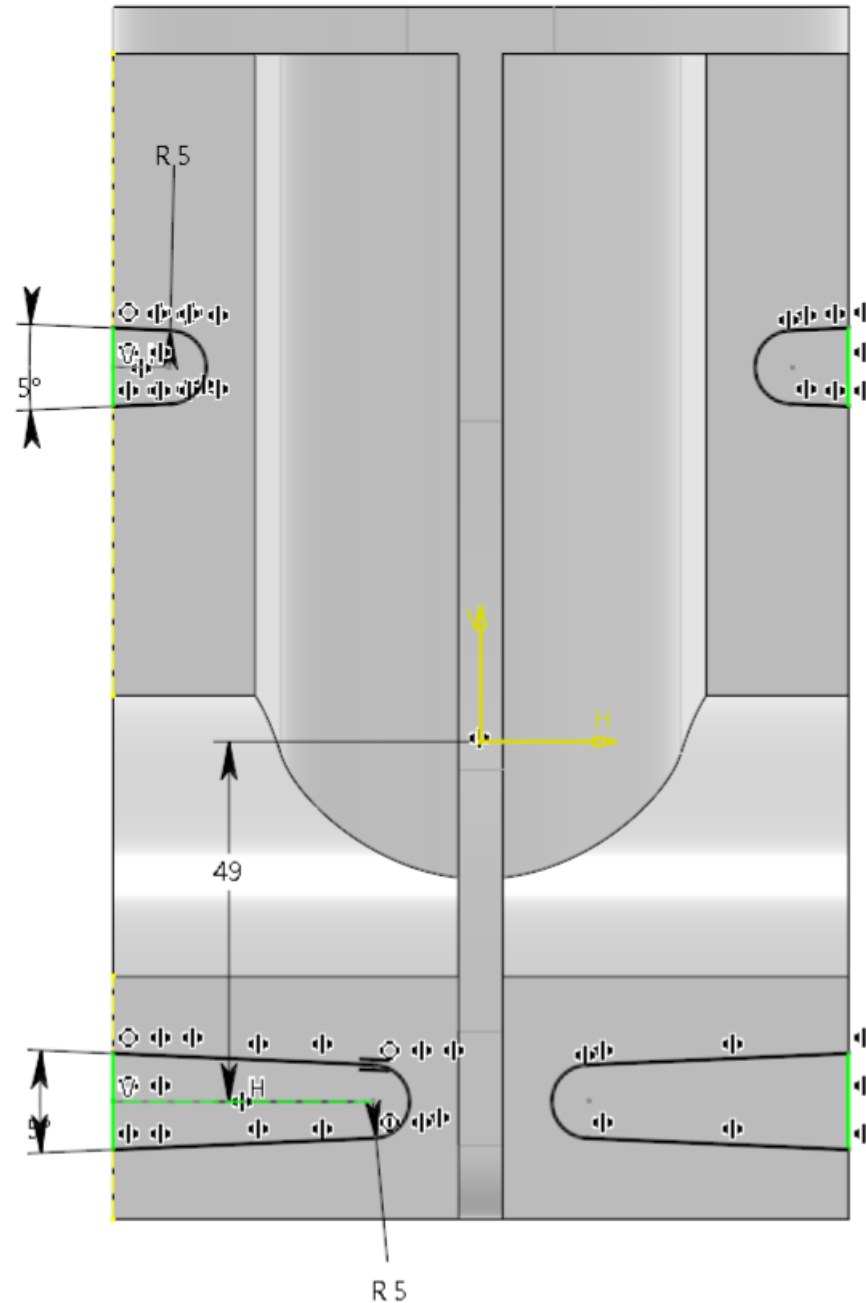
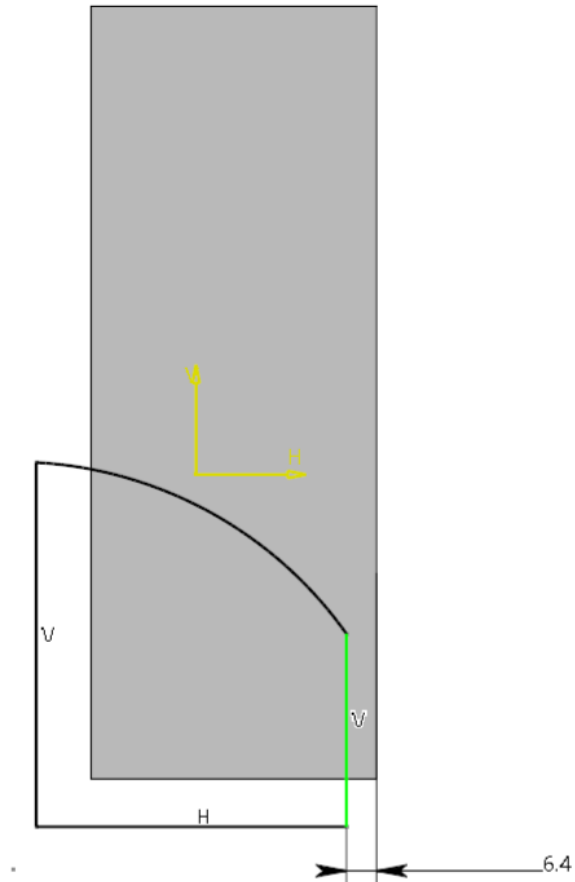
# 3D features

Simple, short list  
(with the unnecessary  
features included)



# Sketch examples

Sketches are only somewhat defined  
(black vs green color in Catia)

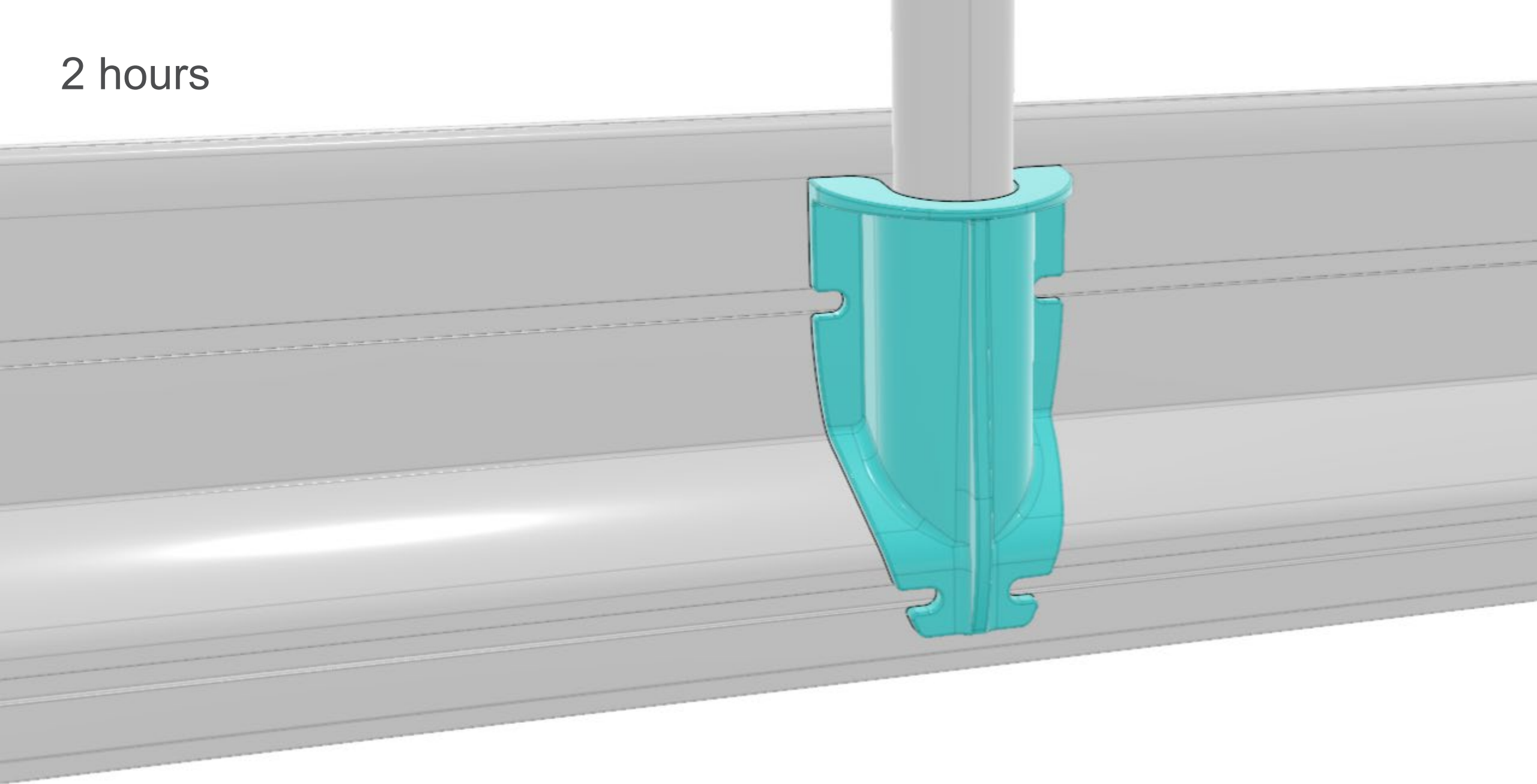


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## 3C. Development / engineering models

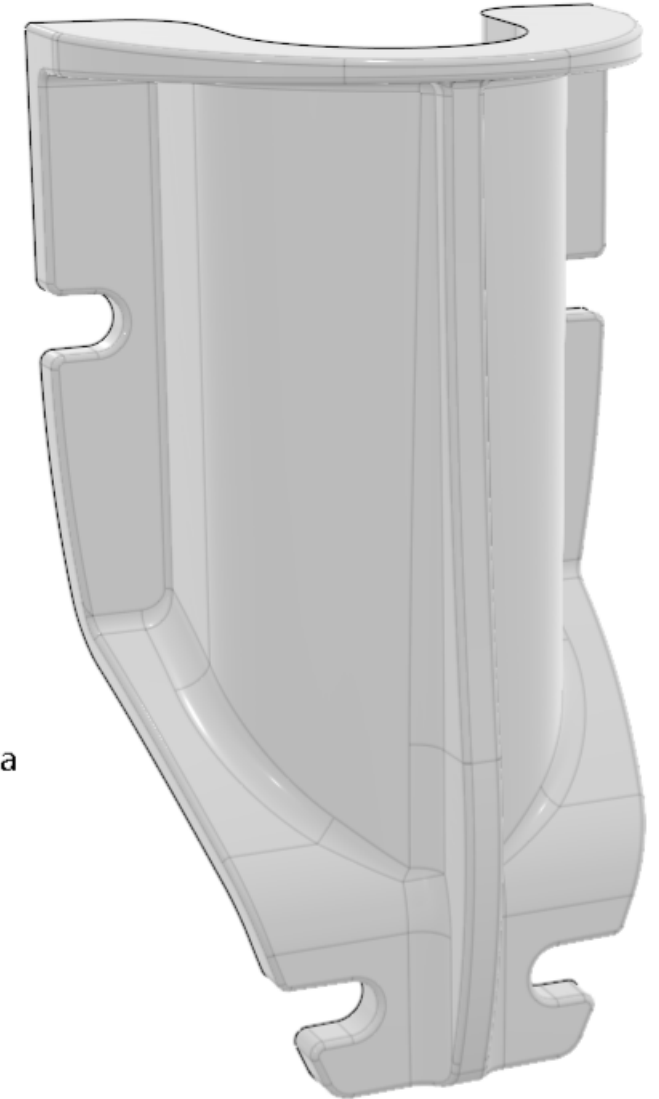
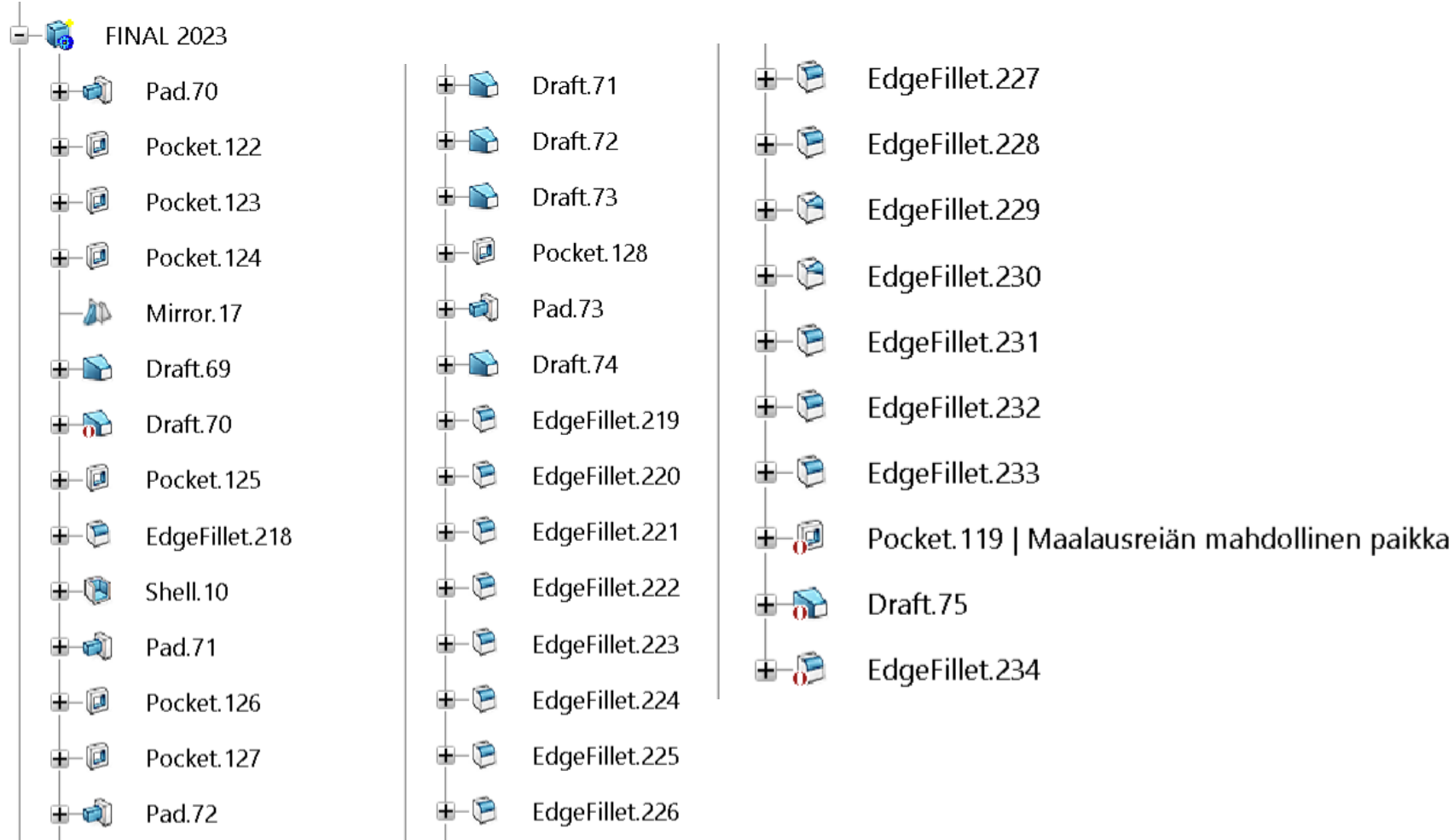
Example:  
2 hours to model

2 hours



# 3D features

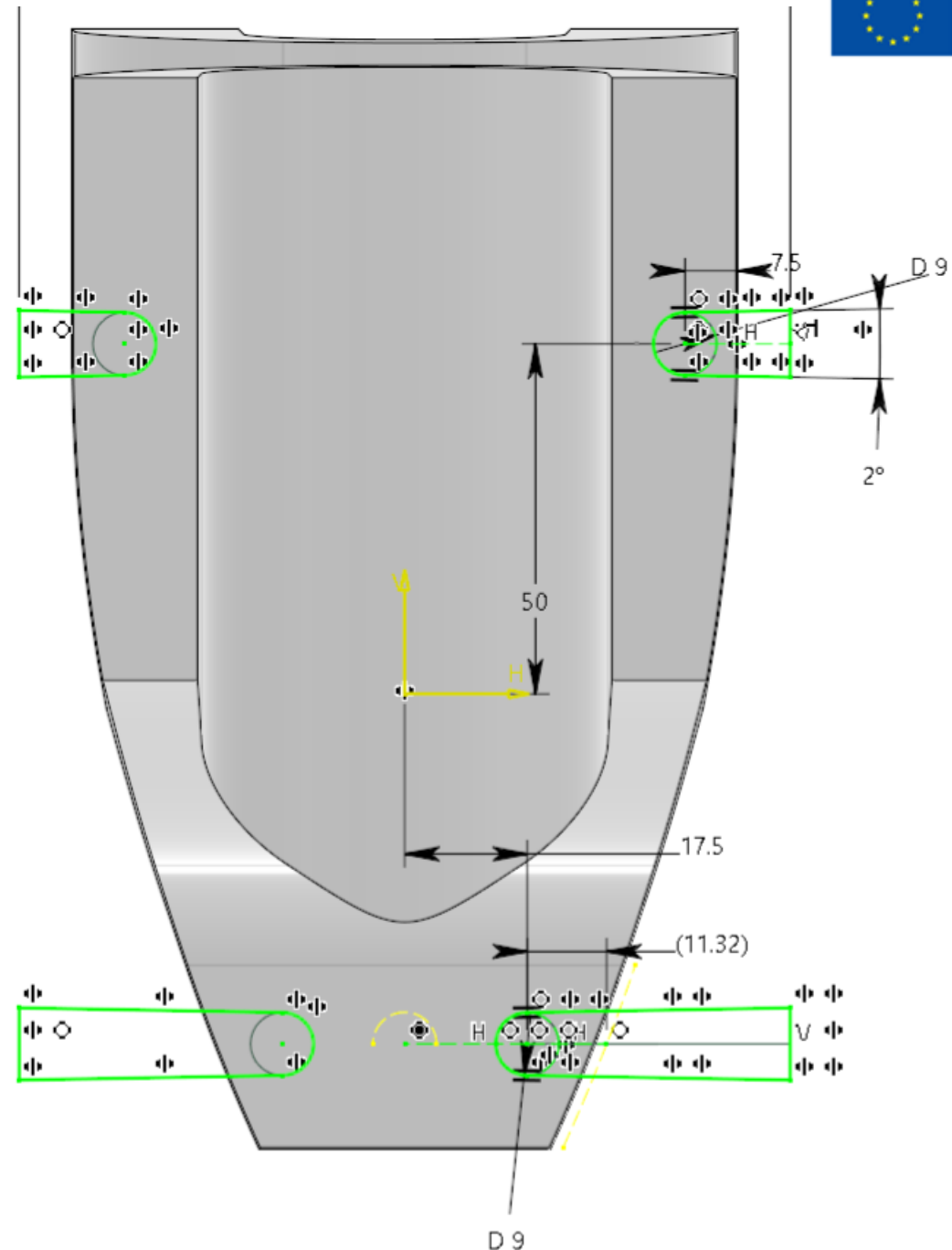
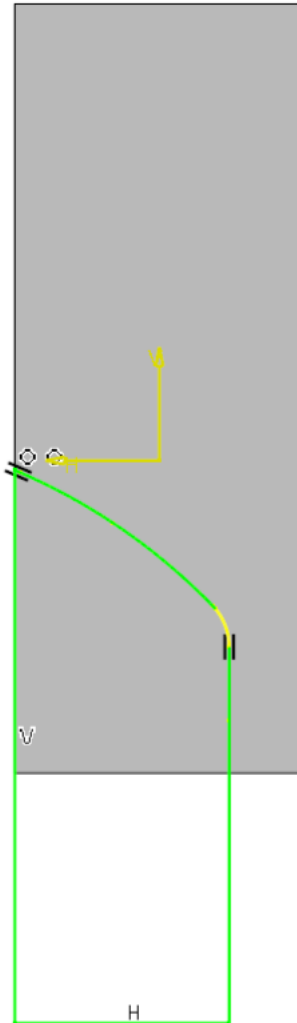
A more extensive list of features (some unnecessary)





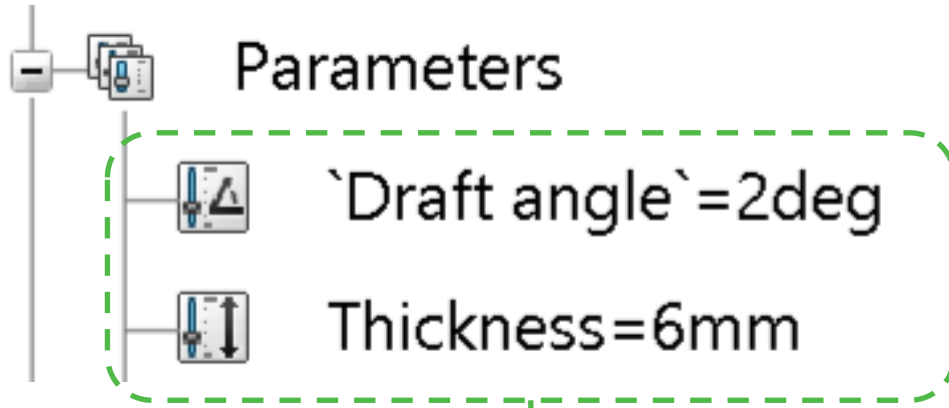
# Sketch examples

The sketches are fully defined (manually)



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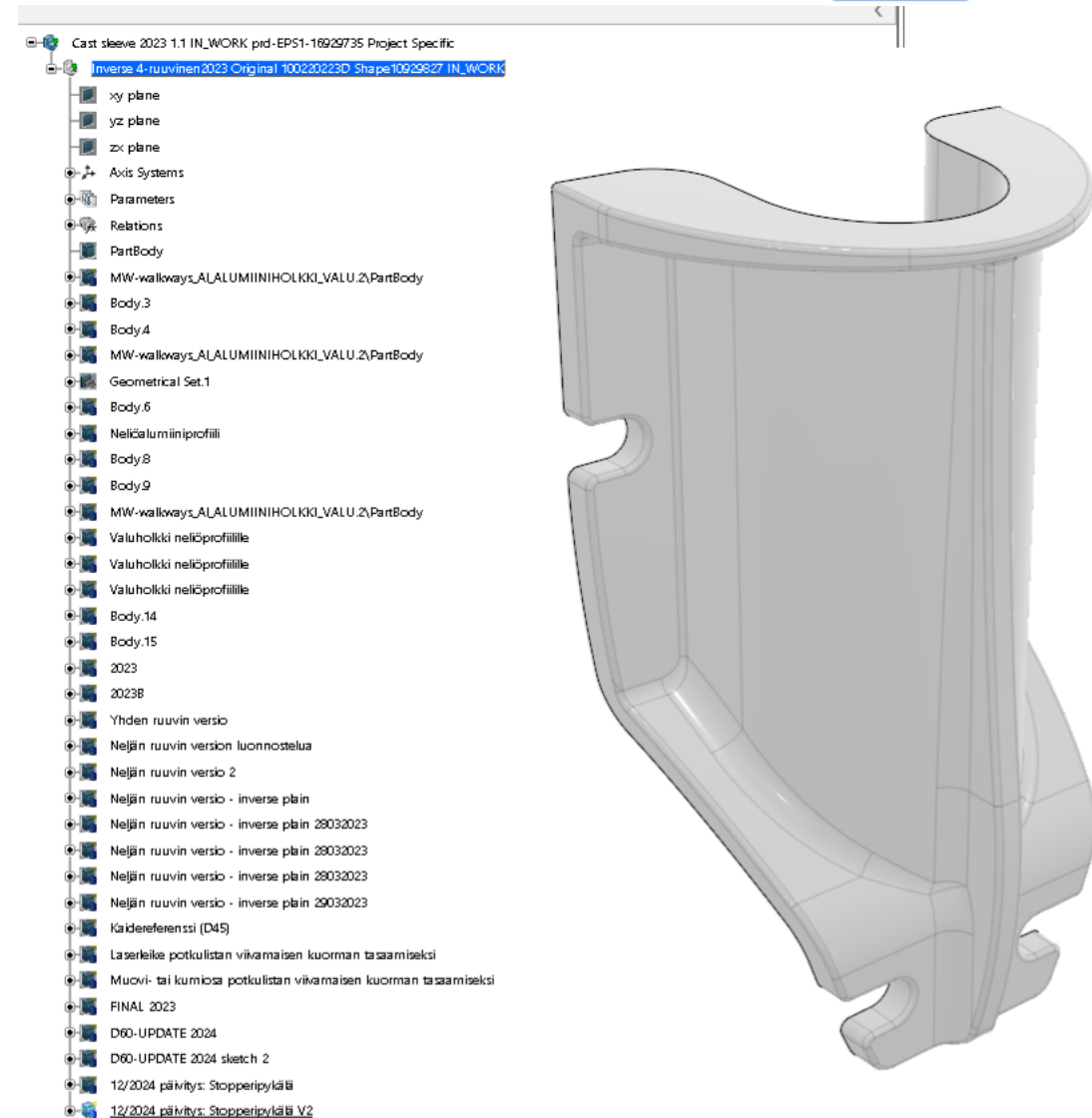
# Engineering model



Even if you're not doing a parametric model, some parameters may still be useful (e.g. measurements that repeat on many instances). Still, don't overdo this!

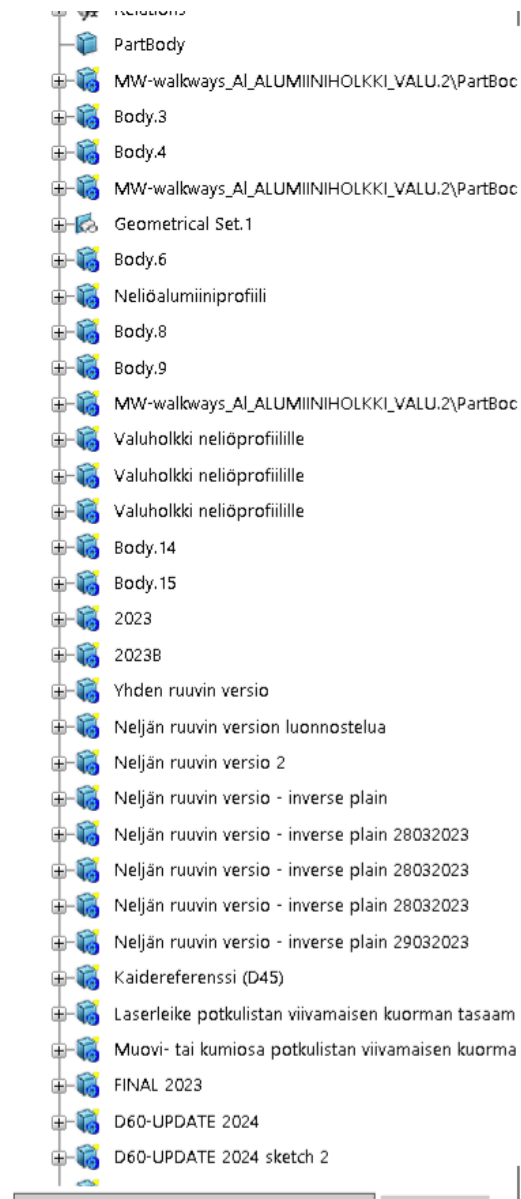
# Development model

- Multibody part with dozens of obsolete sketches and previous development versions
- Obsolete deactivated commands
- No material specified
- No technical drawings made
- Model not released



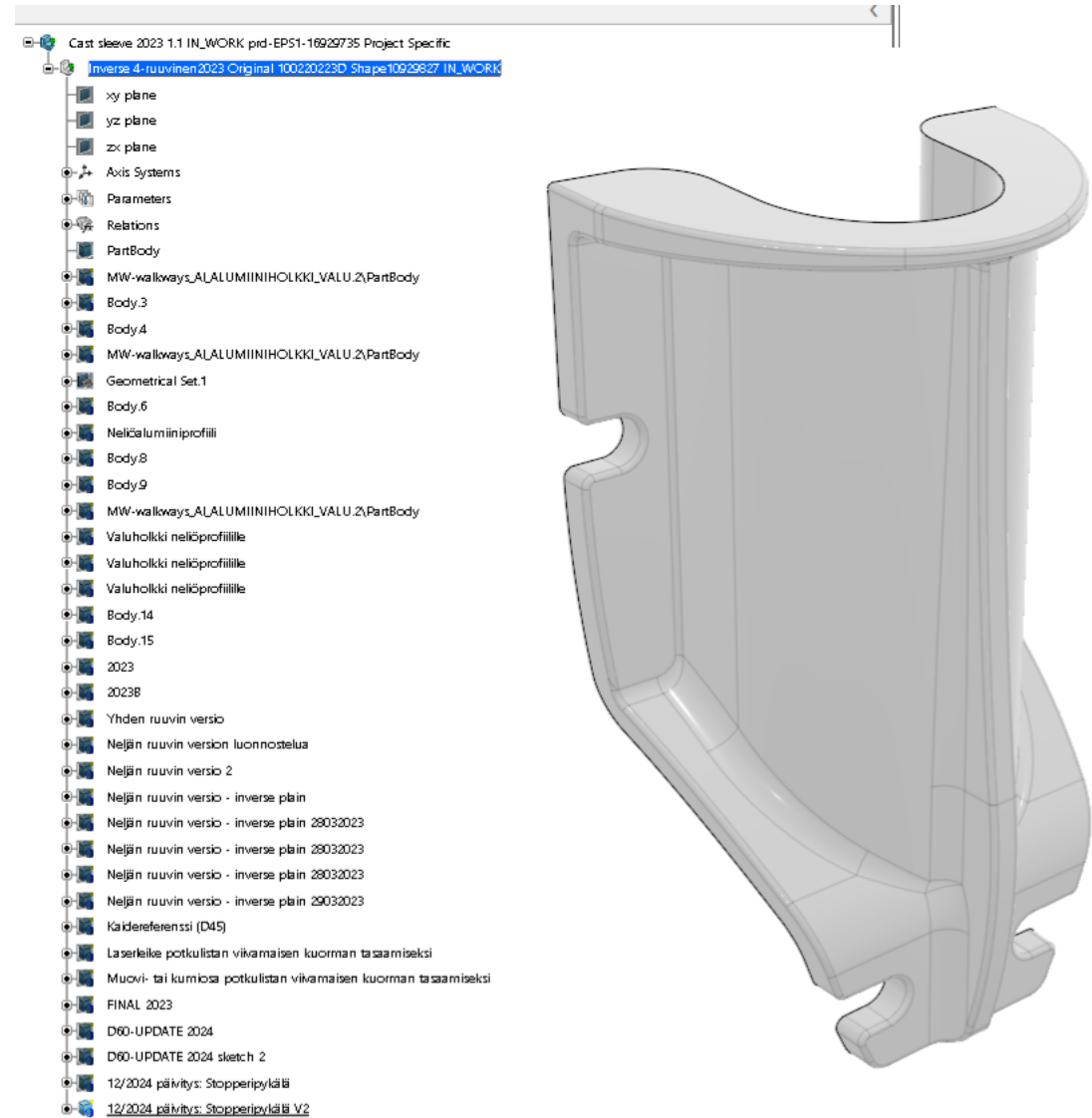
# Development model

- Multibody part with dozens of obsolete sketches and previous development versions
- Obsolete deactivated commands
- No material specified
- No technical drawings made
- Model not released
- (Screenshot: The model with all the hidden bodies made on different development phases unhidden...)



# Development model

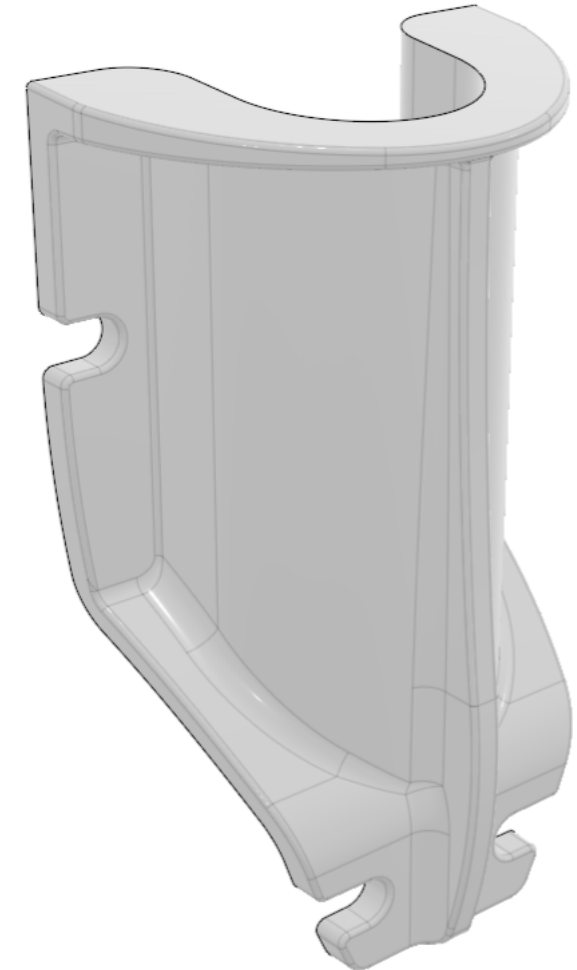
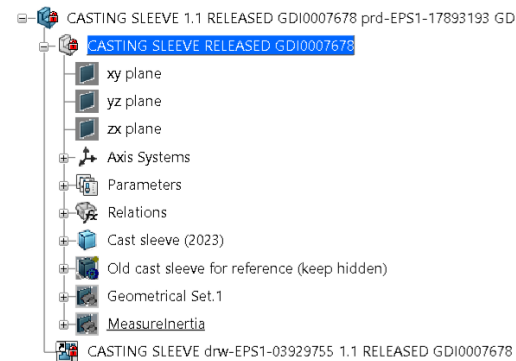
- Multibody part with dozens of obsolete sketches and previous development versions
- Obsolete deactivated commands
- No material specified
- No technical drawings made
- Model not released



# Engineering model

Exact same 3D-geometry but:

- Obsolete bodies deleted
- Obsolete deactivated commands deleted
- Technical drawing made & released in product data management systems
- 3D-model released
- “Global standard item number” created
- Etc.



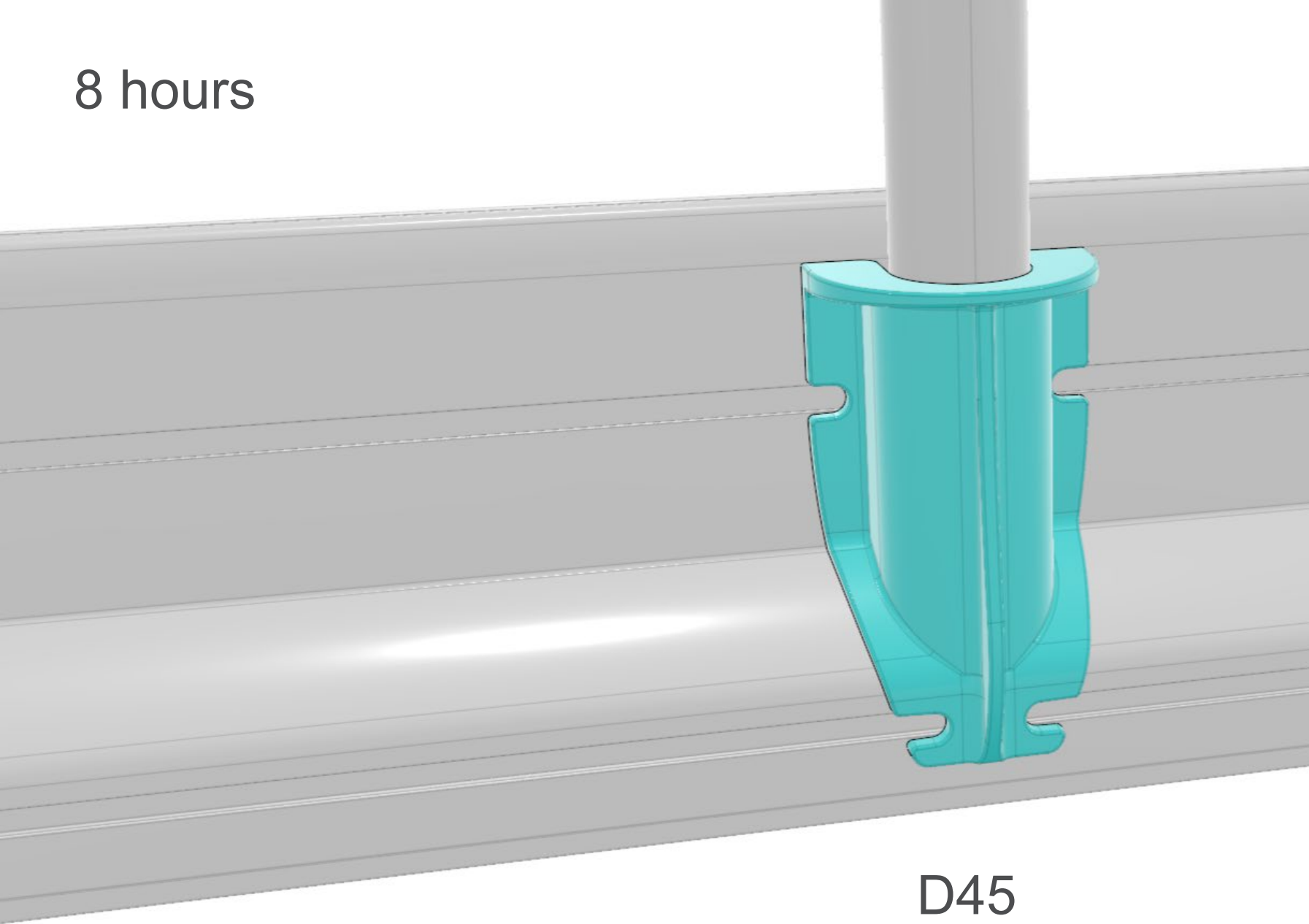
## 3D. Parametric models

Example:

2 hours for a model that works for pipe diameters 22 mm ... 45 mm

8 hours for a model that works for pipe diameters 22 mm ... 75 mm

8 hours



D45

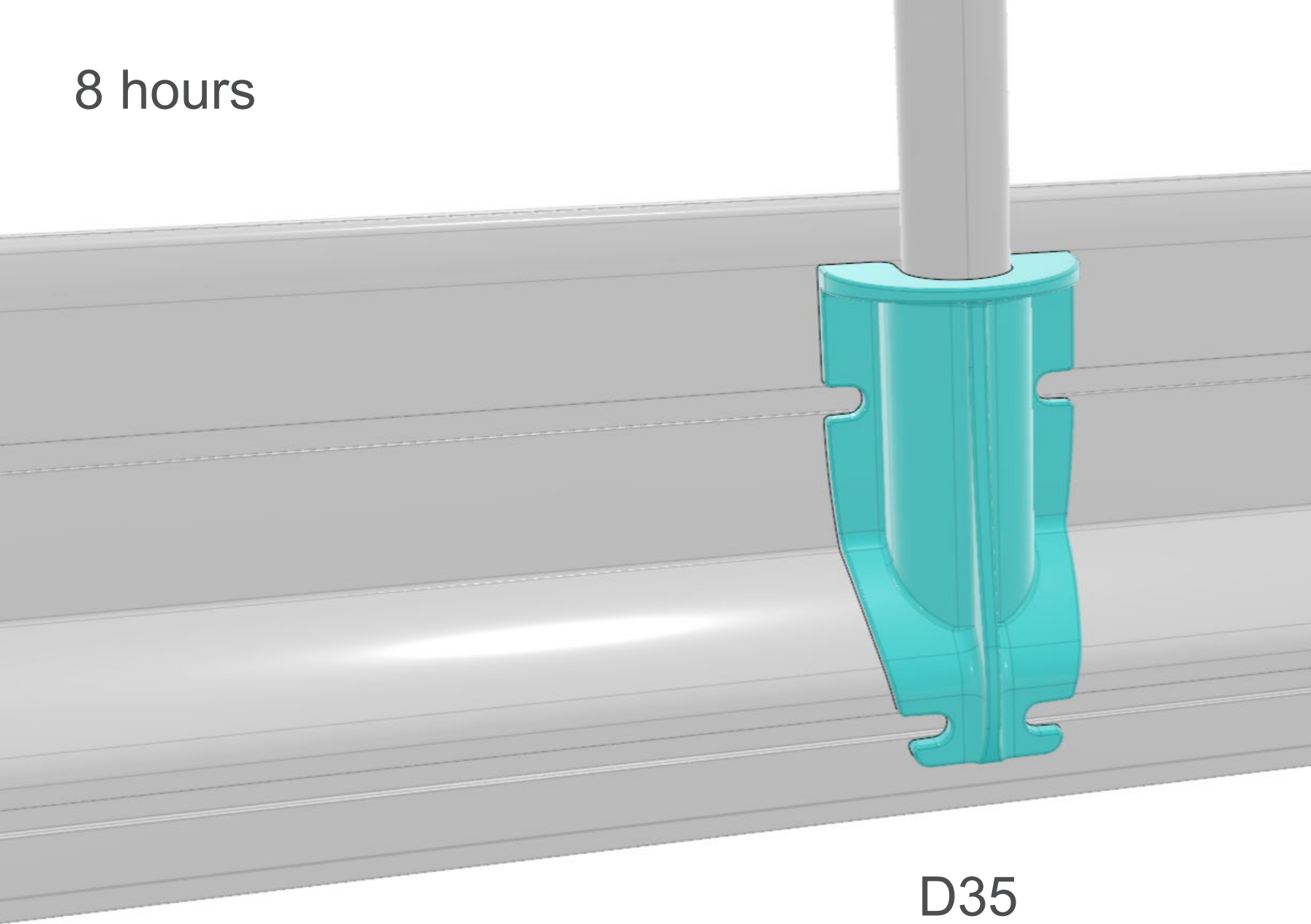




8 hours



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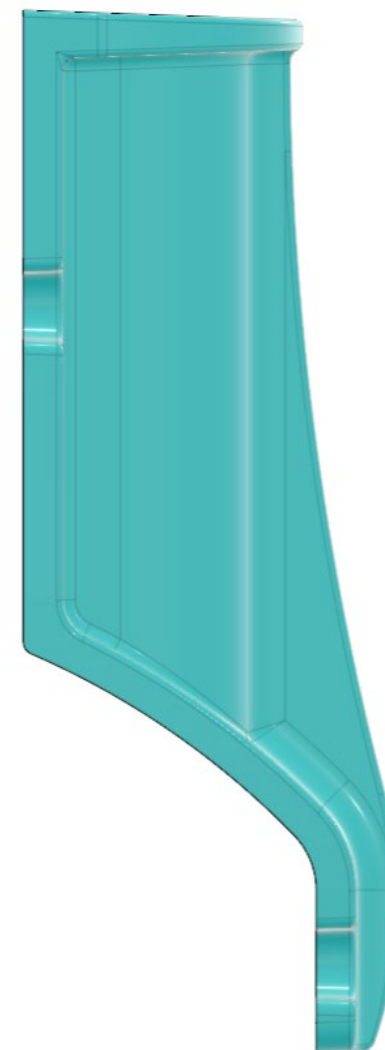
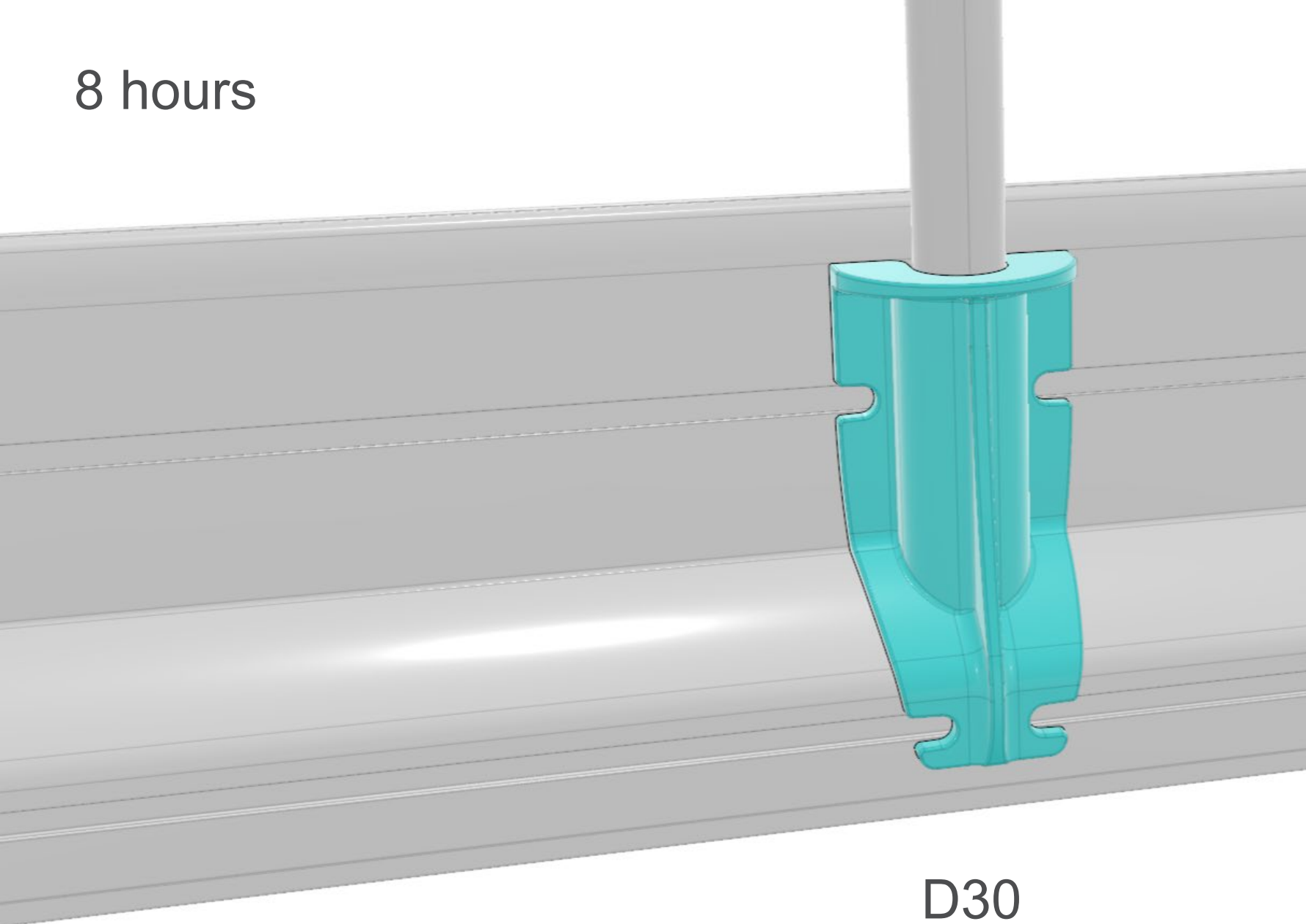
D35



8 hours



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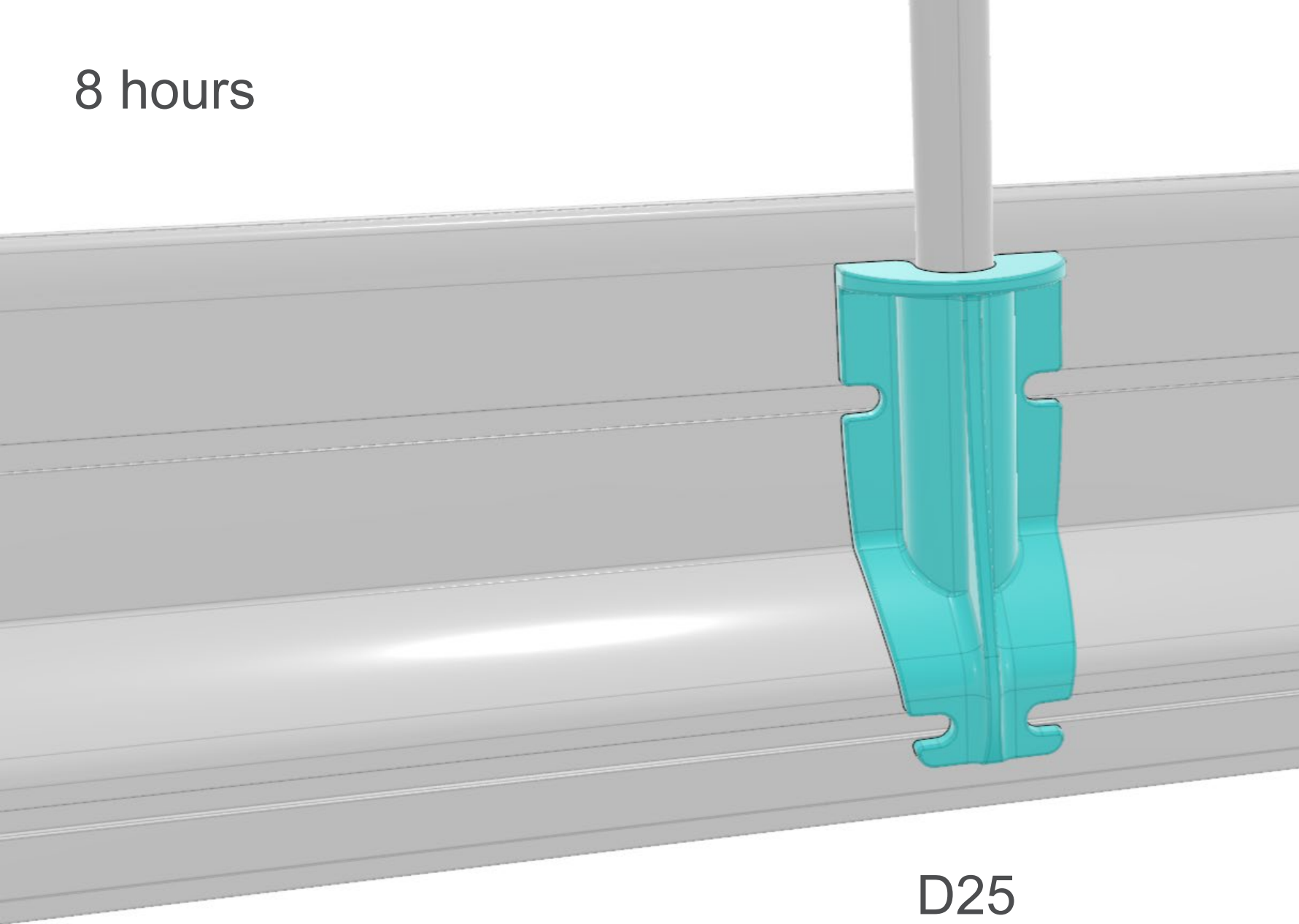


D30

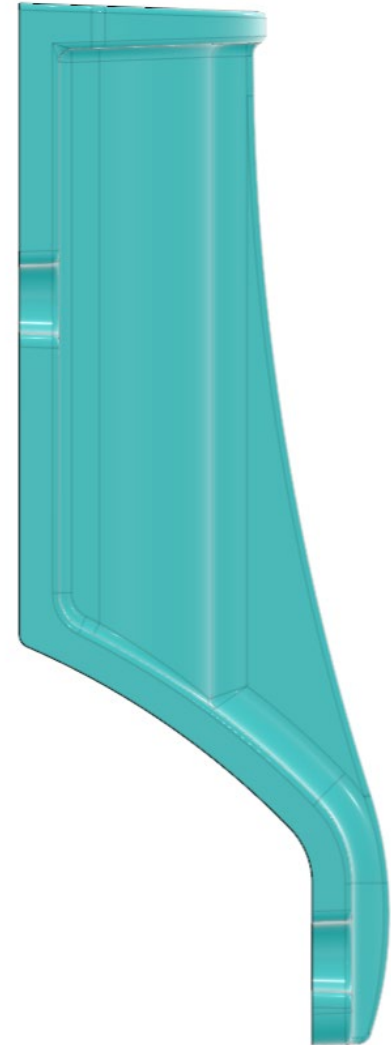
8 hours



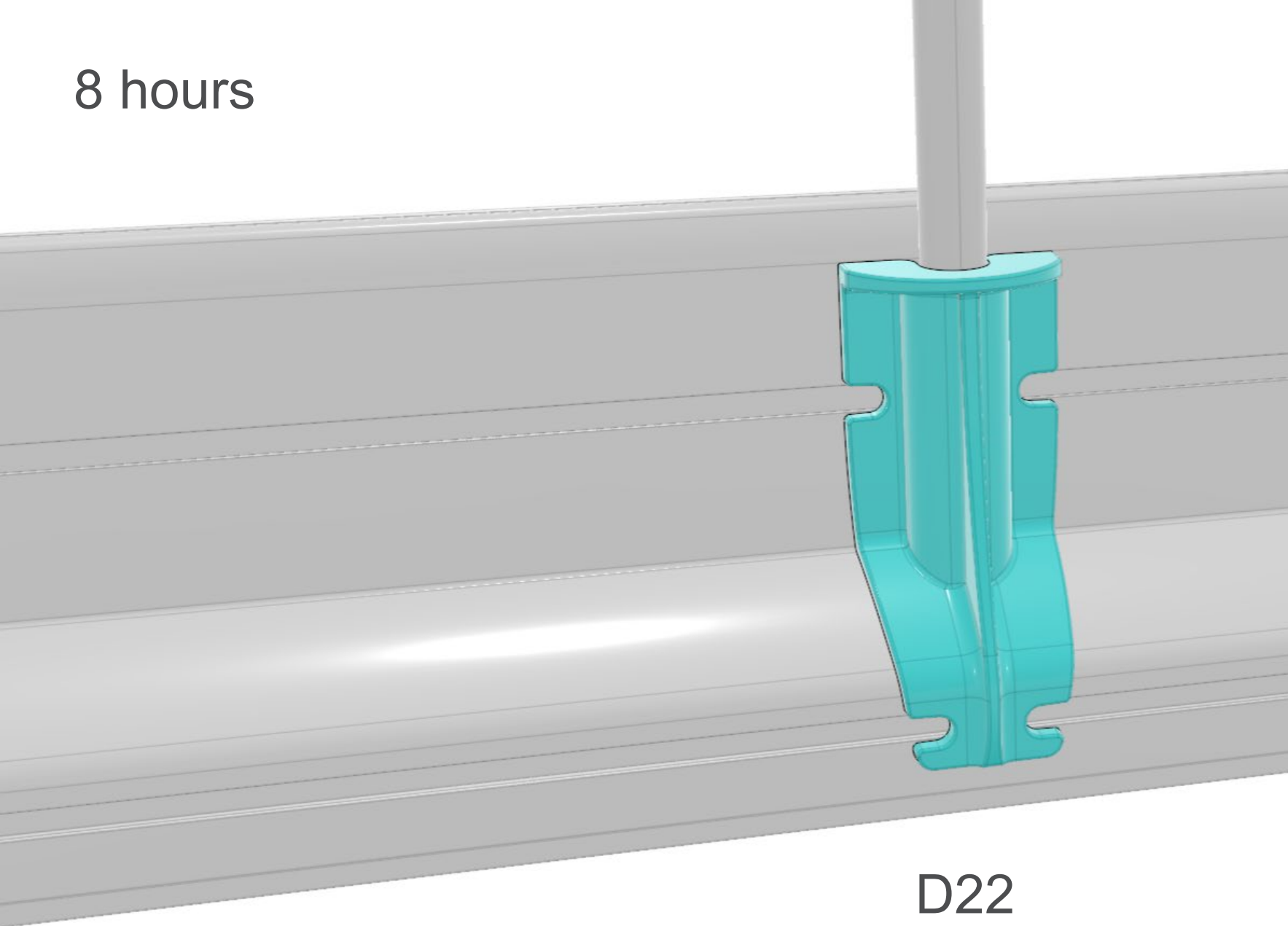
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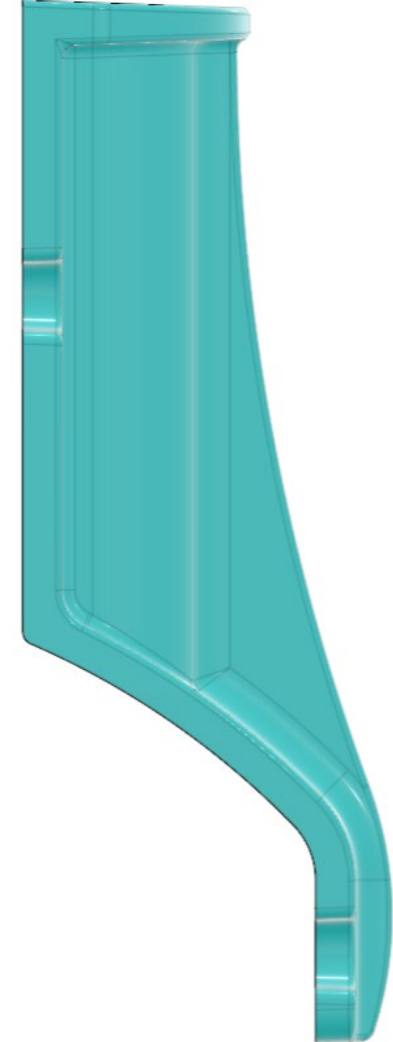
D25



8 hours



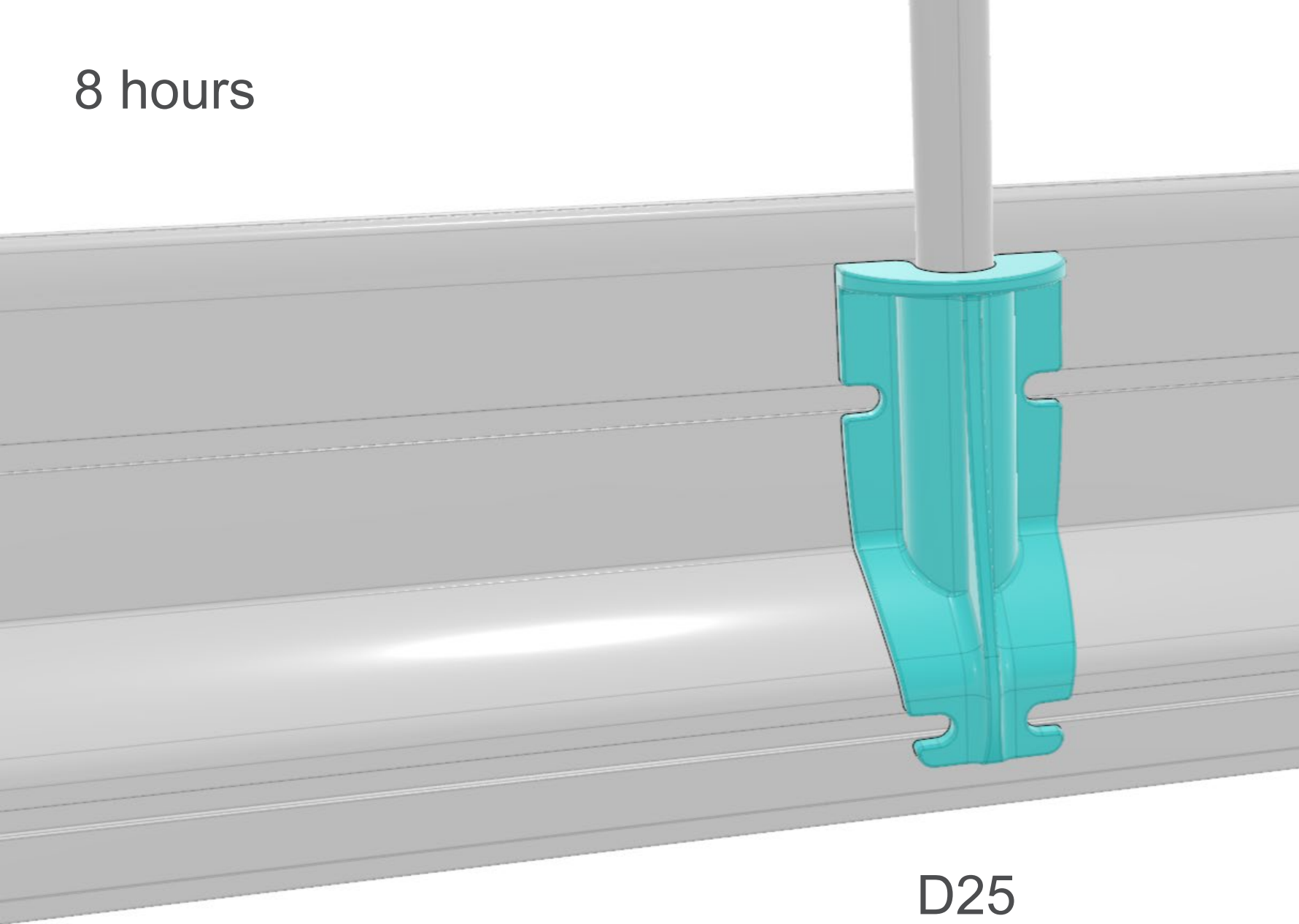
D22



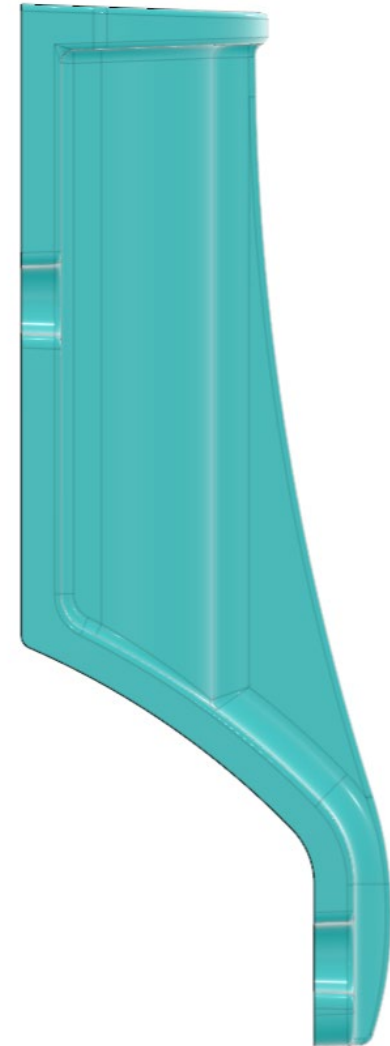
8 hours



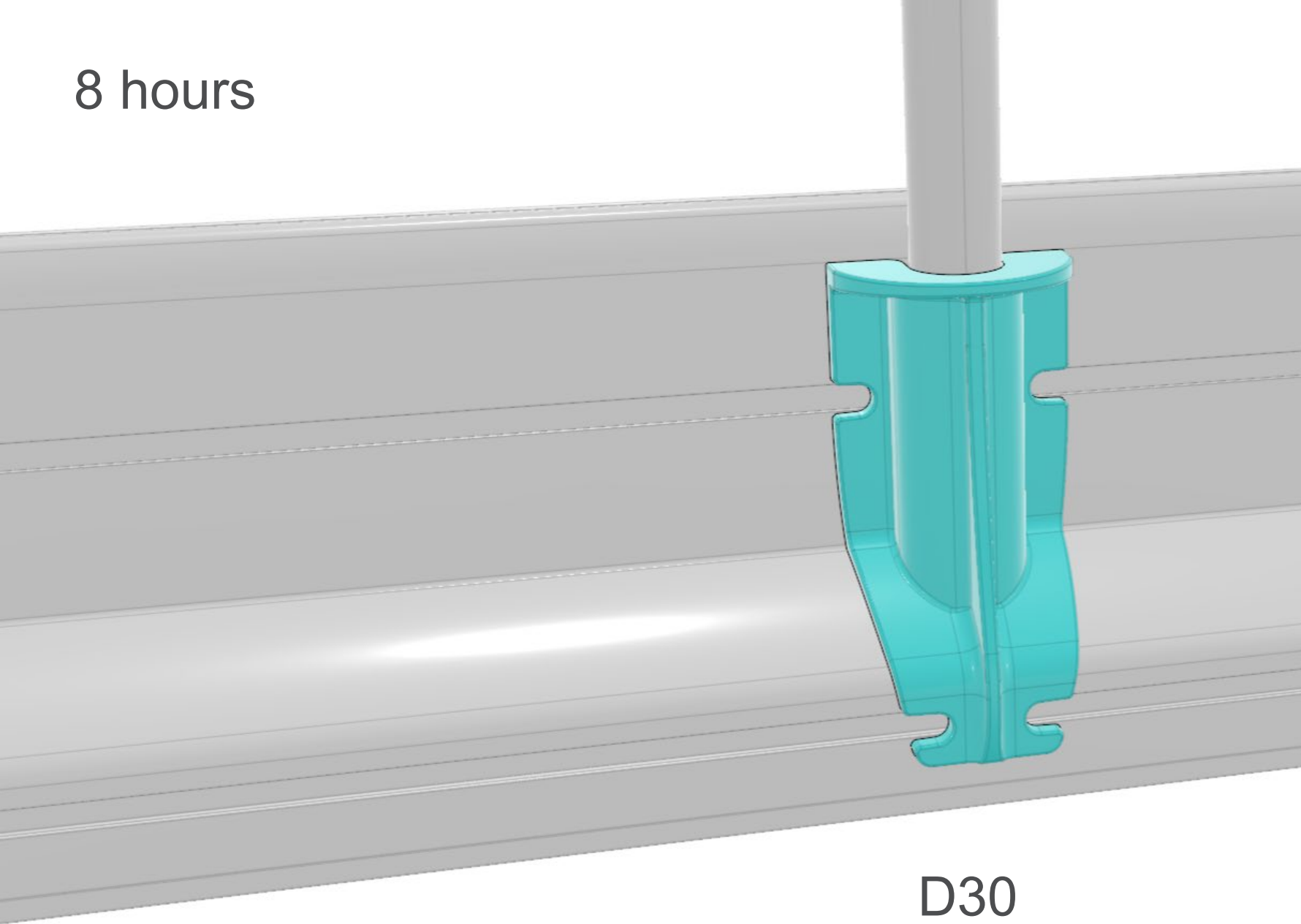
Co-funded by  
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D25



8 hours



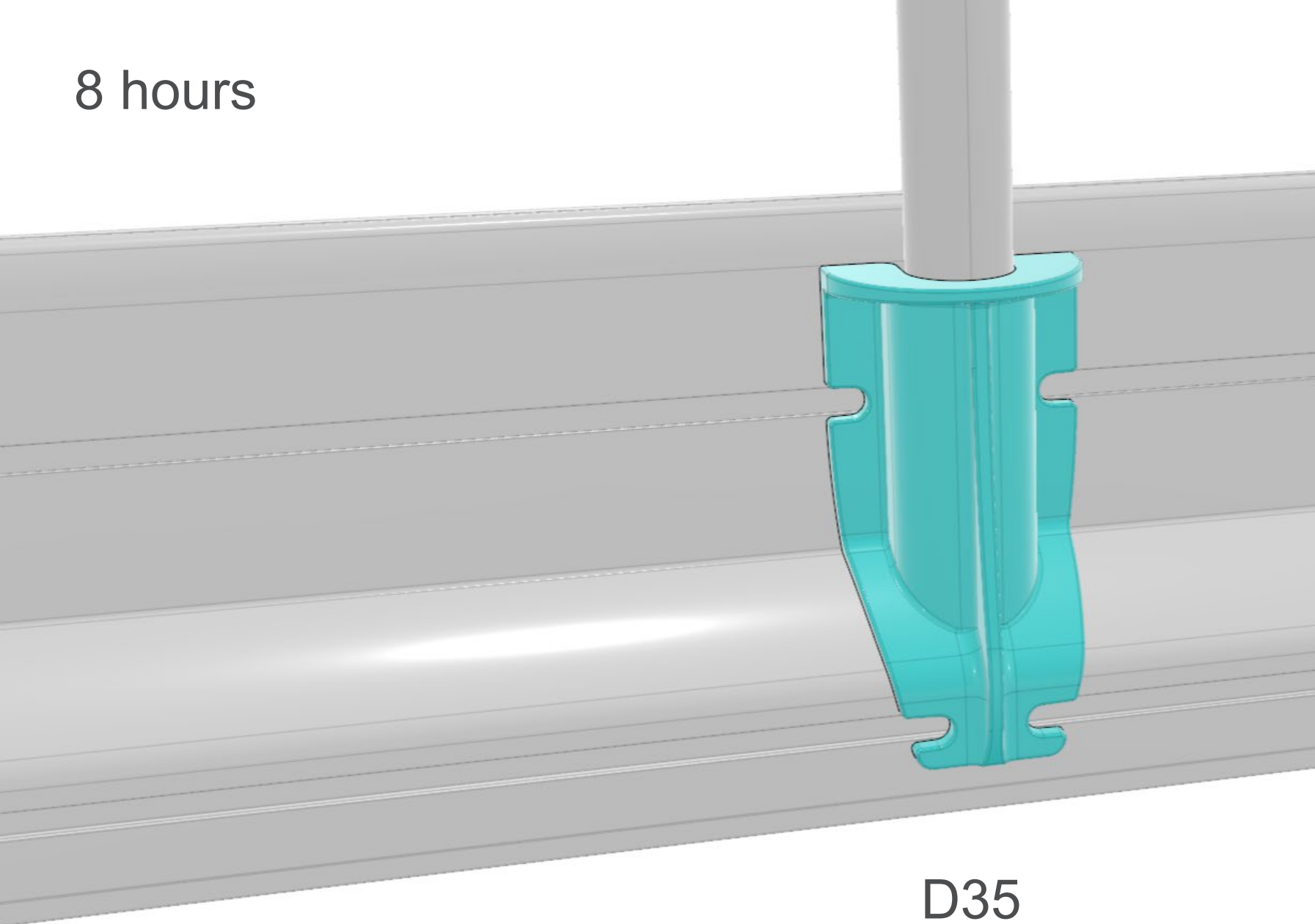
D30



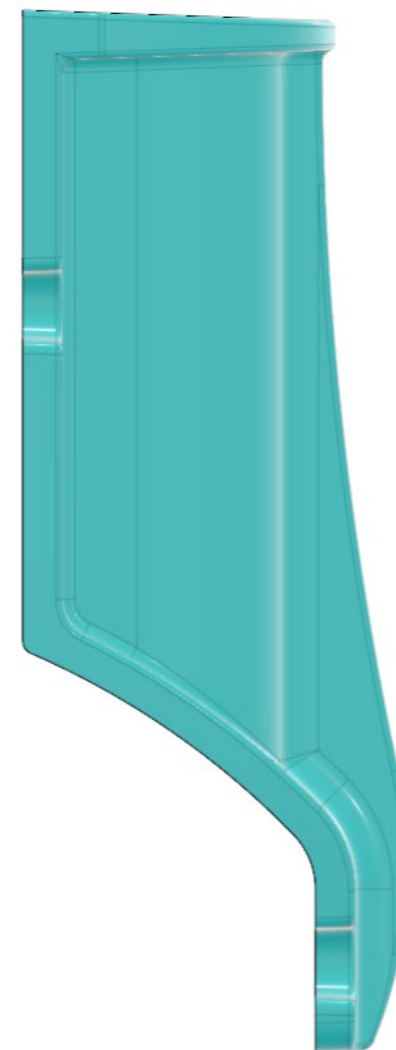
8 hours



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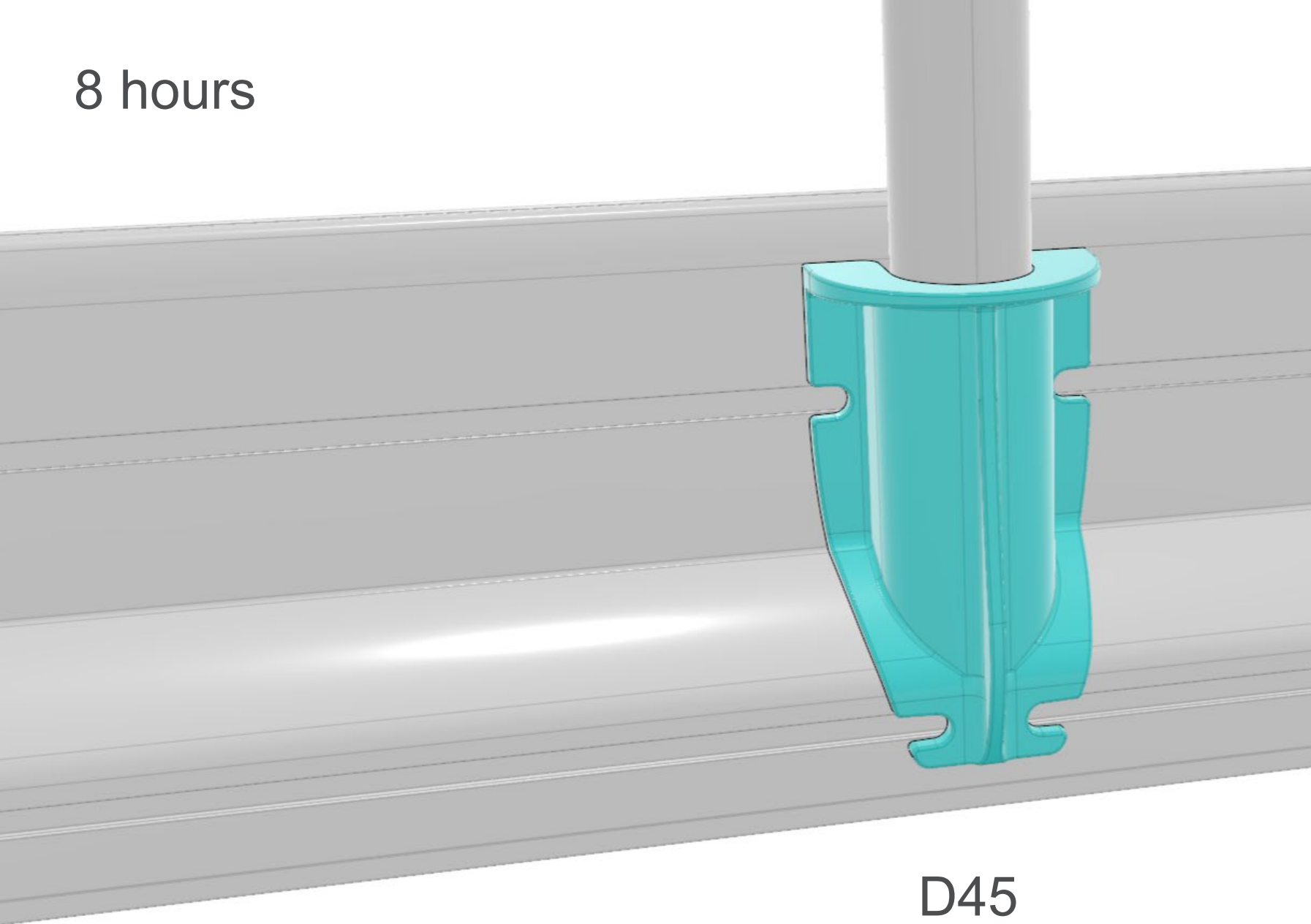


D35





8 hours



D45

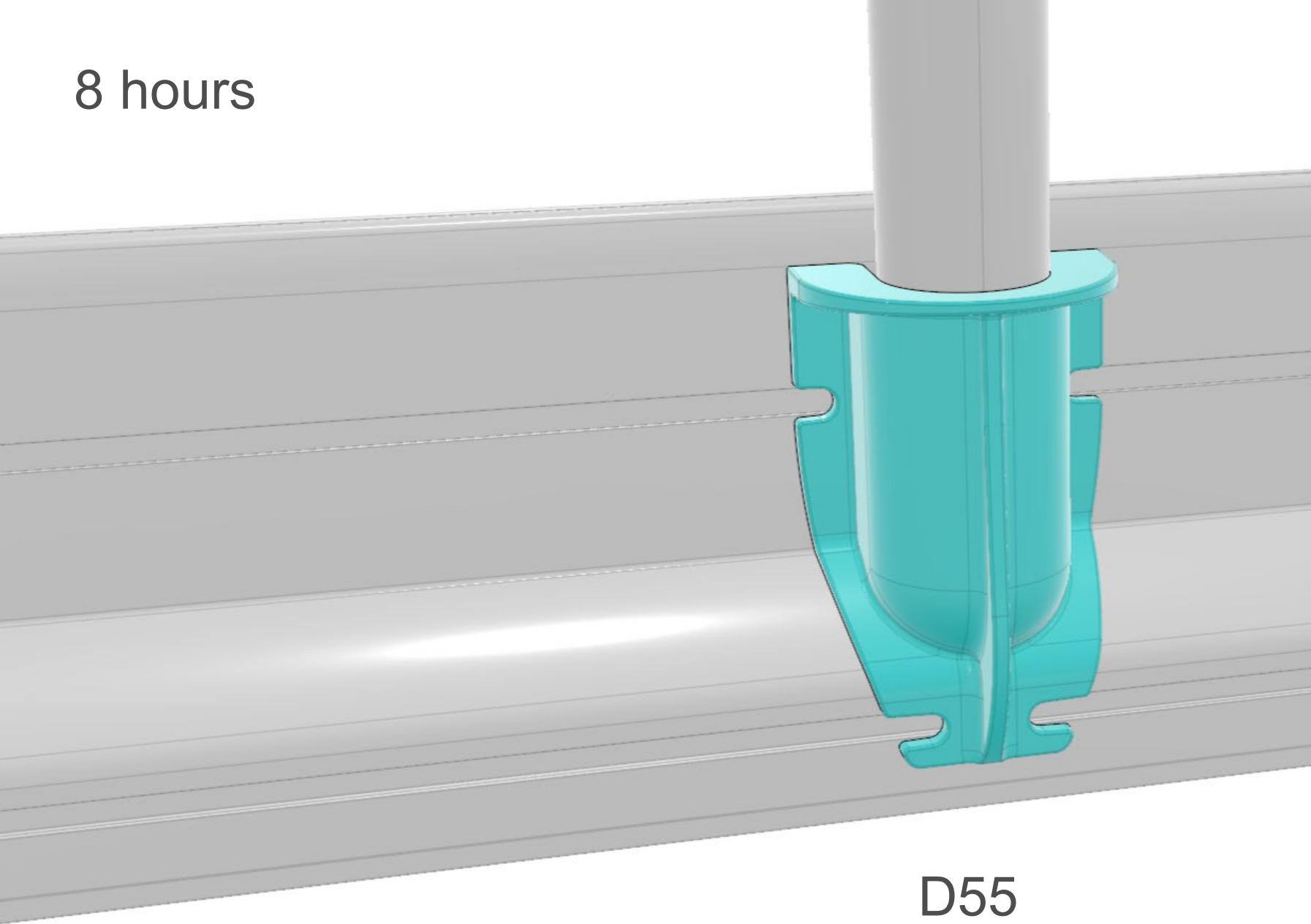




8 hours



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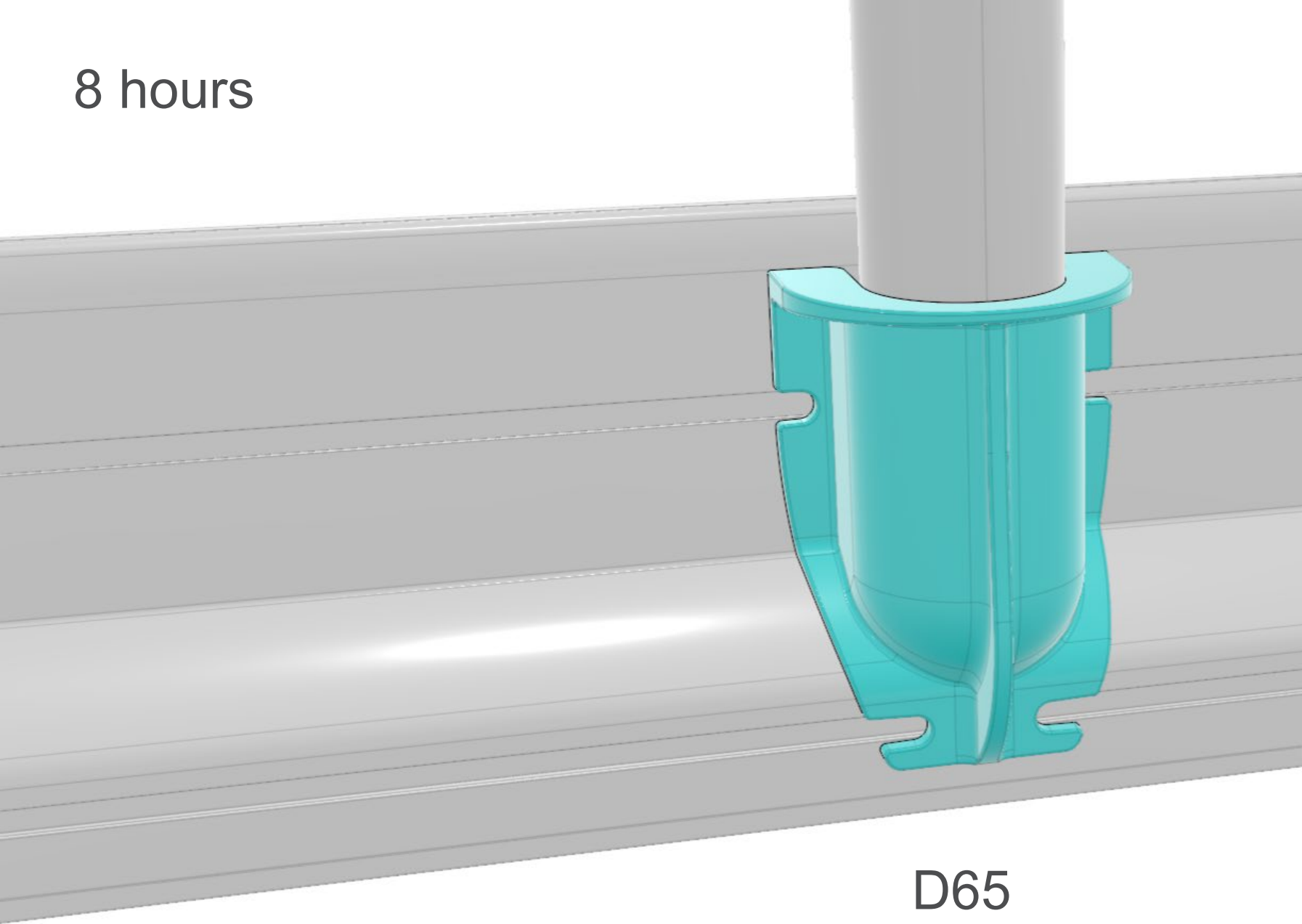
D55



8 hours



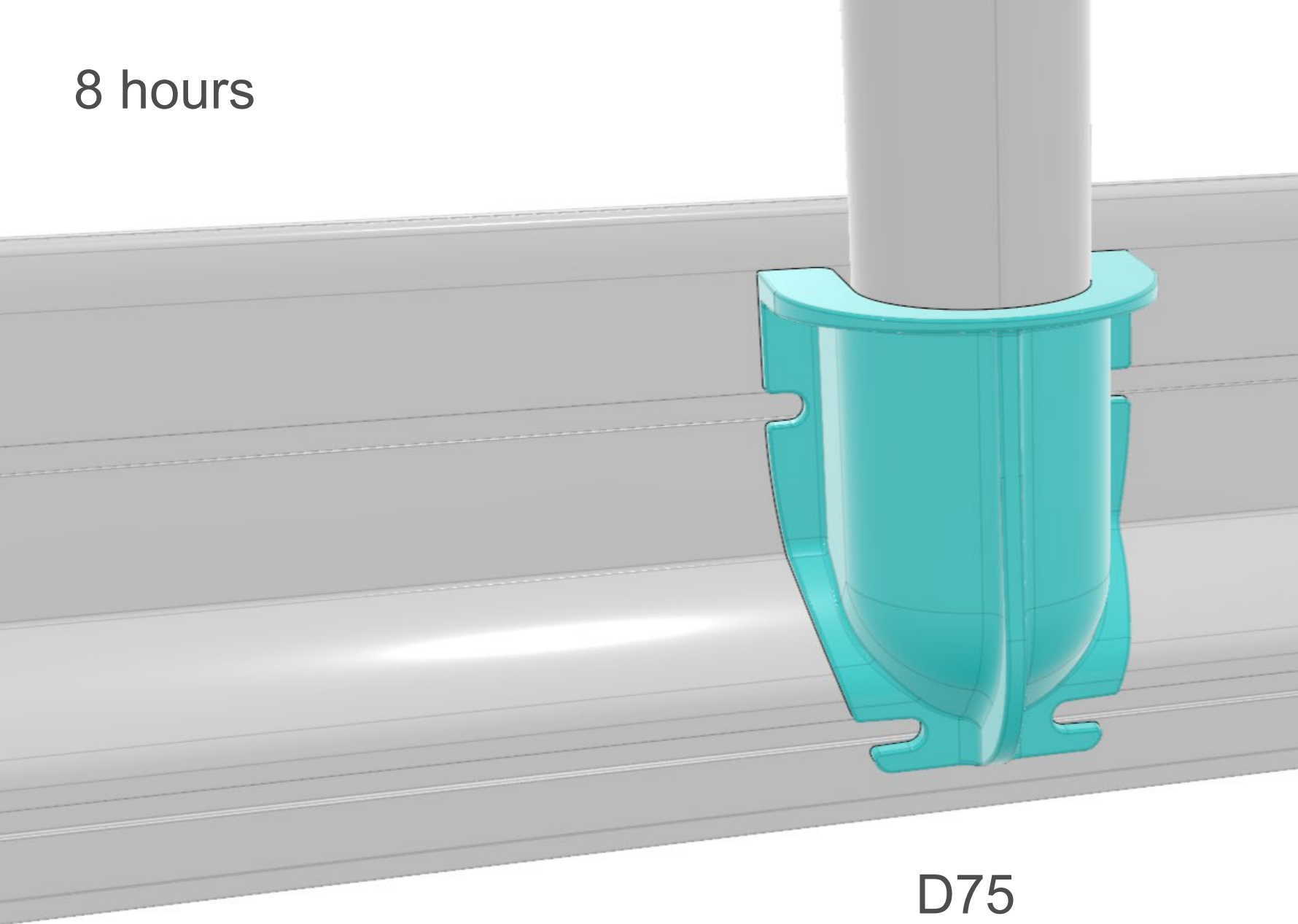
Co-funded by  
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D65



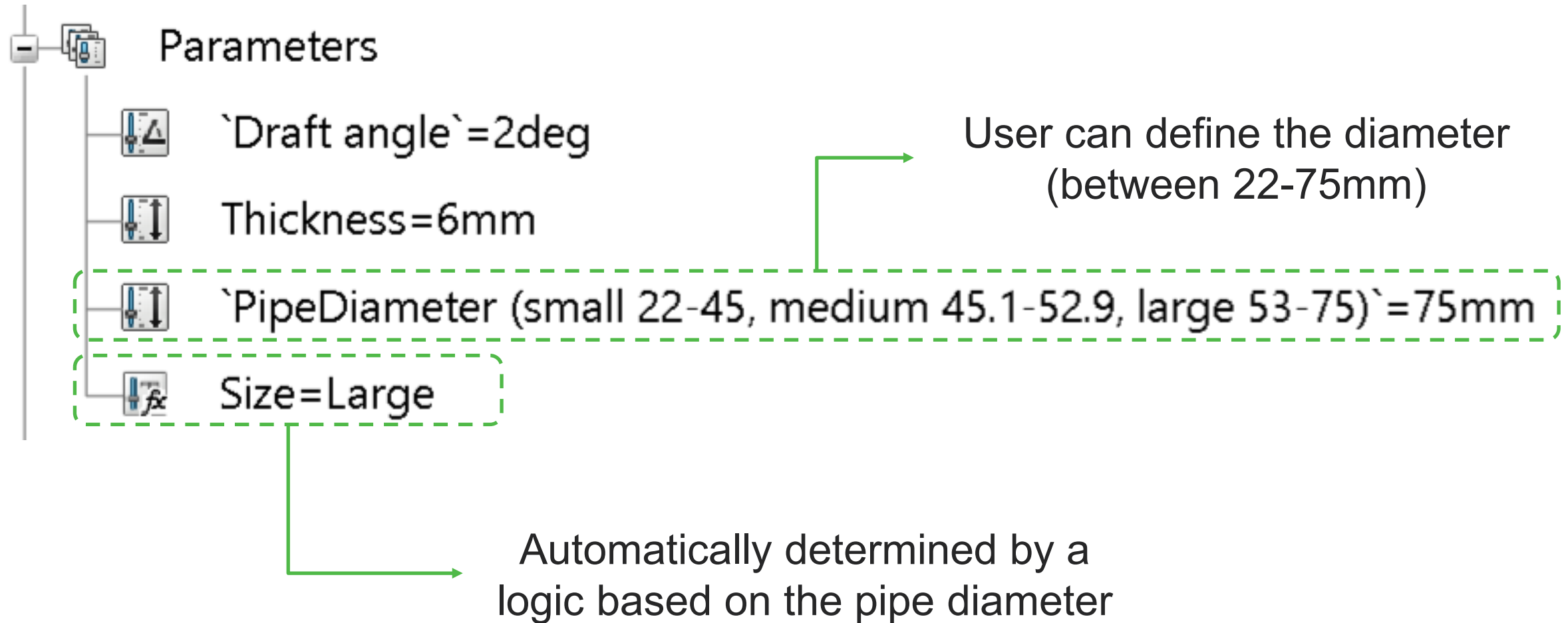
8 hours



D75

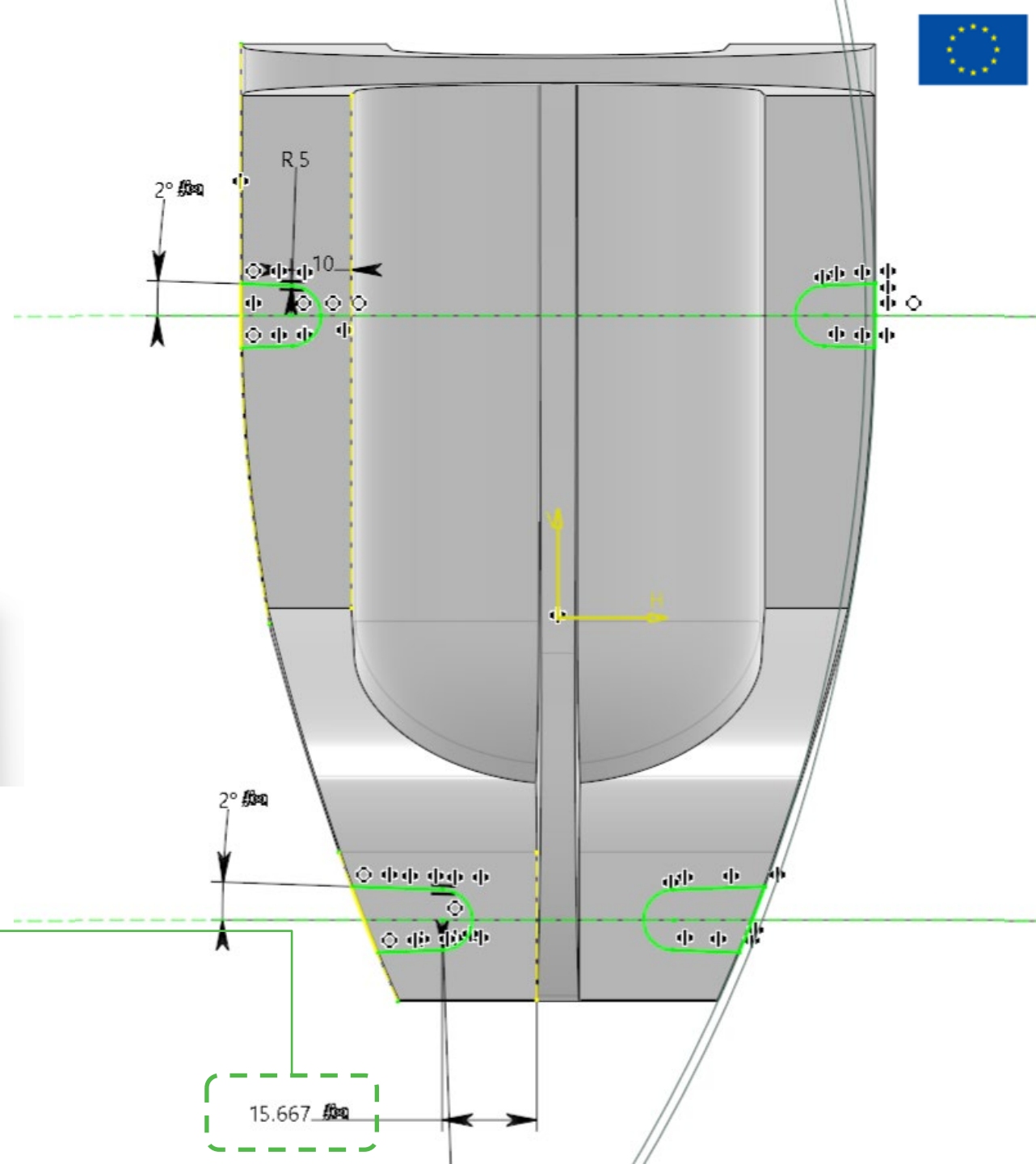
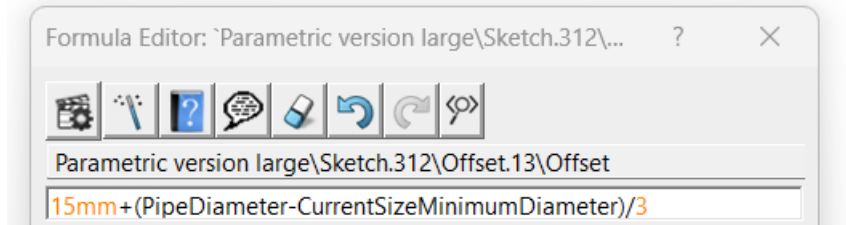


# Parametric model



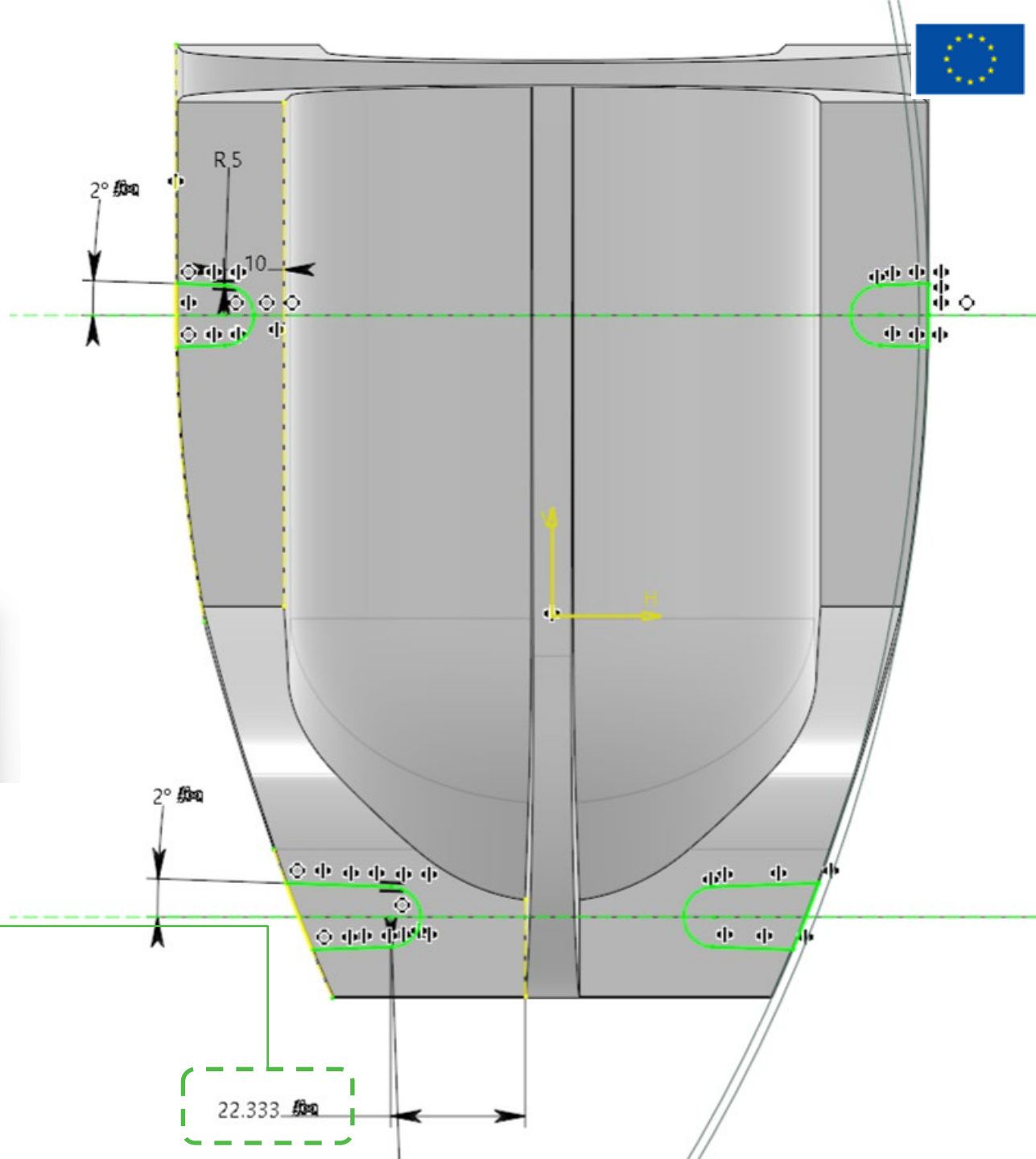
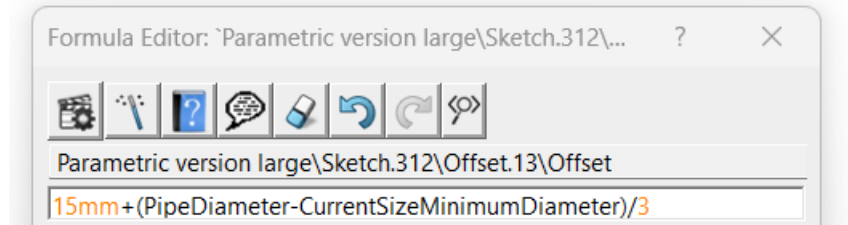
# Sketch example

The sketches are fully defined (with the selected few measurements defined parametrically)



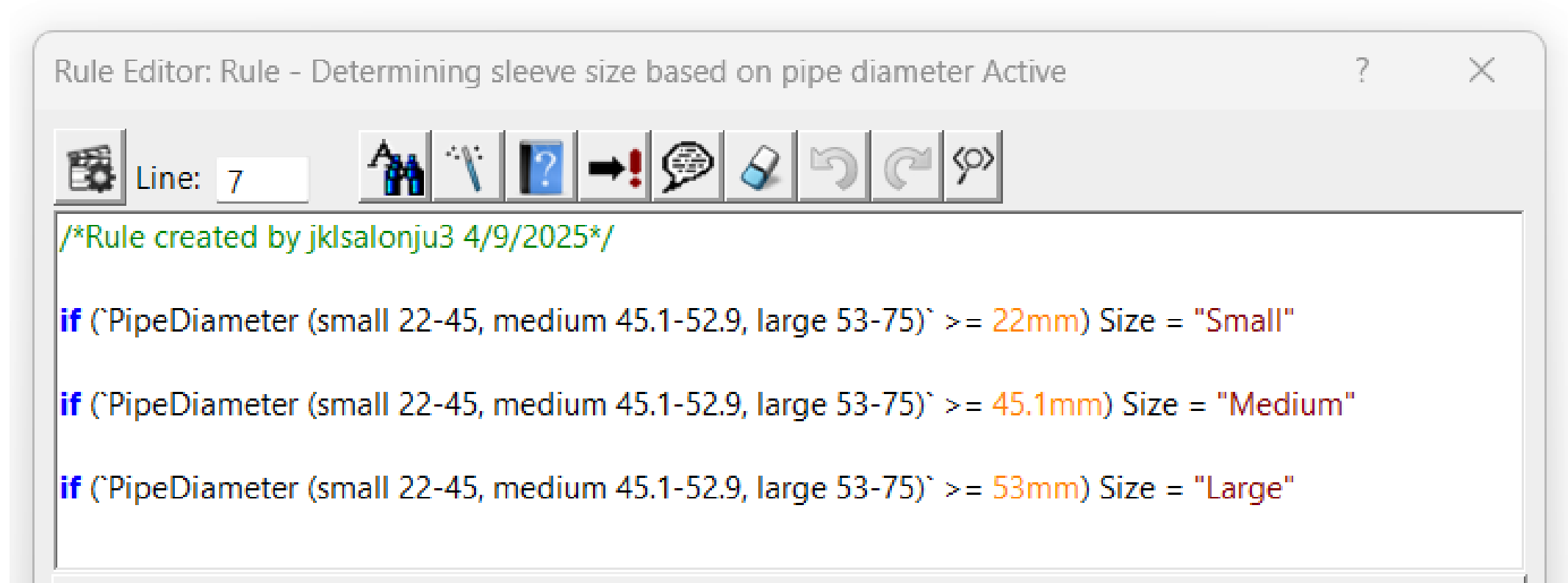
# Sketch example

The sketches are fully defined (with the selected few measurements defined parametrically)



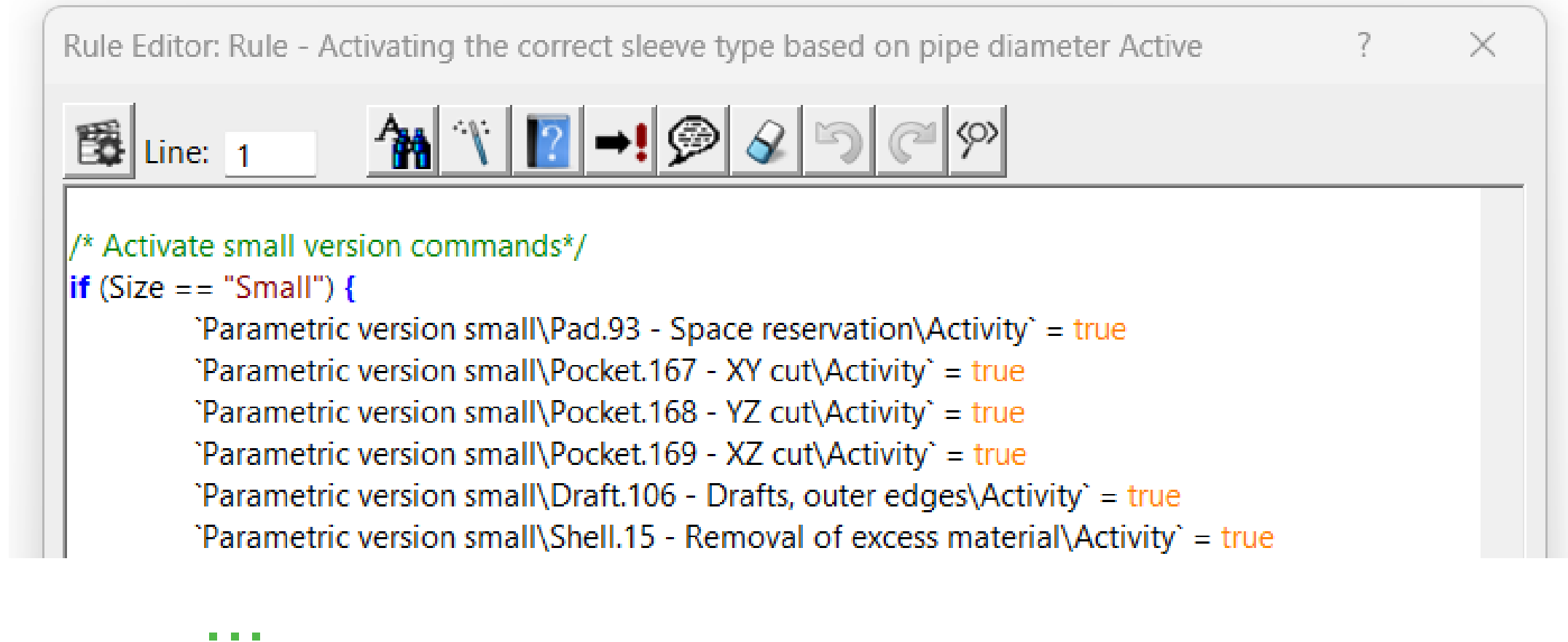
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# Logic: Determining the size based on pipe diameter



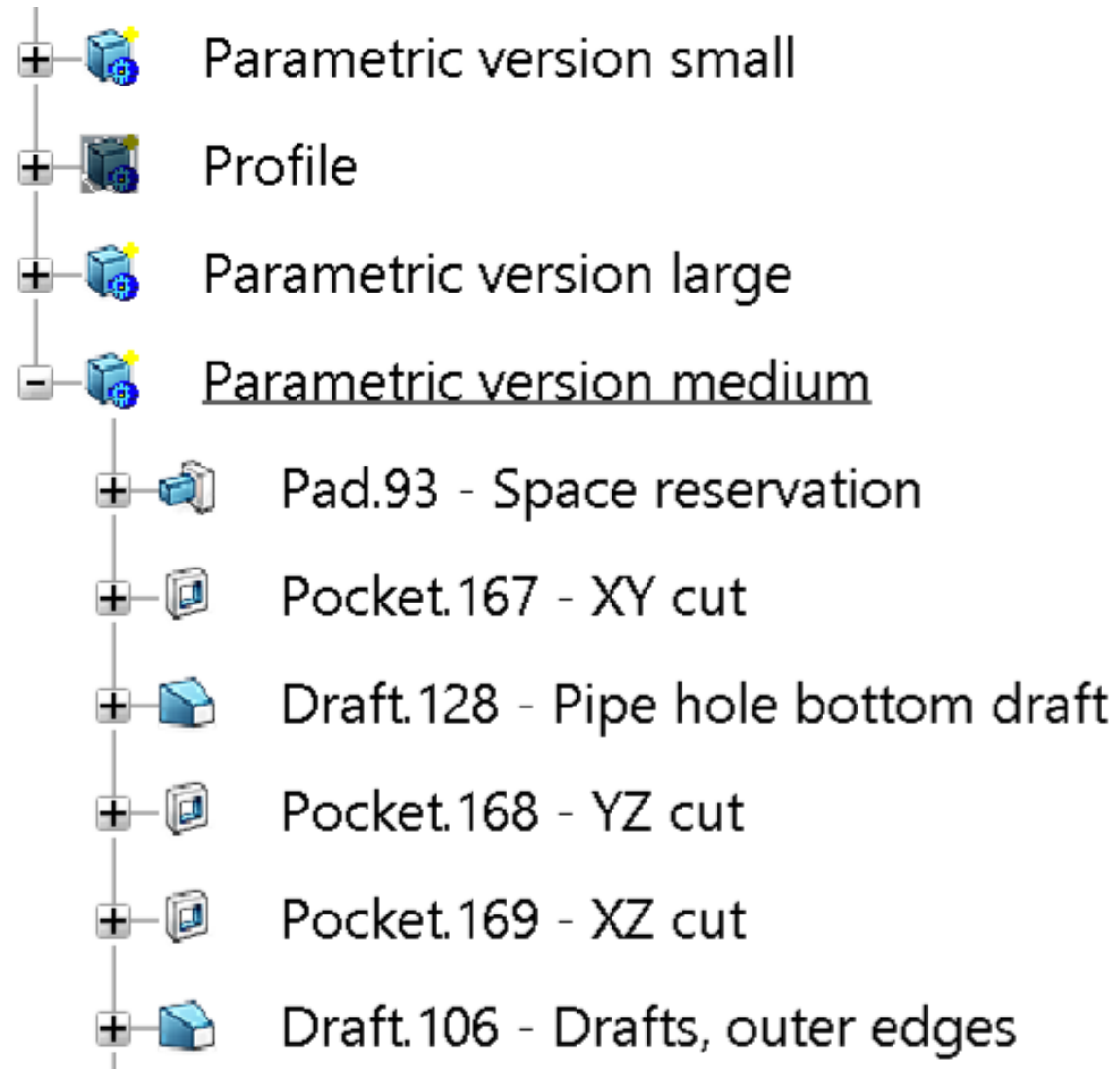


# Logic: Activating the proper features based on the size



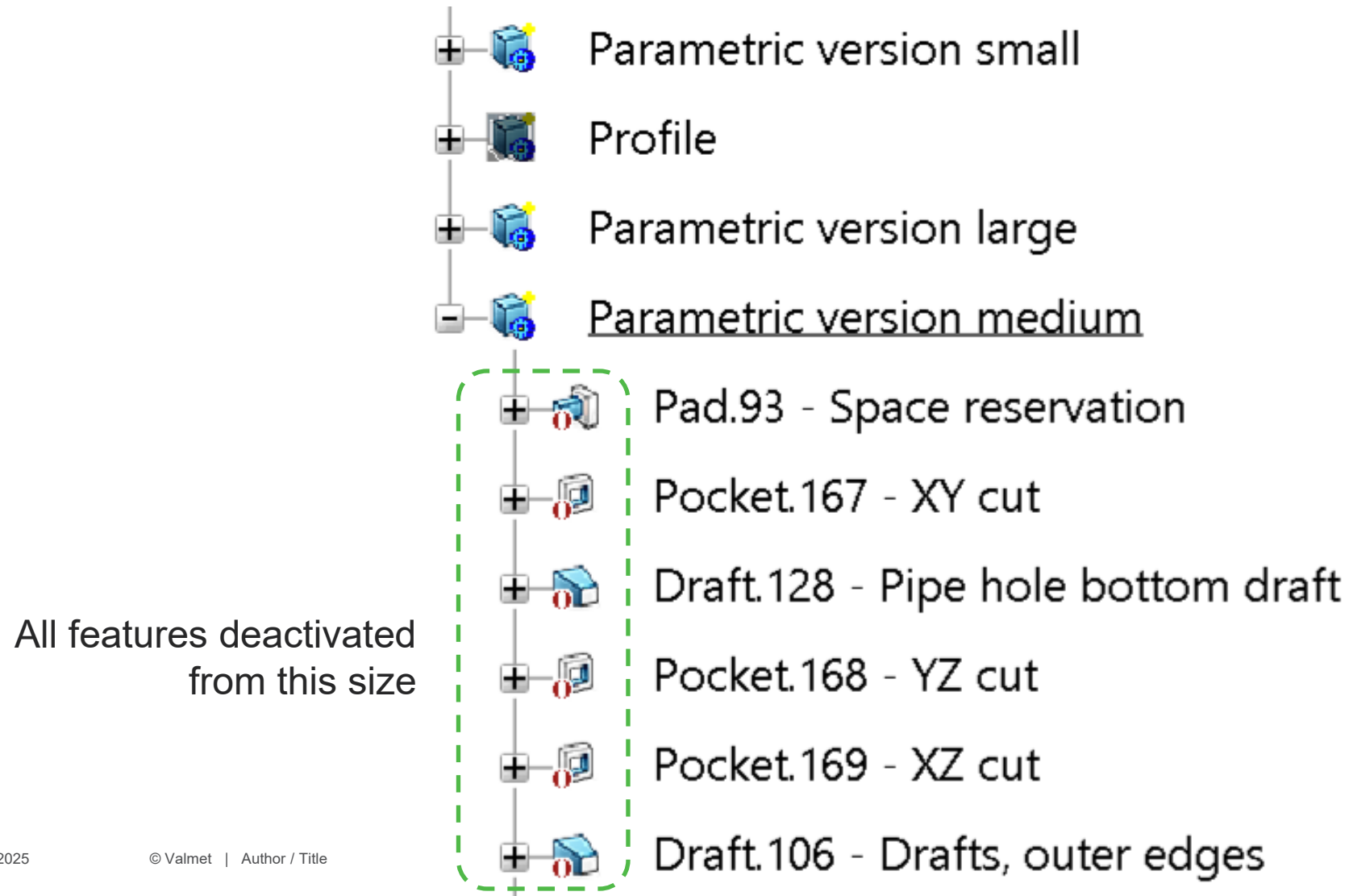
# Logic: Activating the proper features based on the size

Medium size activated (pipe size between the defined limits)













# Logic: Activating the proper features based on the size

Medium size deactivated (pipe size changed to a value outside defined limits)



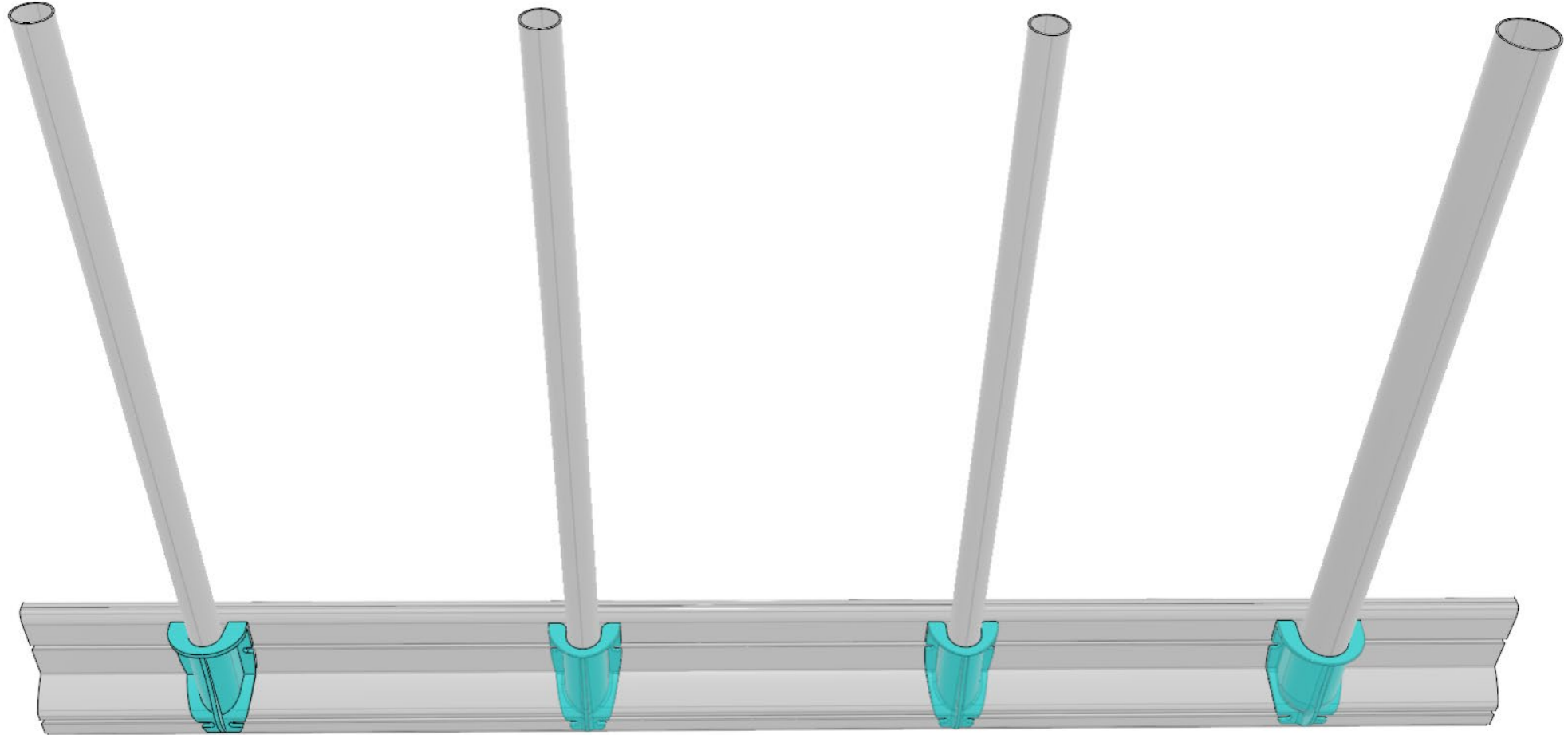
# Other notes

-  Parametric version small
-  Profile
-  Parametric version large
-  Parametric version medium

-  Pad.93 - Space reservation
-  Pocket.167 - XY cut
-  Draft.128 - Pipe hole bottom draft
-  Pocket.168 - YZ cut
-  Pocket.169 - XZ cut
-  Draft.106 - Drafts, outer edges

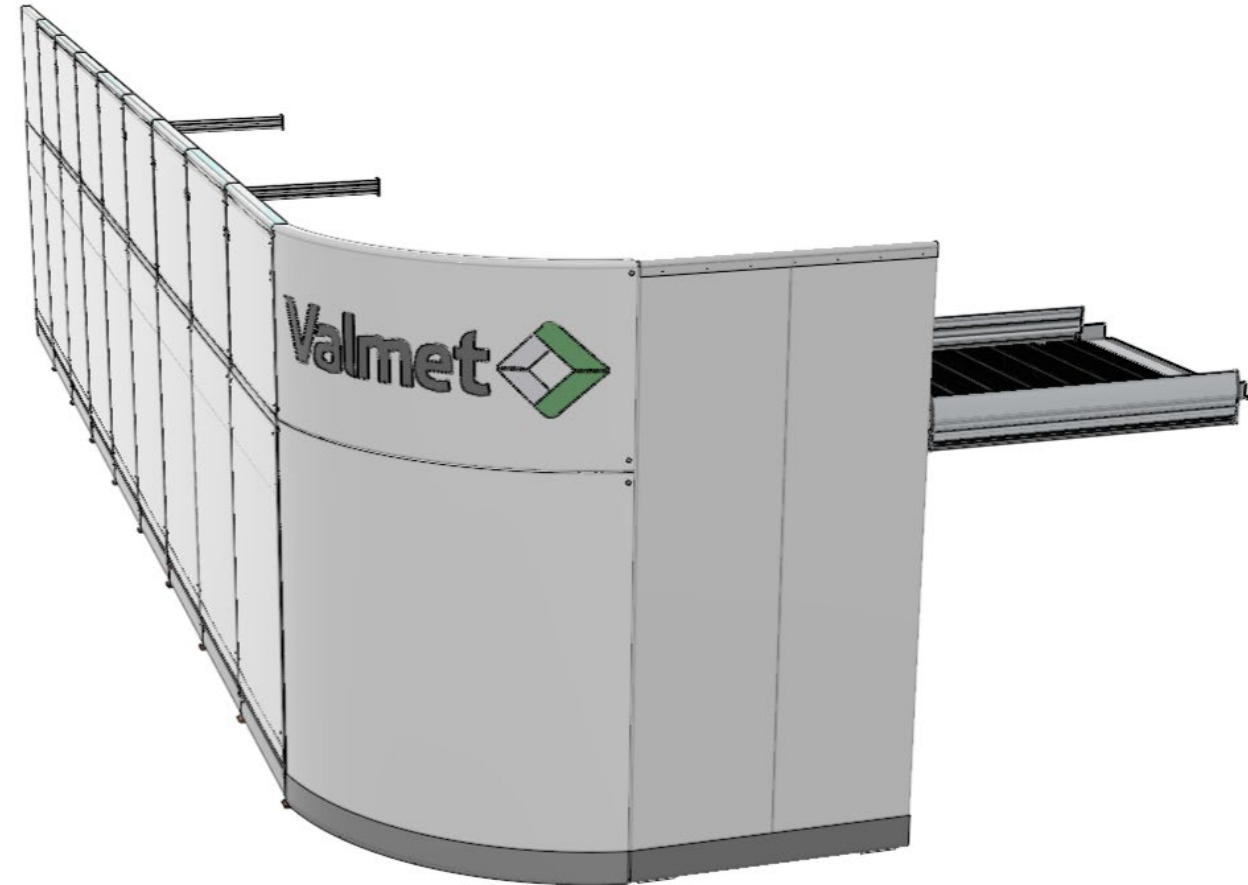
Informatively  
named  
features;  
No excess  
features, only  
what is needed

# All the 3D models side by side

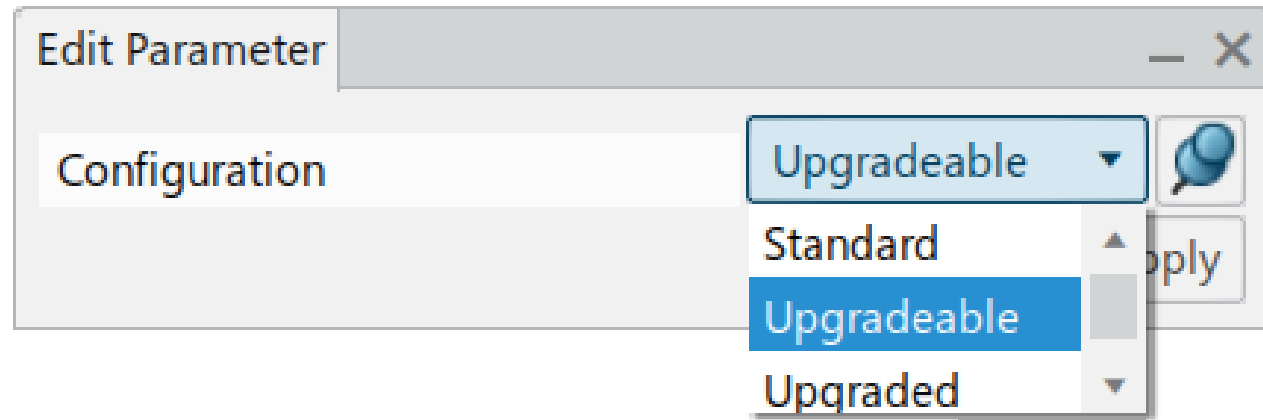
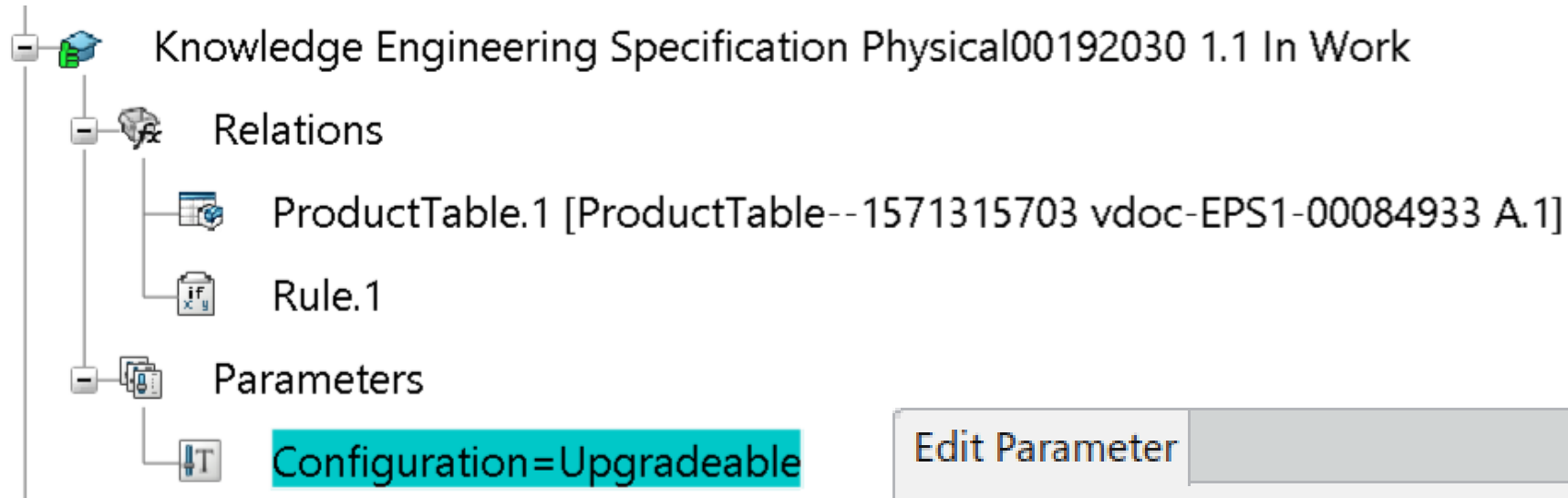


# Product tables: A preferred alternative to varying configurations

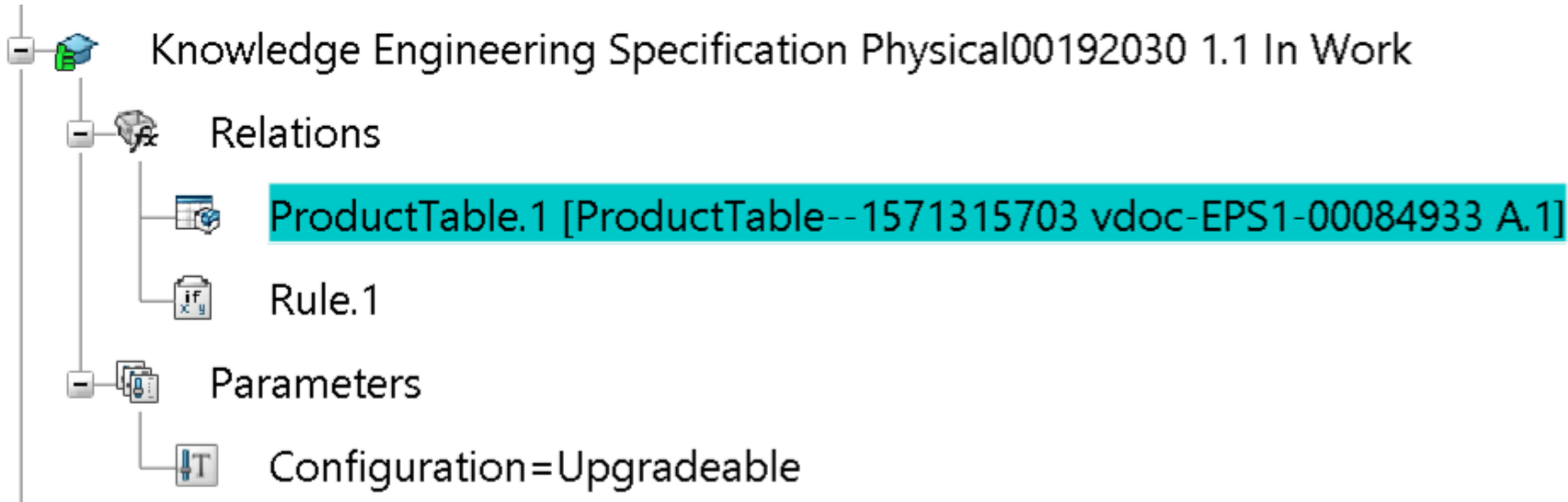
- FRP guard wall assembly 1.1 IN\_WORK prd-EPS1-04761356 Project Specific
  - Standard parts prd-EPS1-24120403 Project Specific (Standard parts.1)
  - Upgradeable parts prd-EPS1-24120404 Project Specific (Upgradeable parts.1)
  - Upgraded parts prd-EPS1-24120405 Project Specific (Upgraded parts.1)



# Product tables: A preferred alternative to varying configurations



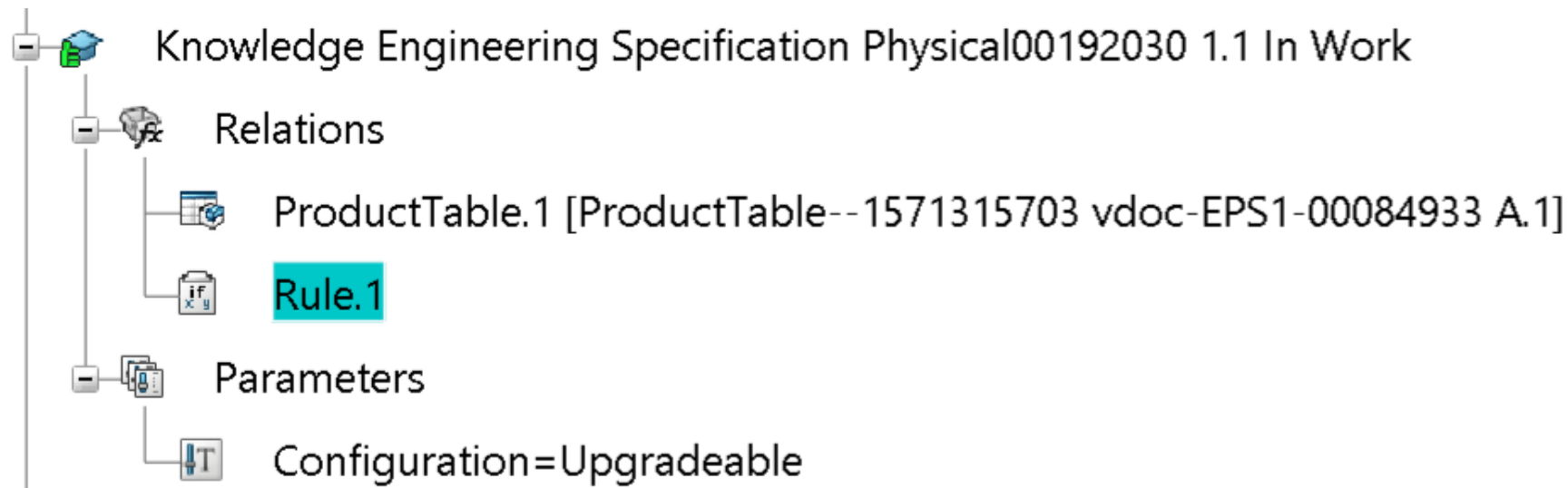
# Design tables: A preferred alternative to varying configurations



	A	B	C	
1	Identifier	Standard	Upgradeable	Upgraded
2	1	true	false	false
3	2	false	true	false
4	3	false	false	true



# Design tables: A preferred alternative to varying configurations



Rule Editor: Rule.1 Active

Line: 10

```
/*Rule created by jksalonju4 17.10.2019*/  
  
IF Configuration == "Standard"  
    `Knowledge Engineering Specification Physical00192030 1.1 In Work\Relations\ProductTable.1`.ConfigurationRow=1  
  
IF Configuration == "Upgradeable"  
    `Knowledge Engineering Specification Physical00192030 1.1 In Work\Relations\ProductTable.1`.ConfigurationRow=2  
  
IF Configuration == "Upgraded"  
    `Knowledge Engineering Specification Physical00192030 1.1 In Work\Relations\ProductTable.1`.ConfigurationRow=3
```

## 5 | Summary

# Takeaways from today

- Use the modelling/visualization method that is just enough for the purpose
  - Check 12 principles of agile software development (= the art of maximizing work not done in particular)
  - Check 8 wastes of LEAN (= no extra processing in particular)
- Only do parametric models when your design is frozen, and you know what parameters are needed and what are their required ranges (e.g. pipe diameter for the cast sleeve)
  - Enabling a wider range of adjustability that is needed can multiply the work required several times over (e.g. 4x more from 22-45mm to 22-75mm)



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# C5 – Computer Aided Design

## L3 – Design of parametrized parts with applications in logistics

### P5 - Bosch Cluj Plant

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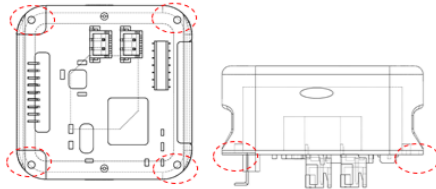
# Design of parametrized parts with application in logistics



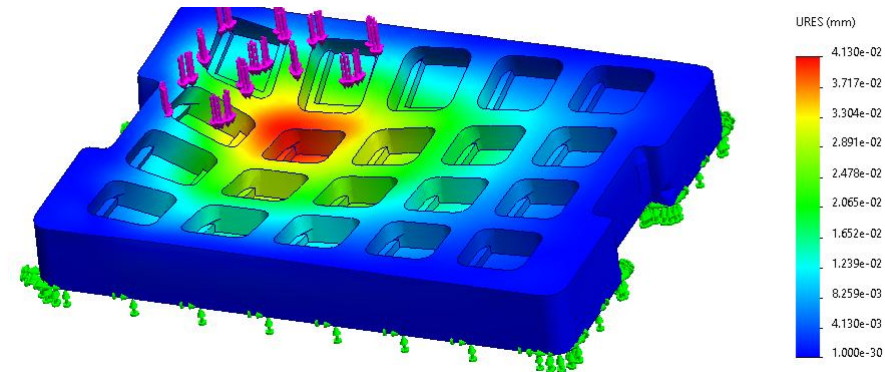
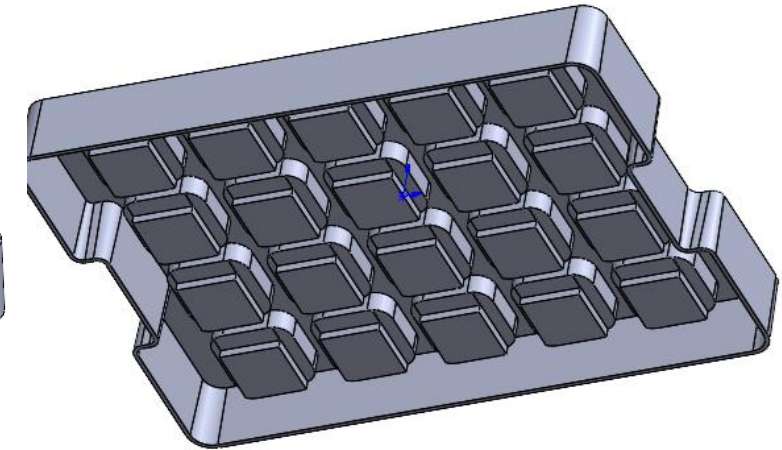
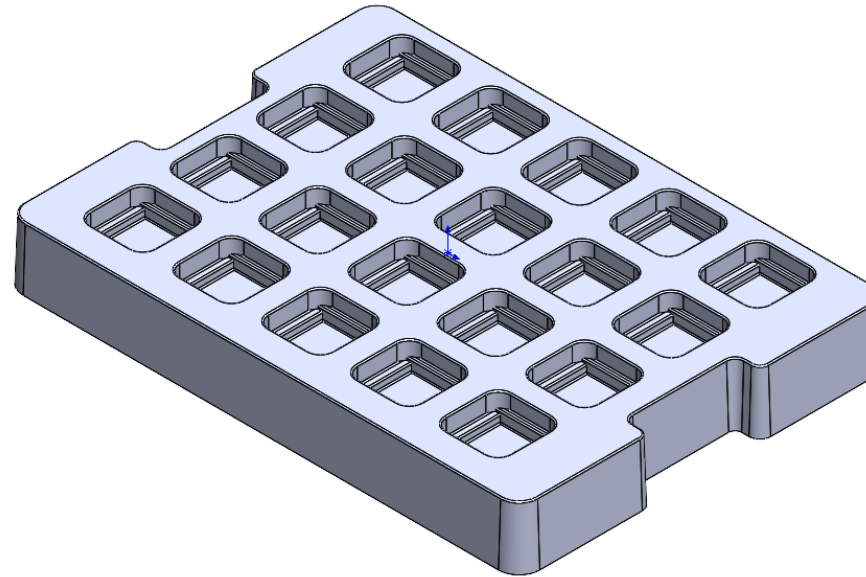
## C5 – Computer Aided Design – Laboratory activity

Topic: Design of parametrized parts with application in logistics

Table 1. Blister design parameters

Student	Parameters		Value	Measurement units
S1	Blister length	L	415-10	[mm]
S1	Blister width	W	300-10	[mm]
S1	Blister height	H	50	[mm]
S1	Blister connection radius (raza racord)	Rc	15	[mm]
S2	Blister lateral support/wall Angle	LSA	2	[deg]
	Handle length	HL	90	[mm]
	Handle width	Hw	20	[mm]
	Handle fillet radius	Hr	15	[mm]
S3	Minimal distance from the blister edge/border	Db	20	[mm]
S3	Positioning height of the piece compared to the blister surface	Hp	10	[mm]
S2	Blister thickness	Tk	2	[mm]
S2	Blister – component contact distance	Cd	1	[mm]
S2	Blister – component clearance distance	Cld	2	[mm]
S3	Blister – component contact zones			
				
S3	Positioning of the component on the blister	<input type="checkbox"/> Parallel with the blister edge <input type="checkbox"/> At an angle Angle value: ..... [deg]		

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# Design of parametrized parts with application in logistics

## Laboratory overview:

### Objectives

- Design a blister based on a set of prerequisite requirements (manipulated part, materials etc.)
- Define the blister geometric parameters to be compatible with manufacturing process

### Pre-requisite

- Basic skills and knowledge of SolidWorks
- Basic knowledge in technical drawings
- Basic knowledge manufacturing and plastic thermoforming

### Equipment used for laboratory

- PCs with SolidWorks



# Design of parametrized parts with application in logistics

**Upon completion of this laboratory, the student will be able to:**

- 1) Define parametrized parts
- 2) Define the negative of a given part that could be used to design dedicated transportation modules (blisters)
- 3) Design parametrized parts that could be manufactured using plastic thermoforming
- 4) Implement rapid prototyping procedures for testing blisters





# Content

- Introduction
- Theoretical concepts
  - Design procedure of a blister used in logistics
  - Defining the negative of a part
  - Parametrized parts / Parametric modelling
- Laboratory task
  - Define the main design parameters and restrictions
  - Design the blister based on the imposed requirements
  - Testing procedures for the designed part
- Summary, Discussions & Feedback

# Introduction



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# Introduction

- **Blister** - pre-formed plastic cavity used to securely hold and protect a large variety of products
- **Applications:**
  - Electronics industry
  - Pharmaceutical industry
  - Consumer goods
  - Food industry
  - Production lines



# Introduction

- **Advantages:**

- Product protection
- Efficient automation
- Cost-effective
- Lightweight
- Customization
- Product visibility

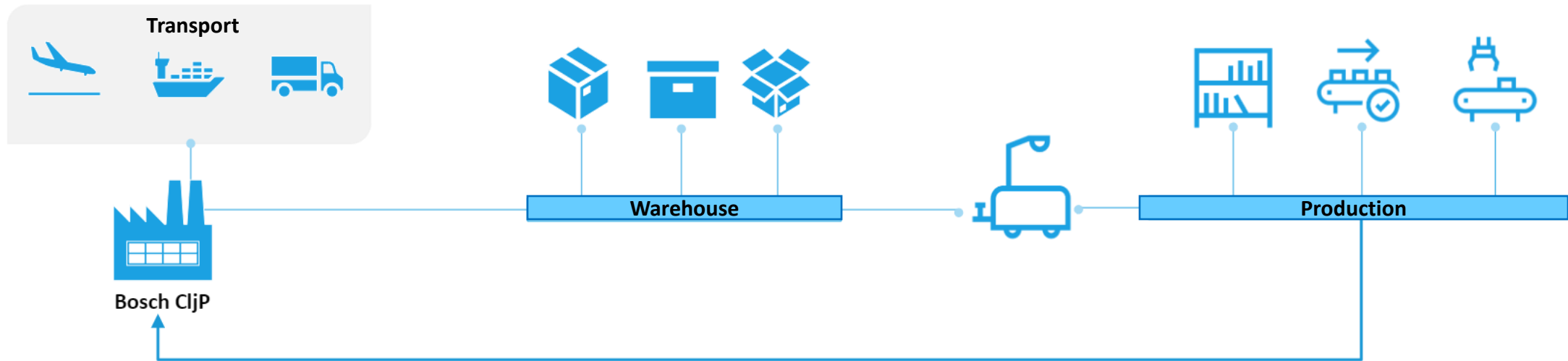
- **Limitations:**

- Limited size and shape flexibility
- Environmental concerns
- Lower structural strength
- Cost of custom tooling

# Introduction

## Logistics processes – *blister* role

- Packaging



# Introduction

- Benefits of using blisters on production lines & logistics



- automation

- Easy and safe transportation



- Optimal storage

# Theoretical concepts



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# Blister design procedure

**Goal** – design a blister that is *functional*, *efficient* and *cost-effective*

## Constraints:

- Product properties
- Material used
- Manufacturing technology
- Production processes





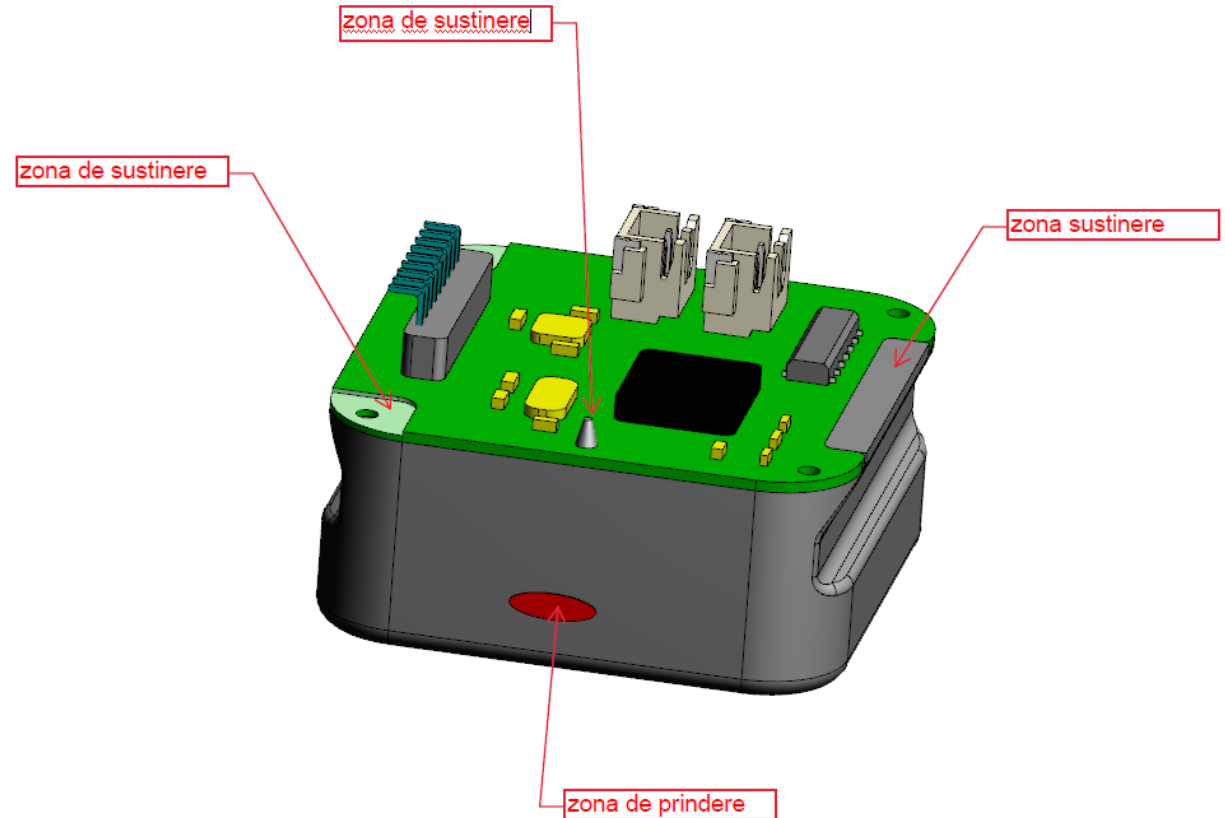
# Blister design procedure

## Design steps for the blister

### I. Understand the Product and Requirements:

#### Product analysis

- evaluate the **physical characteristics** (size, shape, weight) and the manipulated system
- Identify **sensitive areas** on the product that needs to be protected (ex. thin sections, protruding components, or smooth surfaces may need extra space or cushioning in the blister design)



# Blister design procedure

## Design steps for the blister

### I. Understand the Product and Requirements:

#### Logistic specific constrains

- determine how the product is transported, stored, and handled during the logistic process
- *Ergonomic Aspects and Manual Handling*
- *Process Size Limitations (Conveyor Belt, Container, Box, Pallet)*



# Blister design procedure

## Design steps for the blister

### II. Material Selection

- Material selection influence: overall strength, flexibility, environmental impact, and cost of the packaging

#### **PET** **(Polyethylene Terephthalate)**

- good strength
- good protection of product from physical damage and env. Factors

#### **PVC** **(Polyvinyl Chloride)**

- good strength
- good protection of product from physical damage and env. factors

#### **HIPS** **(High Impact Polystyrene)**

- strong impact resistance
- cheap

#### **PP** **(Polypropylene)**

- lightweight
- durable
- chemically resistant
- excellent resistance to moisture and heat

# Blister design procedure

## Design steps for the blister

### II. Material Selection - Environmental Impact

**Eco-friendly measures** in blister packaging:

- **Use of Recyclable Materials**

#### **Polypropylene (PP)**

-most eco-friendly due to its recyclability

#### **Polyethylene Terephthalate (PET)**

- highly recyclable and commonly used in packaging

#### **High Impact Polystyrene (HIPS)**

- less environmentally friendly than PP and PET
- recyclable in certain facilities

#### **Polyvinyl Chloride (PVC)**

- least eco-friendly
- PVC is difficult to recycle
- releases harmful chemicals during production and disposal



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# Blister design procedure

## Design steps for the blister

### II. Material Selection - Environmental Impact

**Eco-friendly measures** in blister packaging:

- **Use of Recyclable Materials** - replacing PVC, which is hard to recycle, with more sustainable alternatives like PET or RPET (recycled PET).
- **Modular Design**: Creating reusable or refillable blister packaging that reduces the need for single-use plastics
- **Sustainable Sourcing**: Using backing materials, such as paper or cardboard, from certified sustainable sources

# Blister design procedure

## Design steps for the blister

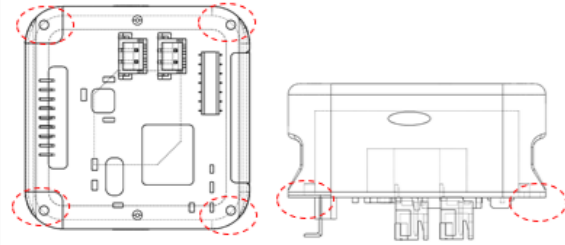
### III. Blister design specification

- Size and shape
- Thickness
- Contact clearance
- Number of parts / blister
- Contact points

## C5 – Computer Aided Design – Laboratory activity

Topic: Design of parametrized parts with application in logistics

Table 1. Blister design parameters

Student	Parameters		Value	Measurement units
S1	Blister length	L	415-10	[mm]
S1	Blister width	W	300-10	[mm]
S1	Blister height	H	50	[mm]
S1	Blister connection radius (raza racord)	Rc	15	[mm]
S2	Blister lateral support/wall Angle	LaA	2	[deg]
	Handle length	Hl	90	[mm]
	Handle width	Hw	20	[mm]
	Handle fillet radius	Hr	15	[mm]
S3	Minimal distance from the blister edge/border	Db	20	[mm]
S3	Positioning height of the piece compared to the blister surface	Hp	10	[mm]
S2	Blister thickness	Tk	2	[mm]
S2	Blister – component contact distance	Cd	1	[mm]
S2	Blister – component clearance distance	Cld	2	[mm]
S3				
S3	Positioning of the component on the blister	<input type="checkbox"/> Parallel with the blister edge <input type="checkbox"/> At an angle Angle value: ..... [deg]		

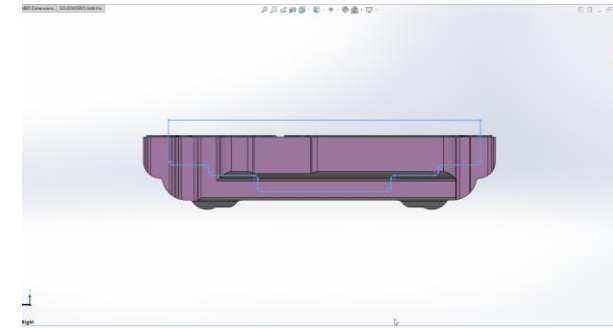
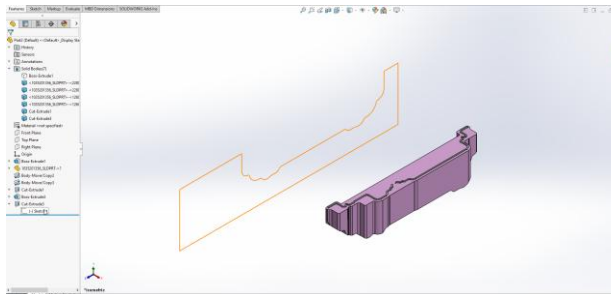
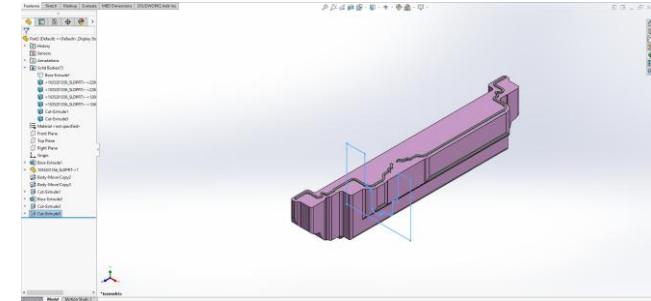
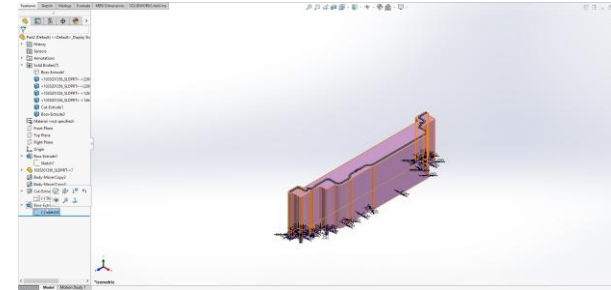
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# Blister design procedure

## Design steps for the blister

### IV. Prototyping

- Develop the negative of the part
  - Method 1

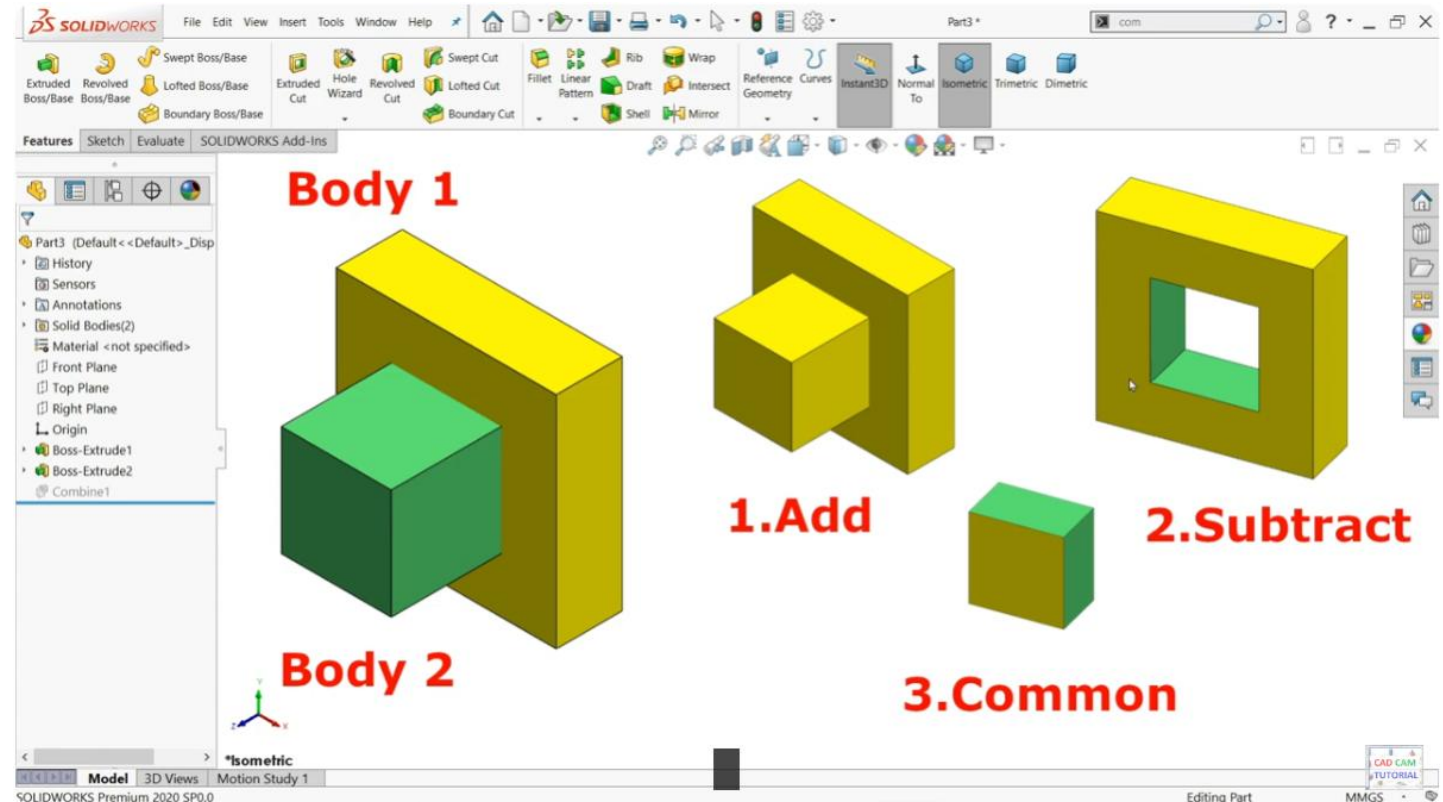


# Blister design procedure

## Design steps for the blister

### IV. Prototyping

- Develop the negative of the part
- Method 2



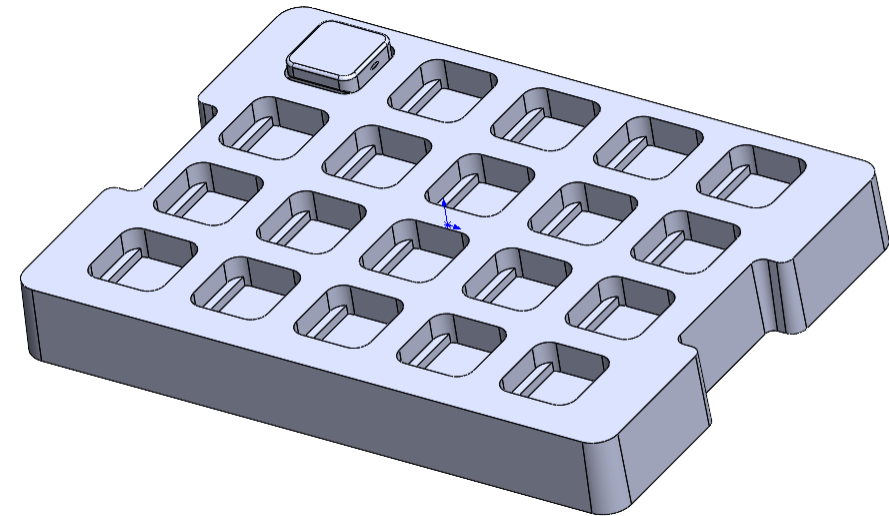
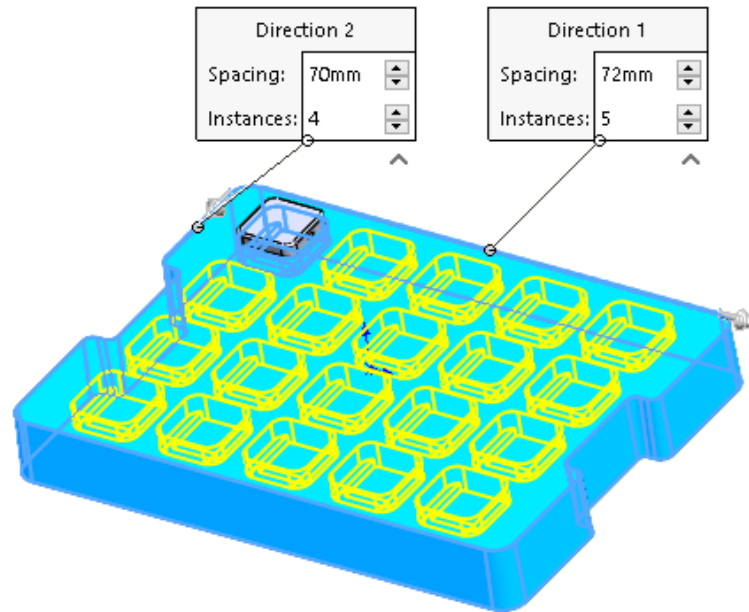


# Blister design procedure

## Design steps for the blister

### IV. Prototyping

- Multiply the negative of the part to obtain the blister



# Blister design procedure

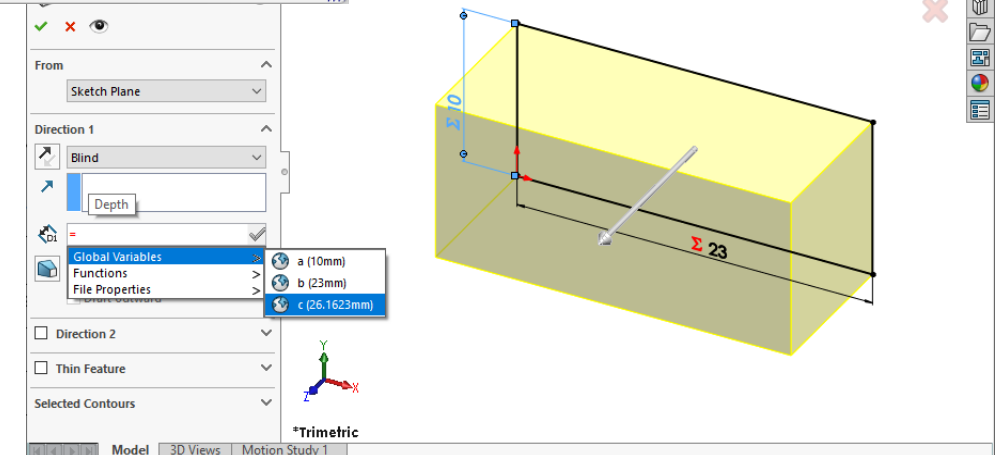
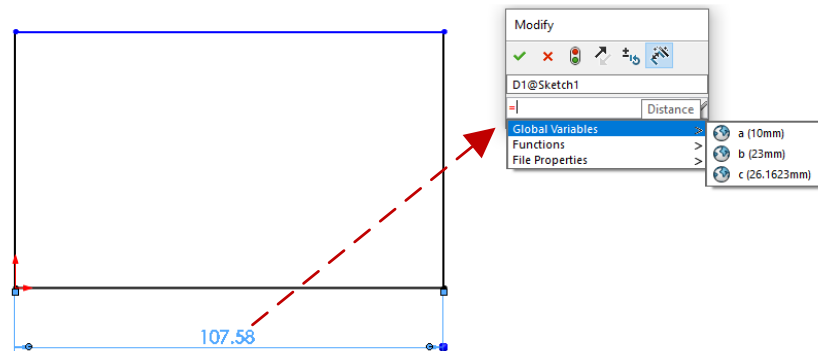
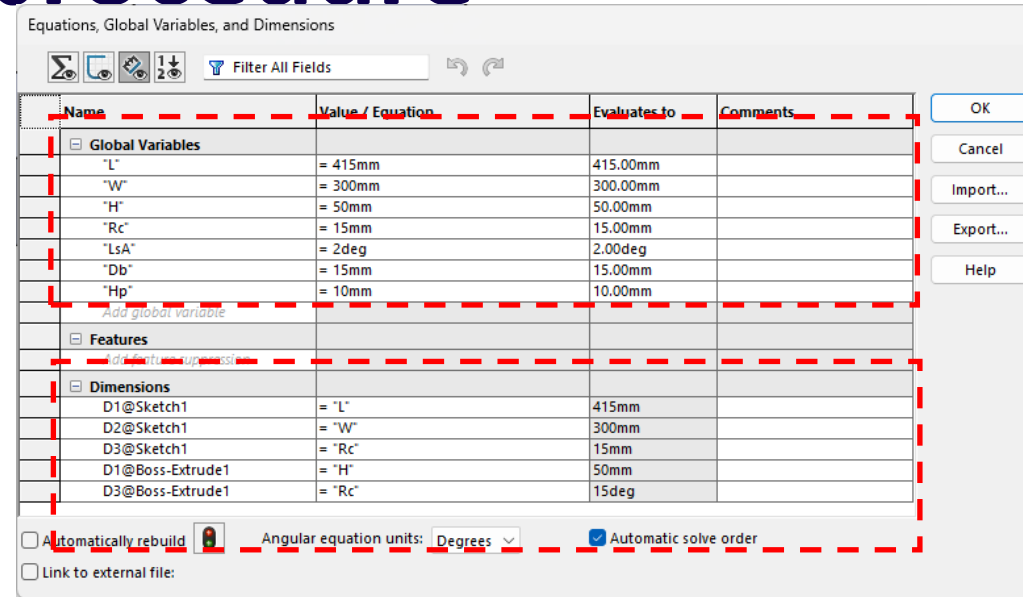
## Parametrized parts / Parametric modelling

- Def - **Parametric modelling** is a process where the geometry of a CAD model is defined using dimensional parameters; these parameters help to alter the model geometry just by adjusting their values.
- Advantages
  - Creating dependencies between the dimensions of the part
  - Simplifies the part modification process
  - Mathematical relationships can be used for dimensioning

# Blister design procedure

## Parametric modelling

- How to?

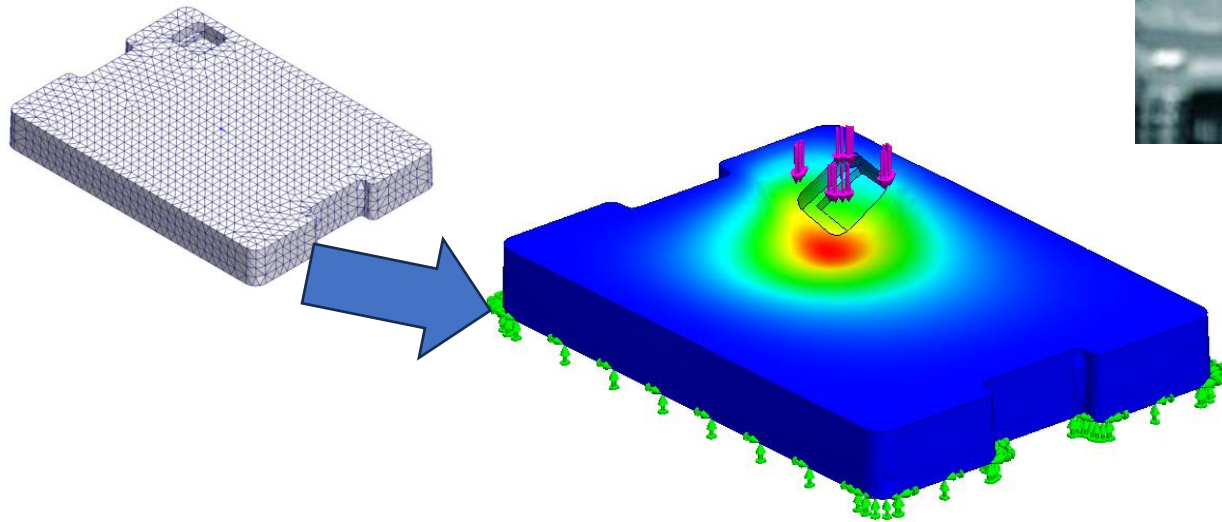


# Blister design procedure

## Design steps for the blister

### IV. Test process of the Prototyping

- Simulations
- 3D printing



# Laboratory work



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# Design requirements

## Working procedure:

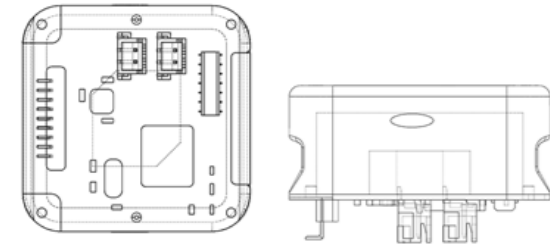
- groups of 3 students
  - student 1 – logistics;
  - student 2 – ergonomics & thermoforming
  - student 3 – engineering & production

**Task:** Each student identifies the parameters specific to its field which influence the blister design and introduce the data inf provided document

## C5 – Computer Aided Design – Laboratory activity

Topic: Design of parametrized parts with application in logistics

Table 1. Blister design parameters

Student	Parameters		Value	Measurement units
S1	Blister length	L	415-10	[mm]
S1	Blister width	W	300-10	[mm]
S1	Blister height	H	50	[mm]
S1	Blister connection radius (raza racord)	Rc	15	[mm]
S2	Blister lateral support/wall Angle	LsA	2	[deg]
S3	Minimal distance between parts	Dp	15	[mm]
S2	Blister thickness	Tk	2	[mm]
S2	Blister – component contact distance	Cd	1	[mm]
S2	Blister – component clearance distance	Cld	2	[mm]
S3	Blister – component contact zones 			
S3	Positioning of the component on the blister	<input type="checkbox"/> Parallel with the blister edge <input type="checkbox"/> At an angle Angle value: ..... [deg]		
S3	Inaltime pozitionare piesa fata de suprafata blister	Hp	5	[mm]

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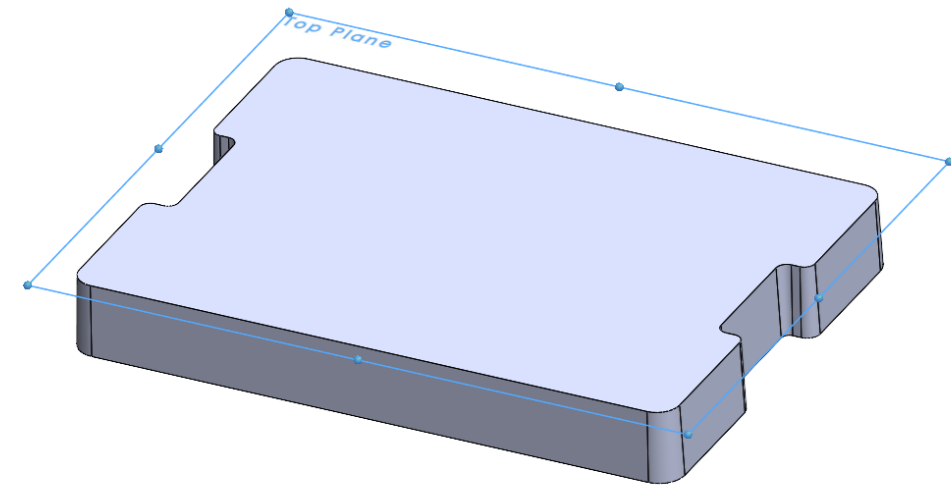
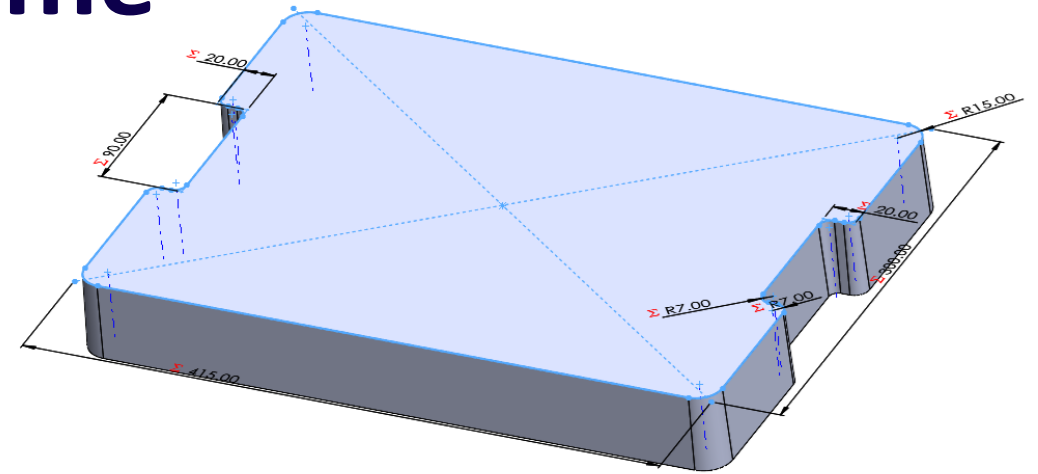
# 3D model of the blister frame

## Working procedure:

- The work is performed by each student individually

## Tasks:

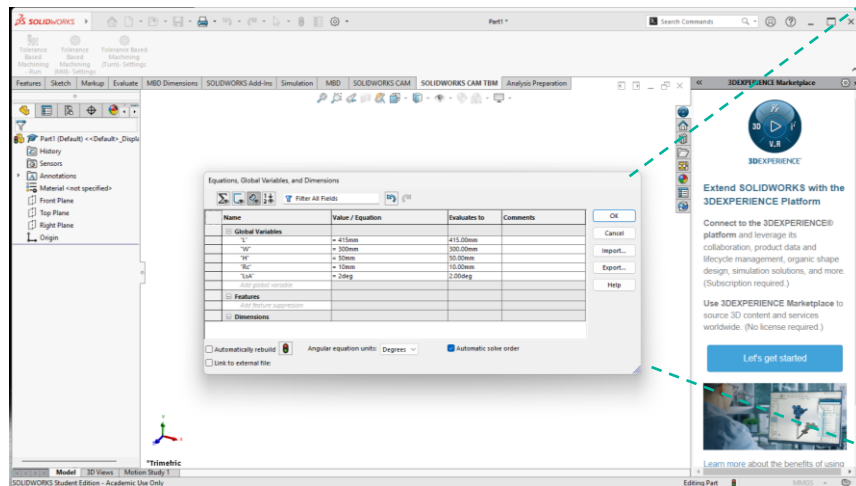
- *Introduce in equations the obtained parameters*
- *Define the blister frames using the eq. param.*



# 3D model of the blister frame

## Step 1

- A new part is created in SolidWorks.
- In the new part, from the *Tools* menu, the *Equation* command is used to define the blister's geometric parameters.



Equations, Global Variables, and Dimensions

☐ Filter All Fields

Name	Value / Equation	Evaluates to	Comments
<b>Global Variables</b>			
"L"	= 415mm	415.00mm	
"W"	= 300mm	300.00mm	
"H"	= 50mm	50.00mm	
"Rc"	= 10mm	10.00mm	
"LsA"	= 2deg	2.00deg	
<b>Features</b>			
<b>Dimensions</b>			

☐ Automatically rebuild ☐ Link to external file: Angular equation units: Degrees ☒ Automatic solve order

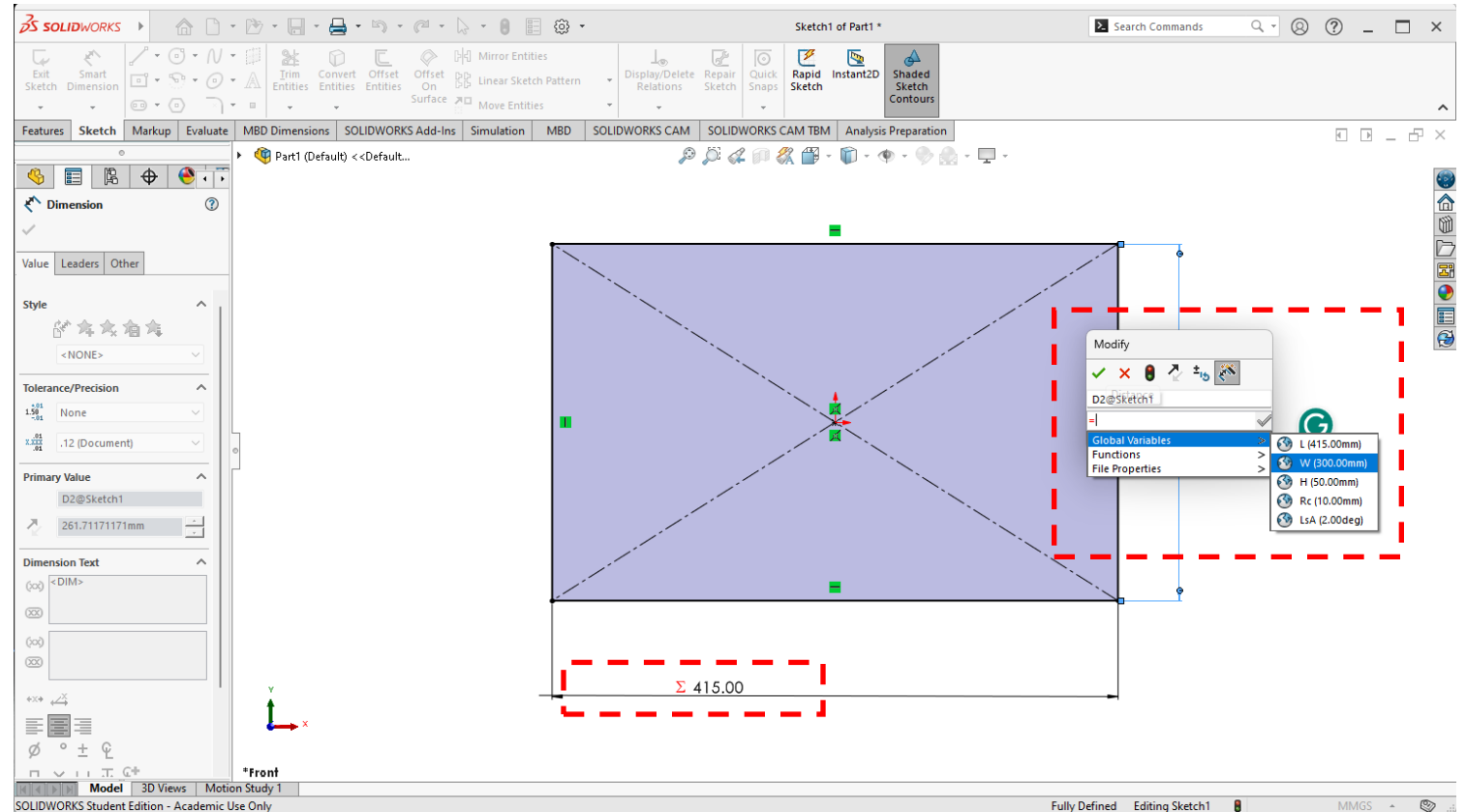




# 3D model of the blister frame

## Step 2

- On the **Top Plane**, a new sketch is created
- define the blister frame using the previously defined parameters.

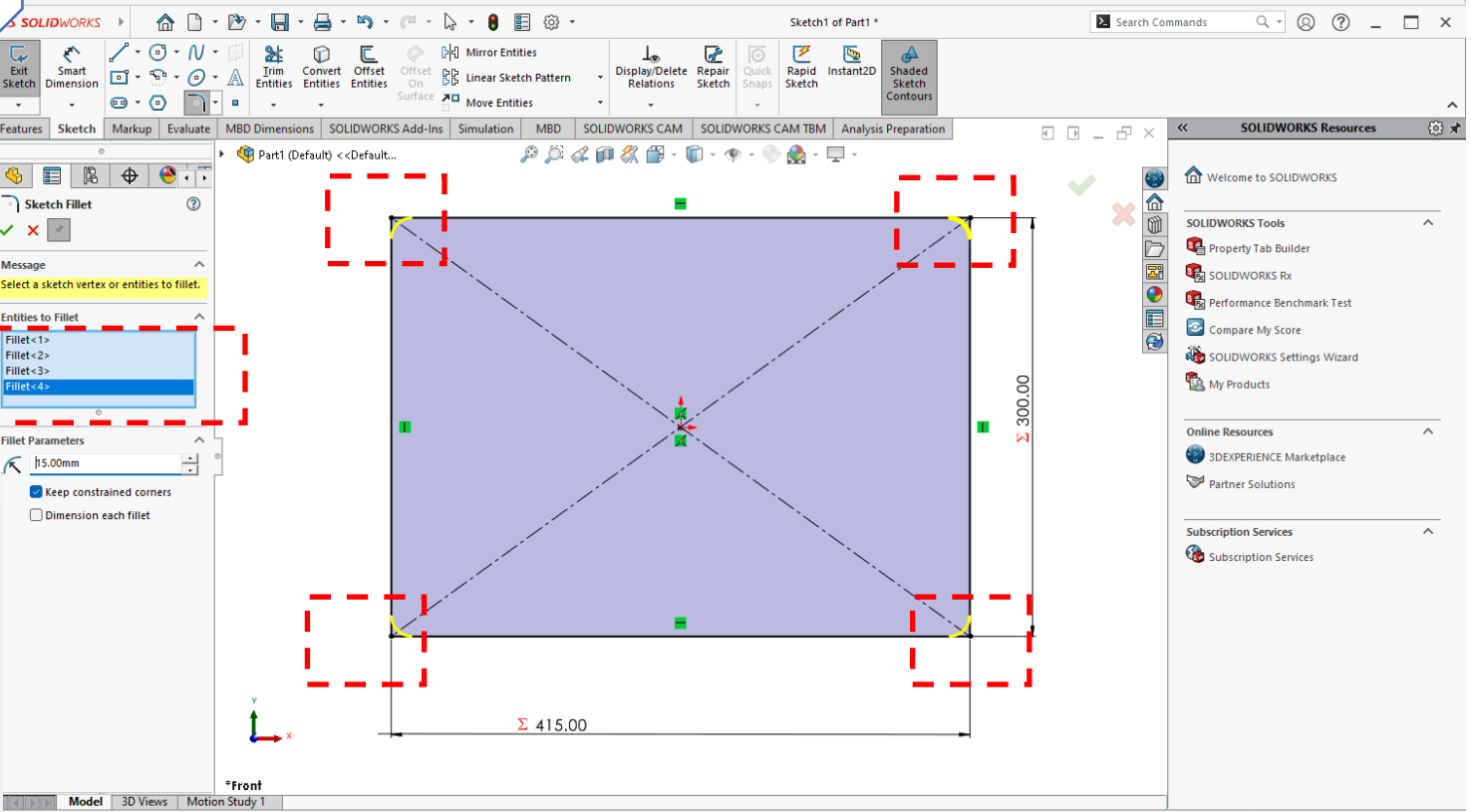


# 3D model of the blister frame

## Step 3

- Use *Sketch-Fillet* command to define the connection radius
- Associate in Equations the new radius with Rc variable

1



2

2

Name	Value / Equation	Evaluates to	Comments
<b>Global Variables</b>			
"L"	= 415mm	415.00mm	
"W"	= 300mm	300.00mm	
"H"	= 50mm	50.00mm	
"Rc"	= 15mm	15.00mm	
"LsA"	= 2deg	2.00deg	
<b>Features</b>			
<b>Dimensions</b>			
D1@Sketch1	= "L"	415mm	
D2@Sketch1	= "W"	300mm	
D3@Sketch1	= "Rc"	15mm	

Global Variables  
Functions  
File Properties

L (415.00mm)  
W (300.00mm)  
H (50.00mm)  
Rc (15.00mm)  
LsA (2.00deg)

OK  
Cancel  
Import...  
Export...  
Help

Equations, Global Variables, and Dimensions

Filter All Fields

Automatically rebuild

Angular equation units: Degrees

Link to external file:

# 3D model of the blister frame

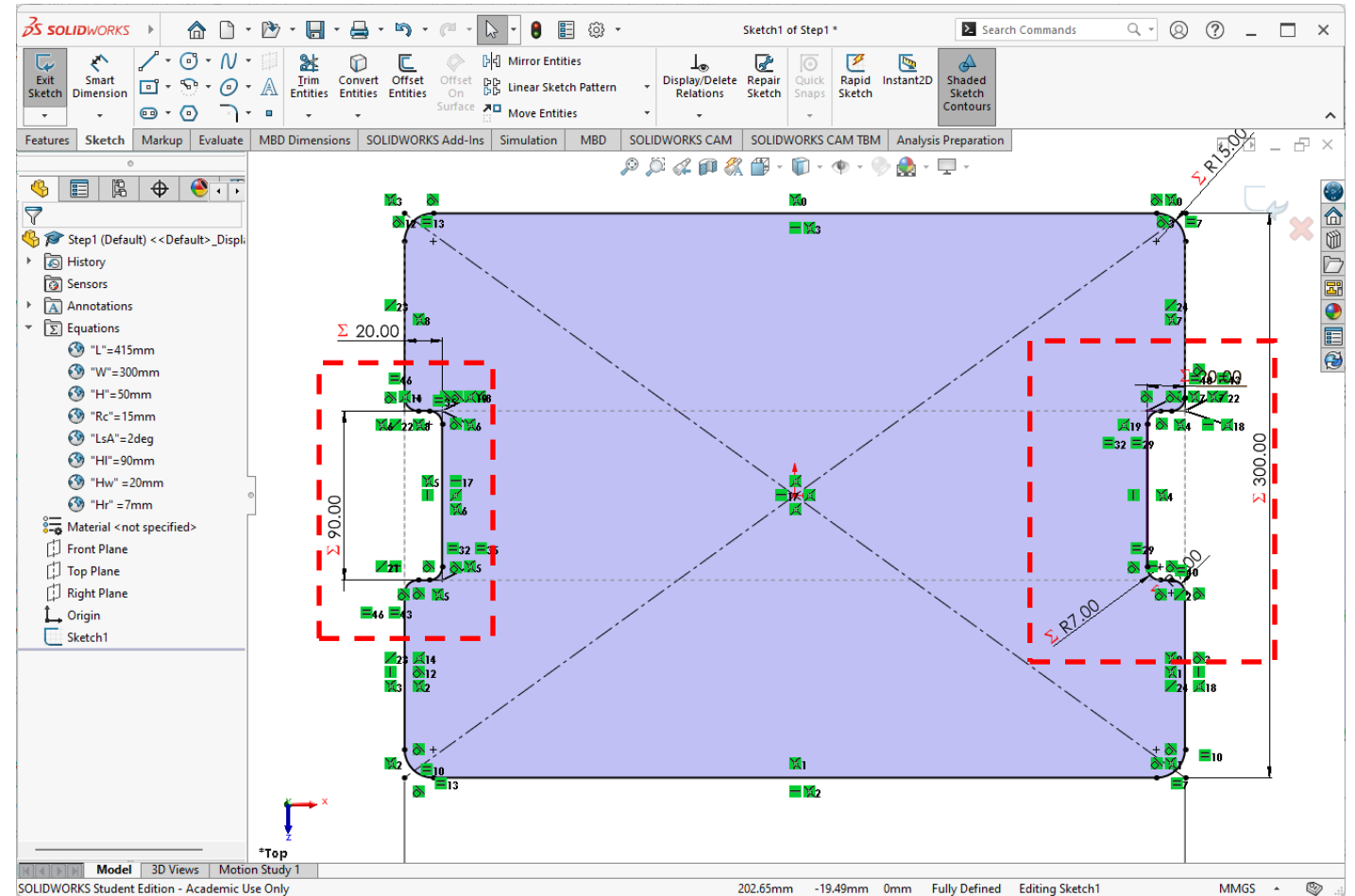
## Step 4

- Define handle for the human operator
  - The handle is centred on the left and right side of the blister
- Dimensions Hr, Hl and Hr

Equations, Global Variables, and Dimensions

Name	Value / Equation	Evaluates to	Comments
<b>Global Variables</b>			
"L"	= 415mm	415.00mm	
"W"	= 300mm	300.00mm	
"H"	= 50mm	50.00mm	
"Rc"	= 15mm	15.00mm	
"LsA"	= 2deg	2.00deg	
"Hl"	= 90mm	90.00mm	
"Hw"	= 20mm	20.00mm	
"Hr"	= 7mm	7.00mm	
<b>Features</b>			
<b>Dimensions</b>			
D1@Sketch1	= "L"	415mm	
D2@Sketch1	= "W"	300mm	
D3@Sketch1	= "Rc"	15mm	
D4@Sketch1	= "Hw"	20mm	
D5@Sketch1	= "Hw"	20mm	
D6@Sketch1	= "Hl"	90mm	
D7@Sketch1	= "Hr"	7mm	
D8@Sketch1	= "Hr"	7mm	

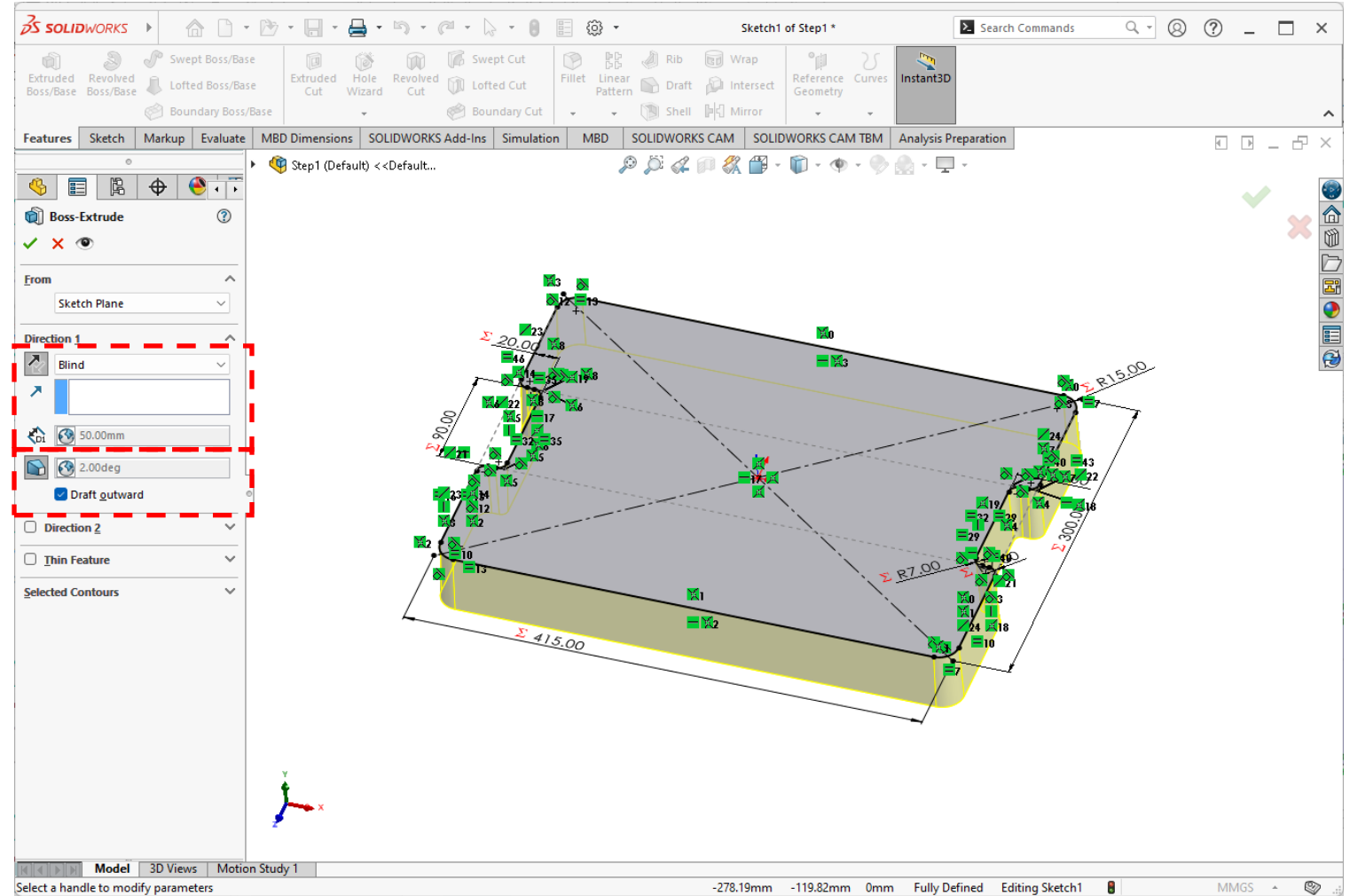
☐ Automatically rebuild ☒ Angular equation units: Degrees ☒ Automatic solve order  
☐ Link to external file



# 3D model of the blister frame

## Step 4

- Use *Boss-extrude* command to define the blister's body



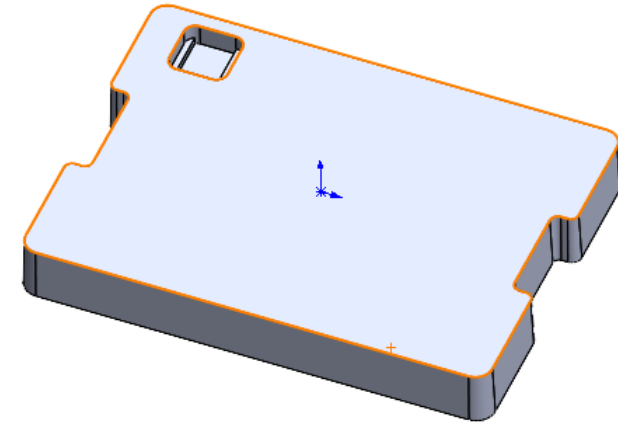
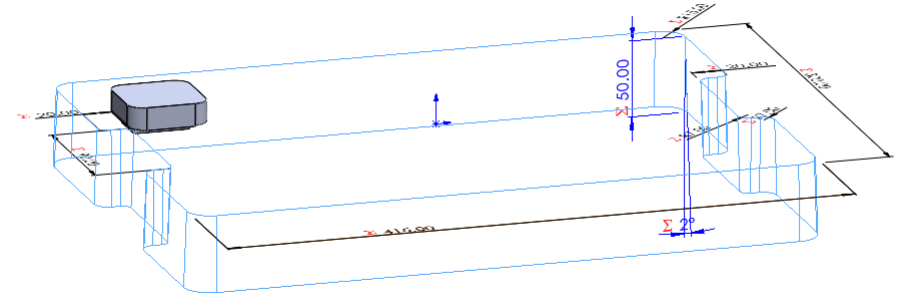
# Define the negative of the part

## *Working procedure:*

- The work is performed by each student individually

## *Tasks:*

- *Insert the part in SW*
- *Create the negative of the part*
- *Create the nest/cavity for the part*






# Define the negative of the part


## Step 1

- Define in Equation the parameters for the position of the first part on the blister

Equations, Global Variables, and Dimensions

 Filter All Fields  

Name	Value / Equation	Evaluates to	Comments
<b>Global Variables</b>			
"L"	= 415mm	415.00mm	
"W"	= 300mm	300.00mm	
"H"	= 50mm	50.00mm	
"Rc"	= 15mm	15.00mm	
"LsA"	= 2deg	2.00deg	
"Db"	= 15mm	15.00mm	
"Hp"	= 10mm	10.00mm	
<b>Features</b>			
Add feature suppression			
<b>Dimensions</b>			
D1@Sketch1	= "L"	415mm	
D2@Sketch1	= "W"	300mm	
D3@Sketch1	= "Rc"	15mm	
D1@Boss-Extrude1	= "H"	50mm	
D3@Boss-Extrude1	= "Rc"	15deg	

☐ Automatically rebuild  Angular equation units: Degrees ☒ Automatic solve order

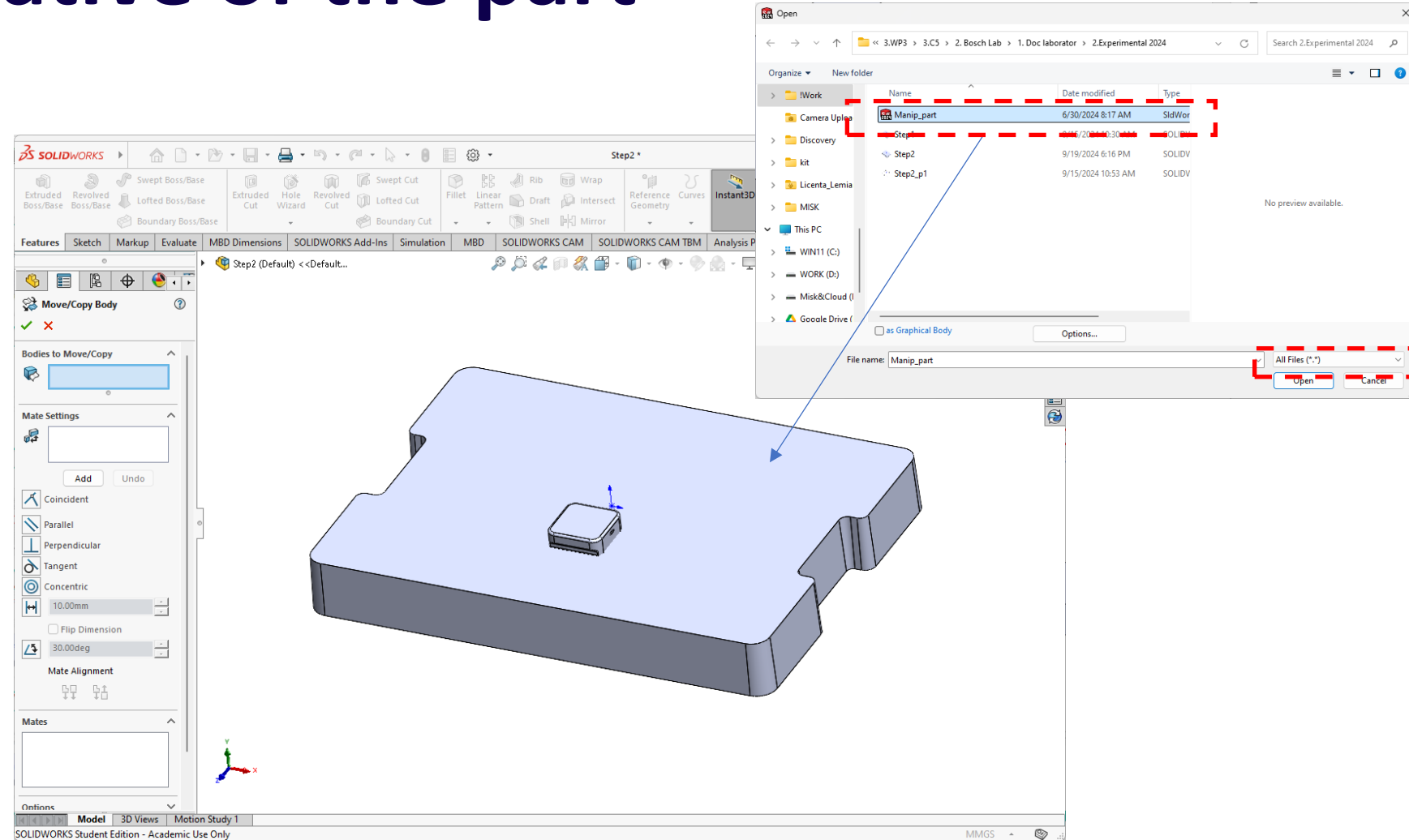
☐ Link to external file:

OK  
Cancel  
Import...  
Export...  
Help

# Define the negative of the part

## Step 2

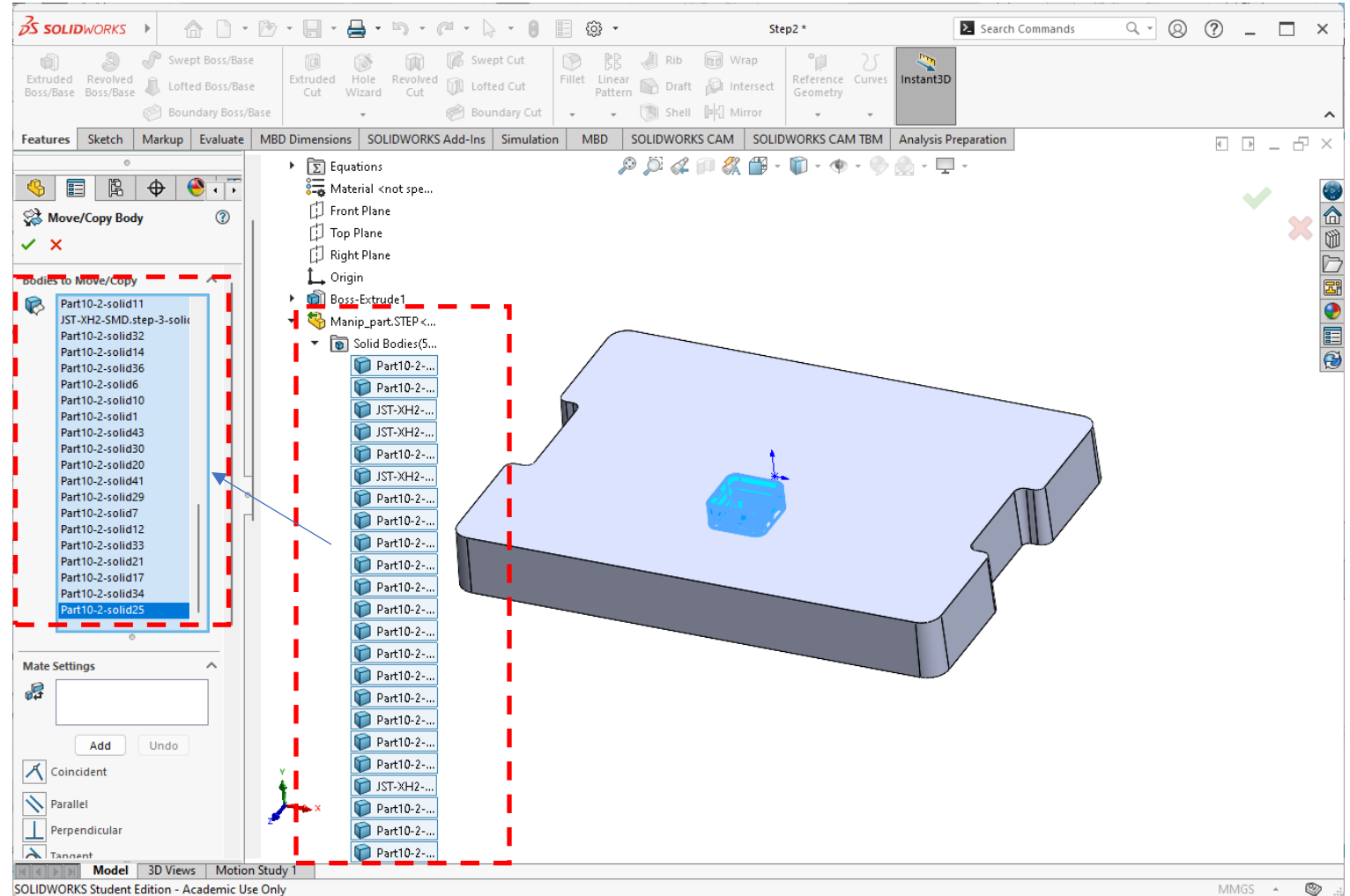
- Insert the component in the part
  - Menu **Insert**, command **Part**
  - In file type select “All files”



# Define the negative of the part

## Step 3

- Position the inserted component to the first nest location
  - menu *Insert/Surface* command *Move/Copy...*
  - in *Bodies to move* select all bodies from the *step* part

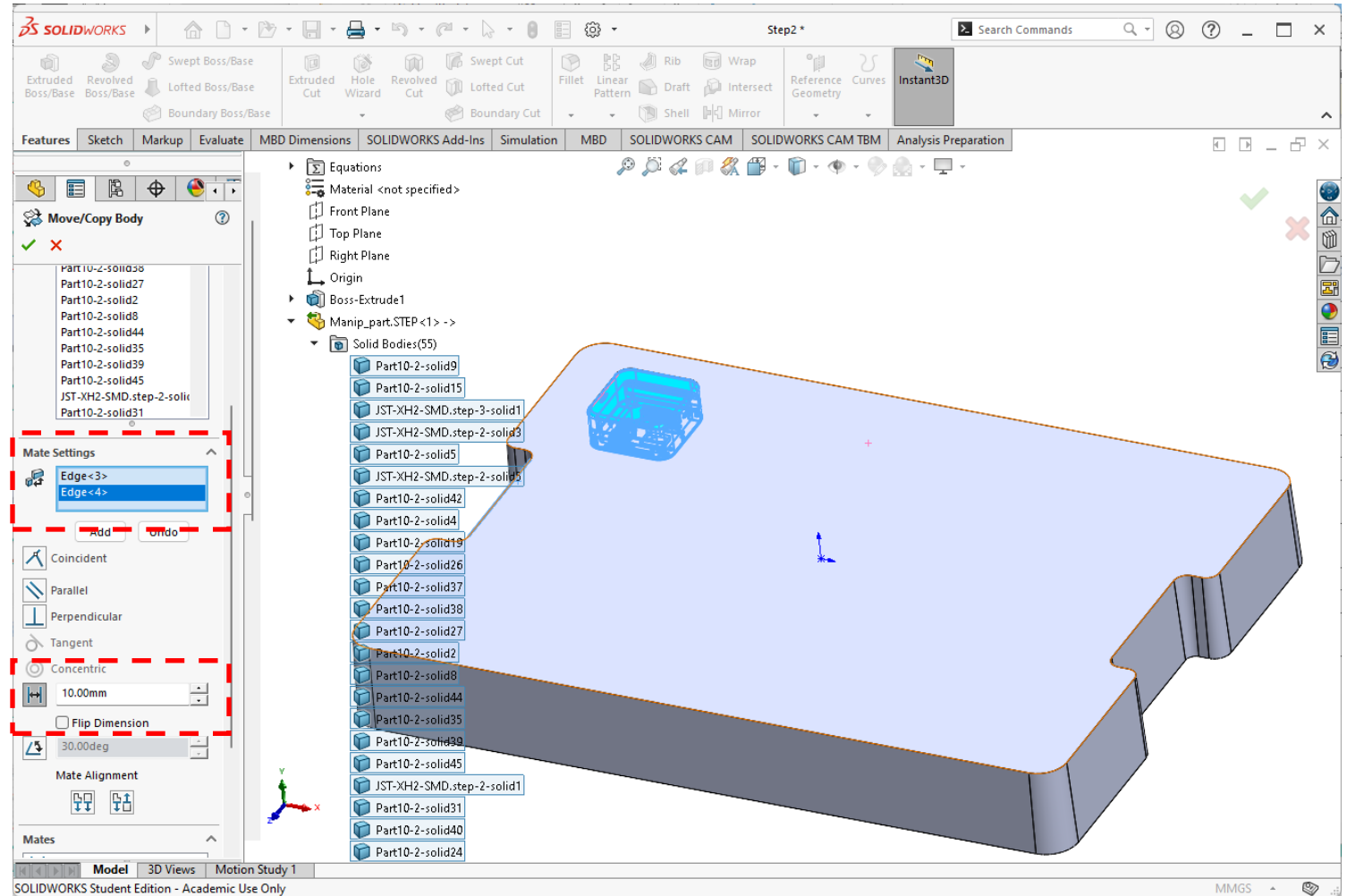




# Define the negative of the part

## Step 3

- Position the inserted component to the first nest location
  - Define distance mates between component and blister margins
  - Define distance mate between the top component face and blister's top face

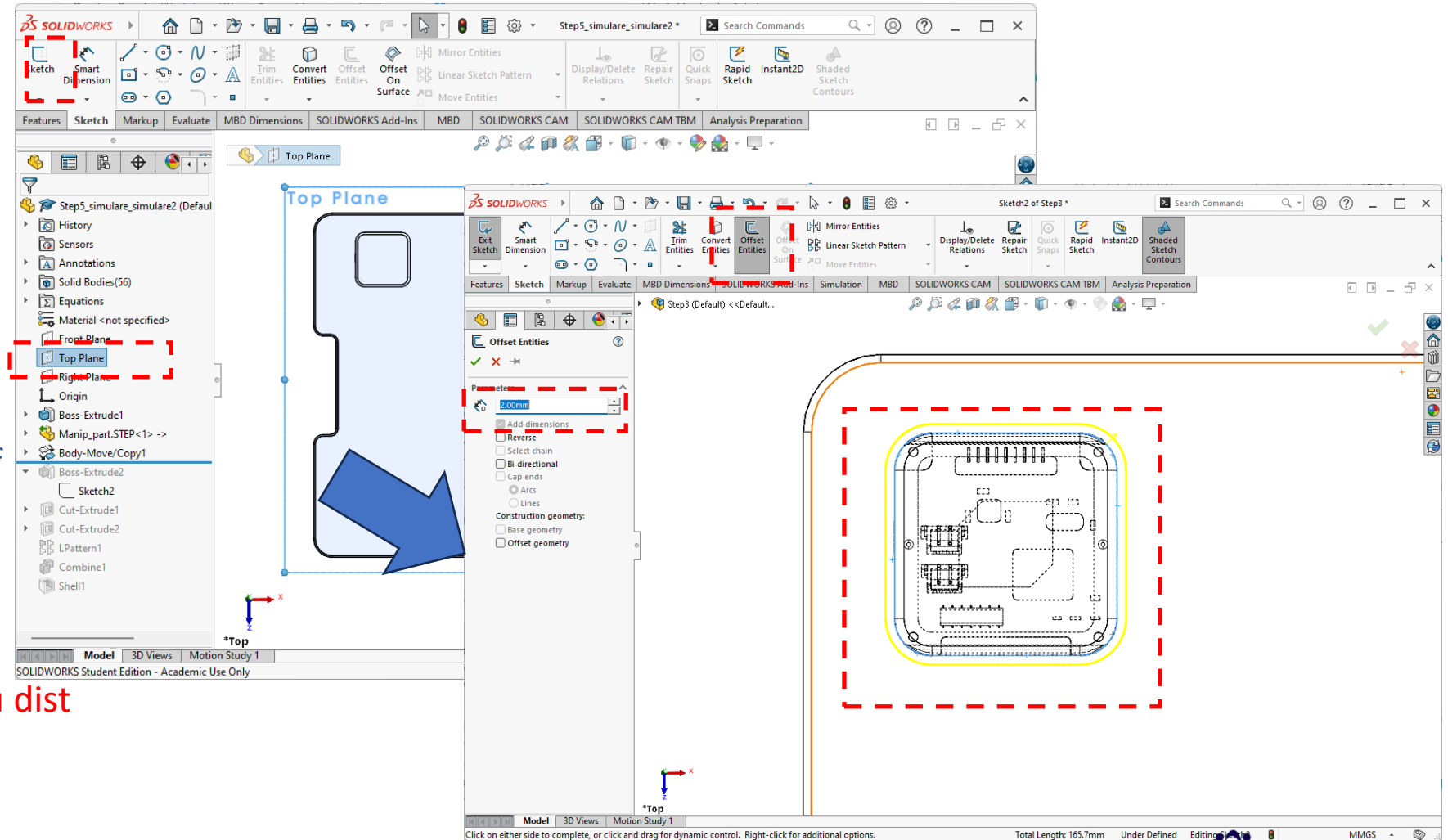


# Define the negative of the part

## Step 4

- Define the component contour on *Top Plane*
  - Create a new sketch on *Top plane*
  - Use *Offset Entities* to define the contour of the part

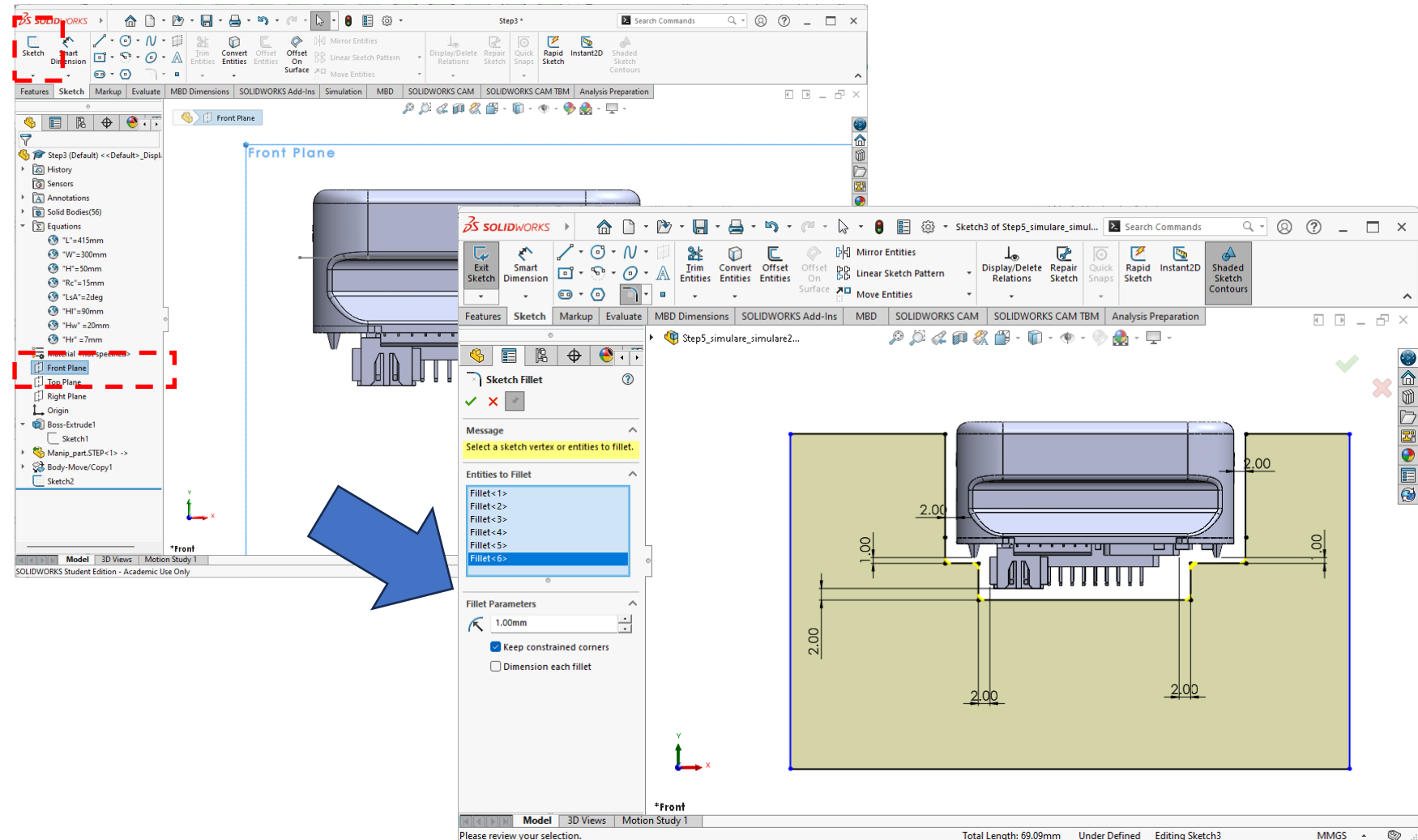
REFACERE POZE cu dist



# Define the negative of the part

## Step 5

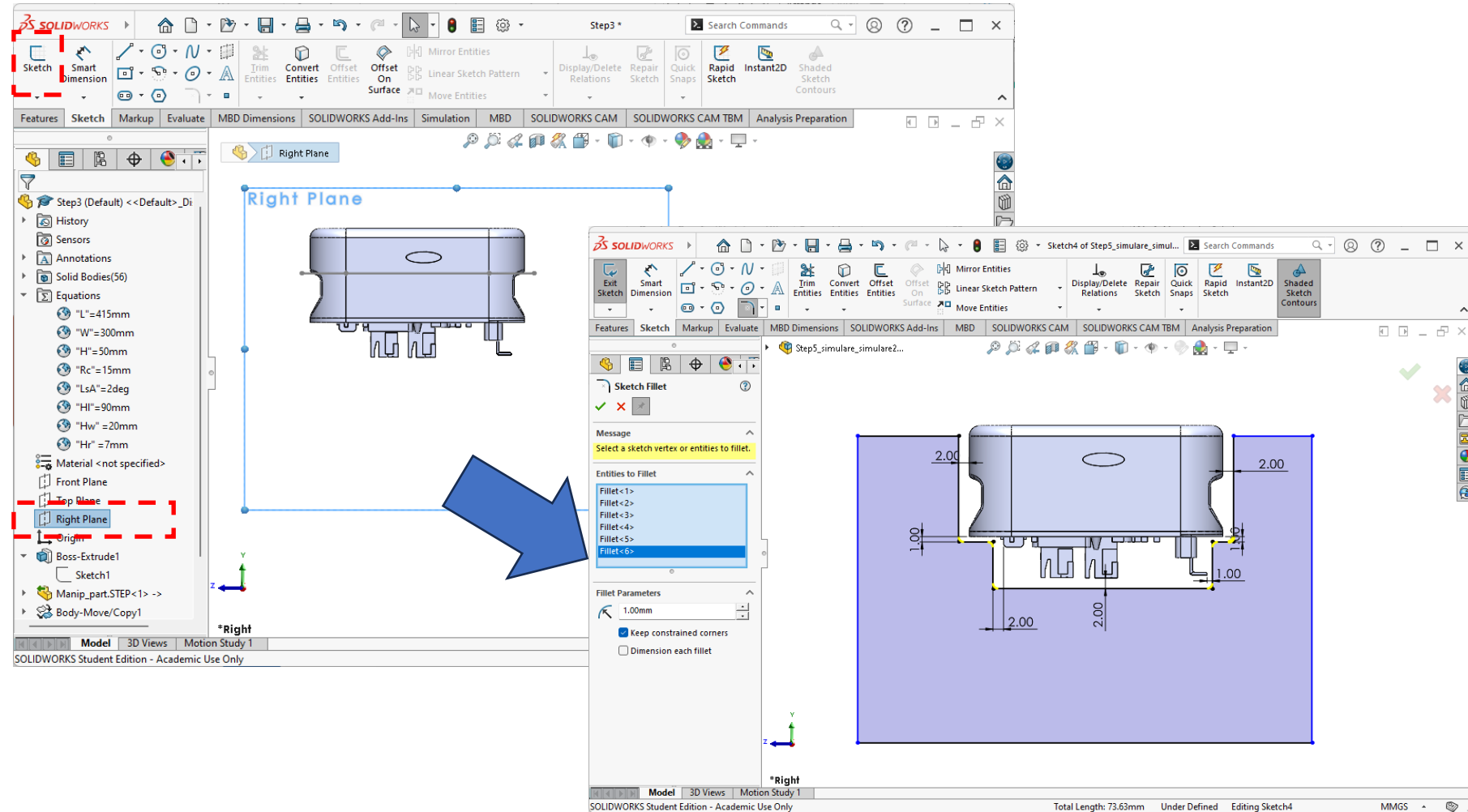
- Define the component contour on **Front Plane**
  - Create a new sketch on **Front plane**
  - Use *Offset Entities* and *lines* to define the contour of the part
    - Clearance – 2 mm
    - Contact 1 mm
    - Filet 1 mm



# Define the negative of the part

## Step 6

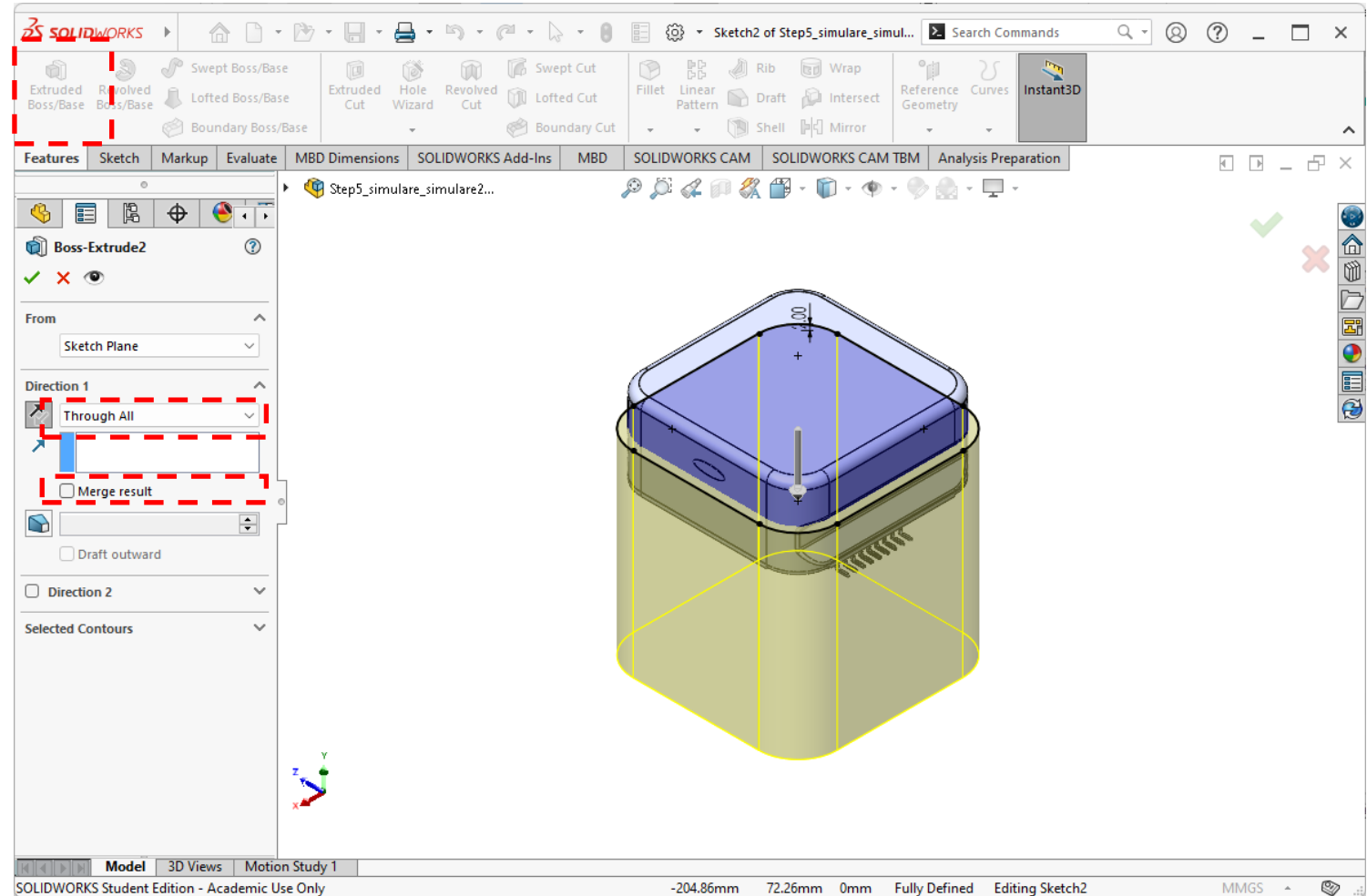
- Define the component contour on **Right Plane**
  - Create a new sketch on **Right plane**
  - Use **Offset Entities and lines** to define the contour of the part



# Define the negative of the part

## Step 7

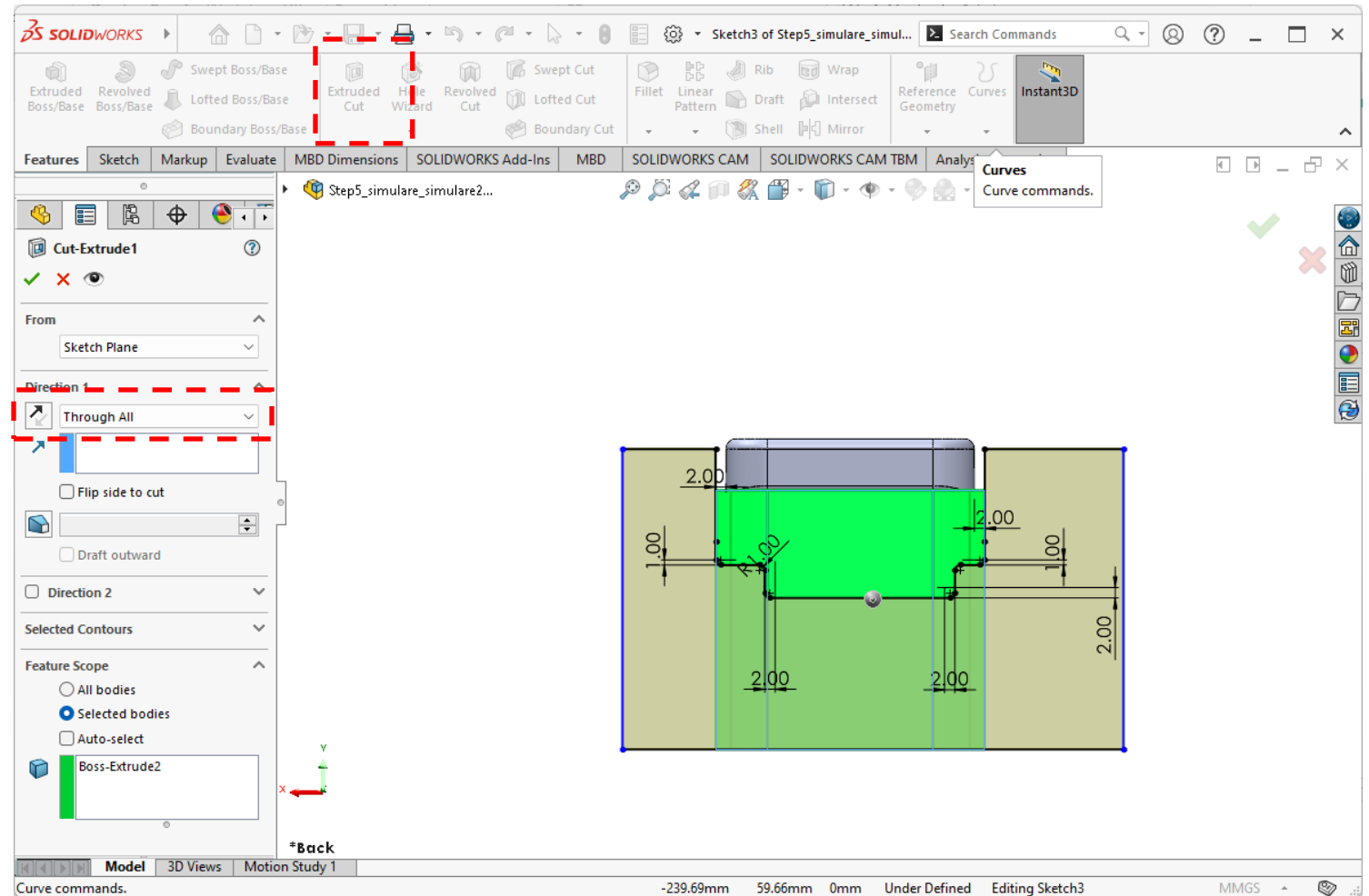
- On *Sketch 2* (Top plane) – use Extrude Boss
  - Through all
  - Unselect *merge result* option



# Define the negative of the part

## Step 8

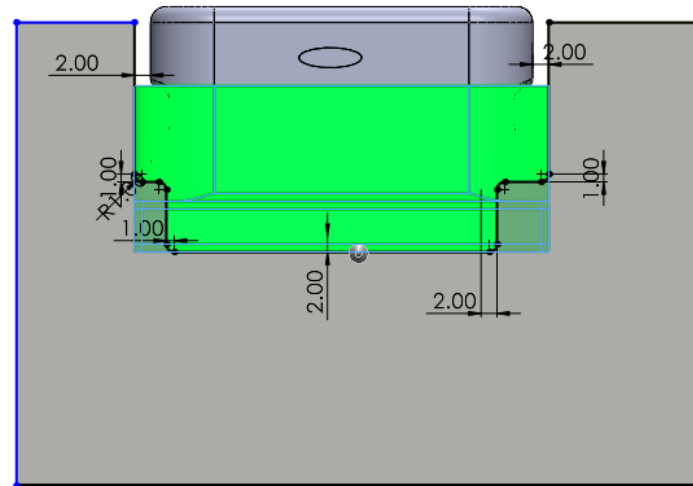
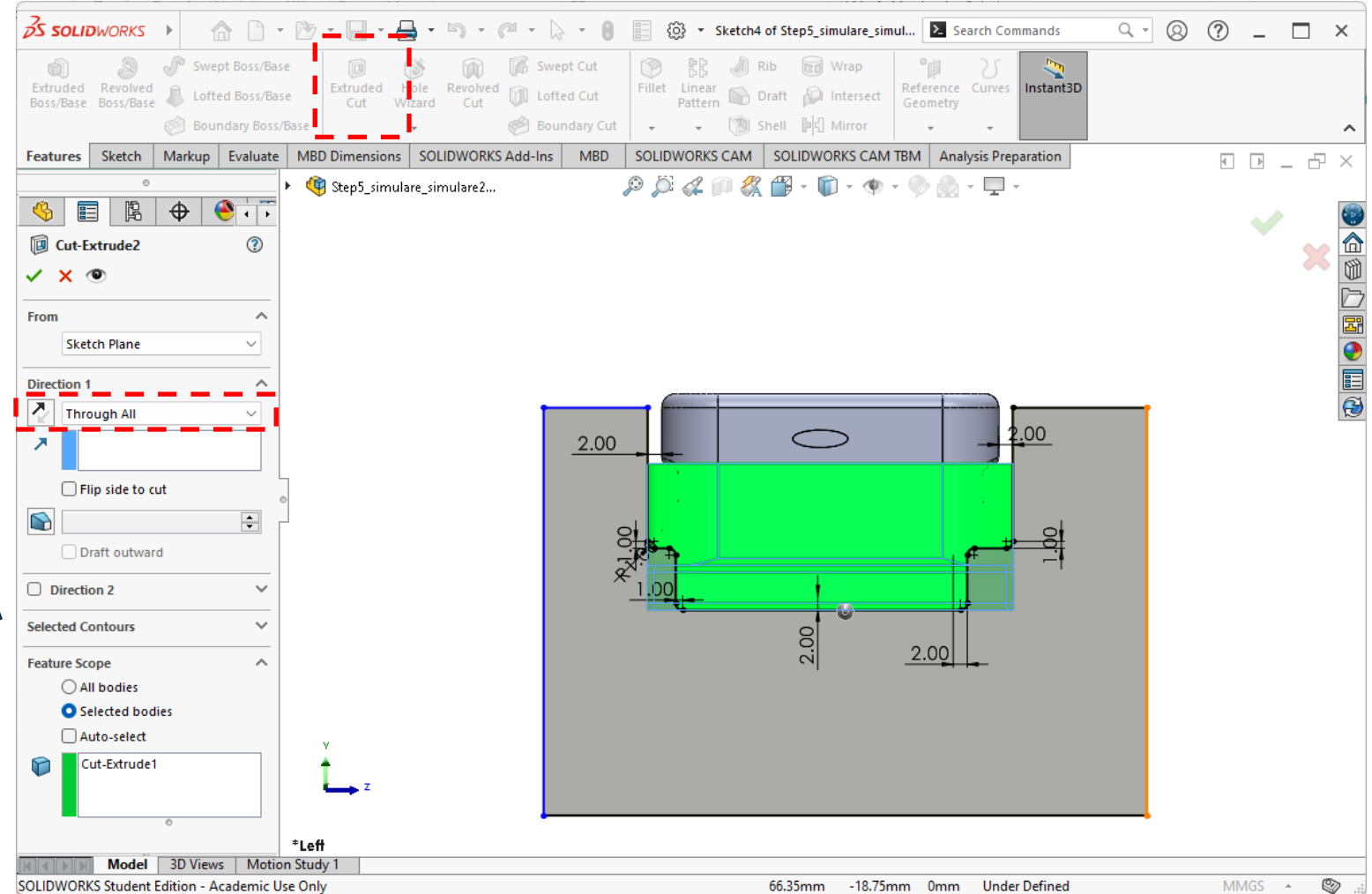
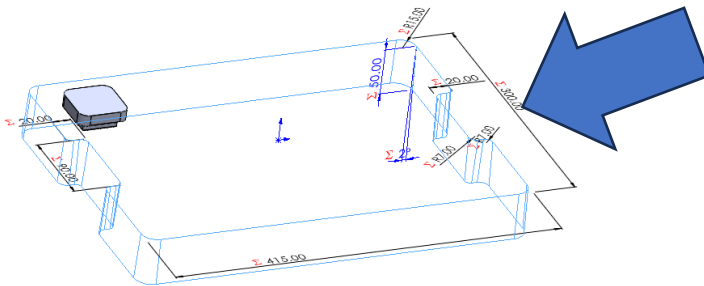
- On *Sketch 3* (Front plane) – use Extrude Cut
  - Option: *Through all*



# Define the negative of the part

## Step 9

- On *Sketch 4* (Right plane) – use Extrude Cut
  - Through all



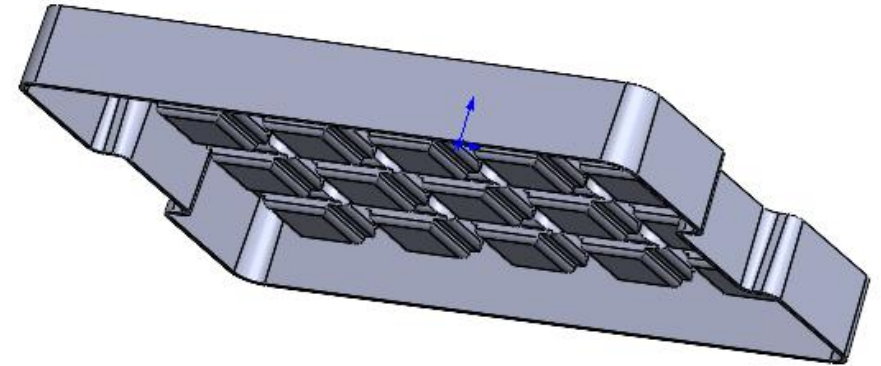
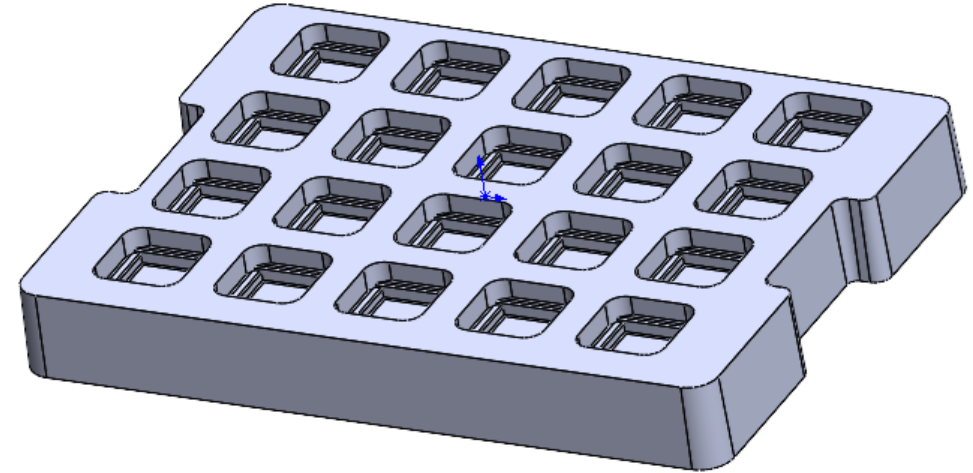
# Define all nest on the blister

## *Working procedure:*

- The work is performed by each student individually

## *Tasks:*

- *Multiply the negative of the part*
- *Use combine command to obtain the nests*
- *Use shell to create the body of the blister*

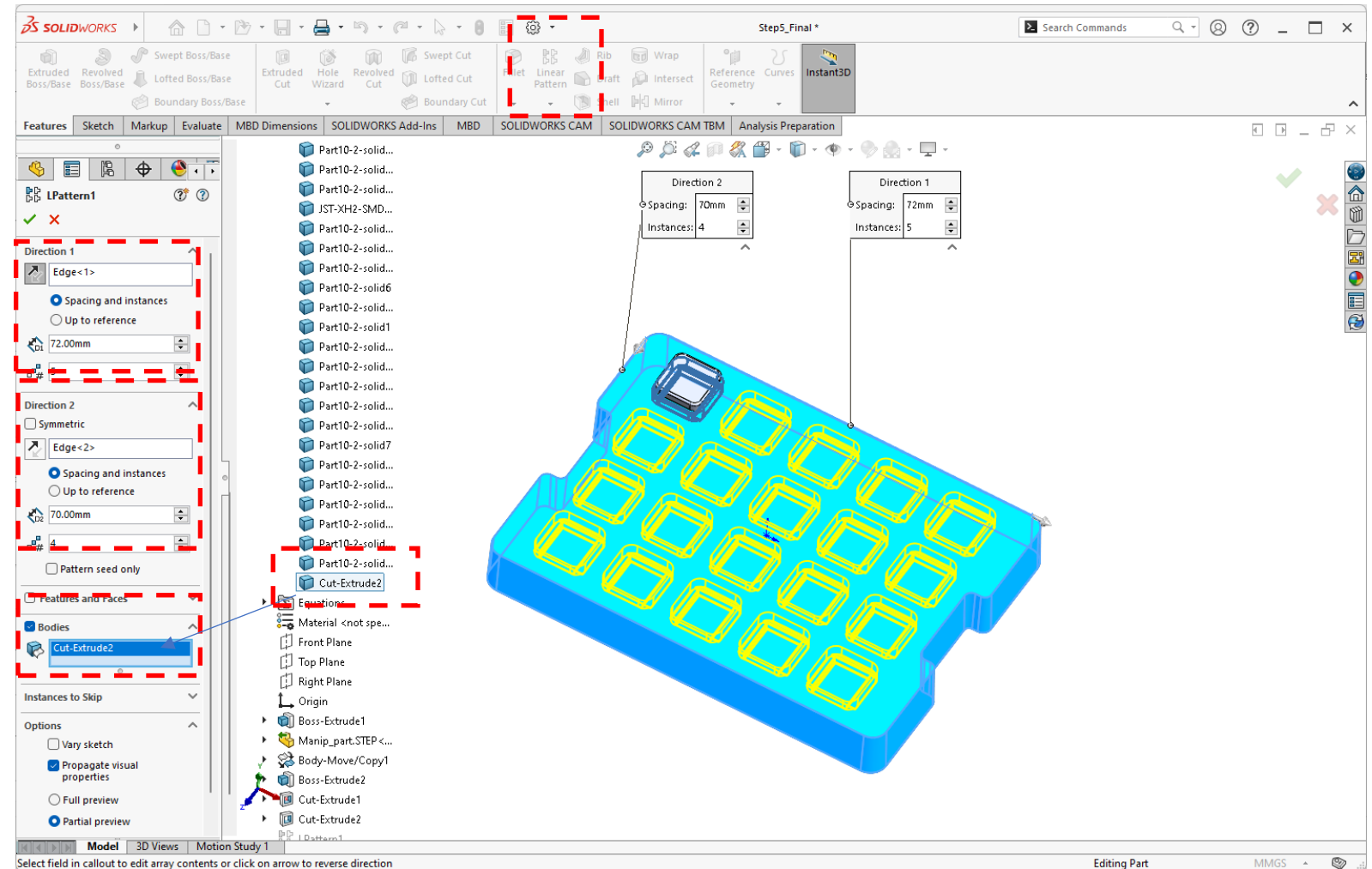




# Define all nests on the blister

## Step 1

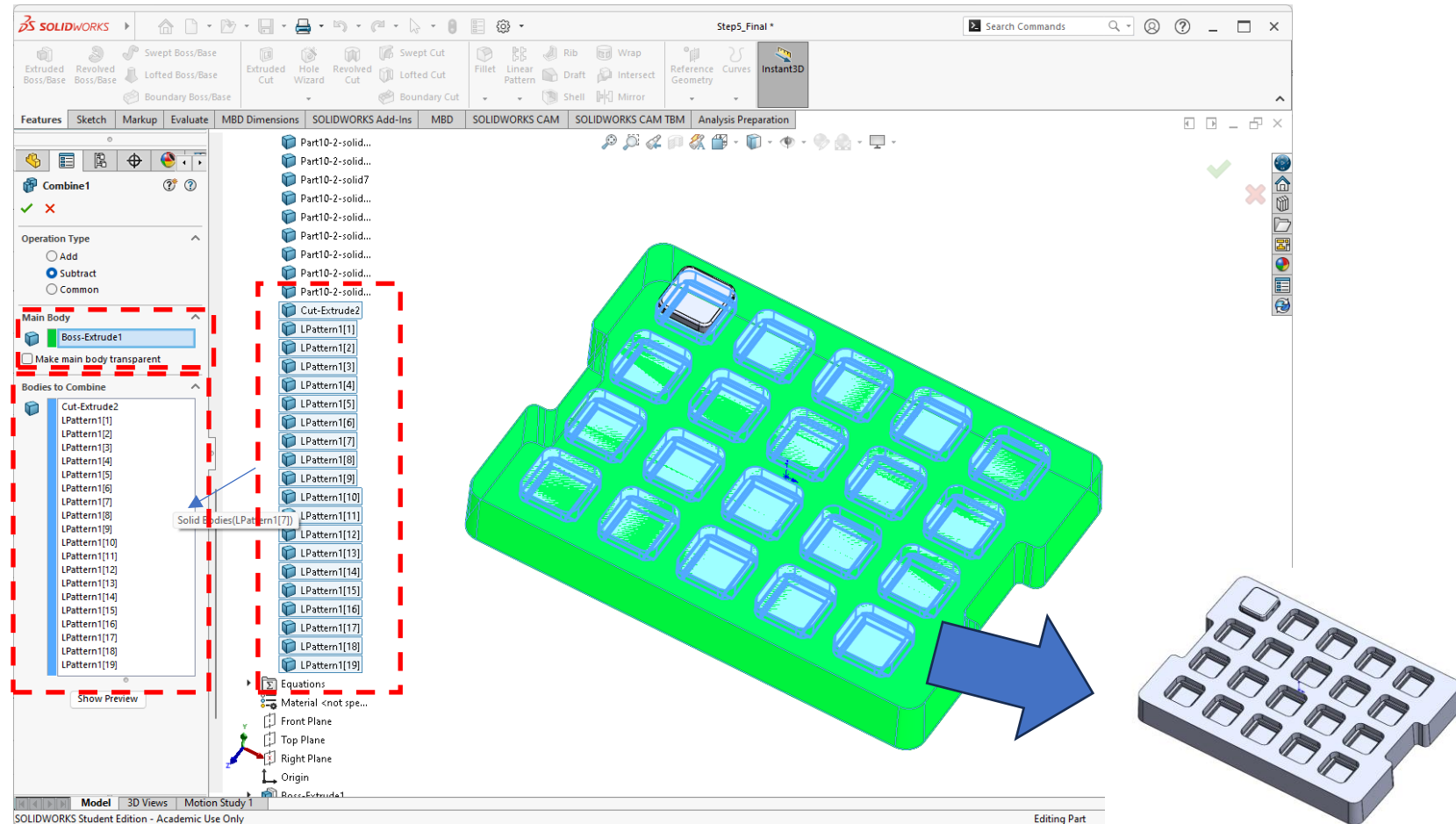
- Use the command *linear pattern*



# Define all nests on the blister

## Step 2

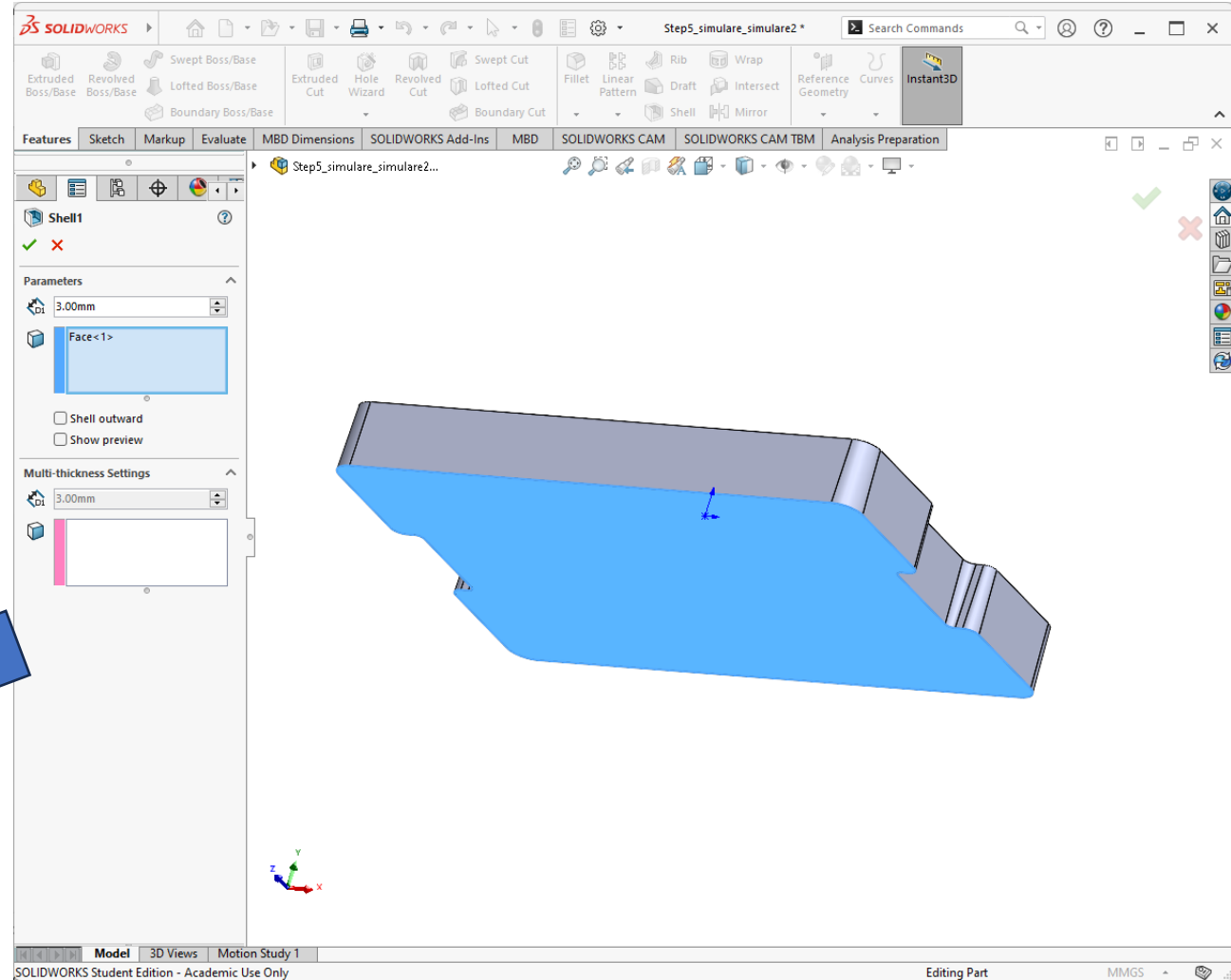
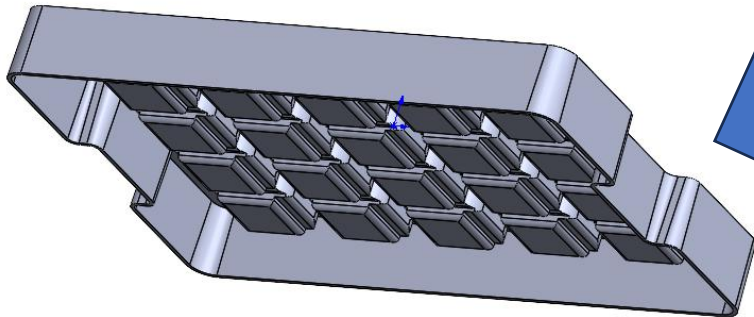
- Create the nests using the command:  
*Insert/Features/Combine*
  - Select from *Solid Bodies*
    - **Main Body:** Boss Extrude 1
    - **Bodies to combine:** Cut extrude 1, LPattern 1...n



# Populate the blister

## Step 3

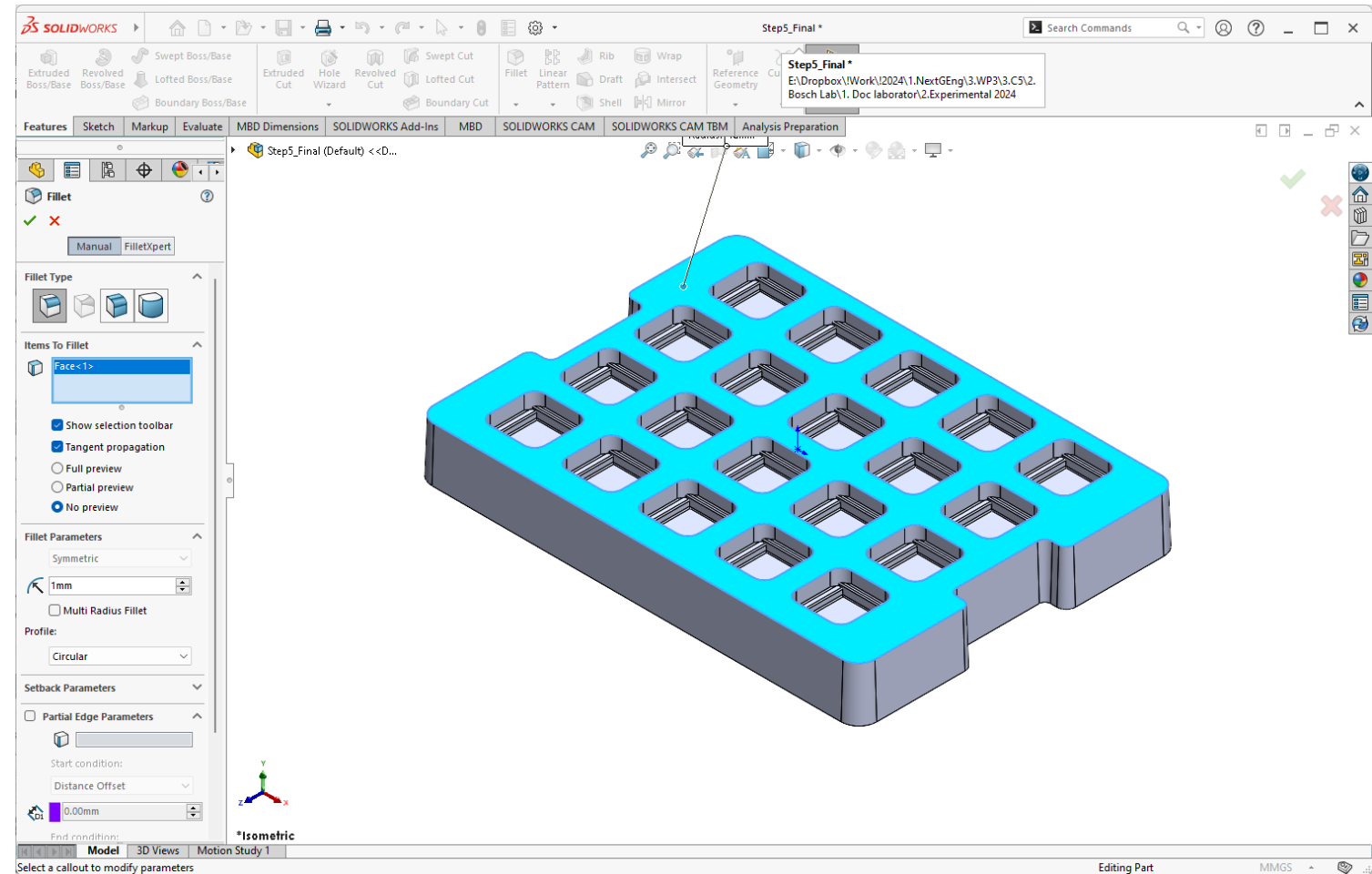
- On *Shell* command with a thickness of 3 mm



# Populate the blister

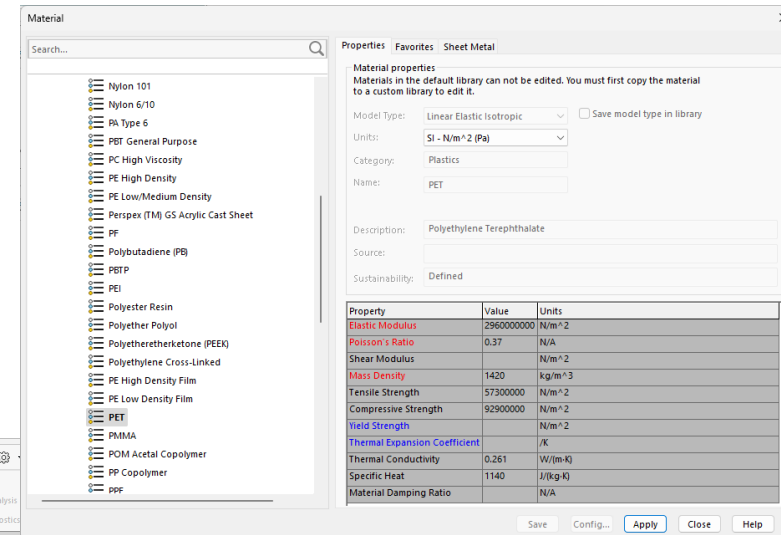
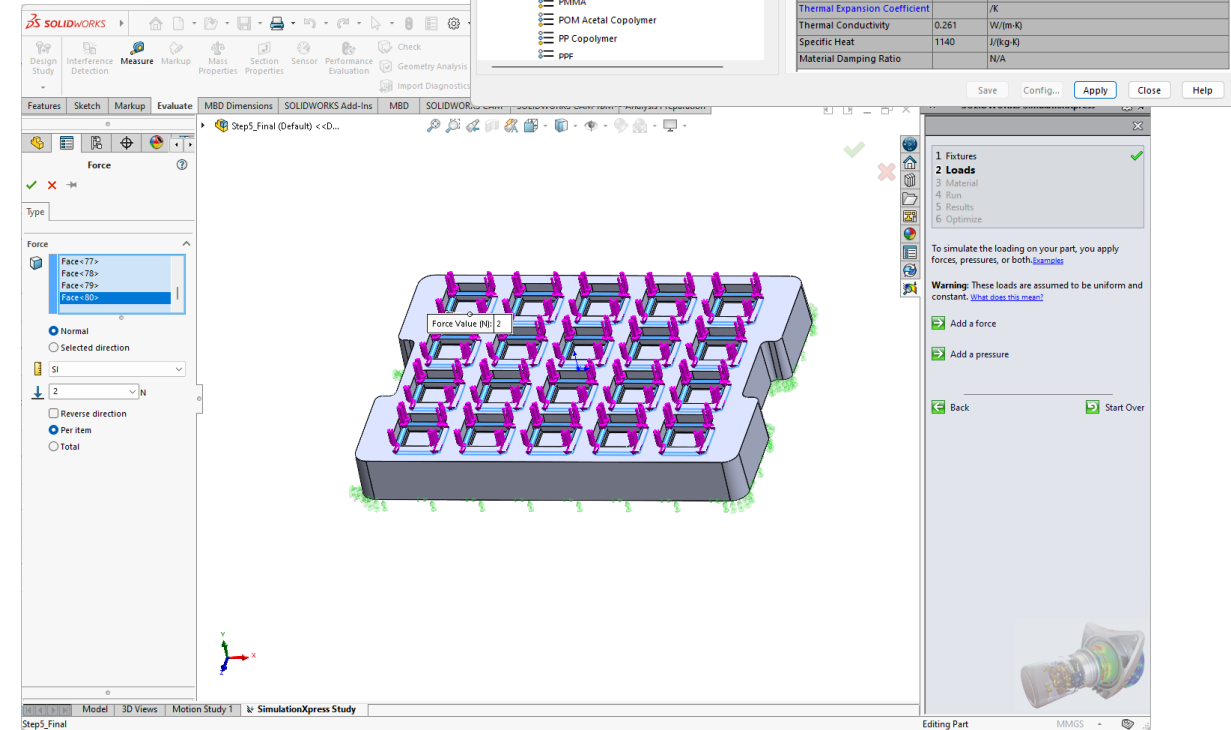
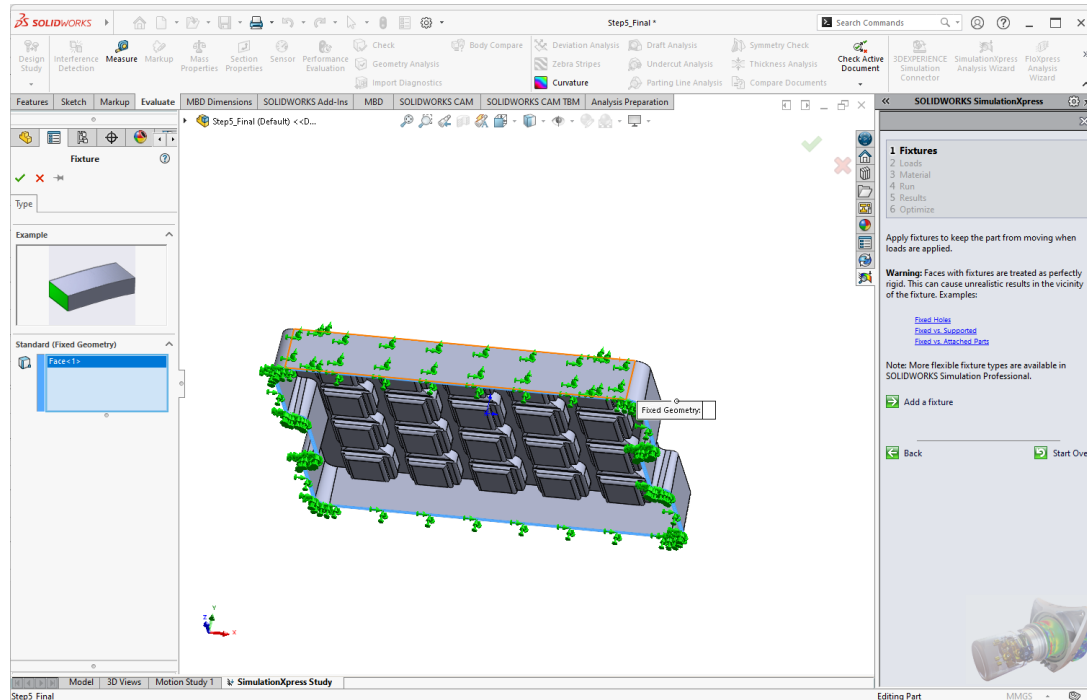
## Step 4

- On *Fillet* command with a radius of 1 mm



# Test the blister

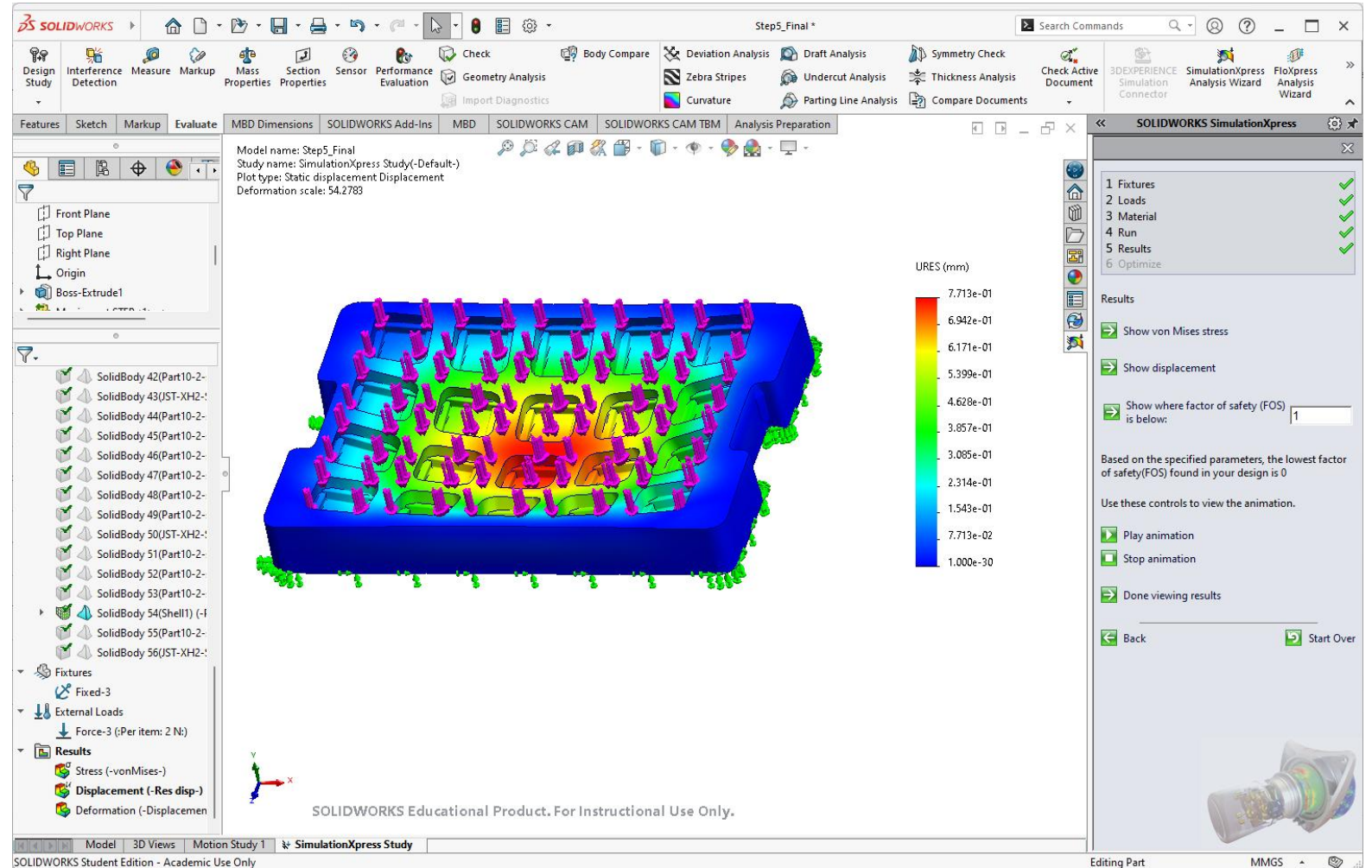
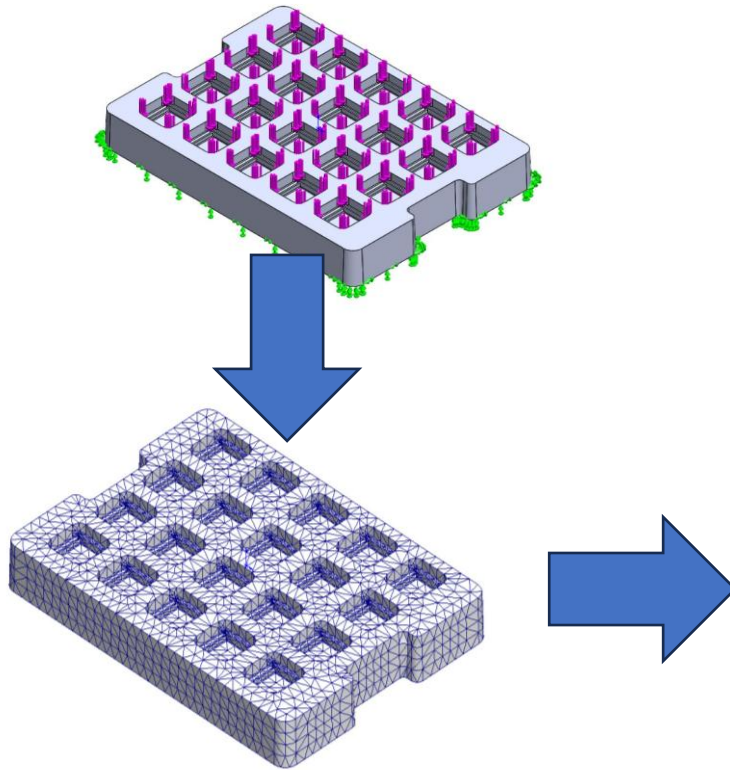
- Test procedure : use FE method to estimate the deformation





# Test the blister

- Analyze the simulation results



# Summary & Discussions



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# Design of blisters prototypes

## Topics of discussions

- The most difficult part of designing the blister
- What are the main factors that influence the environment related to the design process
- What testing methods could be used for the blister







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# C6 – Manufacturing Technology

L1 - Additive manufacturing at Valmet

P4 - VALMET

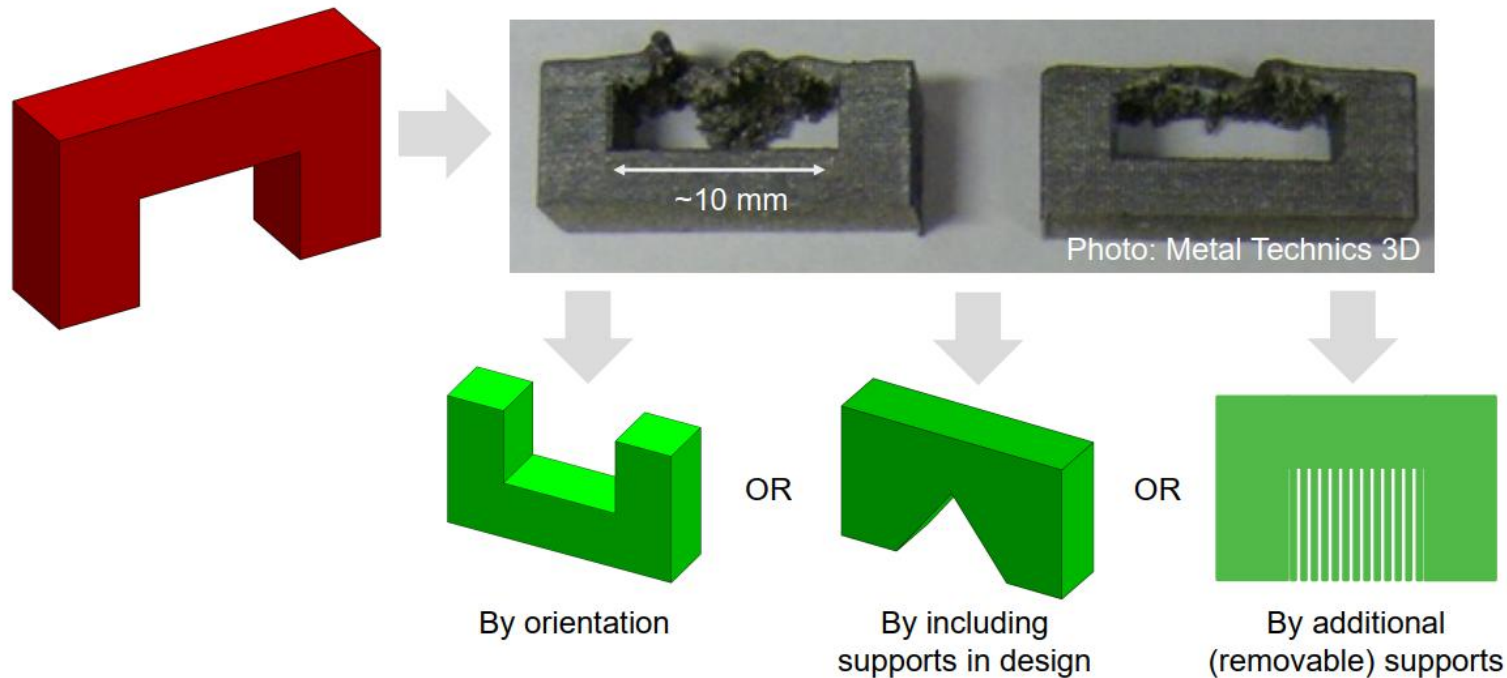
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# Additive manufacturing at Valmet

Make geometry manufacturable



# Additive manufacturing at Valmet

## Laboratory overview:

### Objectives

- To study the principles and process parameters of additive manufacturing technologies (e.g., FDM, SLA, SLS) and their influence on the quality of fabricated parts
- To fabricate and analyze a 3D-printed component in order to evaluate dimensional accuracy, surface finish, and mechanical properties compared to the design specifications.

### Pre-requisite

- Basic knowledge of CAD modeling – ability to design or interpret 3D models using CAD software
- Familiarity with manufacturing processes – understanding of conventional manufacturing methods and their limitations

### Equipment used for laboratory

- PCs with SolidWorks

# Additive manufacturing at Valmet

**Upon completion of this activity, the student will be able to:**

- 1) Explain the fundamental principles and process parameters of additive manufacturing technologies
- 2) Operate a 3D printer to fabricate a part from a CAD model while following proper safety procedures
- 3) Evaluate the quality of printed components by comparing dimensional accuracy, surface finish, and mechanical performance to design specifications.

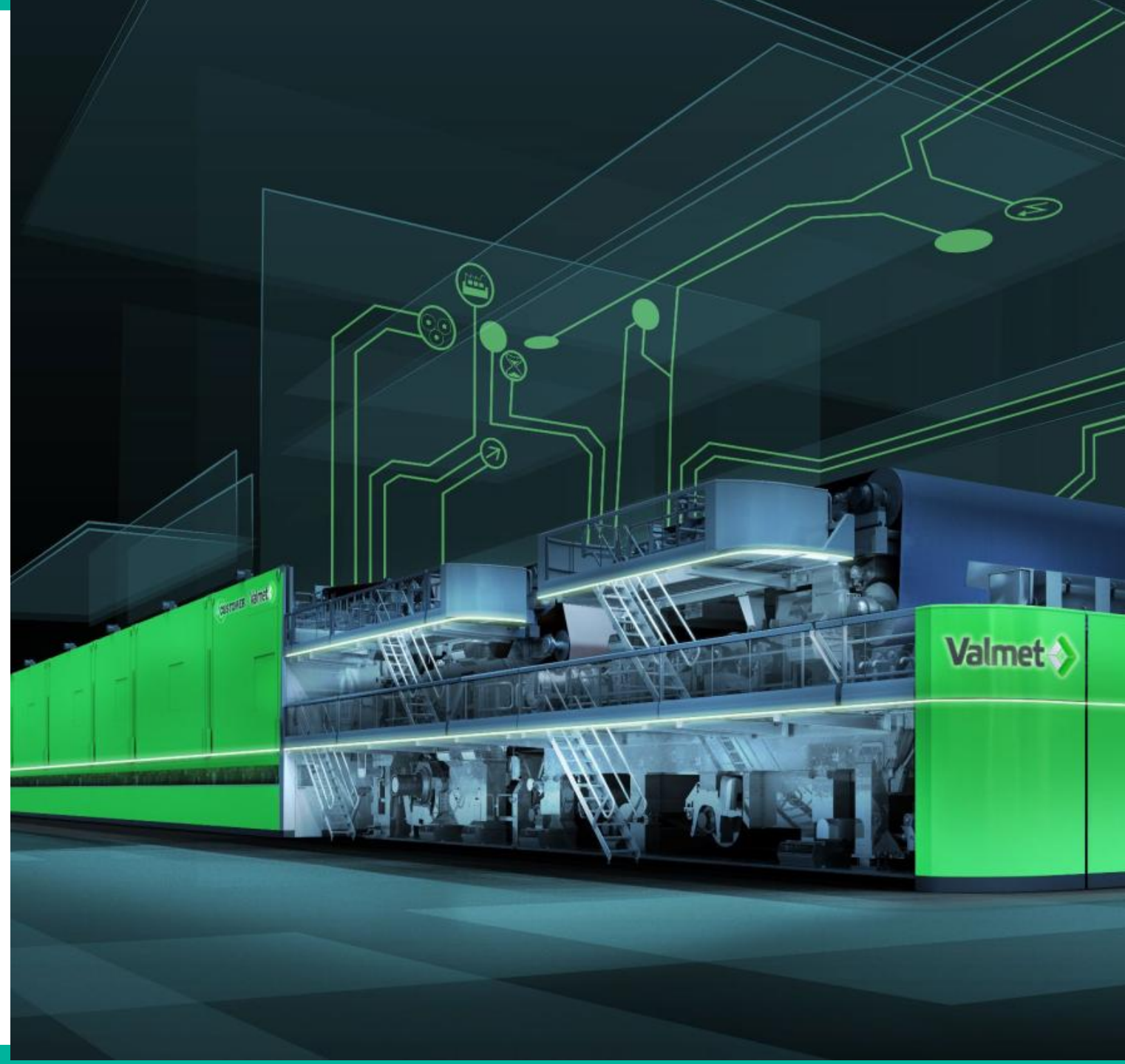


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# Content

- Introduction
- Basics of AM
- Design for additive manufacturing
- Real-life case from Valmet
- Summary, Discussions & Feedback



# Introduction







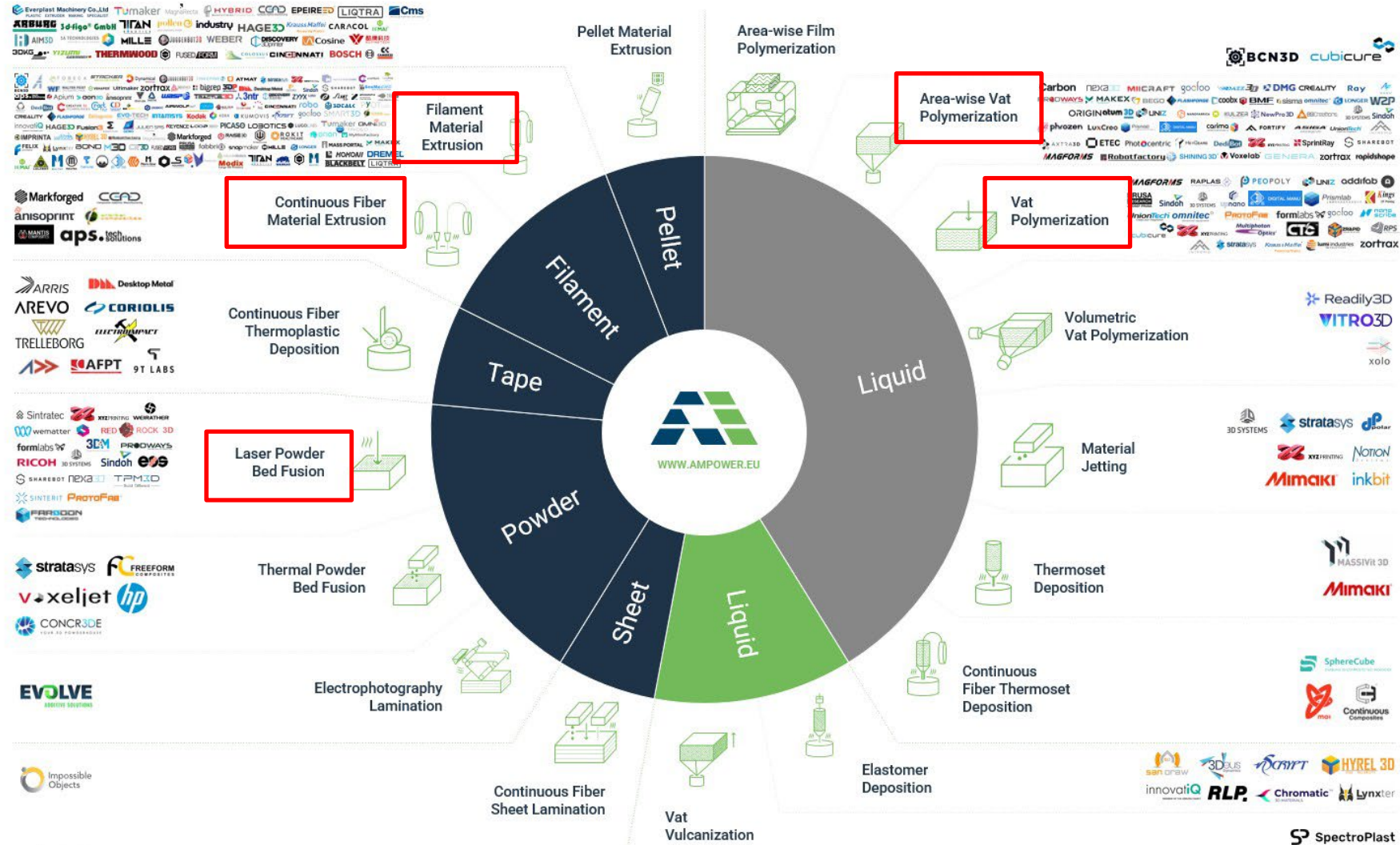


## Valmet in a nutshell

- Global company
- 20 000 employees
- 5 500 MEUR turnover
- Locations on all over the world, mostly in Europe
- Machinery processing natural fiber (Paper, board and tissue machines, automation, flow control, pulp and energy and industrial services)

# Basics of AM

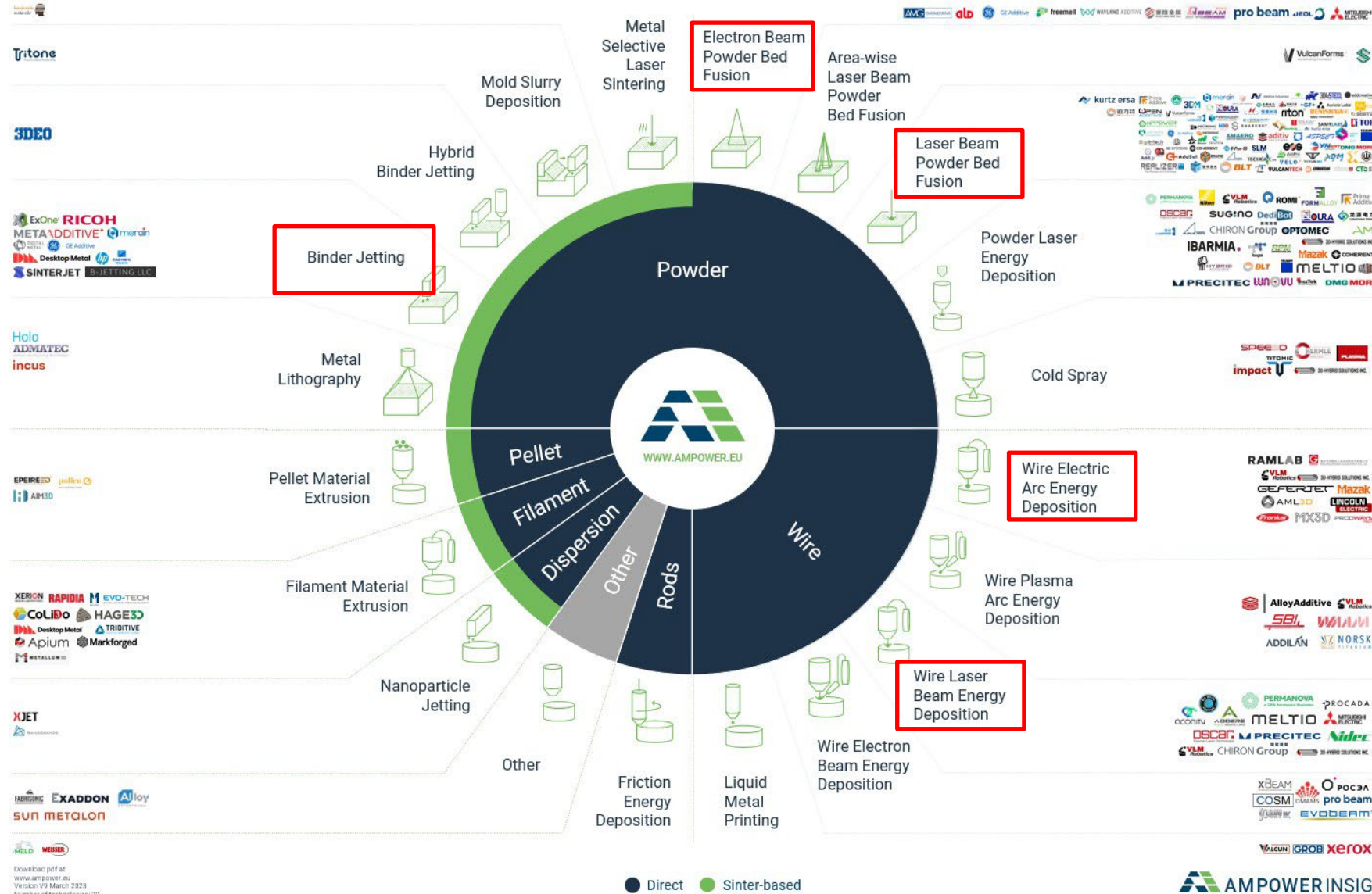
# Polymer Additive Manufacturing technology landscape



Download pdf at:  
[www.ampower.eu](http://www.ampower.eu)  
 Version V6 March 2023  
 Number of technologies: 17  
 Number of suppliers: 234



# Metal Additive Manufacturing technology landscape



# Polymer AM main technologies comparison

	Fused Deposition Modeling (FDM)	Stereolithography (SLA)	Selective Laser Sintering (SLS)
Build envelope	Typically 300 x 250 x 300 mm  Over 1000 x 1000 x 1000 mm possible	Up to 1500 x 750 x 500	300 x 300 x 300 mm  Up to 750 x 550 x 550 mm
Materials	Thermoplastics: ABS, PLA, PC, PETG, PEI...	Photopolymers	Thermoplastics: PA2200 (nylon) and variants, PA3200GF, TPU, Alumide
Dimensional accuracy	$\pm 0.15\%$ (lower limit $\pm 0.2$ mm)	$\pm 0.15\%$ (lower limit $\pm 0.01$ mm) - industrial	$\pm 0.2\%$ (lower limit of $\pm 0.2$ mm)
Advantages	<ul style="list-style-type: none"> <li>- Fast! (for one offs)</li> <li>- Cost-effective</li> </ul>	<ul style="list-style-type: none"> <li>- Very high dimensional accuracy</li> <li>- Excellent surface quality</li> <li>- Special materials available (clear, flexible, castable)</li> </ul>	<ul style="list-style-type: none"> <li>- No need for supports</li> <li>- Good isotropic mechanical properties</li> <li>- Excellent for small &amp; medium batch production</li> </ul>
Drawbacks	<ul style="list-style-type: none"> <li>- Lowest dimensional accuracy</li> <li>- Surface quality</li> <li>- Needs supports</li> <li>- Anisotropic structure</li> </ul>	<ul style="list-style-type: none"> <li>- Generally can be brittle</li> <li>- Needs supports</li> <li>- Some resins properties degrade over time</li> </ul>	<ul style="list-style-type: none"> <li>- Surface quality (but better than FDM)</li> <li>- Internal porosity may exist with some machines (post processing needed for watertightness)</li> <li>- Large flat surfaces &amp; small holes are not accurate (warping &amp; oversintering)</li> </ul>

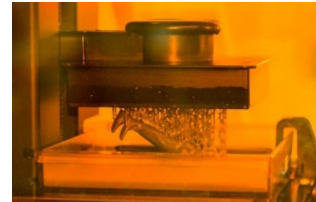
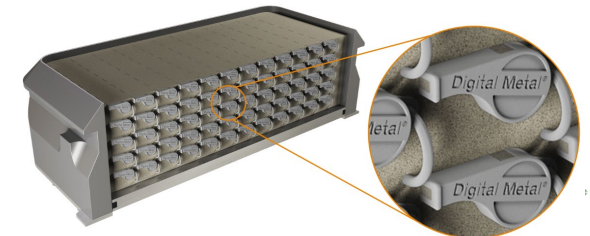
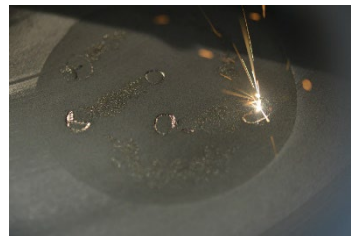


Photo: Materflow

# Achievable properties of metal AM

	Laser Powder Bed Fusion (LPBF)	Direct Energy Deposition (DED)	Binder jetting
Density	99,999 % ->	99,5 % - 99,9 %	~97-99 %
Dimensions	Typically 280 x 280 x 365 mm (as big as the controlled build chamber)	1000 x 1000 x 3000 mm (as big as the range of the robotic arm)	400 x 250 x 250 mm (as big as the build chamber, sintering limits part size)
Materials	316L, Ti6Al4V, AlMg10Si, Maraging steel, Inconel 718 & 625...		316L, copper, 17-4PH Ti6Al4V, ceramics, sand..
Part accuracy	+/- 0,1 mm (typical)	+/- 0,1 % (min +/- 0,1 - 0,2 mm)	+/- 0,1 mm
Surface roughness	In general Ra 10-15 µm	In general Ra 15-50 µm, WAAM even worse	In general Ra 6 µm
Advantages	<ul style="list-style-type: none"> <li>- Very complex internal cavities</li> <li>- High precision</li> <li>- Possibility to affect material properties</li> </ul>	<ul style="list-style-type: none"> <li>- Highest speed</li> <li>- Large parts possible with</li> <li>- Different materials can be used along the build direction</li> </ul>	<ul style="list-style-type: none"> <li>- No thermal stresses</li> <li>- Best surface quality</li> <li>- No need for supports in printing</li> <li>- Highest precision</li> <li>- Faster than LPBF</li> </ul>
Drawbacks	<ul style="list-style-type: none"> <li>- High energy → Thermal stresses</li> <li>- Slowest technology</li> </ul>	<ul style="list-style-type: none"> <li>- Less precise than LPBF, and BJ</li> <li>- Lack of powder bed limits geometrical complexity</li> <li>- No ability to influence material properties through the layers (limited remelting)</li> </ul>	<ul style="list-style-type: none"> <li>- Sintering may distort components</li> <li>- Component size limited but improving (~100 x 100 x 100 mm)</li> </ul>



# Why AM should be used?

Some of the benefits listed

## Design related

- Design freedom
- Lightweighting
- Part consolidation
- Customization
- Part performance



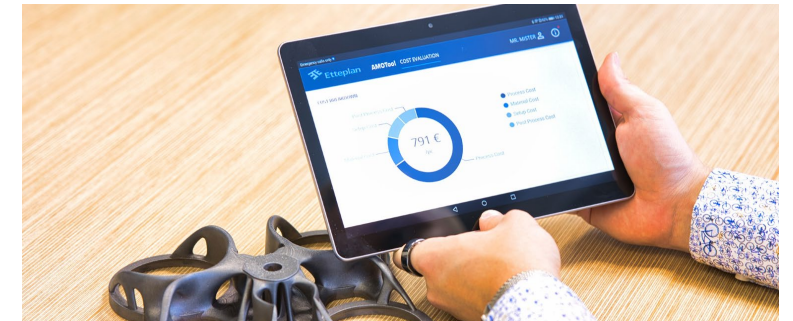
## Production related

- Rapid prototyping
- On-Demand Production
- Reduced lead time
- Toolless production



## Economics related

- Material efficiency
- Supply chain simplification (localized production, reduced logistics)
- Digital inventory





# Design freedom

## Why AM should be used?

- AM allows for the creation of parts with **complex geometries** that would be challenging or impossible to produce with traditional methods
  - This includes intricate internal structures, undercuts, and organic shapes.



Aerospike engine



Aluminum housing



Footrest



# Lightweighting

## Why AM should be used?



Image: EOS

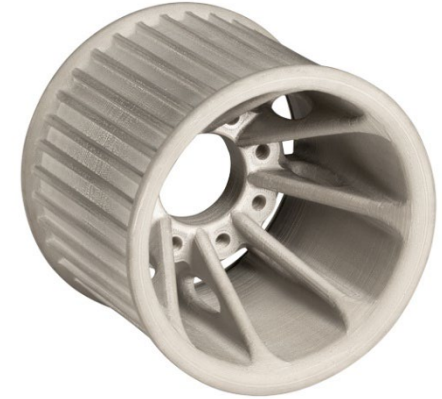


Image: Desktop Metal



Image: EOS



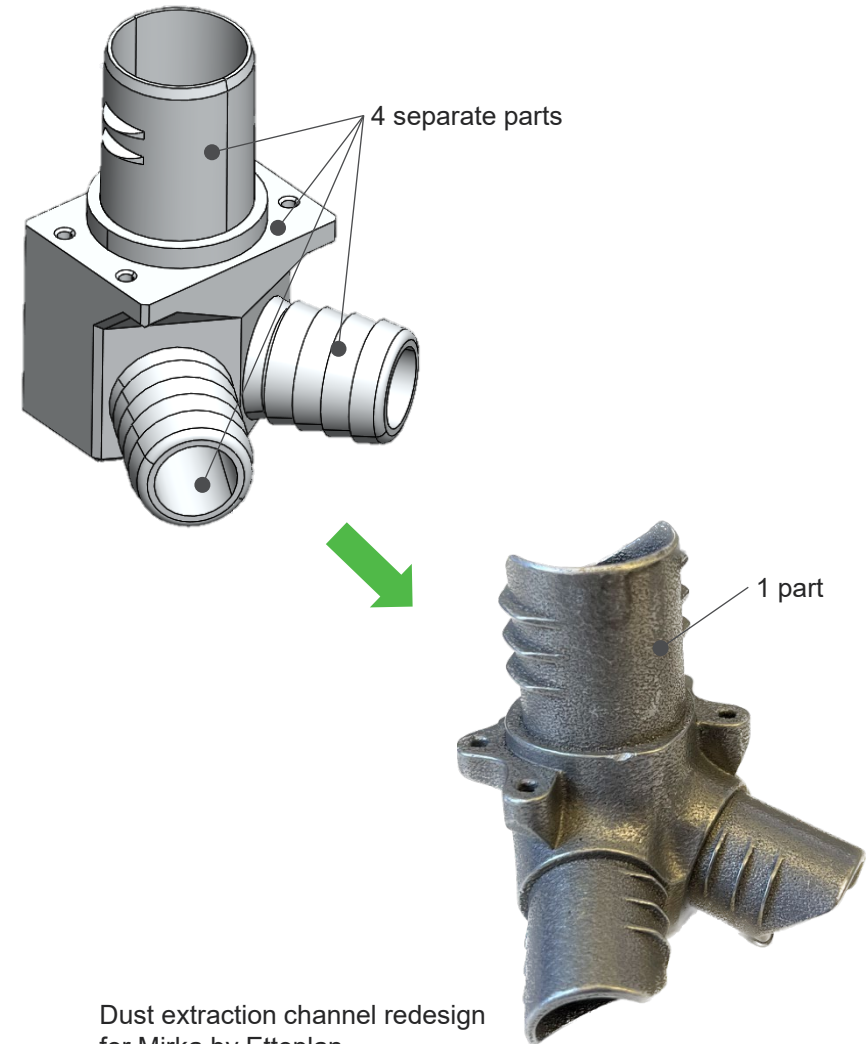
Image: Liebherr

# Part consolidation

Why AM should be used?



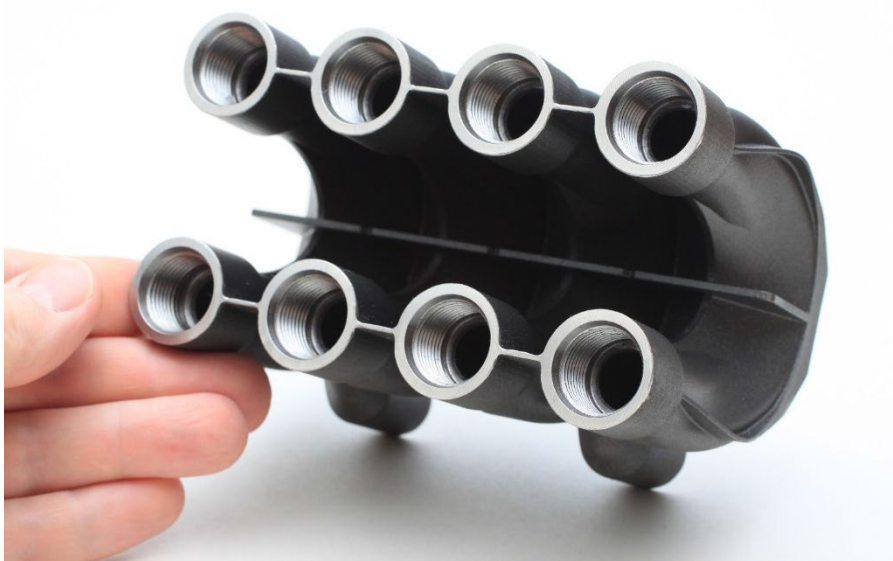
Image: nTop



Dust extraction channel redesign  
for Mirka by Etteplan

# Improving performance

## Why AM should be used?



Hydraulic block for John Deere by Etteplan



Image: Materialise

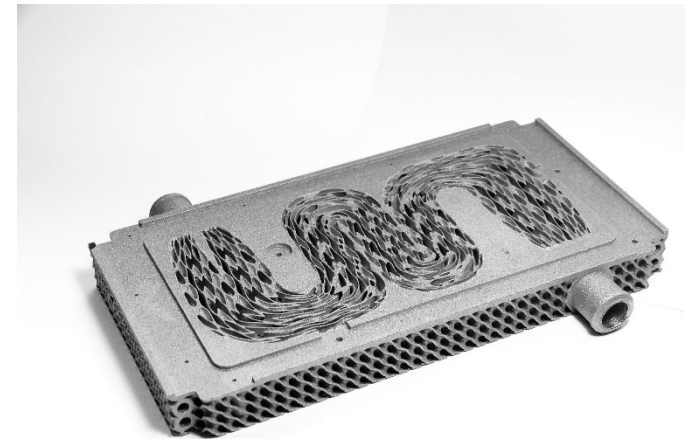


Image: nTop

# Rapid prototyping

## Why AM should be used?



4 years

100 patents pending

600 prototypes



# On-demand production

Why AM should be used?

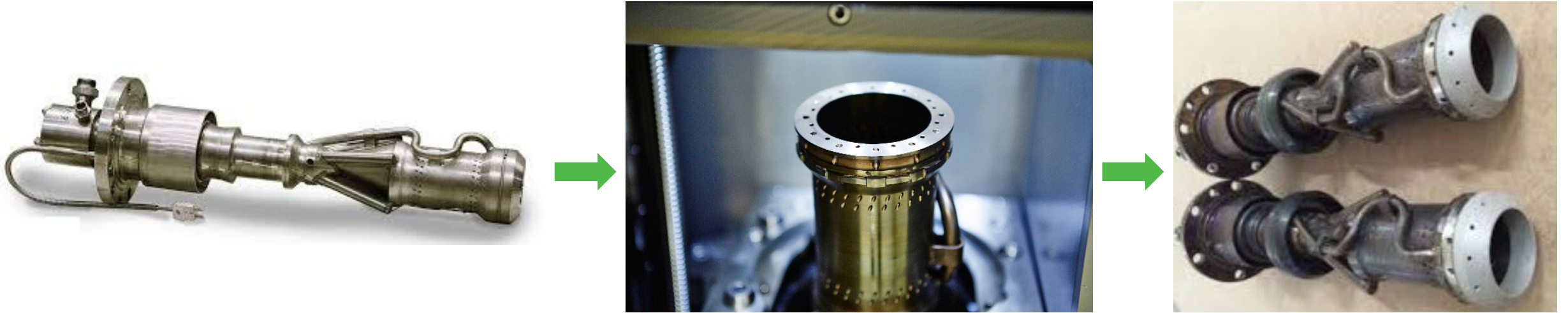


Image: 3D Formtech

- 100+ printed parts
- No actual prototypes
  - Each drone is an end product as well as a prototype
  - If new developed part works, it will be sold
- Continuous development
- No spare parts in storage
  - No risk to waste money
  - FAST delivery times
- *“Nordic Drones wouldn’t exist without 3D printing, because there are no other reasonable ways to make our products”*

# Reducing lead-time

Why AM should be used?



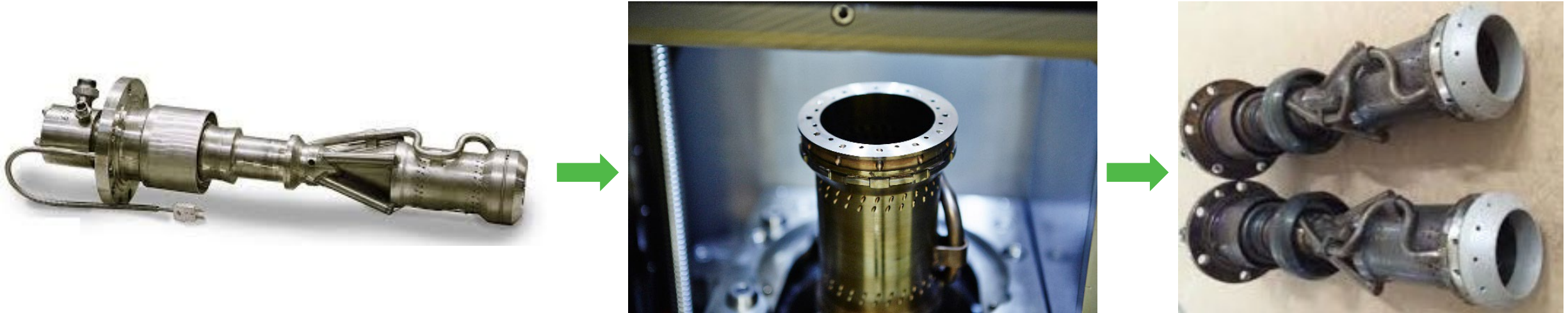
Lead time



44 weeks

# Reducing lead-time

Why AM should be used?



Lead time  
↔  
4 weeks



# Digital inventory

## Why AM should be used?

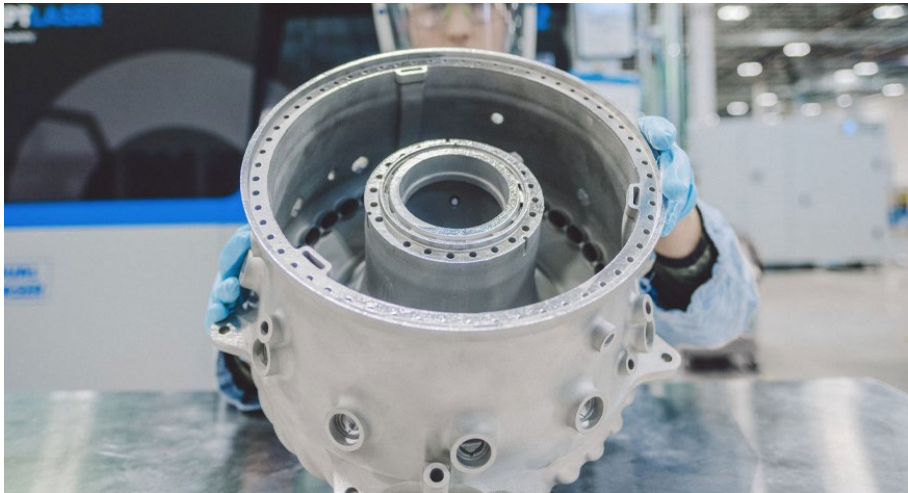


Image: GE

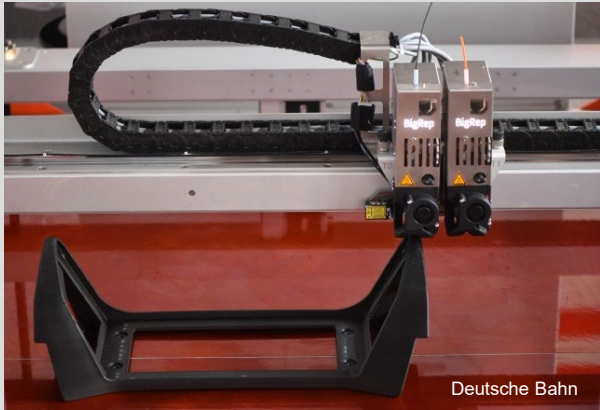


Deutsche Bahn



3D Printing Media Network

3D printed and machined secondary roll stop



Deutsche Bahn

Headrest in the making to old train model



Deutsche Bahn

3D printed and machined bearing cover

Another motivation is that after 20 years, the spare parts are simply no longer produced. Some devices are also obsolete, like everything related to electricity. Over time, standard wear-and-tear and brittleness gradually weaken the injection-molded parts, meaning that they need to be replaced every 10 to 15 years. Rail vehicles are designed to have a service life of over 25 years, but it is not uncommon for a train to remain in service for 40 to 50 years, or even longer in exceptional cases. 3D printing allows you to redo parts you no longer find.

Spare parts for old models / end of service

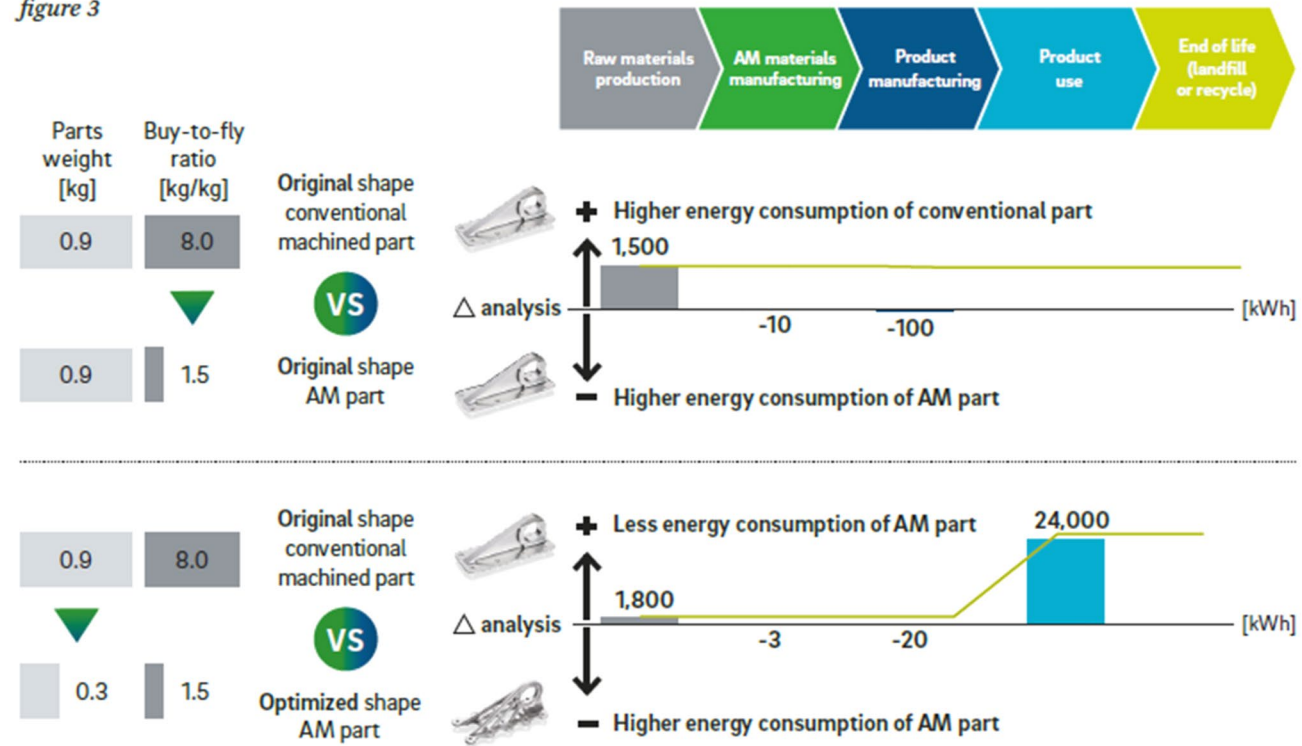
# Energy efficiency = Sustainability

Why AM should be used?

## AM saves energy for an aerospace bracket

Benefits of AM: less material needed and weight reduction

figure 3



Roland Berger Report  
on Sustainable  
Additive Manufacturing

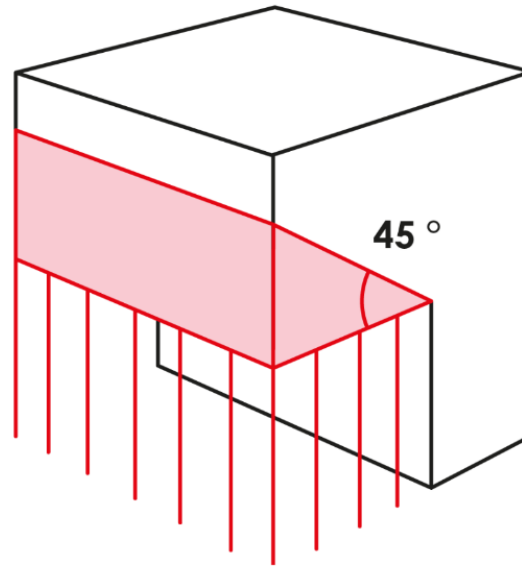
Source: Journal of Manufacturing Systems, Journal of Cleaner Production, Additive Manufacturing Journal, Proceedings of the IEEE International Symposium on Sustainable Systems and Technology, Roland Berger

Image Credits: Courtesy of GE Additive

# Design for additive manufacturing

# Support structures

- Laser Powder Bed Fusion (LPBF)
  - Depends on material and process parameters but rule of thumb is 45 degrees
    - Stainless steels: 30 degrees
    - Inconels: 45 degrees
    - Titanium: ~30 degrees
    - Aluminium: 45 degrees
    - Cobalt chrome: 30 degrees

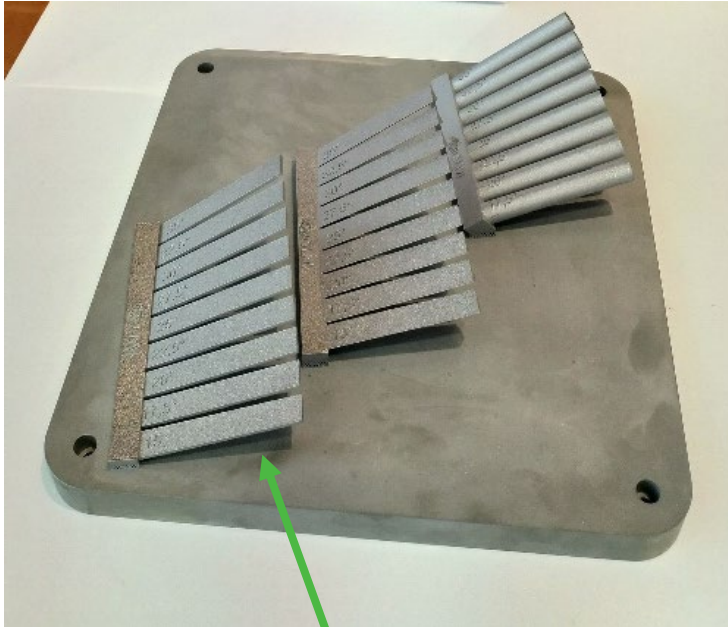


- Fused Deposition Modelling (FDM)
  - 45 degrees
- Selective Laser Sintering (SLS)
  - Not needed



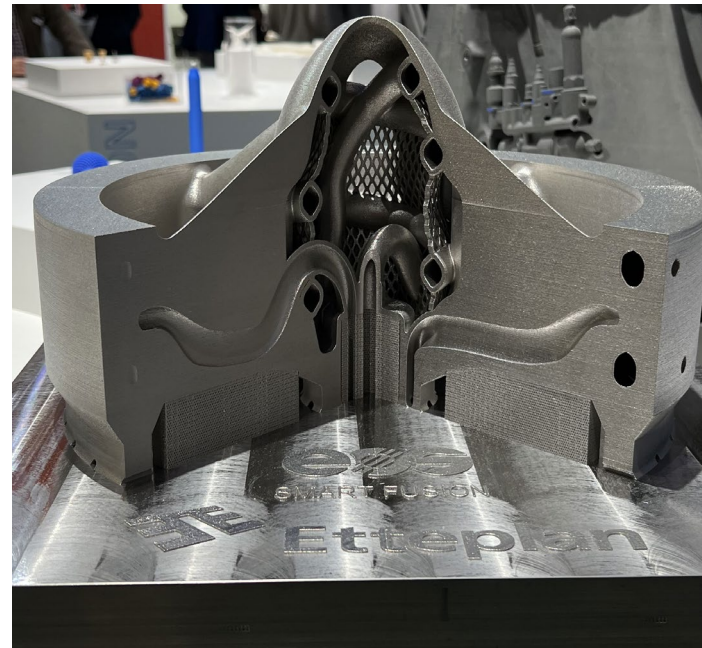
# Constant development to get rid off supports

SLM



15° angle!

Velo3D

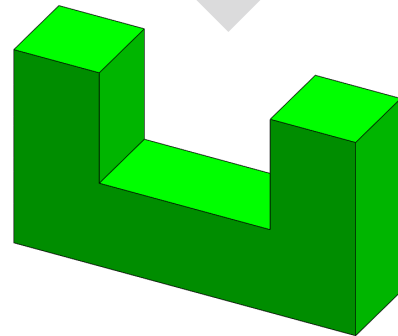
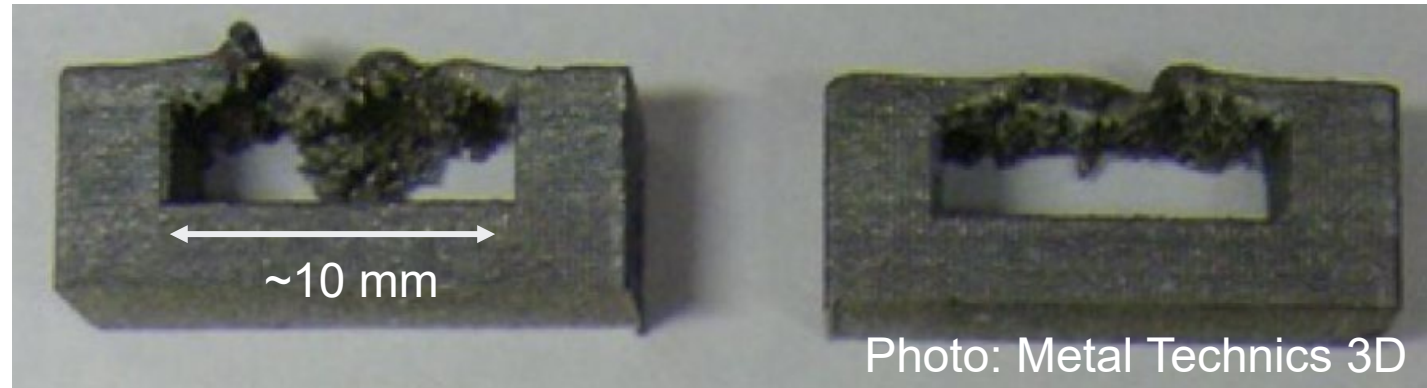
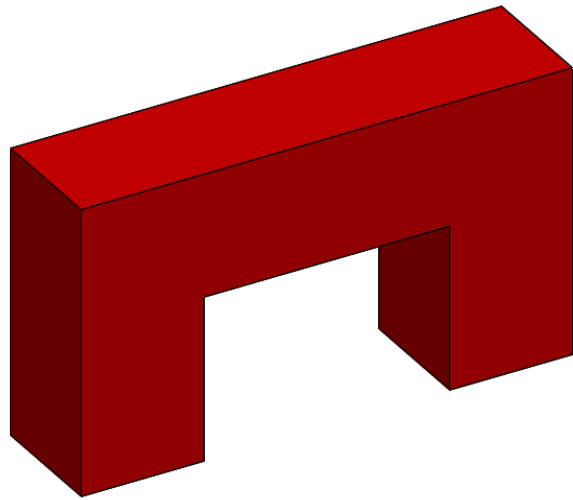


EOS



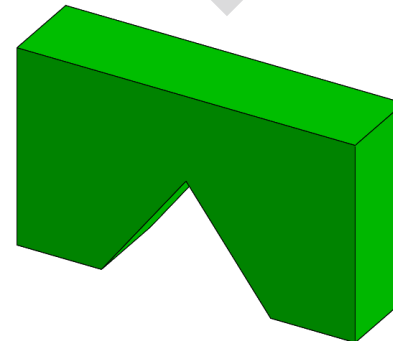
The impeller was produced in an optimized 316L process on an EOS M 290 without internal supports and with a **reduction of 35%** (photo credits: EOS GmbH)

# Make geometry manufacturable (e.g. get rid of overhangs)



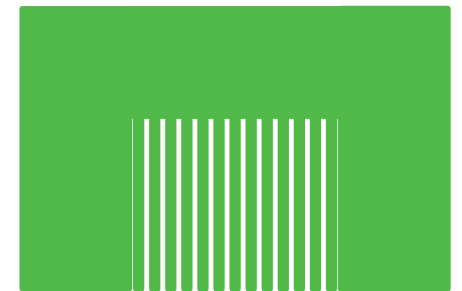
By orientation

OR



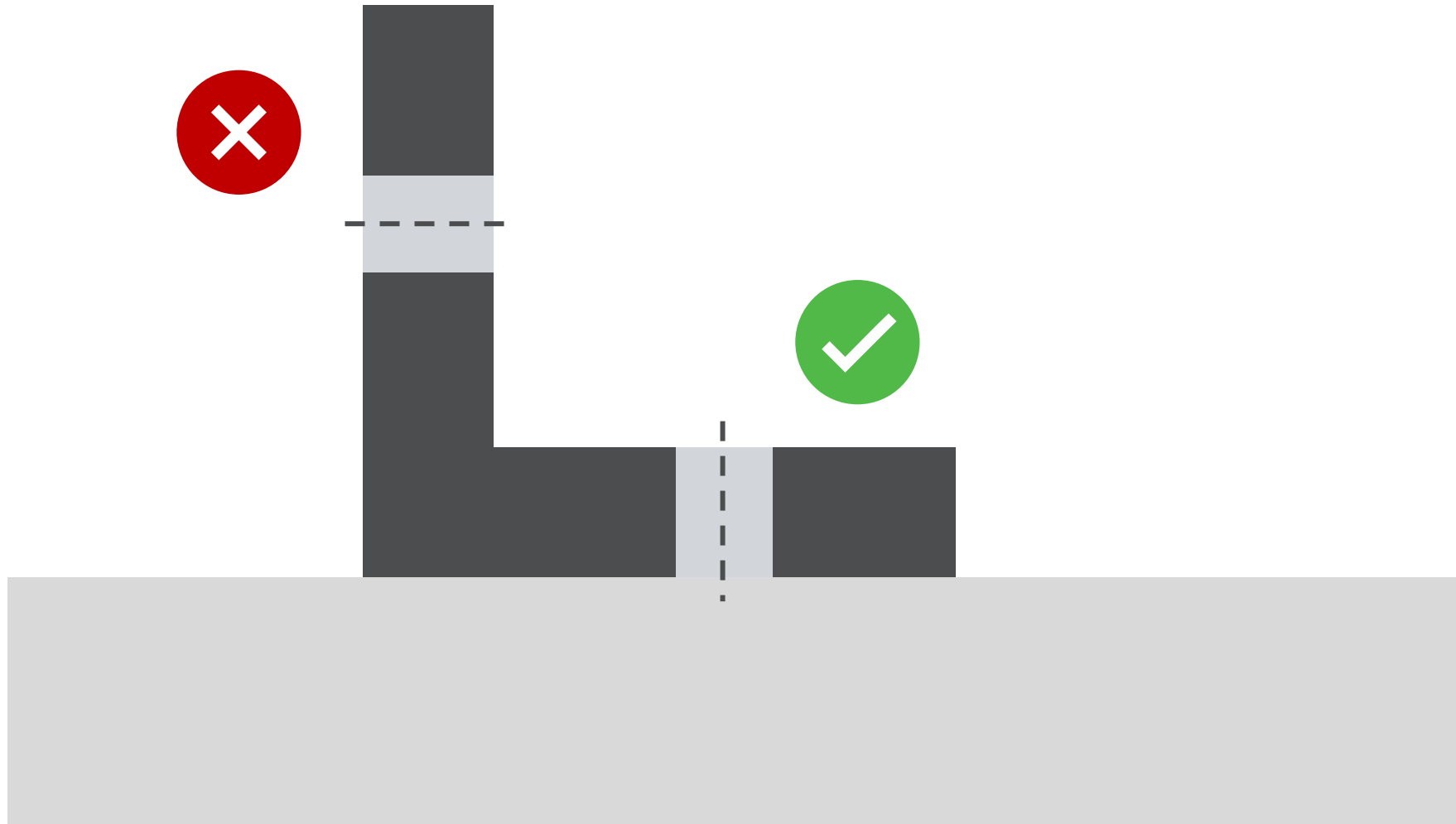
By including  
supports in design

OR



By additional  
(removable) supports

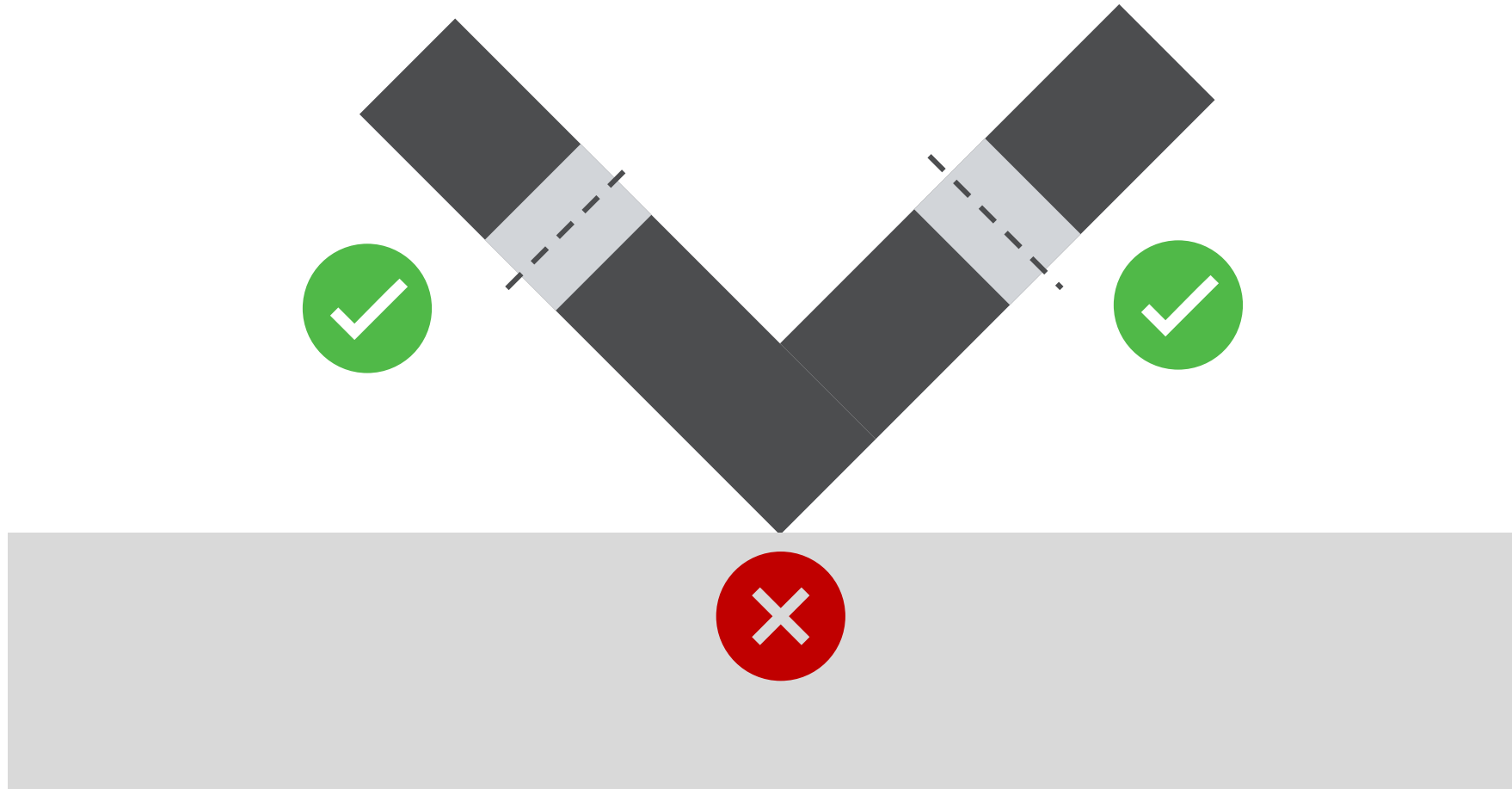
# How to print both holes with good quality?





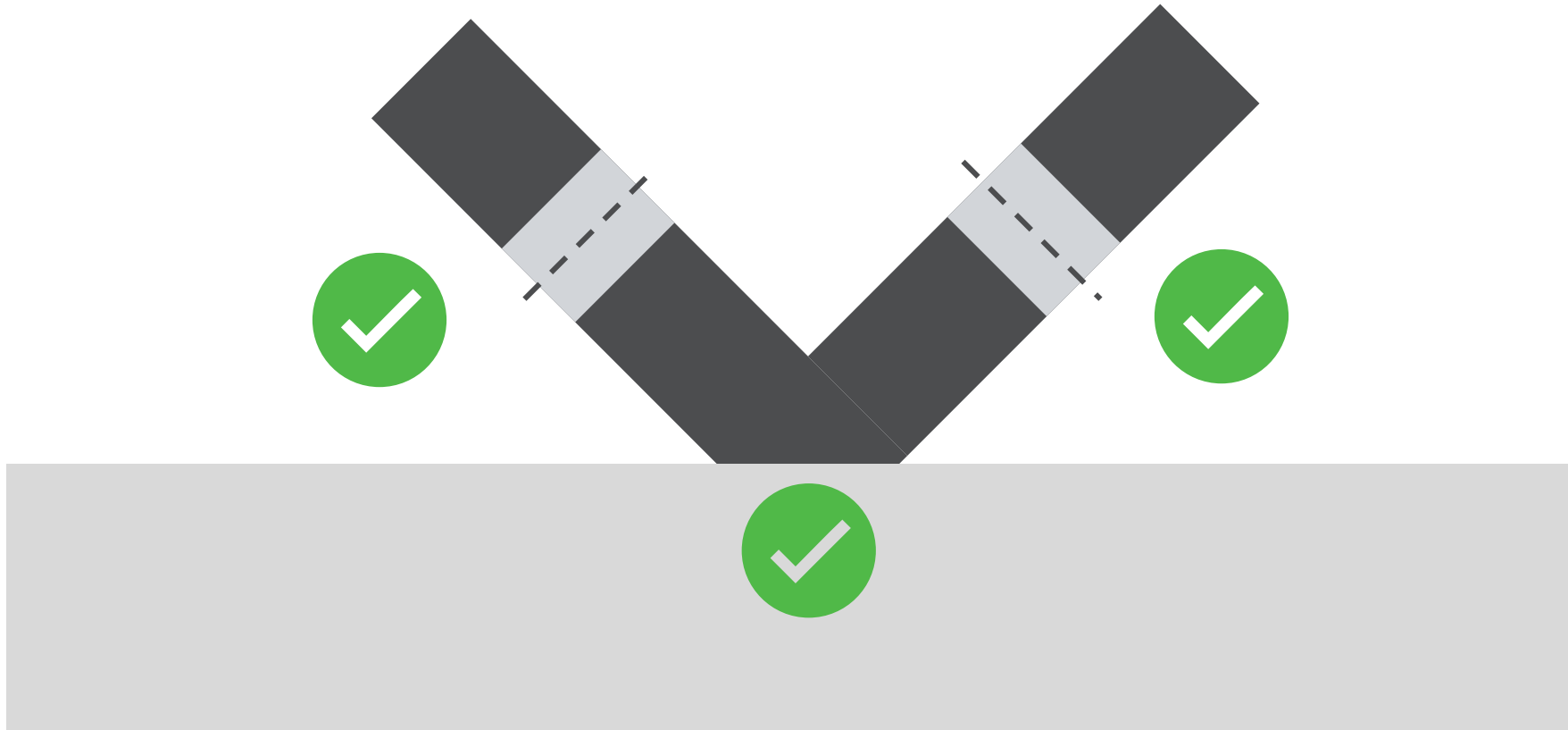
# How to print both holes with good quality?

Reorient the part (not sufficient yet)



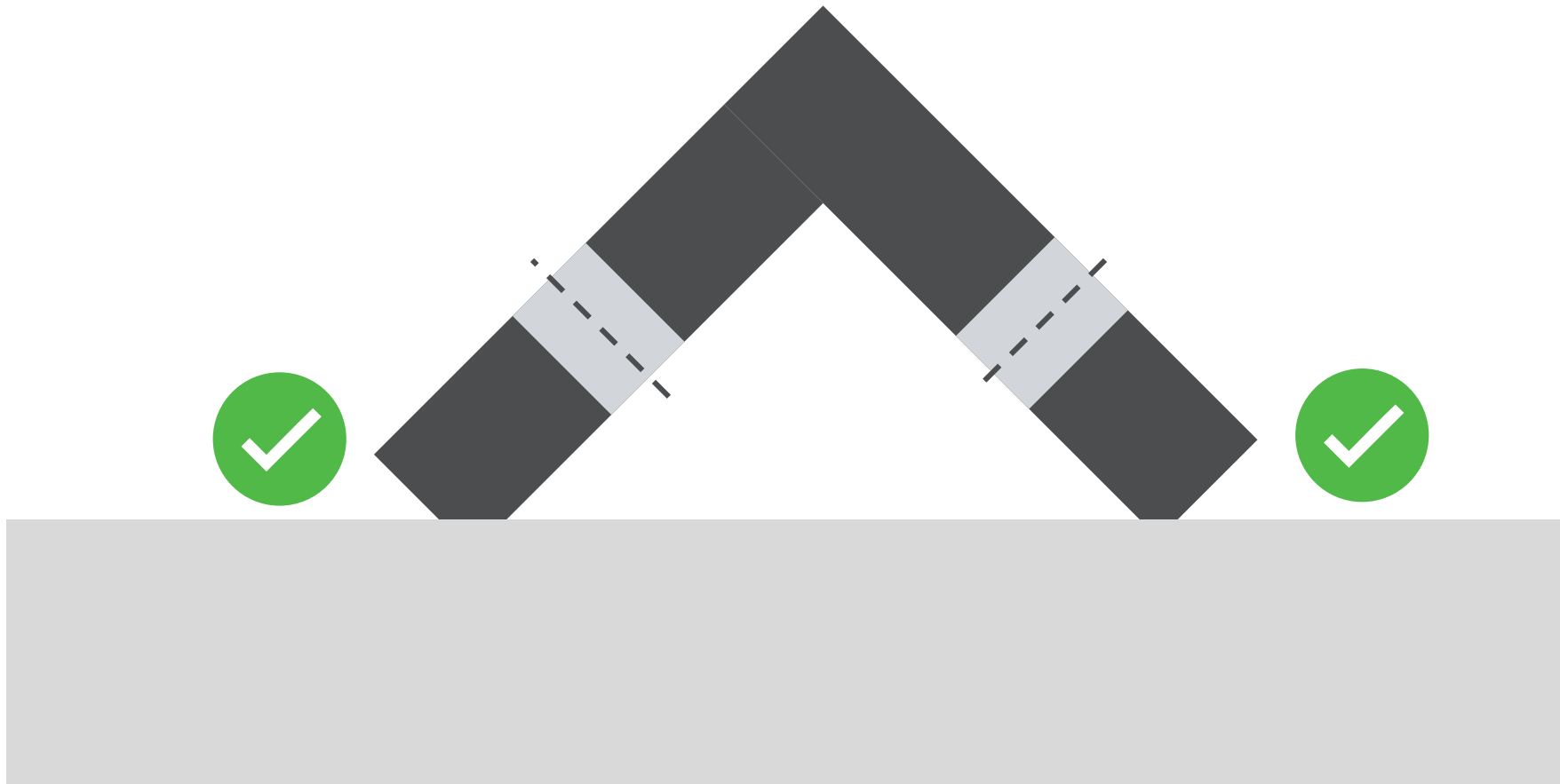
# How to print both holes with good quality?

Reorient the part and alter the geometry



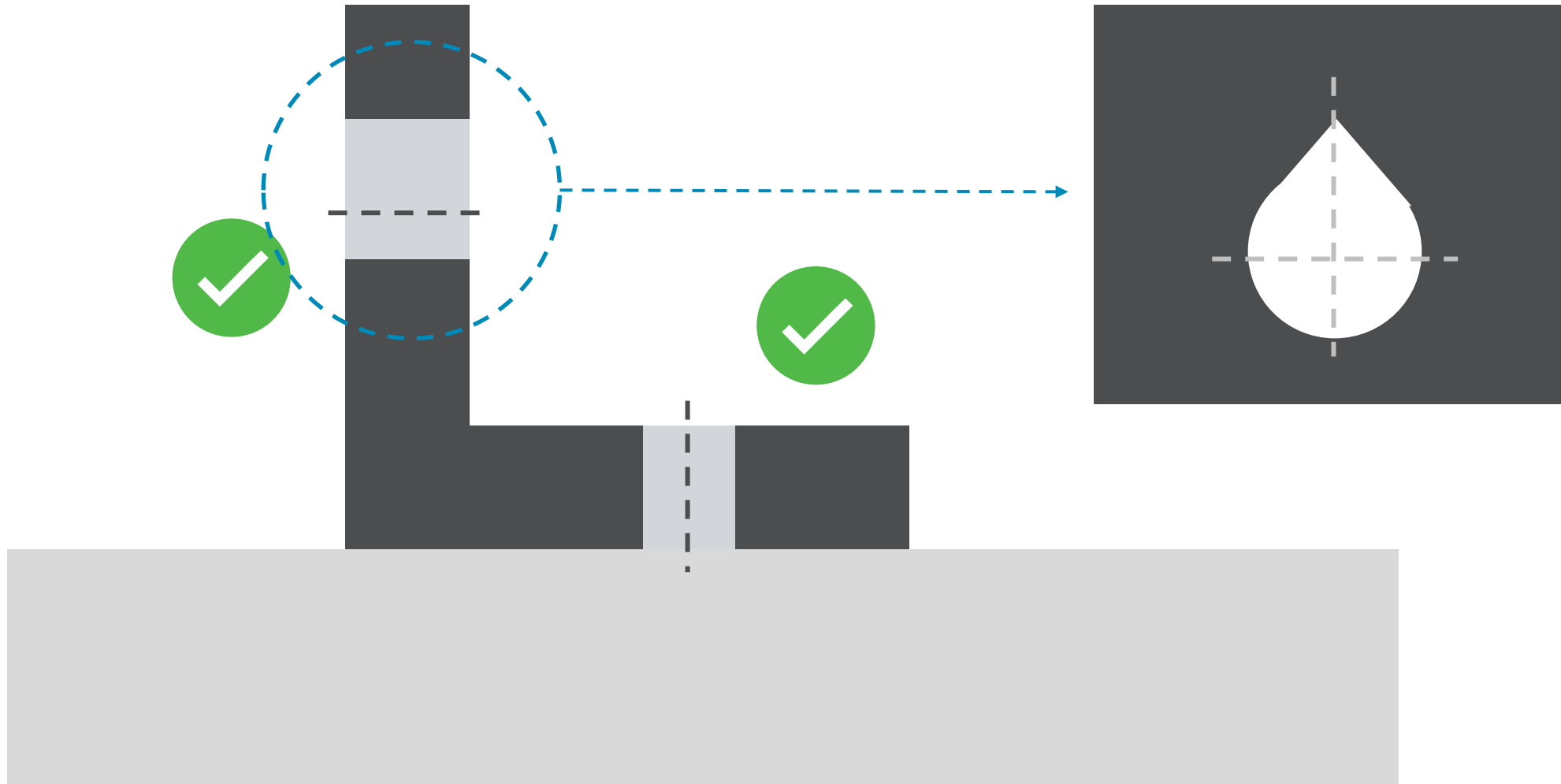
# How to print both holes with good quality?

Reorient the part, option 2



# How to print both holes with good quality?

Make the hole support itself with a teardrop shape



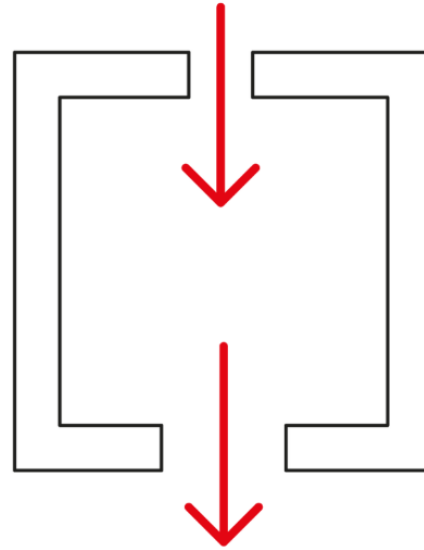
# How to print both holes with good quality?

Divide the part into two



# Escape holes

- Escape holes are needed to get rid off the trapped powder in hollow structures
- Two holes are recommended: one to blow air and other for powder exit
  - For metal one hole is okay
  - For plastic, holes should be on opposite sides

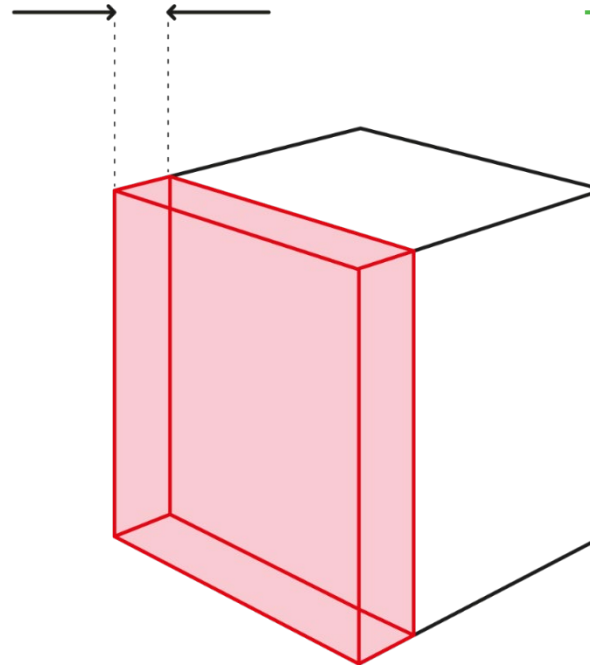


- Laser Powder Bed Fusion (LPBF)
  - $\varnothing$  2-5 mm
- Selective Laser Sintering (SLS)
  - Min  $\varnothing$  4 mm

Trapped powder (especially metal) is a **safety risk!**

# Tolerances / Accuracy

- **Laser Powder Bed Fusion (LPBF)**
  - Accuracy depends on part orientation, material and part size
  - Typically,  $\pm 0.2\%$  ( $\pm 0.1\text{--}0.2\text{ mm}$  up to 100 mm size)
- **Fused Deposition Modelling (FDM)**
  - Typically,  $\pm 0.15\%$  (lower limit  $\pm 0.2\text{ mm}$ )

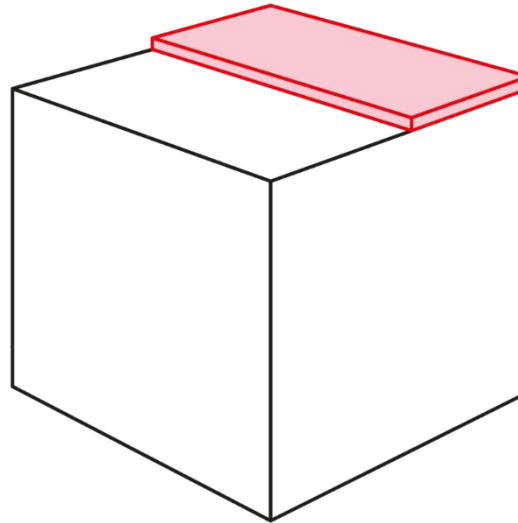


- **Selective Laser Sintering (SLS)**
  - PA2200 / PA3200 / PA2241FR / PA2210FR / Alumide:  $\pm 0.2\%$  (min.  $\pm 0.2\text{ mm}$ )
  - TPU:  $\pm 0.2\%$  (min.  $\pm 0.3\text{ mm}$ )
  - PA11 ESD:  $\pm 0.3\%$  (min.  $\pm 0.4\text{ mm}$ )



# Machining allowance

- Often, the part is not ready right after printing, but machining or other post-processing is needed
- From machining point of view, additive manufacturing is essentially producing a “blank”
- In AM, the added material is only what is needed for the end part



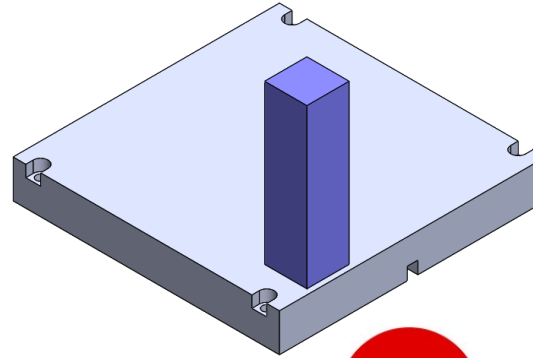
## Remember to account for machining!

- Typically, 0.5 mm machining allowance is enough
  - Sometimes more might be needed so remember to consult your print service provider / machinist!

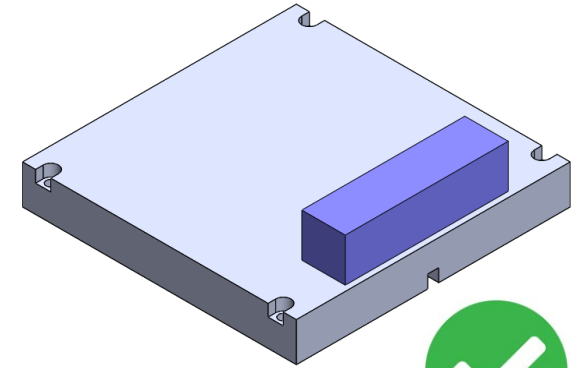
# Nesting & orientation (Metal LPBF)

Single component

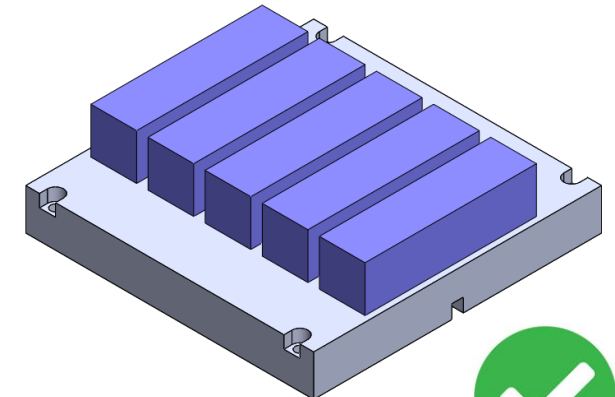
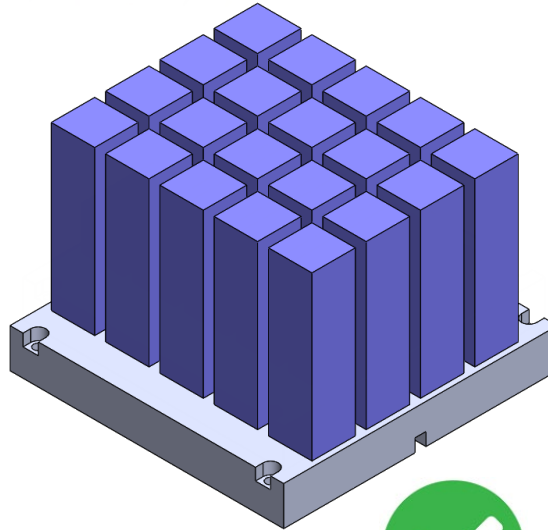
Standing tall



Laying flat <sup>INTERNAL</sup>



As many parts produced as possible



# Design for stacking (maximizing the use of build volume)

## Laser Powder Bed Fusion (LPBF)

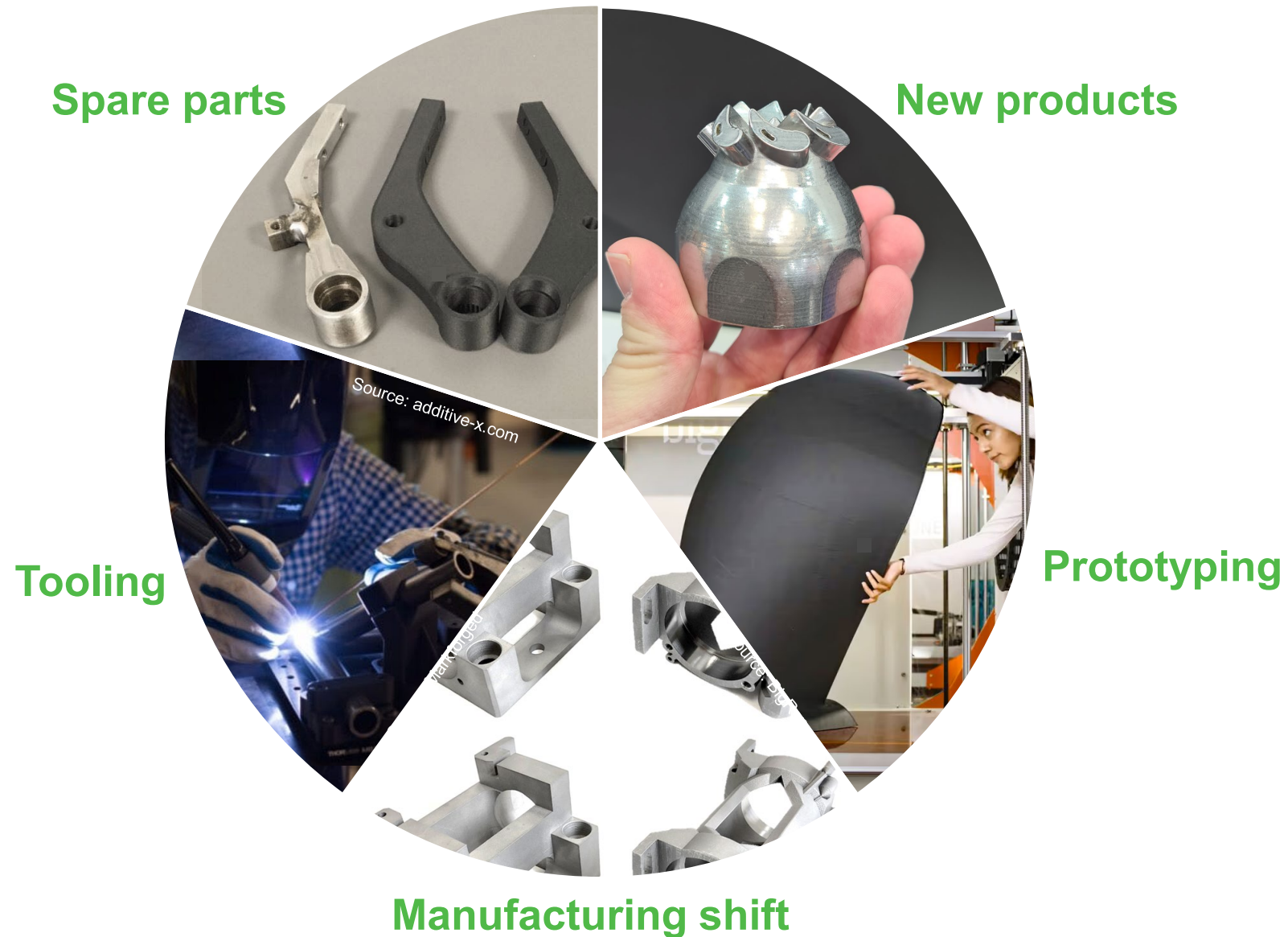


## SLS / MJF / MJB / EBM



## Real-life case from Valmet

# What are the typical application areas for AM?



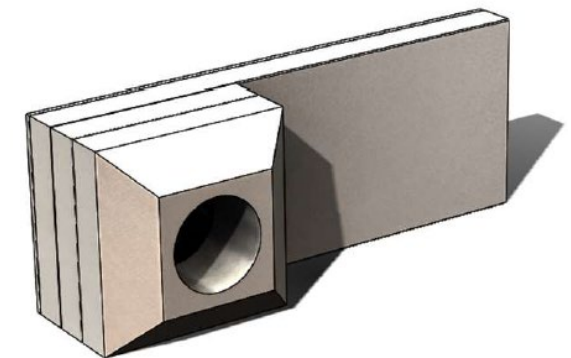
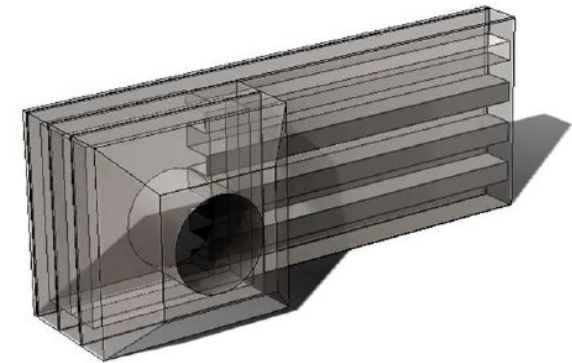


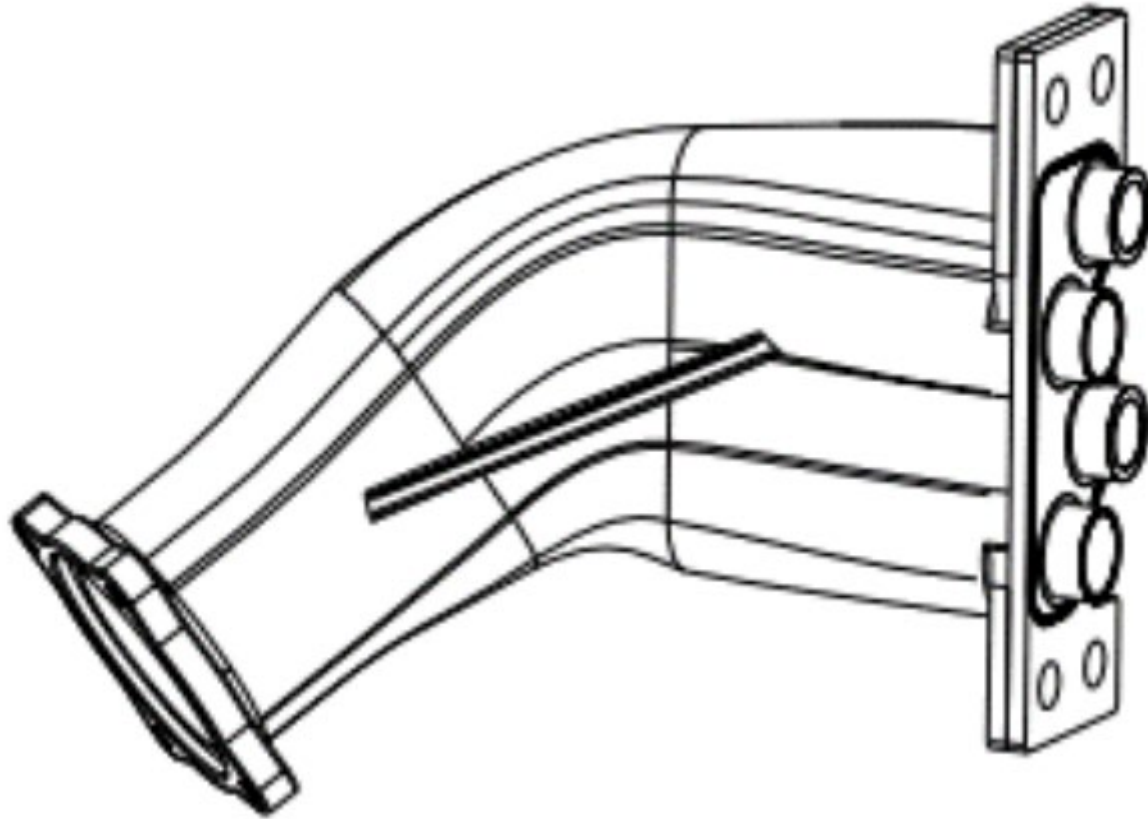
# Real-life new product development case: Headbox Edge Flow

## Valmet

- One of the first, if not the first, application of metal AM-parts at Valmet. This application was identified and first designed as part of a mechanical engineering thesis from JAMK published 2018.
- Design for AM included a) the use of build plate as an integral part of the construction and b) nesting optimization for printing several parts at the same time
- Old design
  - Multi-part assembly from milled parts
  - Previously it had poor manufacturability and considerable amount of welds
  - This resulted into high cost
- Flow properties were also poor with 90-degree sharp corners
- AM approach is to machine a base plate and print on top the geometry that makes sense to be printed
- Benefits
  - Part consolidation: 7 -> 2
  - Improved flow: -60% power loss
  - Cost reduction: -30%
  - Enabled a modular product

Old design pictured below  
(new design censored)





Some of the first sketches of  
the new design (Kuikka 2018)

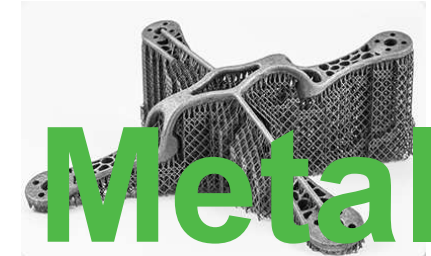
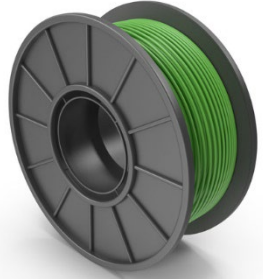


[Slides with further Valmet product examples removed from this version of the presentation]

# Summary

- AM is one group of manufacturing methods that you should be somewhat familiar with – not the only one, not always the best, but among those that should be considered alongside methods such as tooling with milling and turning machines, casting, sheet metal work, and welding.
- A plethora of methods of AM exist. For starters, these are sufficient:
  - FDM (Fused Deposition Modeling) – Traditional desktop 3D-printing. Get one, make your own projects, and learn the basics through it. Supports are needed in FDM prints. Designing and printing such objects can be useful in understanding also metal-AM design.
  - SLA (Stereolithography) / resin-based – Also desktop printing viable for customers, intricate details, mechanically not very viable.
  - SLS (Selective Laser Sintering) – Professional 3D printing with polymers.
  - Metal AM – A lot of different methods (laser powder bed fusion, binder jetting, direct energy deposition, etc.) exist. Supports are needed.
- AM allows for increasingly complex design with localized mechanical properties, complex internal geometries, etc. – at some point, humans won't be able to keep up in designing such pieces. From there, cloud-based computing and automated, iterative design such as generative shape design step in.

# AM cheat sheet – what you need to know / should remember for now



## FDM

- Polymer printing
- Your typically hobby / desktop printer
- Very good for prototyping and getting familiar with the technology
- Needs supports but not escape holes
- Good mechanical properties can be achieved
- If you have an excuse – just buy one (or use the ones at your school)

## SLA

- Polymer printing
- Very cheap machines but bad odors/chemicals
- Allows for extremely intricate details and the surface quality is very good – extremely suitable for visual prototypes
- Common for hobbyists as well (small figures, scale models etc.)
- Generally bad mechanical properties
- Needs supports and escape holes

## SLS

- Polymer printing
- Your typically hobby / desktop printer
- Probably the most typical industrial application of polymer printing

## AM

- Especially interesting field of technologies professionally, but probably learning the basics is easier through polymer methods.
- Escape holes and supports are needed

# Other materials

- Breaking AM video series by Huld:
- [https://www.youtube.com/playlist?list=PL3uWv4yEVZNQUFLsYPJ1\\_tYldDI5FojYT](https://www.youtube.com/playlist?list=PL3uWv4yEVZNQUFLsYPJ1_tYldDI5FojYT)



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# C6 – Manufacturing Technology

## L2 – Solder Paste Printing Process

P5 - Robert Bosch SRL

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# Solder Paste Printing Process

## The purpose of the lab is:

- 1) Understanding the PCB paste printing process;
- 2) Establishing a technological itinerary for PCB manufacturing;
- 3) Identifying possible factors that can lead to paste printing errors;
- 4) Becoming familiar with specialized terminology;
- 5) Understanding the importance of intermediate product quality control/gate.



# Content

- Introduction – Surface Mount Technology Area
- Topic 1 – Solder Paste Printing – Process definition;
- Topic 2 – Offset Printing Exercise;
- Topic 3 – Solder Paste Printing issues;
- Printing Application;

# Introduction – Surface Mount Technology Area



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# Introduction – Surface Mount Technology Area

## Abbreviations and Definitions

<b>SPP</b>	<b>S</b> older <b>P</b> aste <b>P</b> rinting
<b>SPI</b>	<b>S</b> older <b>P</b> aste <b>I</b> nspection
<b>AOI / SJI</b>	<b>A</b> utomatic <b>O</b> ptical <b>I</b> nspection / <b>S</b> older <b>J</b> oint <b>I</b> nspection
<b>AWP</b>	<b>A</b> rrow <b>W</b> ith <b>P</b> olarity
<b>SMT</b>	<b>S</b> urface <b>M</b> ounted <b>T</b> echnology
<b>PCB</b>	<b>P</b> rinted <b>C</b> ircuit <b>B</b> oard
<b>SMD</b>	<b>S</b> urface <b>M</b> ounted <b>D</b> eVICES
<b>THRS</b>	<b>T</b> rough <b>H</b> ole <b>R</b> eflow <b>S</b> oldering
<b>DMD</b>	<b>D</b> ivision <b>M</b> anufacturing <b>S</b> ystem
<b>Fiducial</b>	Reference point used by automated assembly machines to ensure accurate alignment and placement of components during the assembly process.
<b>Pad</b>	Is a metallized area that allows for the connection and attachment of the electrical terminals of electronic components
<b>Aperture</b>	An opening or shape used in the stencil design that controls the application of solder paste onto the pads of the board.
<b>Quality gate</b>	A quality gate in the SMT industry is a checkpoint where products are inspected to ensure they meet standards, identifying defects early to maintain quality and prevent downstream issues.



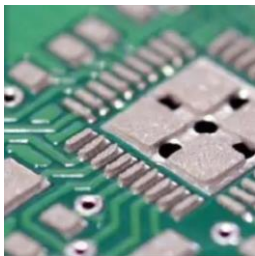
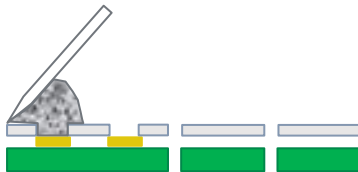
# Introduction – Surface Mount Technology Area

Process flow for Surface Mount Technology (SMT)

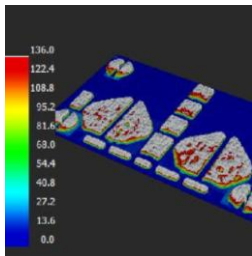
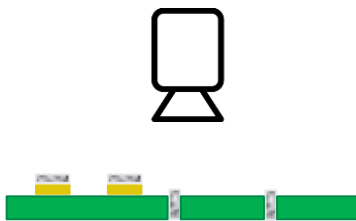
DMC Engraving



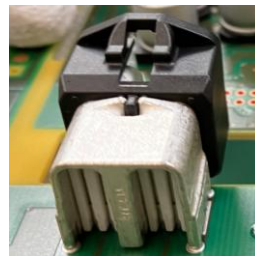
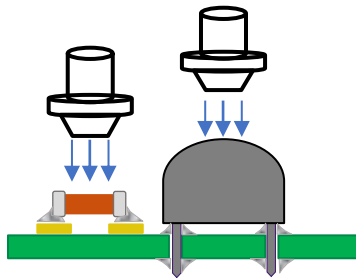
Solder Paste Printing



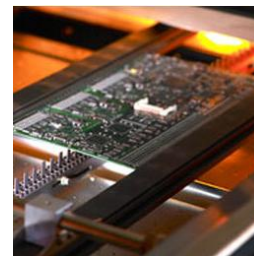
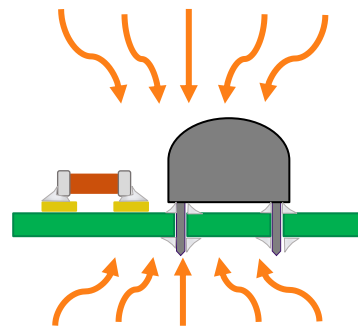
Solder Paste Inspection



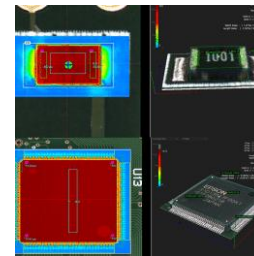
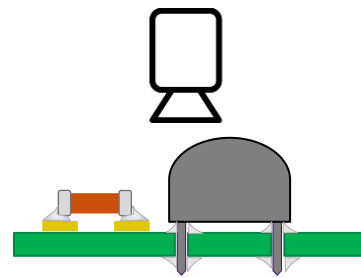
Components Placement



Reflow Soldering



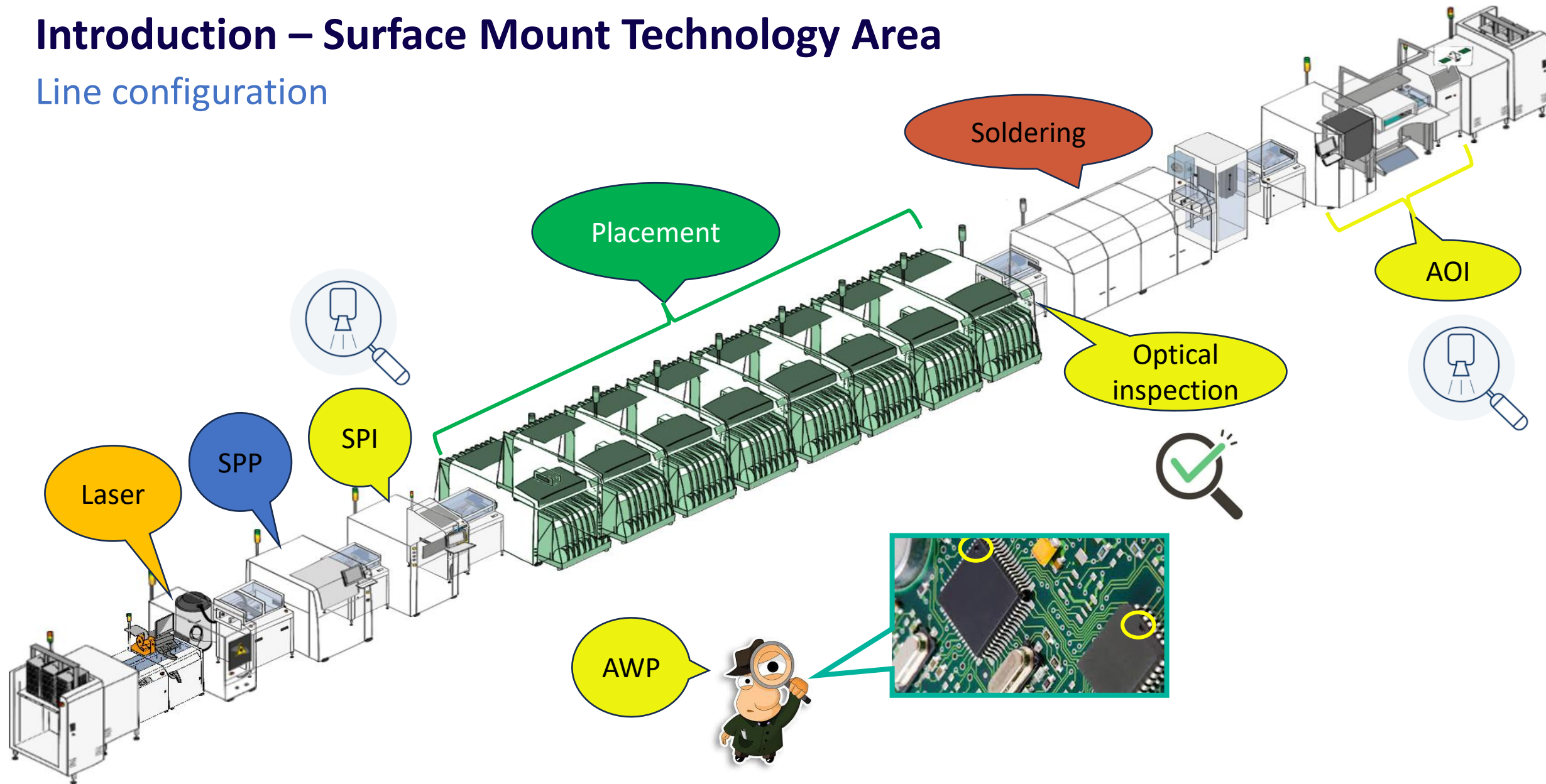
Automated Optical Inspection



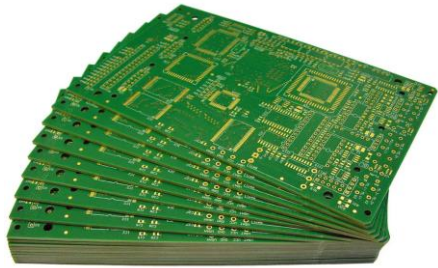
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# Introduction – Surface Mount Technology Area

## Line configuration

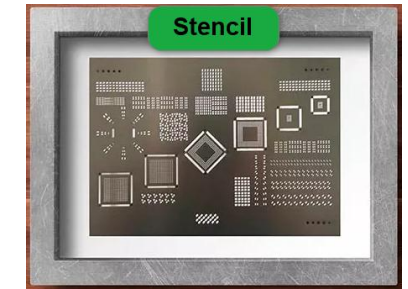
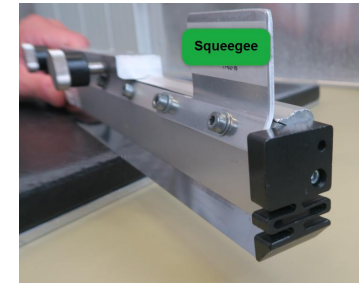


# Printed Circuit Board (PCB)

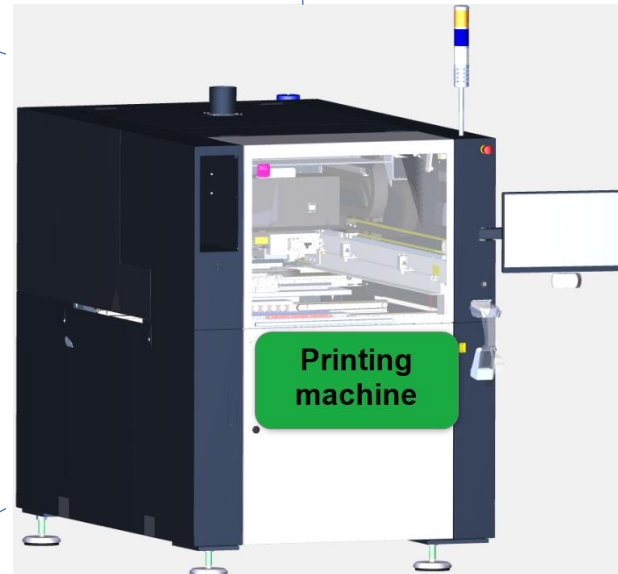
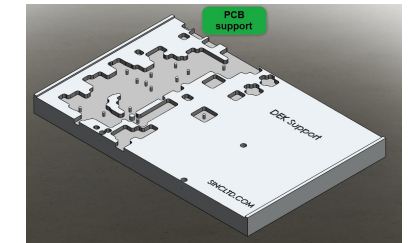


## Parameters:

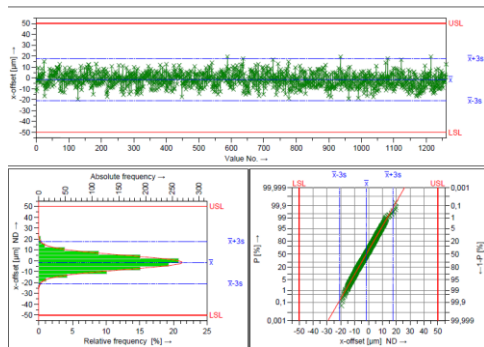
- Printing speed
- Printing pressure
- Cleaning cycle
- Stencil separation speed



## Tools



## Machine Capability Index (CMK)



## Environment

Temperature



Humidity



DMD



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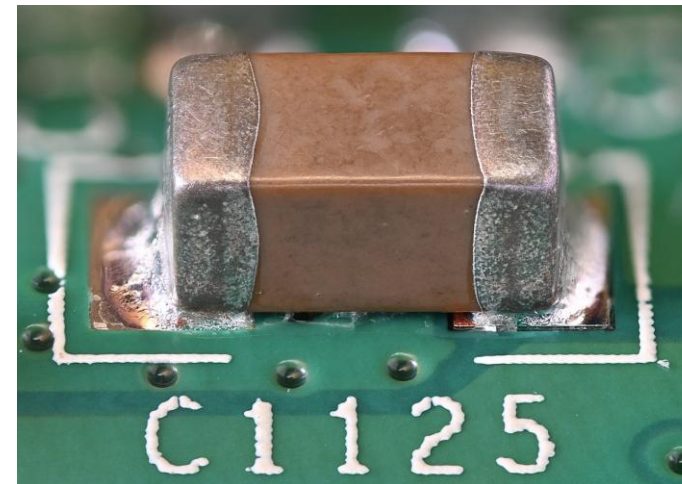
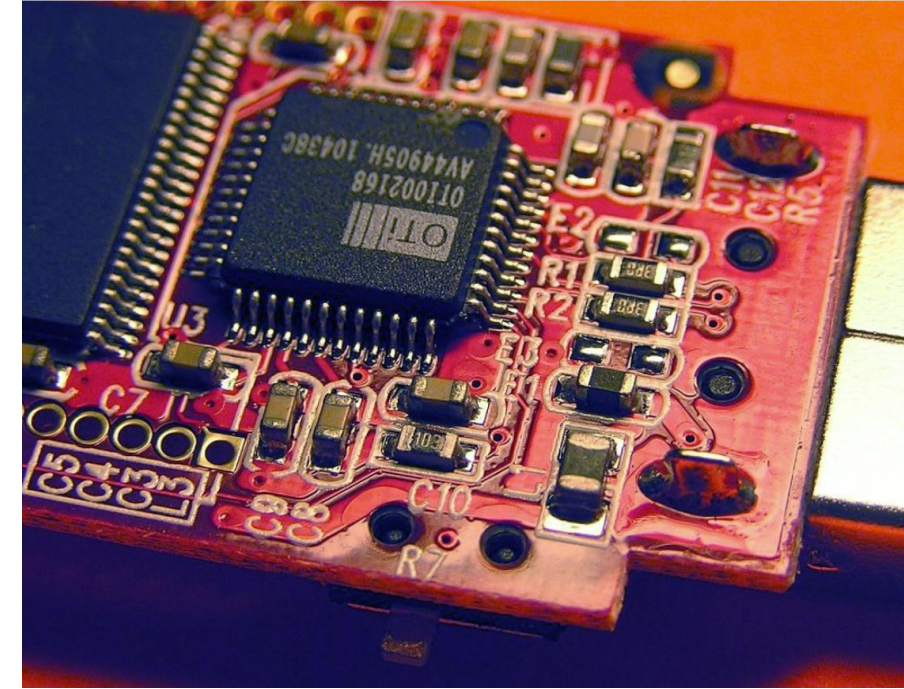


# Introduction - Tools used for Printing Process

## Factors which can influence the printing process

Solder paste printing involves applying solder paste to the pads of a printed circuit board (PCB) through a stencil.

- **Stencil Design:** The size, shape, and thickness of stencil apertures must be optimized for different PCB designs and component sizes.
- **Paste Quality:** The viscosity, particle size, and flux activity of the solder paste must be suitable for the application and the printing equipment.
- **Environmental Conditions:** Temperature and humidity can affect solder paste performance and should be controlled in the printing environment.
- **Printer Calibration:** Regular calibration and maintenance of the printing machine are essential to maintain accuracy and repeatability.





# Topic 1 - Solder Paste Printing - Process Definition



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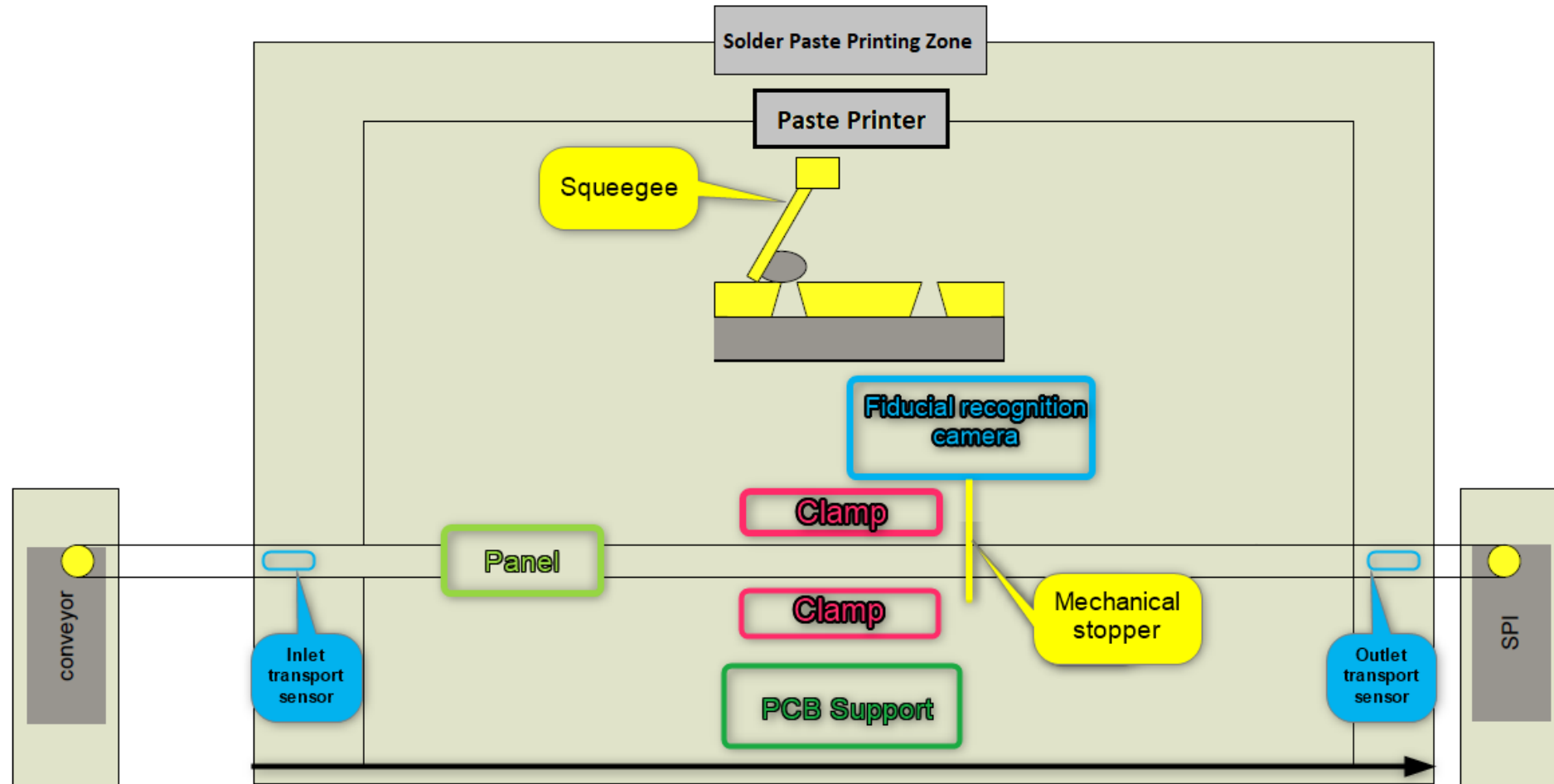


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# Solder Paste Printing – Process Definition

Process inside of printing machine

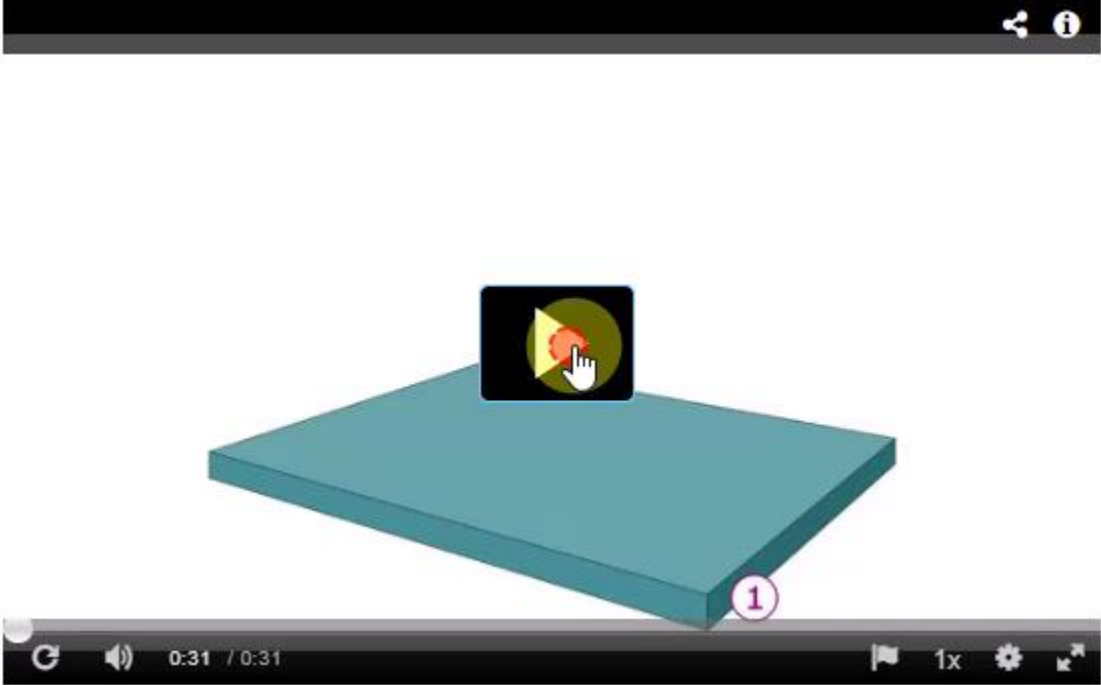


PCB Transport direction

# Solder Paste Printing – Process Definition

## Printing process concept

Step	Description
1	The PCB arrives at the inlet of the printer and enters the solder paste printer via transport belt.
2	The printing table with the PCB support lifts up the PCB from below. Afterwards the clamping is closing.
3	The PCB is lifted up against the stencil.
4	The squeegee pushes the solder past-roll, which is in front of the squeegee, over the stencil.
5	The solder paste is pressed into the apertures of the stencil and smoothly peeled off.
6	The PCB will be separated from the stencil by lowering the printing table.
7	When the PCB is back on the transport belt, the clamp will be released and the printed PCB moves out of the printer.



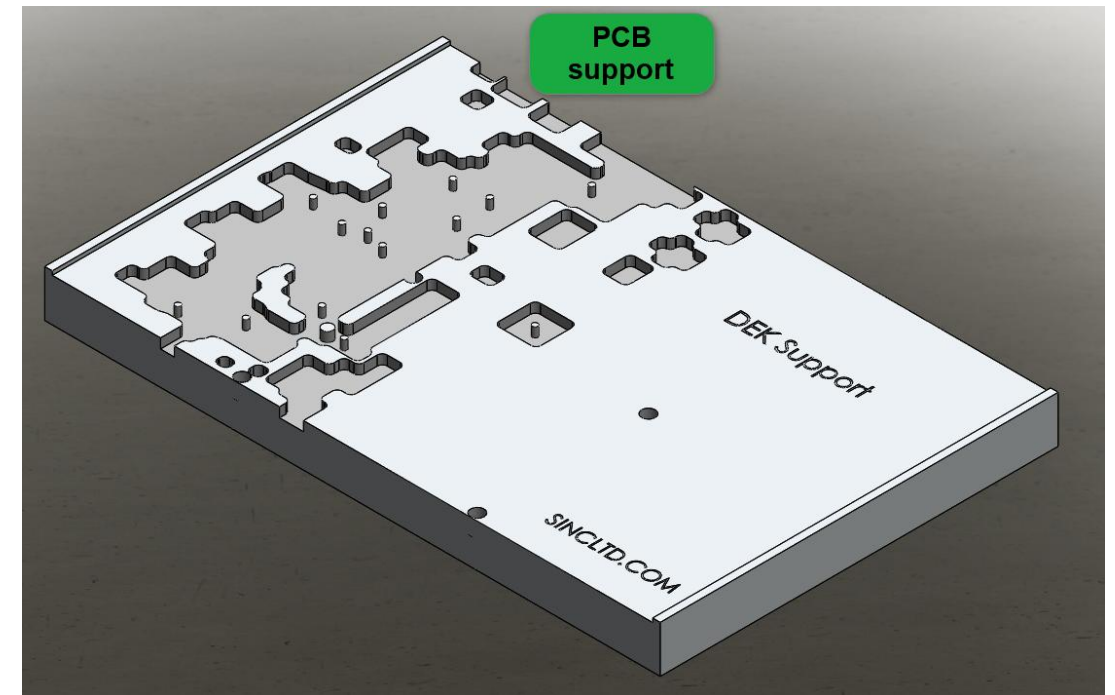
Element	Name
1	PCB Support
2	Stencil
3	PCB with Copper Pads
4	Squeegee
5	Solder Paste



# Solder Paste Printing – Process Definition

## PCB support

- **Support:** PCB support provides a stable and flat surface for the PCB during the solder paste printing process. The main functions and importance of PCB support are:
  - Stabilization - Is essential for ensuring accurate alignment between the stencil and the PCB pad;
  - Preventing Bending and Warping - Thin or large PCBs can bend or warp under the pressure applied by the squeegee, and support fixture helps to hold the PCB flat.
  - Alignment Assistance - PCB supports often include features that assist in the precise alignment of the PCB with the stencil.



# Solder Paste Printing – Process Definition

## Solder paste

- **Solder paste:** Solder paste is a mixture of powdered solder (typically an alloy of tin, lead, or lead-free alternatives) and a flux medium.

Once applied and reflowed, the solder in the paste melts and forms solid, electrically conductive joints between the PCB pads and the component leads. Besides electrical conductivity, solder paste secures components to the PCB, ensuring they remain in place during the operational life of the device, even under mechanical stresses like vibration or thermal cycling.

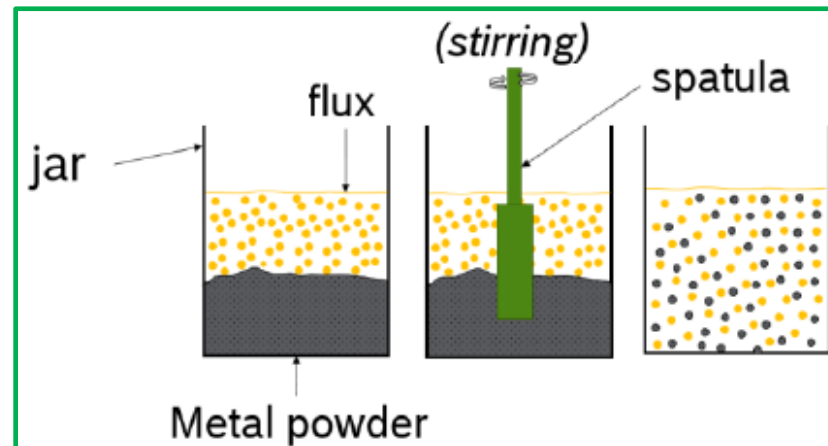
<https://www.youtube.com/watch?v=1JFoh4TppDM>

De interes Sec 14-20

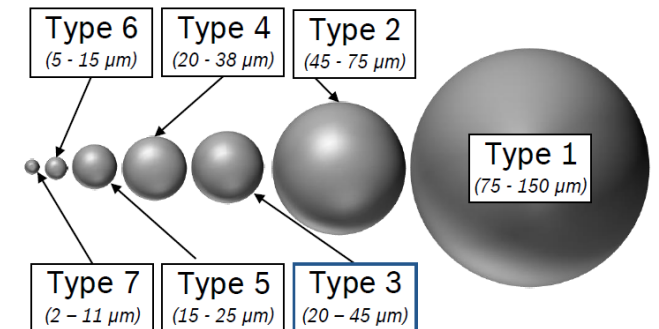


- **Ingredients:**

- Metal powder of tin, lead, cooper;
  - ➔ Electronic connection between components and PCB
- Flux consisting solid and fluid particles:
  - ➔ Removing the oxide layer of pads, holding SMD components on PCB



- **Classification of solder pastes by grain sizes:**



- AE standard solder paste: type 3

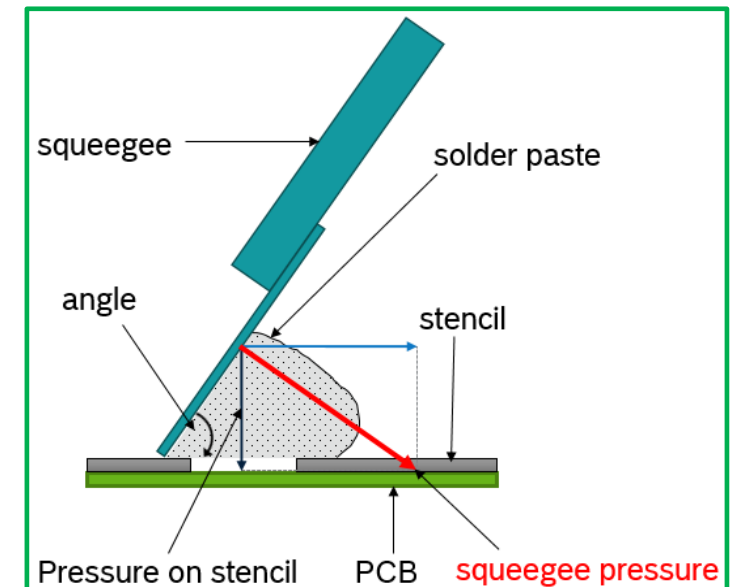
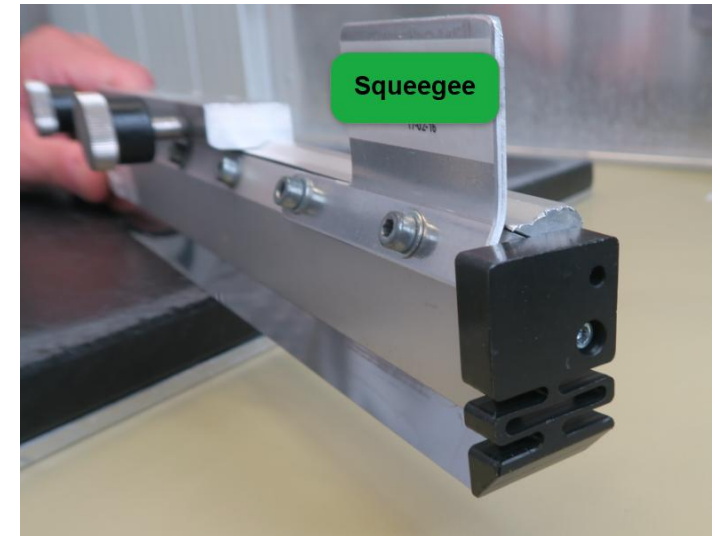


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# Solder Paste Printing – Process Definition

## Squeegees

- **Squeegees:** The primary role of the squeegee is to apply solder paste uniformly across the stencil's surface.
  - Paste Application - By moving the squeegee over the stencil, it forces the paste through the stencil apertures onto the PCB pads.
  - Paste Distribution - The squeegee ensures an even distribution of solder paste across the entire stencil. This uniformity is essential for consistent deposition of paste on all the pads, which is critical for the quality and reliability of the solder joints.
  - Pressure Control - The squeegee applies the necessary pressure to push the solder paste through the stencil apertures.
  - Angle and Speed - The angle and speed at which the squeegee moves are carefully controlled to optimize paste deposition.



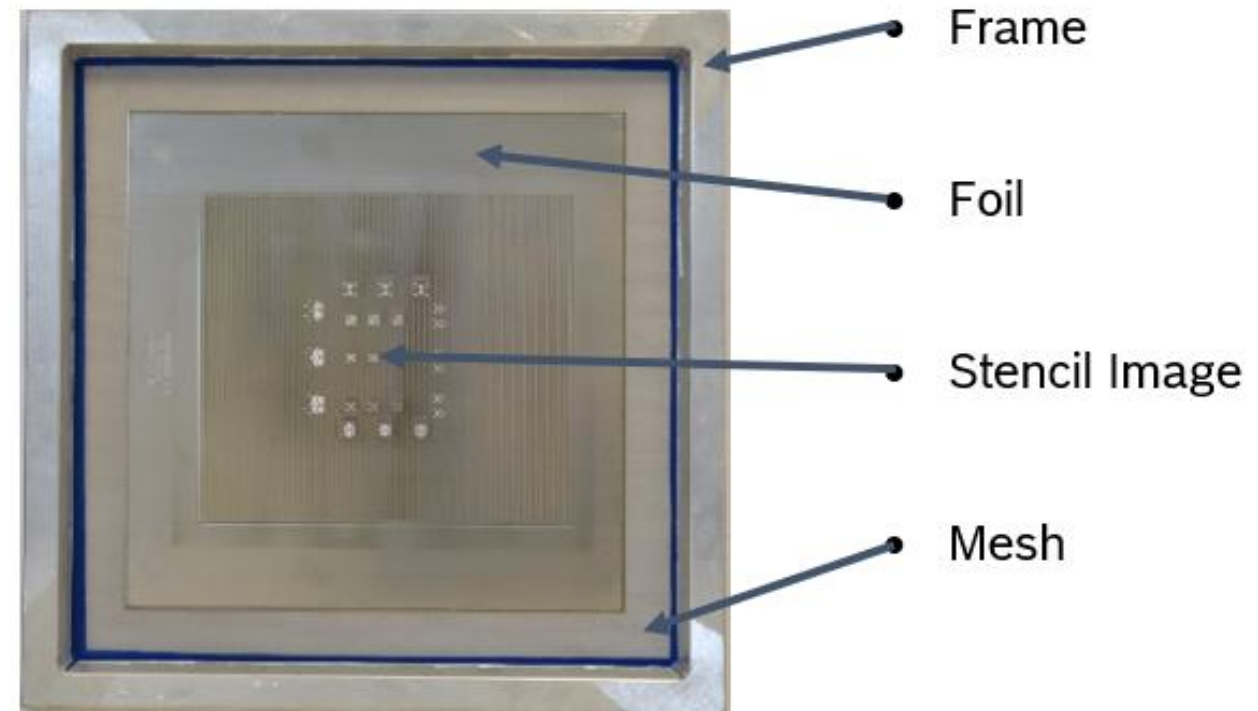
# Solder Paste Printing – Process Definition

## Stencil

- **Stencil Design:** The size, shape, and thickness of stencil apertures must be optimized for different PCB designs and component sizes.

The apertures of a stencil used in solder paste application for a printed circuit board (PCB) are intentionally designed to be slightly smaller than the pads on the PCB. This design choice serves several important purposes:

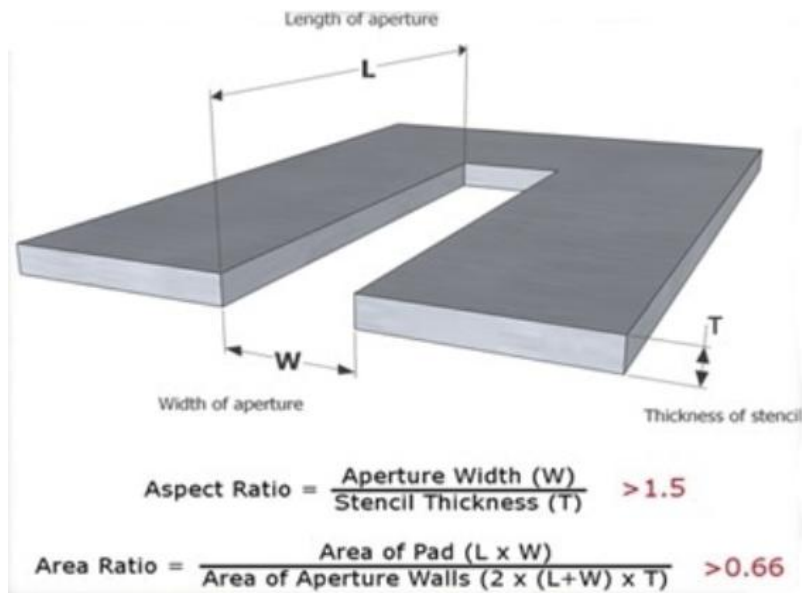
- Solder paste control - Smaller apertures help to control the amount of solder paste deposited on the PCB pads;
- Paste spread - Solder paste tends to spread slightly after being deposited;
- Stencil wear - Stencils are subjected to mechanical wear during the printing process;
- Improved Adhesion - By depositing a slightly smaller volume of solder paste, the paste can better adhere to the pad during the reflow process.





# Solder Paste Printing – Process Definition

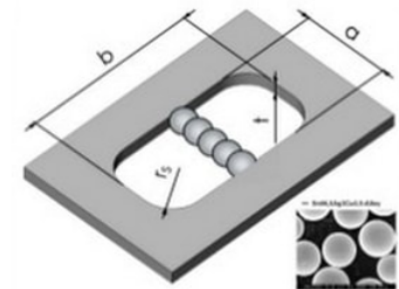
## Stencil



The release of solder paste from the apertures of the stencil is also affected by the particle size of the selected solder paste. Below are the types and particle sizes available:-

### Particle size in microns

Type	Less than 0.5% larger than	10% Max. between	80% Min. Between	10% Max. Less than
1	160	150-160	75-150	75
2	80	75-80	45-75	45
3	60	45-60	25-45	25
4	50	38-50	20-38	20
5	40	25-40	15-25	15
6	25	15-25	5-15	5
7	15	11-15	2-11	2



5 Solder Ball Rule

There is a rule of thumb which says ideally a minimum of 5 solder particles should span the width of the smallest aperture.

<https://www.surfacemountprocess.com/a-guide-to-effective-stencil-design.html>

## Topic 2 – Alignment between pads and apertures



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# Alignment Between Pads and Apertures

## Offset printing

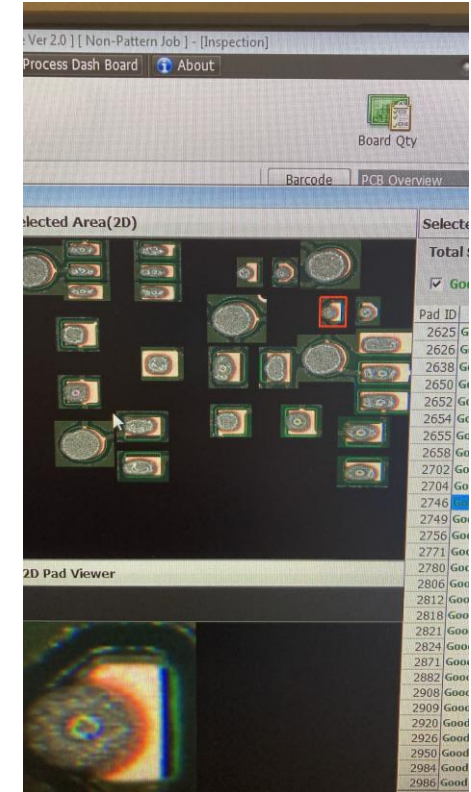
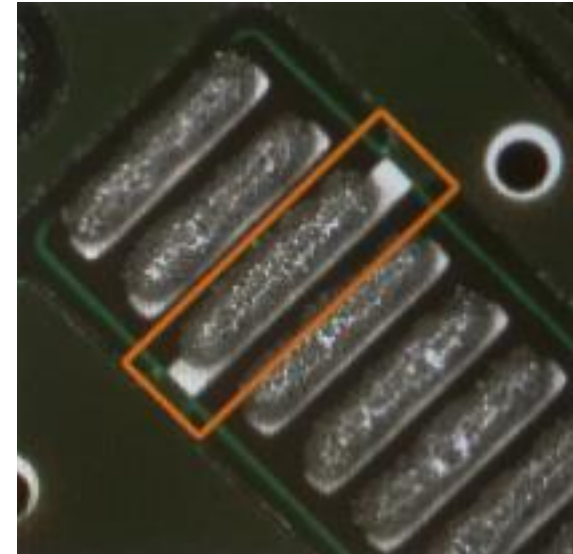
**Offset printing:** In SMT, solder paste offset detected by SPI poses major quality risks for automotive products due to strict reliability standards.

### Possible causes:

- **Stencil Misalignment:** The stencil is not properly aligned with the PCB, leading to incorrect paste deposition;
- **PCB Warpage:** The PCB is warped, causing uneven contact with the stencil.
- **Improper Machine Setup:** Incorrect programming of the solder paste printer or poor clamping of the PCB;
- **Stencil Damage or Wear:** A damaged stencil may result in uneven paste deposition.
- **Squeegee Issues:** Worn-out or improperly adjusted squeegees can cause inconsistent paste application.
- **Environmental Factors:** Temperature, humidity, or contamination in the printing environment can affect paste consistency and placement.

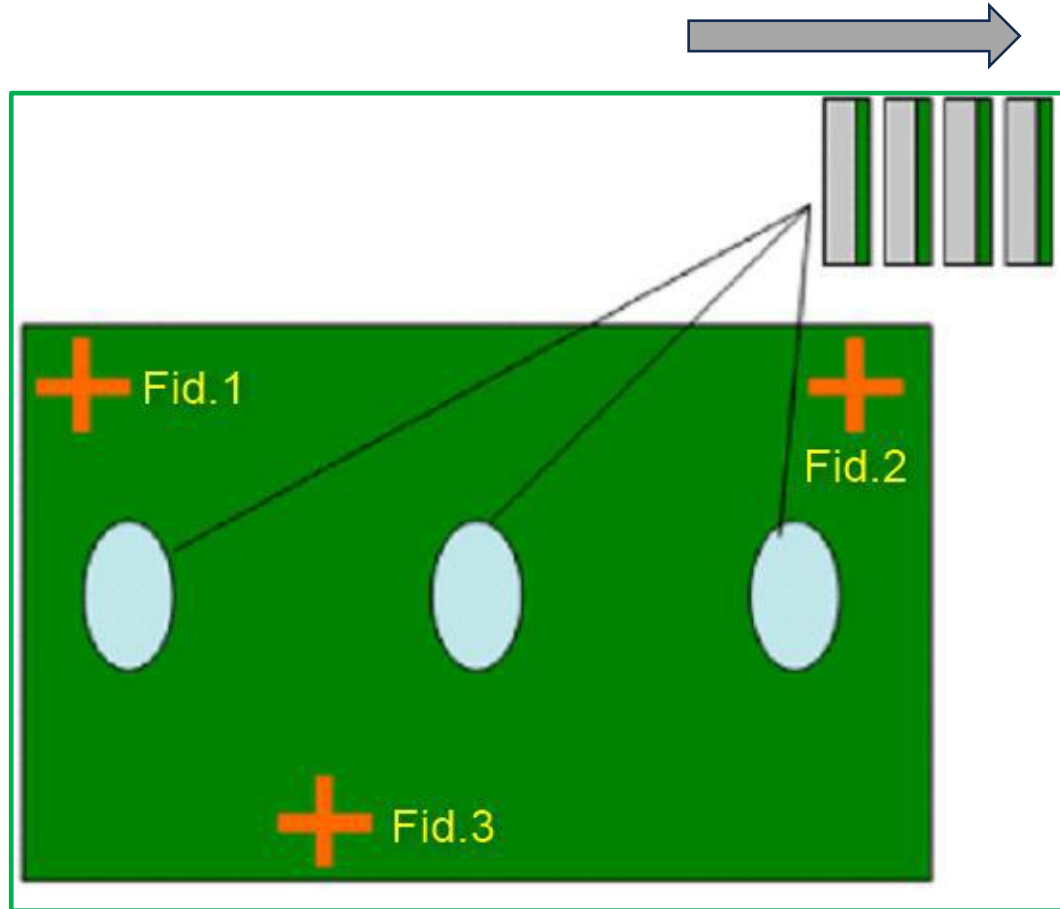
### Containment actions:

- Apply offset on the SPP machine;



# Alignment Between Pads and Apertures

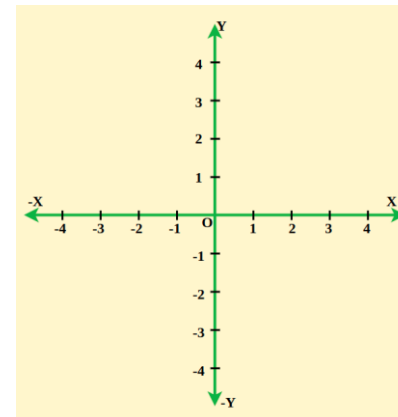
## Exercise Nr.1



1. Offset printing over the entire PCB to the left side. On which fiducial point should I apply the correction, and with what sign (plus or minus) to properly align the printing?

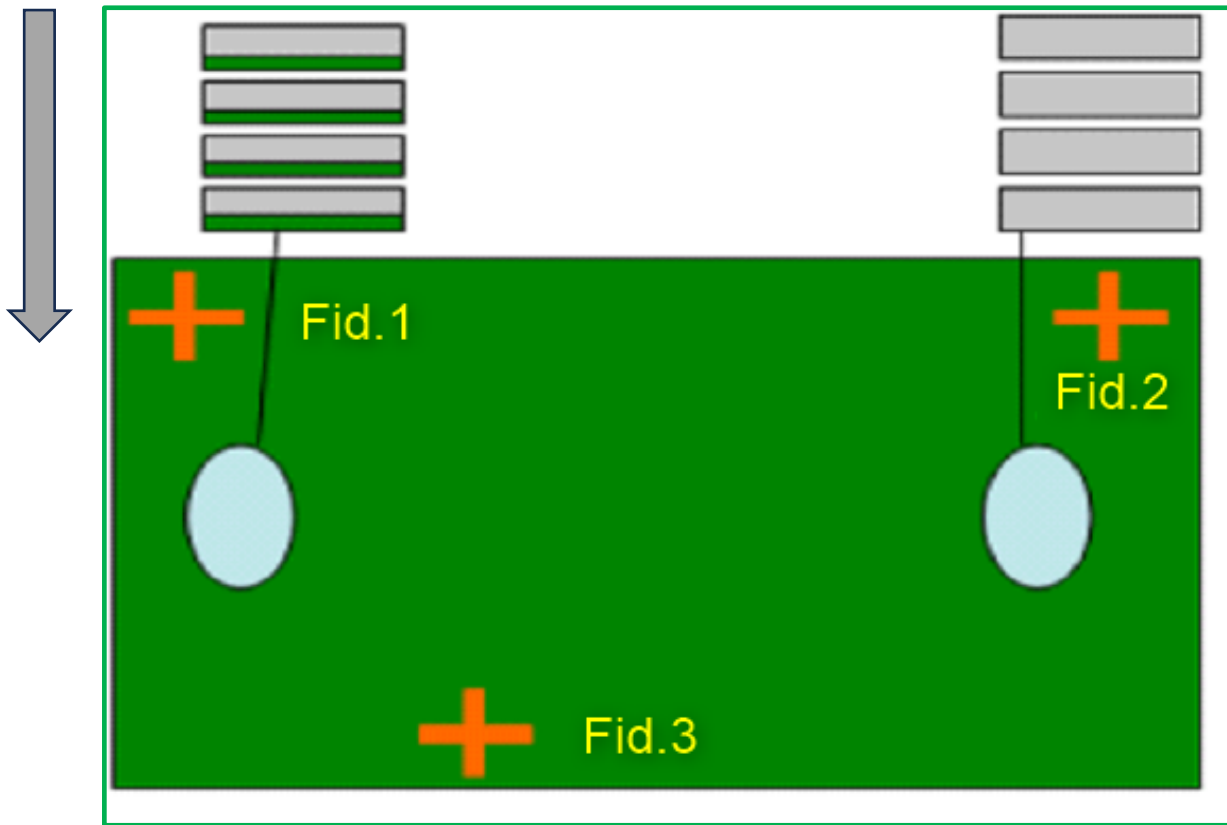
A correction will be applied for all fiducials in the positive +X direction (ex.  $0.40\mu\text{m}$ ).

No correction is applied in the Y direction.



# Alignment Between Pads and Apertures

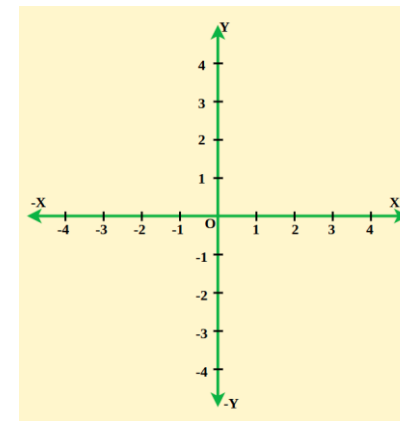
## Exercise Nr.2



2. Offset printing to the left corner only on 1<sup>st</sup> fiducial.

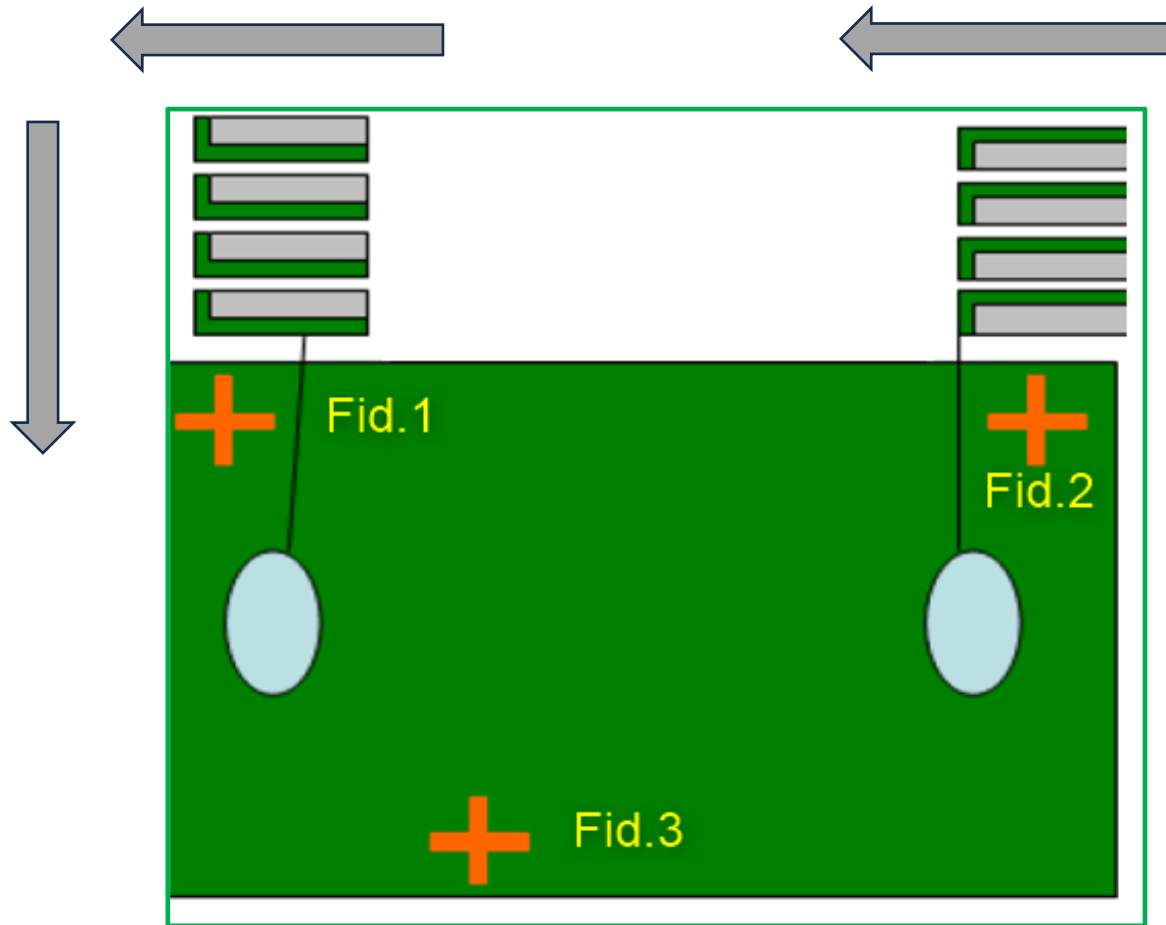
A correction is applied to the first fiducial in the -Y direction (ex. 0.40 $\mu$ m).

No correction is applied in the X direction.



# Alignment Between Pads and Apertures

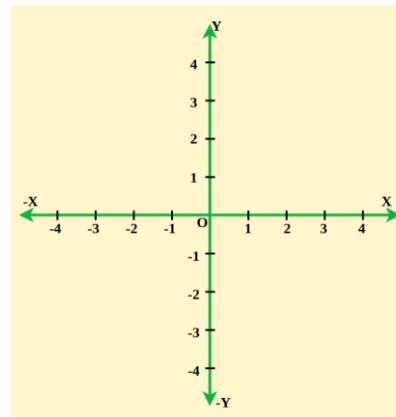
## Exercise Nr.3



3. On 1<sup>st</sup> fiducial is an offset printing into the right and upward direction;  
On 2<sup>nd</sup> fiducial is an offset printing into the right and downwards direction;

On 1<sup>st</sup> fiducial will be applied on  $-Y$  and  $-X$ .

On 2<sup>nd</sup> fiducial will be applied on  $+Y$  and  $-X$ .



# Topic 3 – Solder Paste Printing – Printing issues



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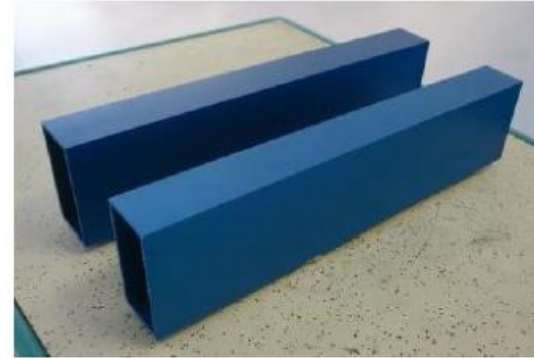
# Solder Paste Printing – Printing Issues

## Tools influences – PCB support

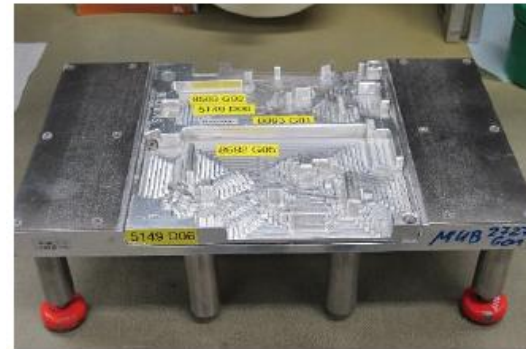
### PCB - Support:

- Purpose:  
Supports PCB against squeegee pressure to avoid a critical bending
- Usage:
  - Universal: for unpopulated PCBs
  - Product specific: for populated PCBs
- Handling:
  - Check PCB support surface for damages and contamination (e.g., Dry solder paste, bumps, worn out) before and after usage

Universal support



Product specific support

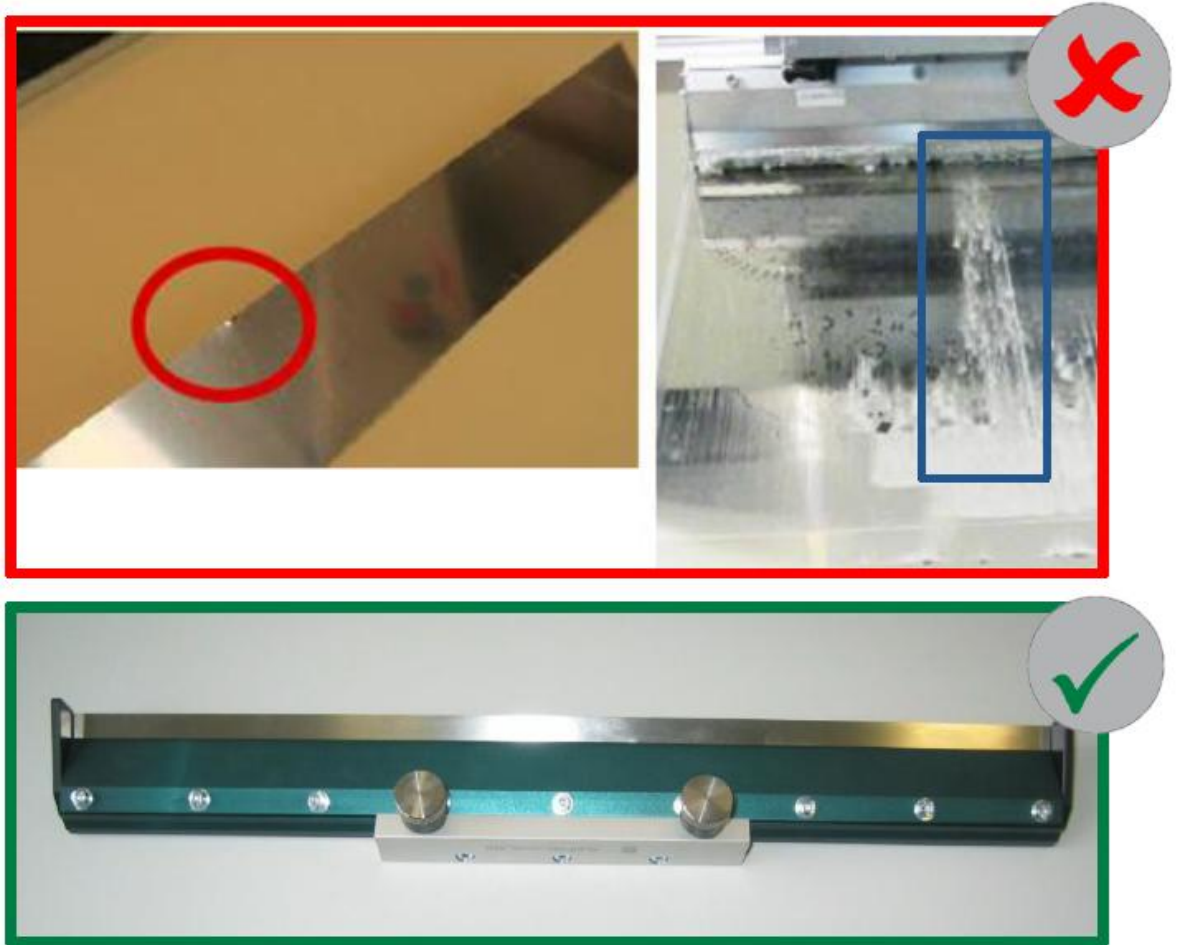


# Solder Paste Printing – Printing Issues

## Tools influences - Squeegees

### Squeegee:

- Purpose:  
Strokes solder paste over stencil and into apertures
- Usage:  
Only for specific solder paste to avoid contamination
- Handling:
  - Check before and after usage for
    - Blocked apertures
    - Bulges
    - Cracks in wire cloth
    - Foreign particles
    - Scratches



# Solder Paste Printing – Printing Issues

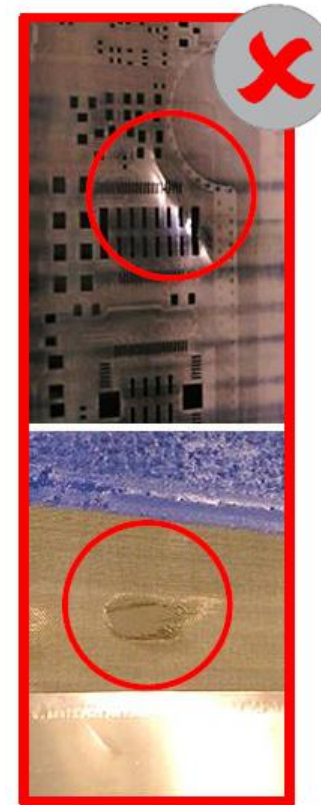
## Tools influences – Stencil

### Stencil:

- Purpose:  
Defines locations on PCB where solder paste is printed at
- Usage:

Only for specific layout of PCB

- Handling:
  - Do not touch any apertures
  - Check before and after usage for
    - Blocked apertures
    - Bulges
    - Cracks in wire cloth
    - Foreign particles
    - Scratches



# Solder Paste Printing – Printing Issues

## Insufficient Printing

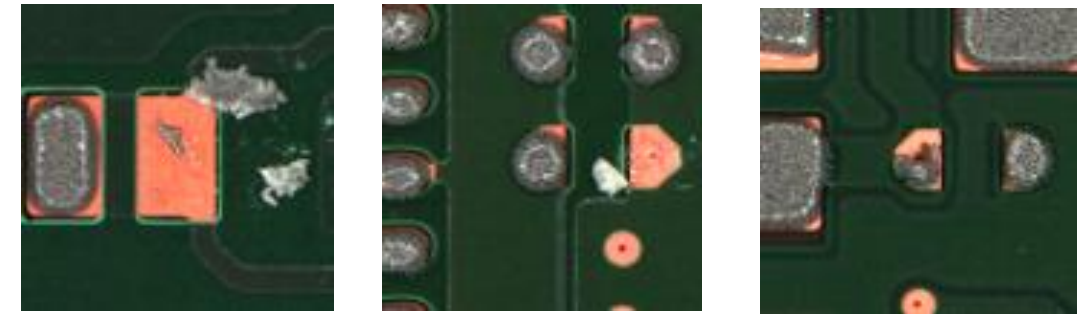
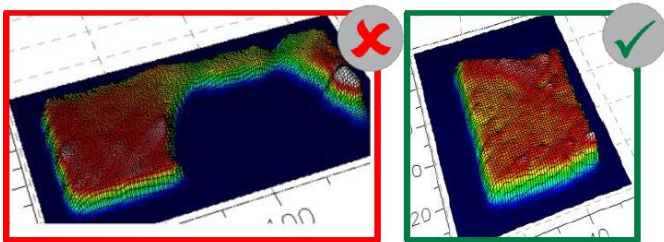
- **Insufficient Paste:** Paste deposits that are below the allowed limits can result in poor solder joints. Ensuring consistent printing parameters and stencil cleanliness helps address this problem.

### Possible causes:

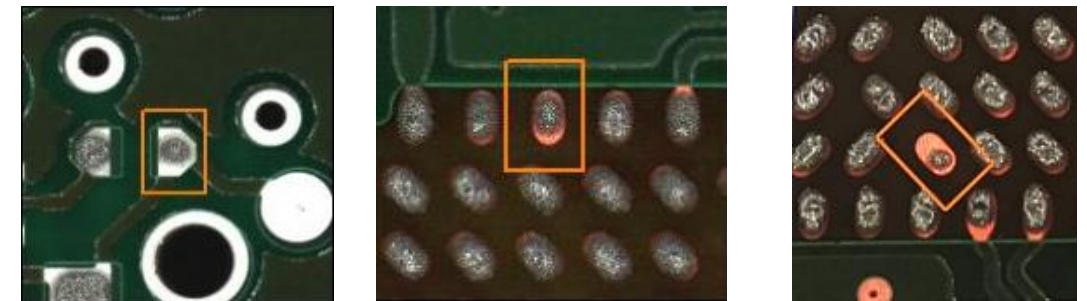
- Clogged apertures;
- Exposure and mixing paste;
- Quality of the raw material;
- Dirty or damaged tools;
- Improper cleaning process inside of the printing machine;
- Wrong settings on SPI machine;
- Contaminations;
- Environment;

### Corrective actions:

- Check printing parameters
- Check stencil and PCB support



Insufficient due to contamination



Real defect



# Solder Paste Printing – Printing Issues

## Excessive Printing

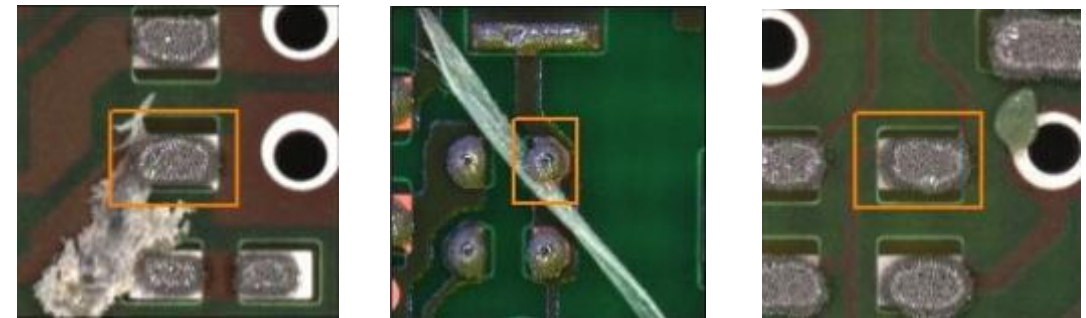
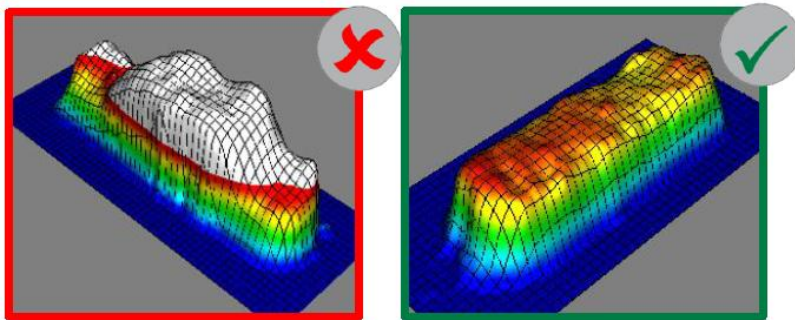
- **Excessive paste:** Paste deposits that are over the allowed limits can result in non-conform solder joints.

### Possible causes:

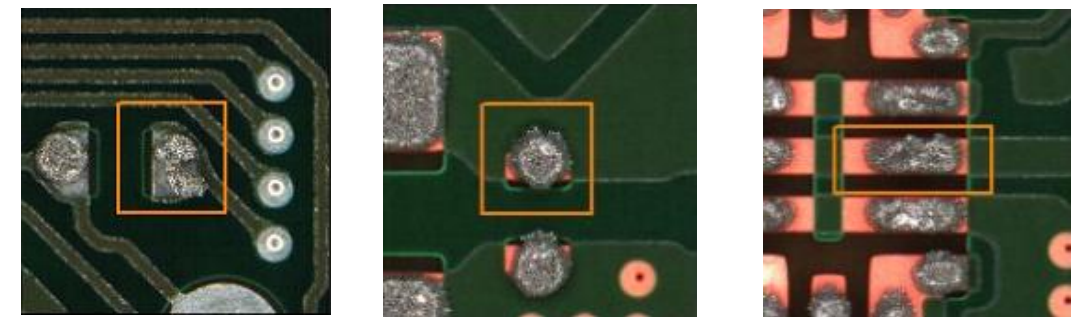
- Worn out or damaged squeegees;
- Exposure and mixing paste;
- Environment;
- Dirty or damaged tools;
- Gap between PCB and Stencil;
- Improper cleaning process inside of the printing machine;
- Contaminations;

### Corrective actions:

- Check printing parameters
- Check stencil and PCB support
- Check PCB warpage



Excessive due to contamination



Real defect



# Solder Paste Printing – Printing Issues

## Bridging Printing

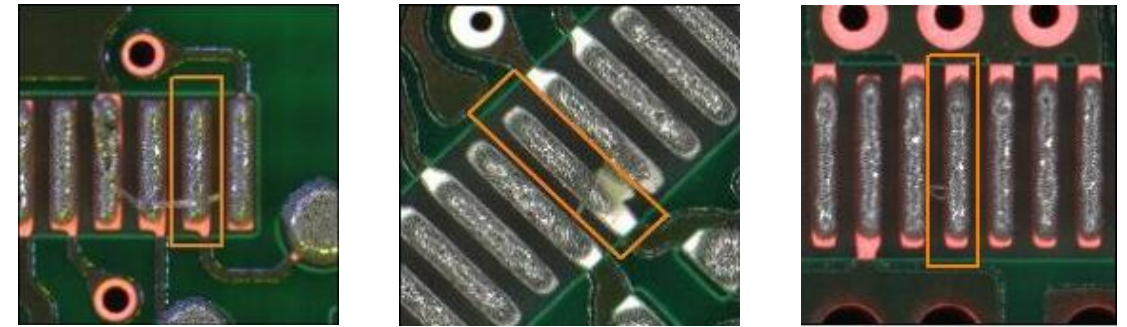
- **Bridging:** Excessive solder paste can lead to bridging between adjacent pads. Proper stencil design and paste selection can mitigate this issue.

### Possible causes:

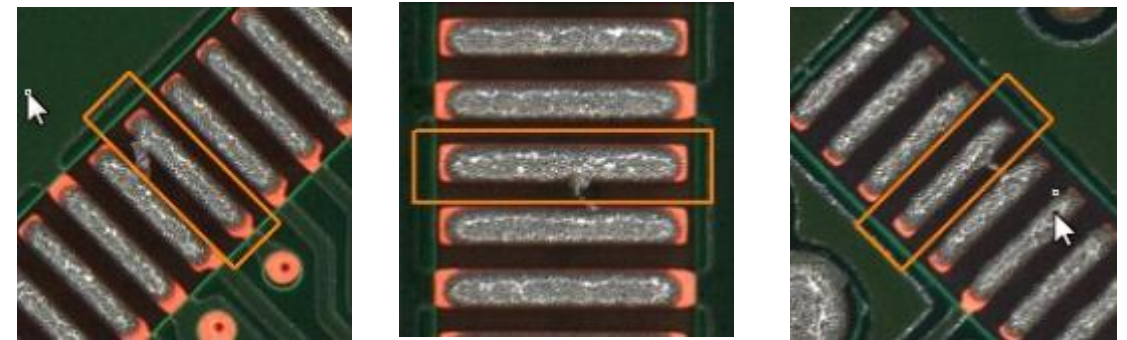
- Worn out or damaged squeegees;
- Exposure and mixing paste;
- Environment;
- Dirty or damaged tools;
- Gap between PCB vs Stencil;
- Improper cleaning process inside of the printing machine;
- Contaminations;

### Corrective actions:

- Check stencil bottom side
- Check cleaning frequency
- Check stencil position
- Check solder paste



Bridging due to contamination



Real defect



# Printing Application



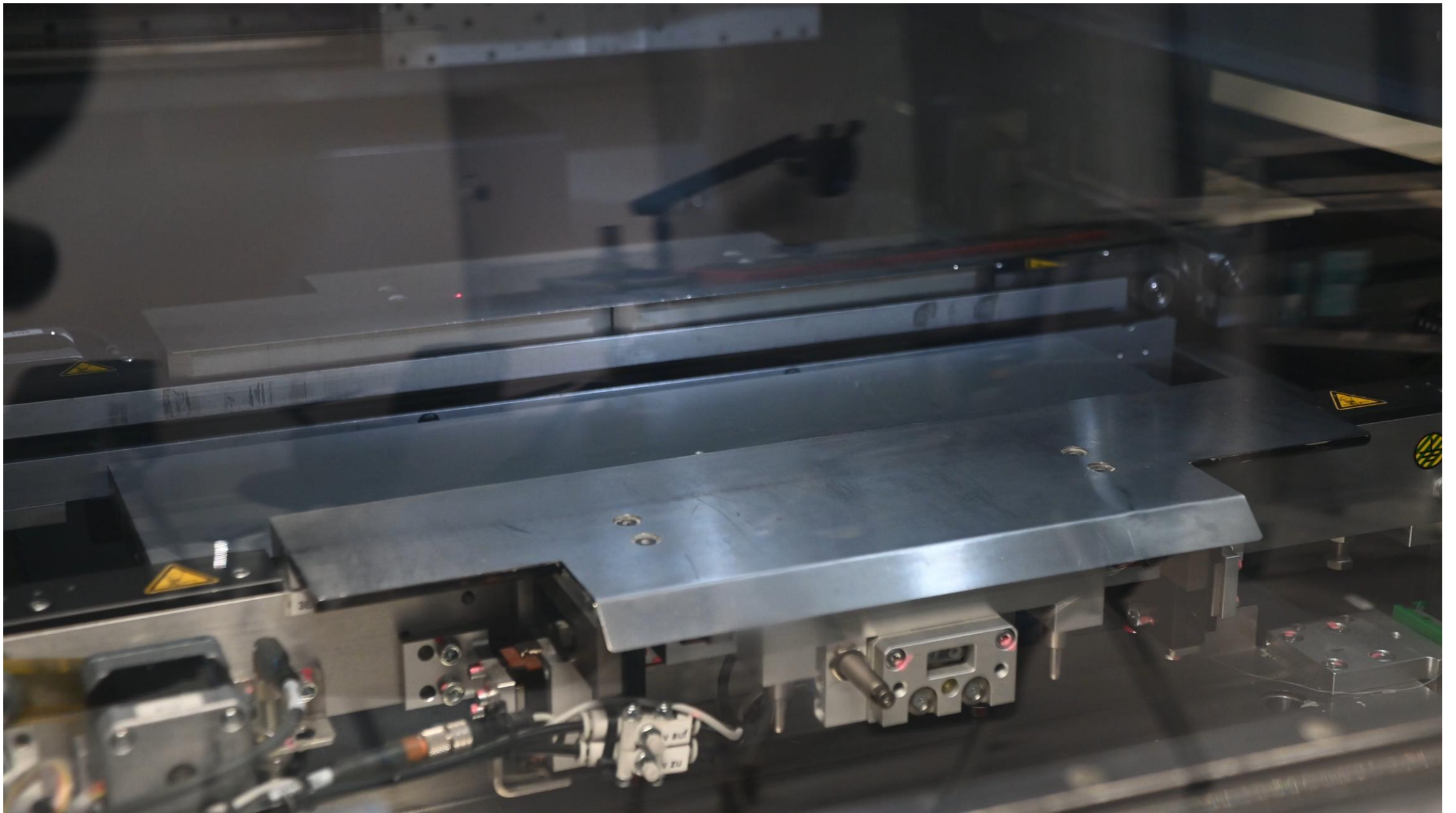
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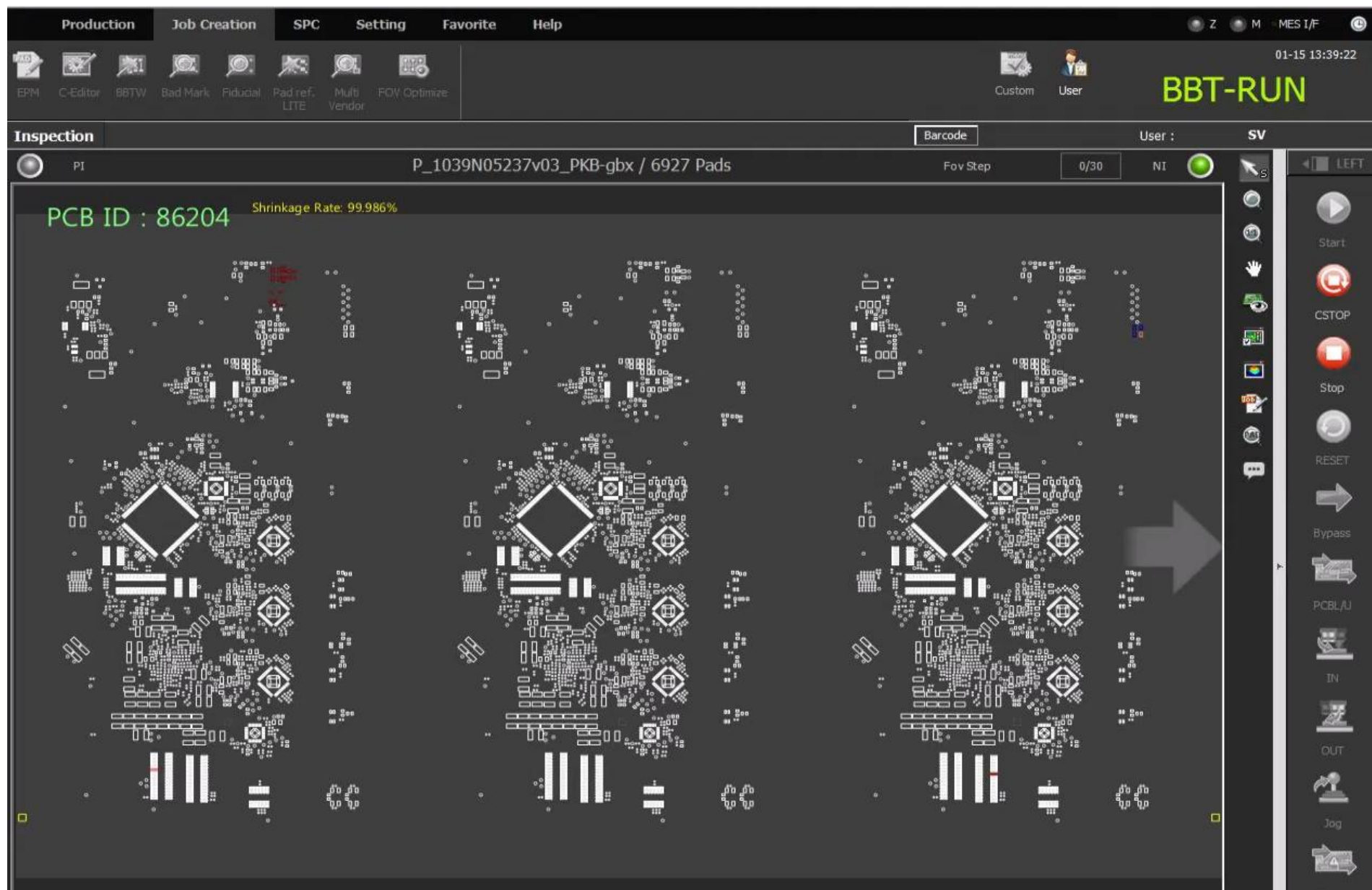


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The European Union's research and innovation programme





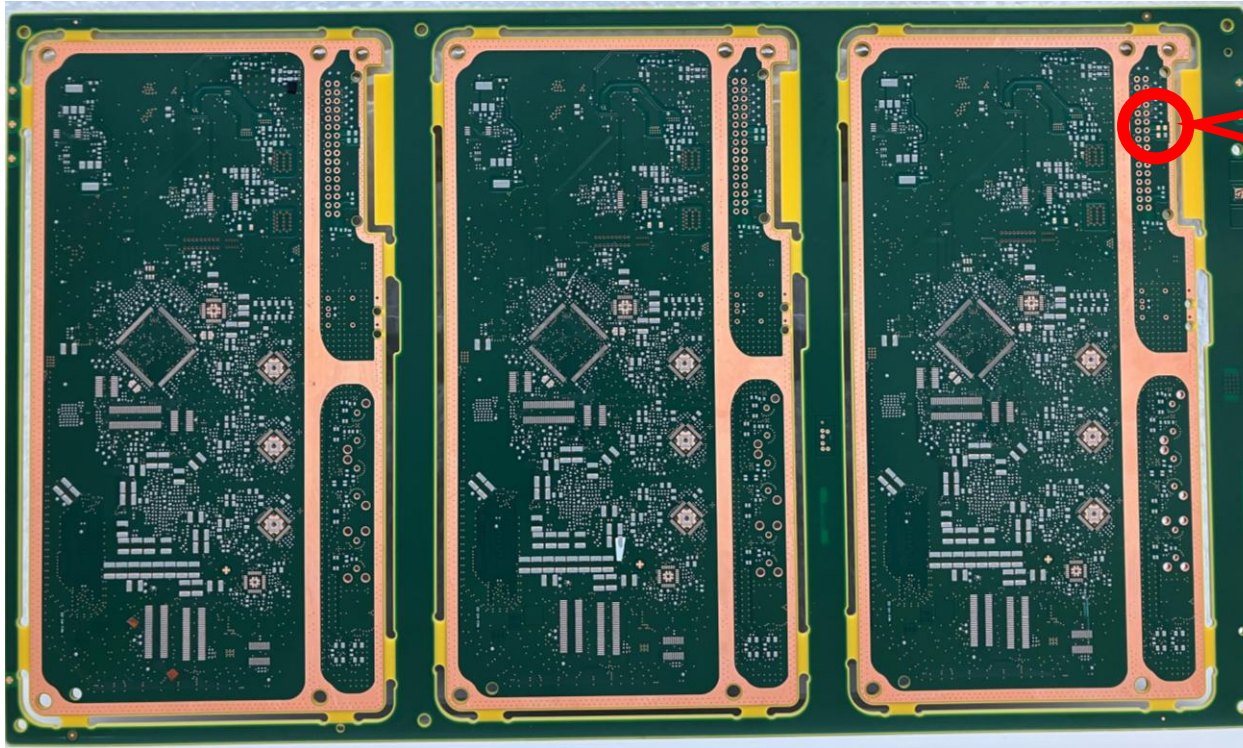
Co-funded by  
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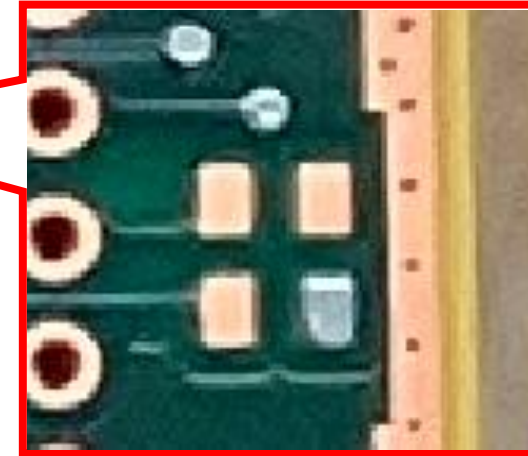


# Printing Application

## Insufficient printing

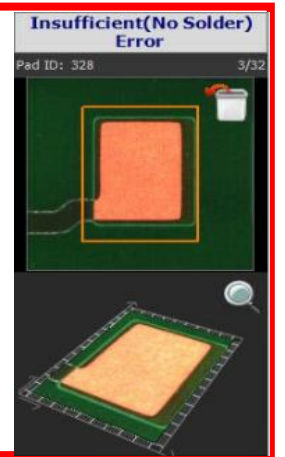


Real image



3 pads

SPI image



### Possible causes:

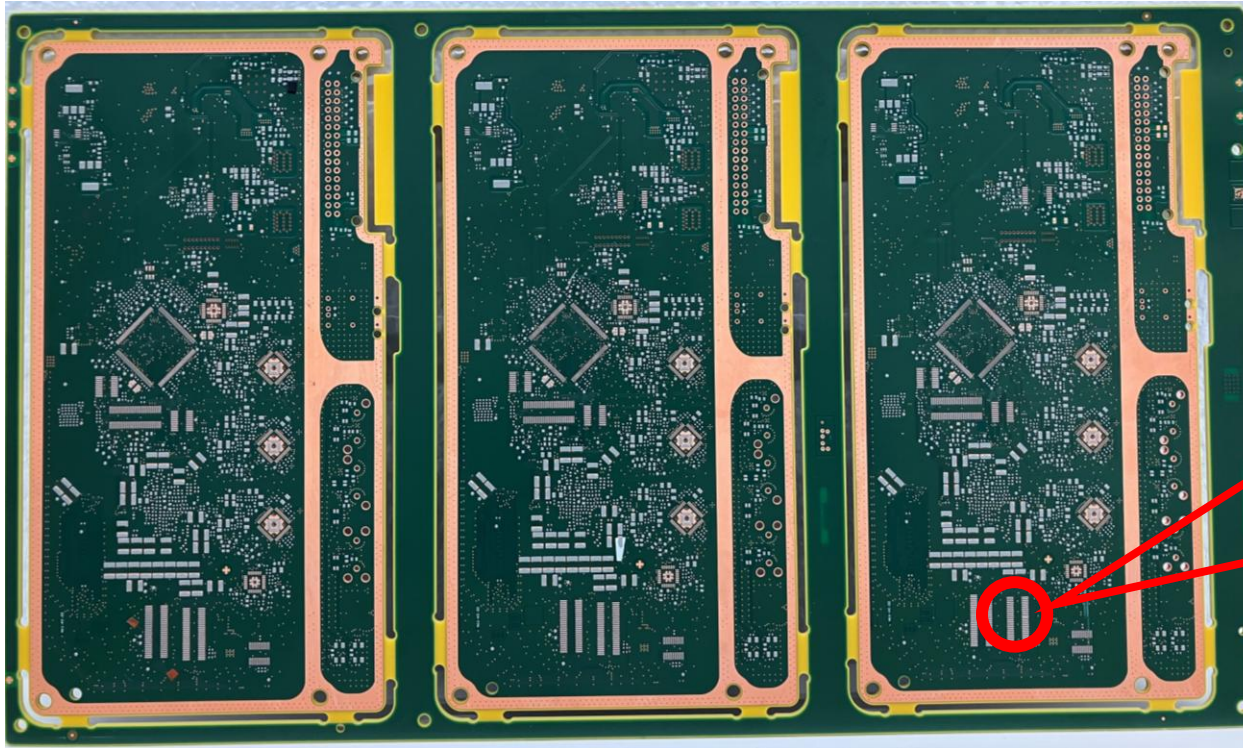
- Clogged aperture due to paste deposit or contamination;

### Corrective actions:

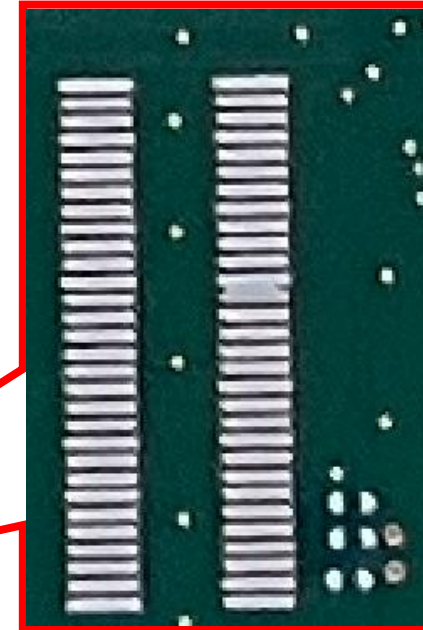
- Scrap the PCB;
- Clean the stencil;
- Check the equipment;

# Printing Application

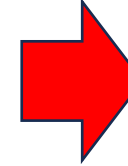
## Bridging



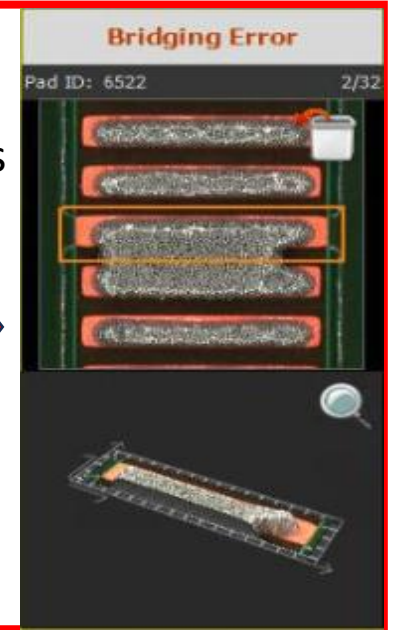
Real image



2 pads



SPI image



### Possible causes:

- Damaged aperture due to manipulation or worn out;

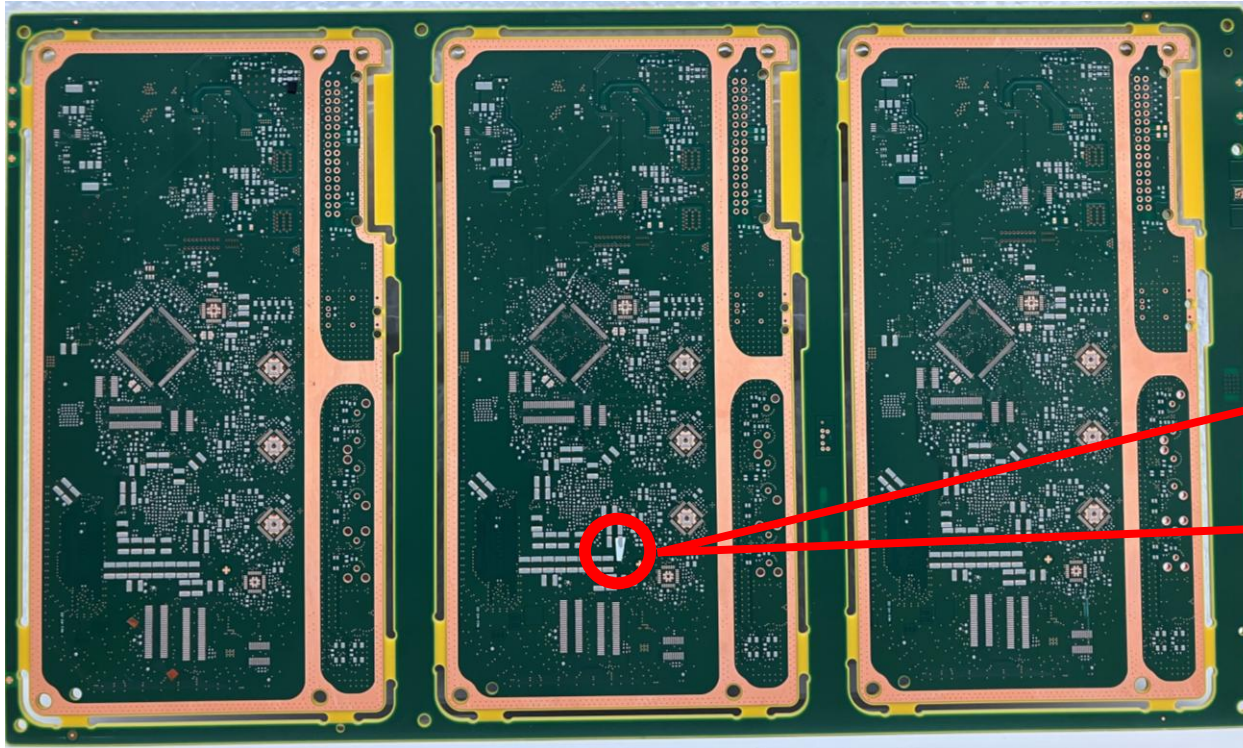
### Corrective actions:

- Scrap the PCB;
- Replace the stencil;

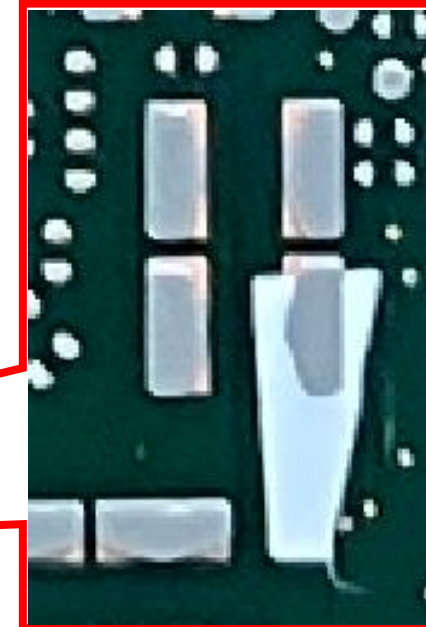


# Printing Application

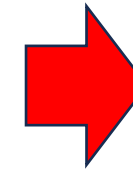
## Excessive printing



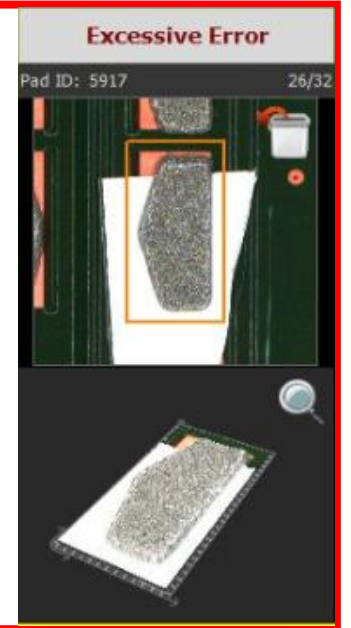
Real image



1 pad



SPI image



### Possible causes:

- Raw material or external factors;

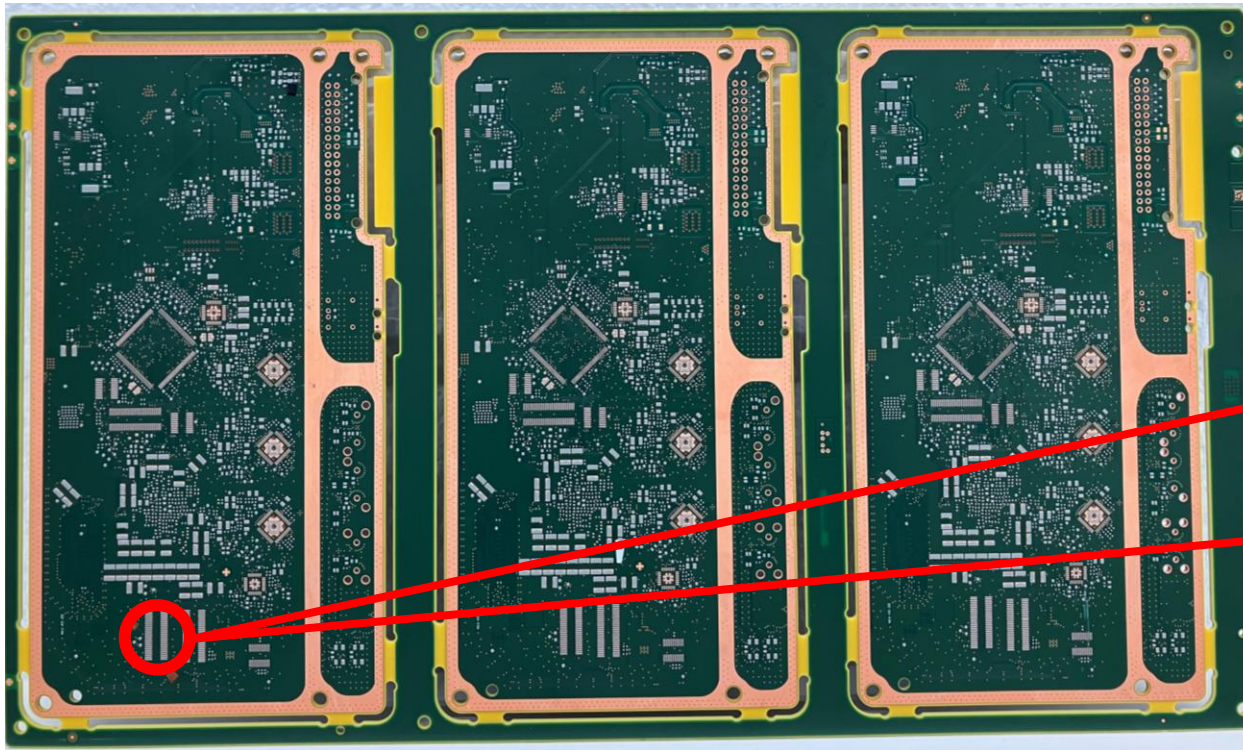
### Corrective actions:

- Scrap the PCB;
- Check the cleaning station;
- Check the equipment;
- Check the raw material;

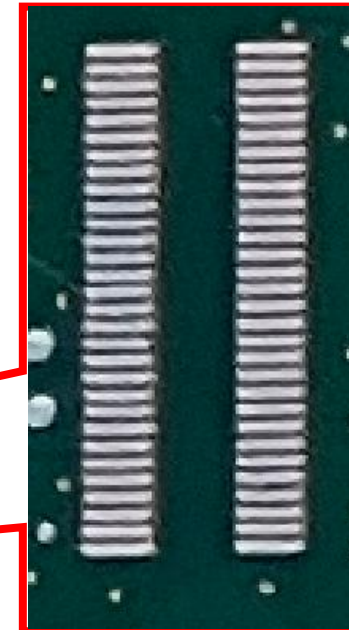


# Printing Application

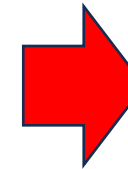
## Bridging



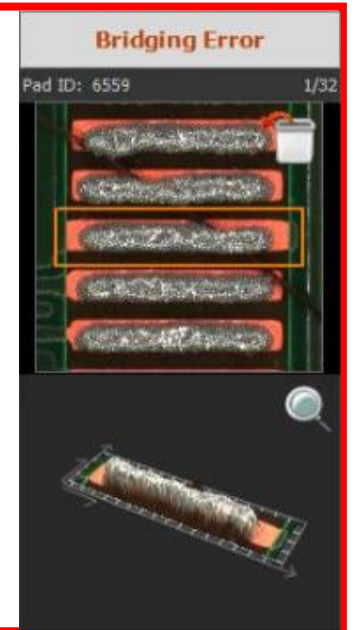
Real image



Several  
pads



SPI image



### Possible causes:

- Raw material or external factors;

### Corrective actions:

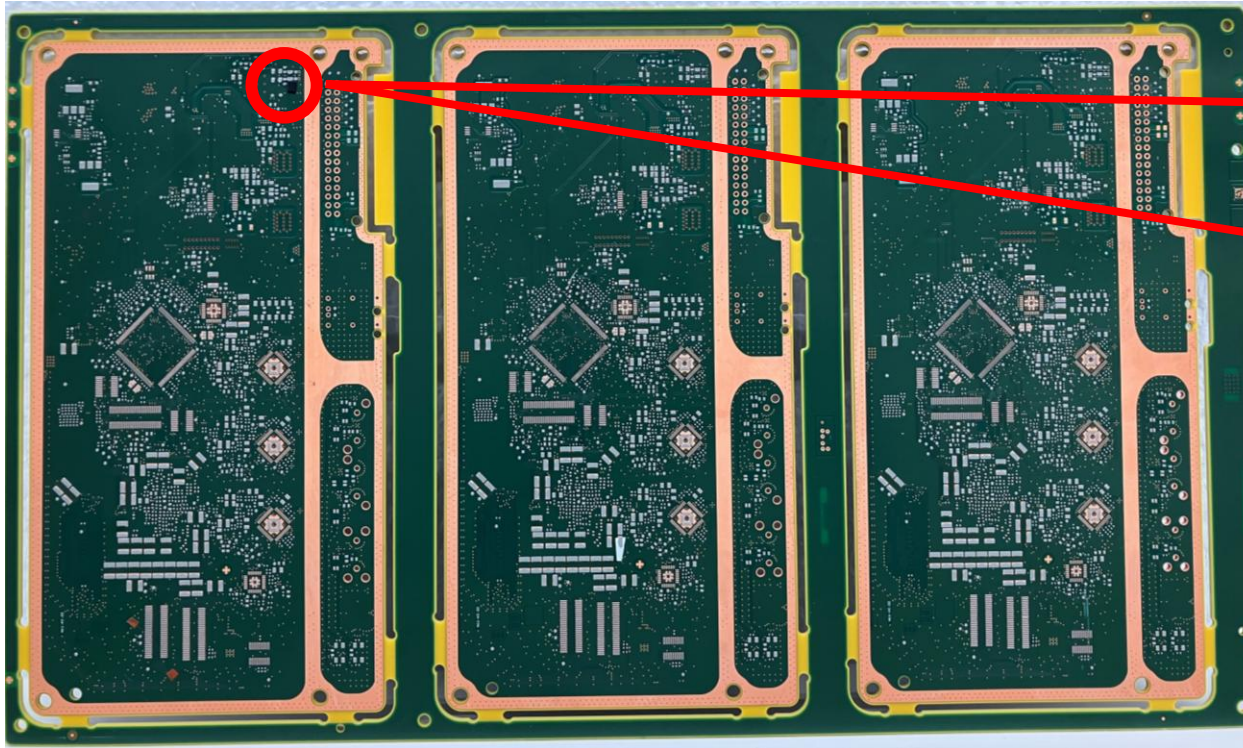
- Scrap the PCB;
- Check the cleaning station;
- Check the equipment;
- Check the raw material;



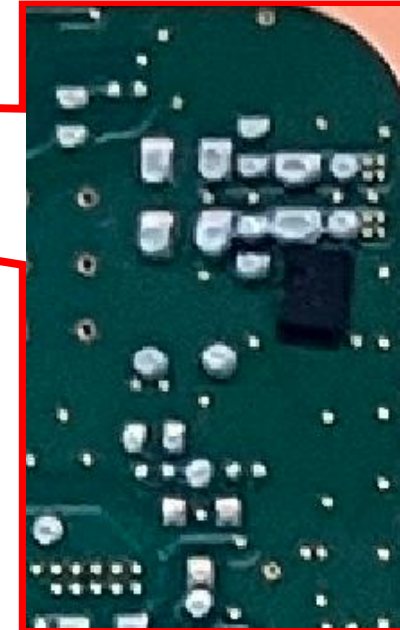


# Printing Application

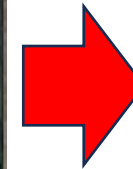
## Excessive printing



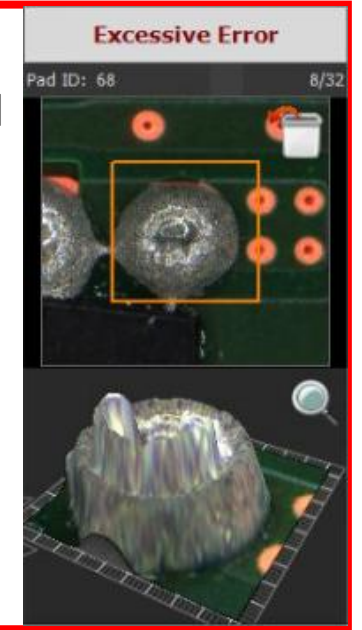
Real image



Several pads



SPI image



### Possible causes:

- Raw material or external factors;

### Corrective actions:

- Scrap the PCB;
- Check the cleaning station;
- Check the equipment;
- Check the raw material;





# Quiz

## 1. What is a quality gate?

A quality gate in the SMT industry is a checkpoint where products are inspected to ensure they meet standards, identifying defects early to maintain quality and prevent downstream issues.

## 2. What are the tools used in Solder Paste Printing Process?

- ❖ PCB support
- ❖ Stencil
- ❖ Squeegees
- ❖ Solder paste

## 3. What are common defects in solder paste printing, and their causes?

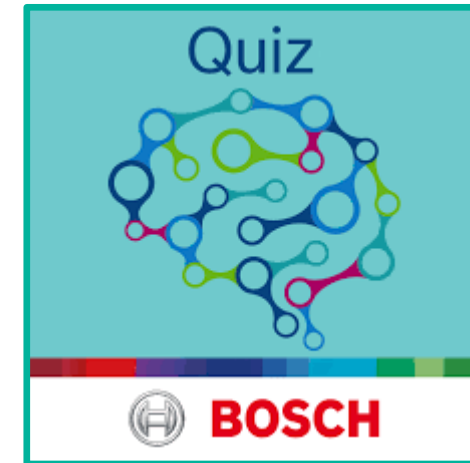
- ❖ Insufficient paste: Caused by blocked stencil apertures or improper squeegee pressure.
- ❖ Excessive paste: Due to damaged stencils or too much squeegee pressure.
- ❖ Offset printing: Stencil misalignment with the PCB. Solder bridging: Paste spreads between adjacent pads, often due to excessive paste or stencil design flaws.

## 4. What actions can be taken if an offset printing defect is detected?

Actions include recalibrating the stencil alignment, cleaning and reprinting the affected PCB, and verifying the stencil's condition.

## 5. What are the critical parameters in the solder paste printing process?

Key parameters include stencil alignment, squeegee pressure, squeegee speed, stencil thickness, and solder paste properties such as viscosity and particle size.



# Conclusions

In conclusion, today we've covered the essential elements of the **Solder Paste Printing Process** in the **SMT industry**. We started with a comprehensive introduction to **Surface Mount Technology (SMT)**, outlining the SMT line, the process flow, and the critical parameters that influence solder paste printing quality.

We explored the **Solder Paste Printing Process** in detail, focusing on the working concept of printing machines and the tools used to ensure precise and efficient paste application. Moving on, we emphasized the importance of **Alignment between pads and apertures**, along with a practical exercise on how to apply the correct offset on the machine to achieve perfect alignment.

Finally, we discussed common **Printing Issues** and the factors that can influence them, highlighting the need for constant monitoring and adjustments to prevent defects.

Understanding these key steps and techniques is crucial for ensuring the **quality and reliability** of SMT assemblies, which are essential for high-performance electronic devices. **With this knowledge, you are now equipped to address the challenges and optimize the solder paste printing process for better outcomes in future projects.**

Thank you for your attention, and I look forward to your questions!





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